

MSP430F677xA, MSP430F676xA, MSP430F674xA Polyphase Metering SoCs

1 Device Overview

1.1 Features

- Accuracy < 0.1% Over 2000:1 Dynamic Range for Phase Current
- Meets or Exceeds ANSI C12.20 and IEC 62053 Standards
- Support for Multiple Sensors Such as Current Transformers, Rogowski Coils, or Shunts
- Power Measurement for up to Three Phases Plus Neutral
- Dedicated Pulse Output Pins for Active and Reactive Energy for Calibration
- 4-Quadrant Measurement per Phase or Cumulative
- Exact Phase-Angle Measurements
- Digital Phase Correction for Current Transformers
- Temperature-Compensated Energy Measurements
- 40-Hz to 70-Hz Line Frequency Range Using Single Calibration
- Flexible Power Supply Options With Automatic Switching
- Display Operates at Very Low Power During AC Mains Failure: 3 μ A in LPM3
- LCD Driver With Contrast Control for up to 320 Segments
- Password-Protected Real-Time Clock (RTC) With Tamper Detection, Crystal Offset Calibration, and Temperature Compensation
- Integrated Security Modules to Support Anti-Tamper and Encryption
- Multiple Communication Interfaces for Smart Meter Implementations
- High-Performance Analog
 - Up to Seven Independent 24-Bit Sigma-Delta ADCs With Differential Inputs and Variable Gain
 - 10-Bit 200-ksps SAR ADC With Six External Channels and Two Internal Channels, Including Supply and Temperature Sensor Measurement
- Highly Integrated Digital
 - Three-Channel Direct Memory Access (DMA) Controller
 - Integrated Hardware AES-128 Module for Encryption
 - 16-Bit Cyclic Redundancy Check (CRC) Module
 - Four 16-Bit Timers With Nine Total Capture/Compare Registers
- Six Enhanced Universal Serial Communication Interfaces (eUSCIs)
 - eUSCI_A0, eUSCI_A1, eUSCI_A2, and eUSCI_A3 Support UART, IrDA, and SPI
 - eUSCI_B0, eUSCI_B1 Support SPI and I²C
- Ultra-Low Power Consumption
 - Multiple Low-Power Modes
 - Standby Mode (LPM3): 2.1 μ A at 3 V, Wake up in Less Than 5 μ s
 - RTC Mode (LPM3.5): 0.34 μ A at 3 V
 - Shutdown Mode (LPM4.5): 0.18 μ A at 3 V
- CPU
 - High-Performance 25-MHz CPU With 32-Bit Multiplier
 - Wide Input Supply Voltage Range: 3.6 V Down to 1.8 V
- Memory
 - Up to 512KB of Single-Cycle Flash
 - Up to 32KB of RAM With Single-Cycle Access
- Package Options
 - 128-Pin LQFP (PEU) Package With 90 I/O Pins
 - 100-Pin LQFP (PZ) Package With 62 I/O Pins
- Development Tools (Also See [Tools and Software](#))
 - Energy Measurement Design Center for MSP430 MCUs with 24-Bit Sigma-Delta ADCs ([MSP-EM-DESIGN-CENTER](#))
 - Three-Phase Electronic Watt-Hour EVM for Metering ([EVM430-F6779](#))
 - Target Development Board ([MSP-TS430PEU128](#))

1.2 Applications

- 3-Phase Electronic Watt-Hour Meters
- Utility Metering
- Energy Monitoring



1.3 Description

MSP430F67xxA polyphase metering SoCs are powerful highly integrated solutions that offer high accuracy and low system cost with few external components. The MSP430F67xxA microcontroller (MCU) family is part of the MSP430™ Metrology and Monitoring MCU portfolio targeting energy measurement and power monitoring applications including smart grid and building automation.

MSP430F67xxA MCUs feature up to seven independent 24-bit sigma-delta ADCs that can provide better than 0.1% accuracy. MSP430F67xxA devices integrate a high-performance MSP430 CPU with a 32-bit multiplier to perform all metrology calculations. Family members include up to 512KB of flash, 32KB of RAM, and an LCD controller with support for up to 320 segments.

The ultra-low power consumption of the MSP430F67xxA enables the system power supply to be minimized to reduce overall cost. Low standby power requires minimal energy storage, and critical data can be retained longer in case of a mains power failure.

The MSP430F67xxA MCU family is supported by an extensive software and hardware ecosystem. The Texas Instruments [Energy Measurement Design Center \(EMDC\)](#) can simplify development and accelerate designs by quickly configuring the [Energy Measurement software library](#), automatically generating code, performing calibration, and viewing results. MSP430F67xxA MCUs execute the Energy Measurement software library, which calculates all relevant energy and power results. Development kits include the [EVM430-F6779](#) three-phase electricity meter evaluation module and the [MSP-TS430PEU128](#) 128-pin target development board. Industry standard development tools and hardware platforms are available to speed development of meters that meet all of the ANSI and IEC standards globally.

For complete module descriptions, see the [MSP430F5xx and MSP430F6xx Family User's Guide](#).

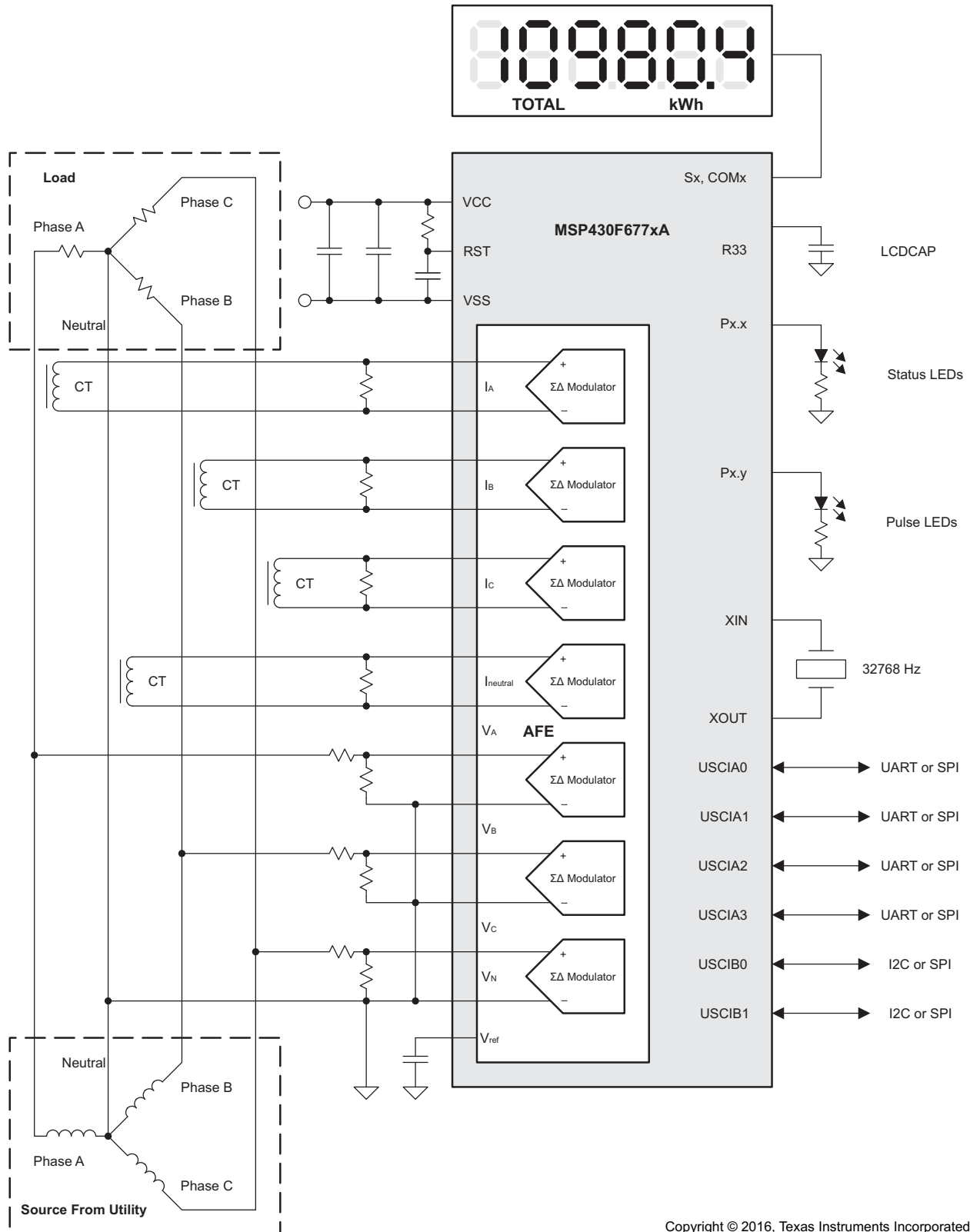
Device Information⁽¹⁾

| PART NUMBER | PACKAGE | BODY SIZE ⁽²⁾ |
|-----------------|------------|--------------------------|
| MSP430F6779AIPZ | LQFP (128) | 20 mm x 14 mm |
| MSP430F6779AIPZ | LQFP (100) | 14 mm x 14 mm |

- (1) For the most current part, package, and ordering information, see the *Package Option Addendum* in [Section 9](#), or see the TI website at www.ti.com.
(2) The dimensions shown here are approximations. For the package dimensions with tolerances, see the *Mechanical Data* in [Section 9](#).

1.4 Application Diagram

Figure 1-1 shows a typical application diagram.



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Figure 1-1. 3-Phase 4-Wire Star Connection Using MSP430F677xA

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2 Revision History

| Changes from May 29, 2014 to September 28, 2018 | Page |
|--|---------------------|
| • Updated Section 1.1, Features | 1 |
| • Updated Section 1.3, Description | 2 |
| • Added Section 3.1, Related Products | 7 |
| • Corrected the port number (P4.2) on pin 61 in Figure 4-2, 100-Pin PZ Package (Top View) | 10 |
| • Added note to P1.3/ADC10CLK/A3 (pin 8) in Table 4-3, Terminal Functions – PEU Package | 12 |
| • Added typical conditions statements at the beginning of Section 5, Specifications | 26 |
| • Added SD24_B input pins and AUXVCCx pins to exception list on "Voltage applied to pins" parameter, and added SD24_B input pin limits in "Diode current at pins" parameter in Section 5.1, Absolute Maximum Ratings | 26 |
| • Added Section 5.2, ESD Ratings | 26 |
| • Added Section 5.7, Thermal Resistance Characteristics | 31 |
| • Updated notes (1) and (2) and added note (3) in Table 5-1, Wake-up Times From Low-Power Modes and Reset .. | 32 |
| • Changed the TYP value of the $C_{L,eff}$ parameter with Test Conditions of "XTS = 0, XCAPx = 0" from 2 pF to 1 pF in Table 5-2, Crystal Oscillator, XT1, Low-Frequency Mode | 33 |
| • Corrected bit name in Test Conditions of R_{CHARGE} parameter (changed CHCx to AUXCHCx) in Table 5-25, Auxiliary Supplies, Charge Limiting Resistor | 44 |
| • Replaced f_{Frame} parameter with f_{LCD} , $f_{FRAME,4mux}$, and $f_{FRAME,8mux}$ parameters in Table 5-37, LCD_C, Operating Conditions | 52 |
| • On the $V_{ID,FS}$ parameter in Table 5-39, SD24_B Power Supply and Recommended Operating Conditions : Changed the MIN value from " $V_{REF}/GAIN$ " to " $-V_{REF}/GAIN$ "; Removed "Unipolar mode" test condition (mode is not supported) | 54 |
| • Removed ADC10DIV from the formula for the TYP value in the second row of the $t_{CONVERT}$ parameter in Table 5-48, 10-Bit ADC, Switching Characteristics , because ADC10CLK is after division..... | 60 |
| • Changed Test Conditions for all parameters in Table 5-49, 10-Bit ADC Linearity Parameters : Removed " V_{REF-} "; Changed from " $(V_{eREF+} - V_{eREF-})_{min} \leq (V_{eREF+} - V_{eREF-})$ " to " $1.4 V \leq (V_{eREF+} - V_{eREF-})$ "; Changed from " $C_{VREF+} = 20 pF$ " to " $C_{VeREF+} = 20 pF$ "; Added " $C_{VeREF+} = 20 pF$ " to E_i ; Added "ADC10SREFx = 11b" to E_T and E_G | 61 |
| • Changed from " V_{REF-}/V_{eREF-} " to " V_{eREF-} " in Test Conditions for V_{eREF+} , V_{eREF-} , and $(V_{eREF+} - V_{eREF-})$ parameters in Table 5-50, 10-Bit ADC, External Reference | 61 |
| • Changed the MIN value of $A_{VCC(min)}$ with Test Conditions of "REFVSEL = {0} for 1.5 V" from 2.2 V to 1.8 V in Table 5-51, REF Built-In Reference | 62 |
| • Changed the MAX value of the $t_{EN,CMP}$ parameter with Test Conditions of "CBPWRMD = 10" from 50 μs to 100 μs in Table 5-52, Comparator_B | 63 |
| • Corrected the name of the RTC module (changed from RTC_CE to RTC_C) in Figure 6-1, Functional Block Diagram – PEU Package | 66 |
| • Corrected the name of the RTC module (changed from RTC_CE to RTC_C) in Figure 6-2, Functional Block Diagram – PZ Package | 66 |
| • Throughout document, changed all instances of "bootstrap loader" to "bootloader"..... | 72 |
| • Corrected spelling of NMIFG in Table 6-13, System Module Interrupt Vector Registers | 80 |
| • Deleted mention of counter mode in Section 6.11.22, Real-Time Clock (RTC_C) (feature is not supported in this device) | 85 |
| • Replaced former section <i>Development Tools Support</i> with Section 8.3, Tools and Software | 165 |
| • Changed format and added content to Section 8.4, Documentation Support | 167 |

3 Device Comparison

Table 3-1 summarizes the available family members.

Table 3-1. Device Comparison⁽¹⁾⁽²⁾

| DEVICE | FLASH (KB) | SRAM (KB) | SD24_B CONVERTERS | ADC10_A CHANNELS | Timer_A ⁽³⁾ | eUSCI | | I/Os | PACKAGE |
|-----------------|------------|-----------|-------------------|------------------|------------------------|----------------------------|----------------------------------|------|---------|
| | | | | | | CHANNEL A: UART, IrDA, SPI | CHANNEL B: SPI, I ² C | | |
| MSP430F6779AIEU | 512 | 32 | 7 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6778AIEU | 512 | 16 | 7 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6777AIEU | 256 | 32 | 7 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6776AIEU | 256 | 16 | 7 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6775AIEU | 128 | 16 | 7 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6769AIEU | 512 | 32 | 6 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6768AIEU | 512 | 16 | 6 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6767AIEU | 256 | 32 | 6 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6766AIEU | 256 | 16 | 6 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6765AIEU | 128 | 16 | 6 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6749AIEU | 512 | 32 | 4 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6748AIEU | 512 | 16 | 4 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6747AIEU | 256 | 32 | 4 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6746AIEU | 256 | 16 | 4 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6745AIEU | 128 | 16 | 4 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 90 | 128 PEU |
| MSP430F6779AIPZ | 512 | 32 | 7 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6778AIPZ | 512 | 16 | 7 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6777AIPZ | 256 | 32 | 7 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6776AIPZ | 256 | 16 | 7 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6775AIPZ | 128 | 16 | 7 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6769AIPZ | 512 | 32 | 6 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6768AIPZ | 512 | 16 | 6 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6767AIPZ | 256 | 32 | 6 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6766AIPZ | 256 | 16 | 6 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6765AIPZ | 128 | 16 | 6 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6749AIPZ | 512 | 32 | 4 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6748AIPZ | 512 | 16 | 4 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6747AIPZ | 256 | 32 | 4 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6746AIPZ | 256 | 16 | 4 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |
| MSP430F6745AIPZ | 128 | 16 | 4 | 6 ext, 2 int | 3, 2, 2, 2 | 4 | 2 | 62 | 100 PZ |

- (1) For the most current package and ordering information, see the *Package Option Addendum* in [Section 9](#), or see the TI website at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
- (3) Each number in the sequence represents an instantiation of Timer_A with its associated number of capture/compare registers and PWM output generators available. For example, a number sequence of 3, 5 would represent two instantiations of Timer_A, the first instantiation having 3 and the second instantiation having 5 capture/compare registers and PWM output generators, respectively.

3.1 Related Products

For information about other devices in this family of products or related products, see the following links.

Products for TI Microcontrollers TI's low-power and high-performance MCUs, with wired and wireless connectivity options, are optimized for a broad range of applications.

Products for MSP430 Ultra-Low-Power Microcontrollers One platform. One ecosystem. Endless possibilities. Enabling the connected world with innovations in ultra-low-power microcontrollers with advanced peripherals for precise sensing and measurement.

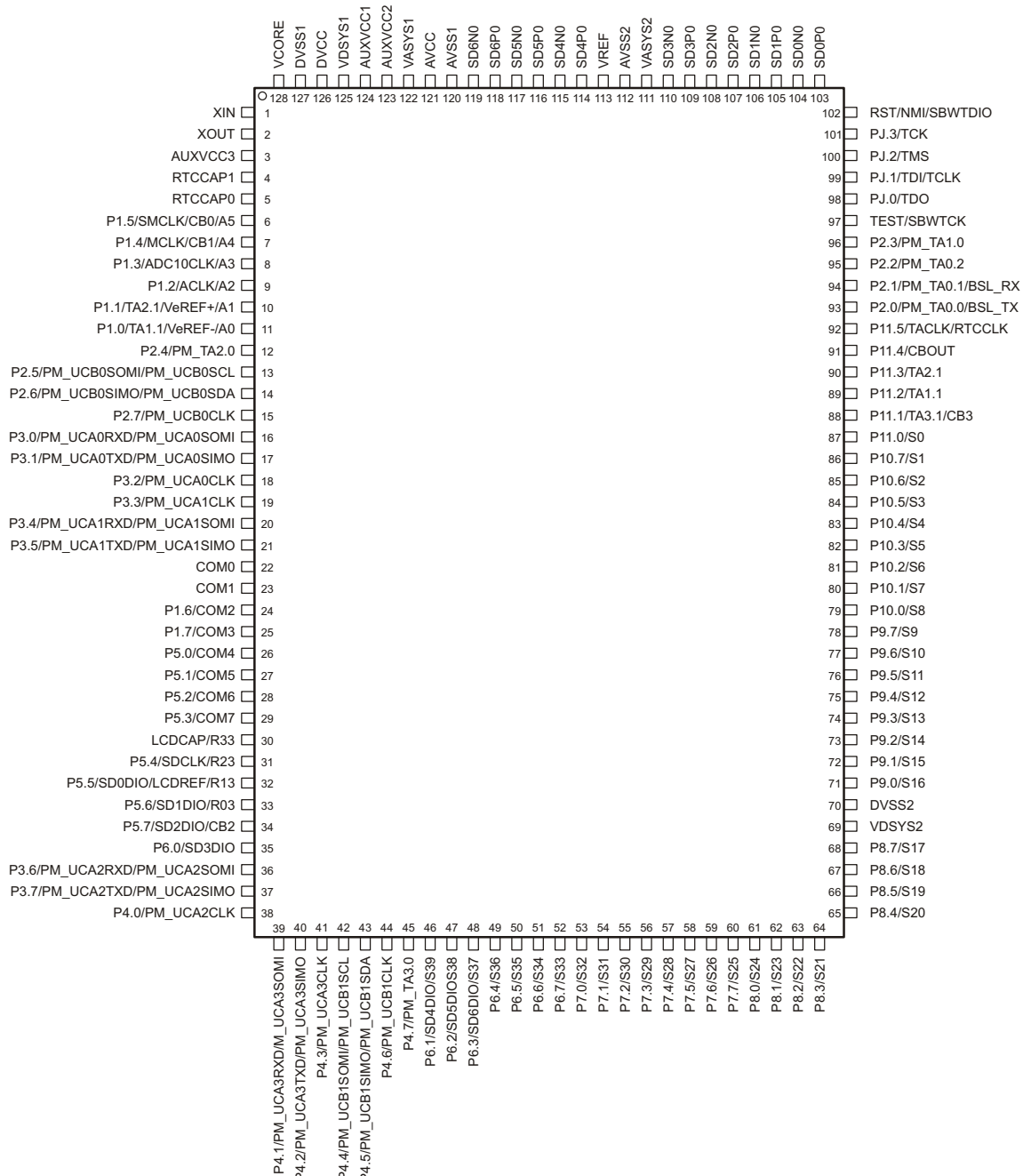
Companion Products for MSP430F6779A Review products that are frequently purchased or used with this product.

Reference Designs for MSP430F6779A The TI Designs Reference Design Library is a robust reference design library that spans analog, embedded processor, and connectivity. Created by TI experts to help you jump start your system design, all TI Designs include schematic or block diagrams, BOMs, and design files to speed your time to market.

4 Terminal Configuration and Functions

4.1 Pin Diagrams

Figure 4-1 shows the pinout for the 128-pin PEU package. Table 4-1 summarizes the differences in the pinout among the device variants.



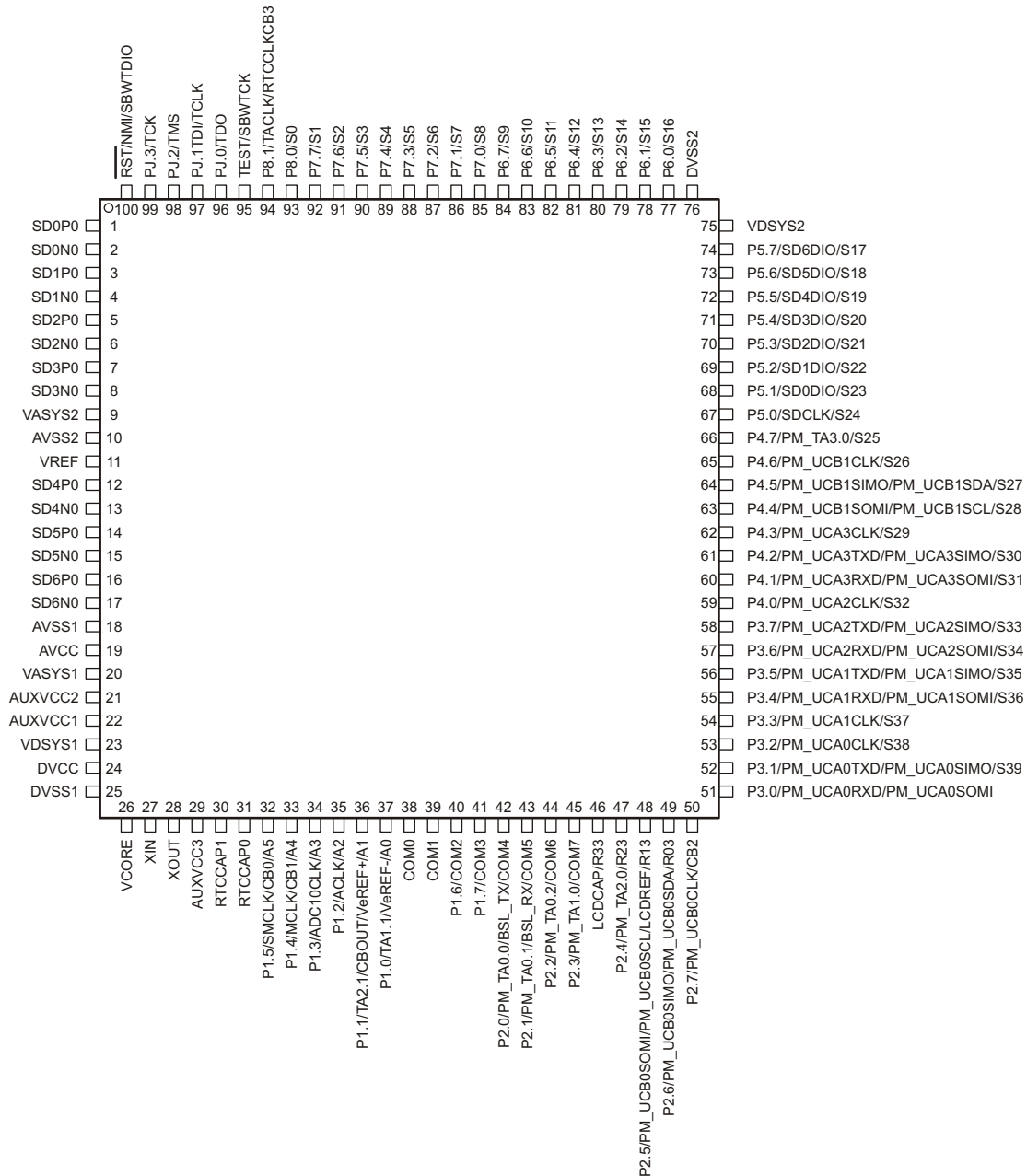
- The secondary digital functions on Ports P2, P3, and P4 are fully mappable. This pinout shows only the default mapping. See Section 6.11.6 for details.
- The pair of pins VDSYS1 and VDSYS2, VASYS1 and VASYS2 must be connected externally on board for proper device operation.
- CAUTION:** The LCDCAP/R33 pin must be connected to DVSS if it is not used.

Figure 4-1. 128-Pin PEU Package (Top View)

Table 4-1. Pinout Differences for PEU Package, F677xA, F676xA, and F674xA

| PIN NUMBER | PIN NAME | | |
|------------|------------------|------------------|------------------|
| | MSP430F677xAIPEU | MSP430F676xAIPEU | MSP430F674xAIPEU |
| 46 | P6.1/SD4DIO/S39 | P6.1/SD4DIO/S39 | P6.1/S39 |
| 47 | P6.2/SD5DIO/S38 | P6.2/SD5DIO/S38 | P6.2/S38 |
| 48 | P6.3/SD6DIO/S37 | P6.3/S37 | P6.3/S37 |
| 113 | VREF | VREF | VREF |
| 114 | SD4P0 | SD4P0 | NC |
| 115 | SD4N0 | SD4N0 | NC |
| 116 | SD5P0 | SD5P0 | NC |
| 117 | SD5N0 | SD5NO | NC |
| 118 | SD6P0 | NC | NC |
| 119 | SD6N0 | NC | NC |

Figure 4-2 shows the pinout for the 100-pin PZ package. Table 4-2 summarizes the differences in the pinout among the device variants.



- The secondary digital functions on Ports P2, P3, and P4 are fully mappable. This pinout shows only the default mapping. See Section 6.11.6 for details.
- The pair of pins VDSYS1 and VDSYS2, VASYS1 and VASYS2 must be connected externally on board for proper device operation.
- CAUTION:** The LCDCAP/R33 pin must be connected to DVSS if it is not used.

Figure 4-2. 100-Pin PZ Package (Top View)

Table 4-2. Pinout Differences for PZ Package, F677xA, F676xA, and F674xA

| PIN NUMBER | PIN NAME | | |
|------------|-----------------|-----------------|-----------------|
| | MSP430F677xAIPZ | MSP430F676xAIPZ | MSP430F674xAIPZ |
| 11 | VREF | VREF | VREF |
| 12 | SD4P0 | SD4P0 | NC |
| 13 | SD4N0 | SD4N0 | NC |
| 14 | SD5P0 | SD5P0 | NC |
| 15 | SD5N0 | SD5NO | NC |
| 16 | SD6P0 | NC | NC |
| 17 | SD6N0 | NC | NC |
| 72 | P5.5/SD4DIO/S19 | P5.5/SD4DIO/S19 | P5.5/S19 |
| 73 | P5.6/SD5DIO/S18 | P5.6/SD5DIO/S18 | P5.6/S18 |
| 74 | P5.7/SD6DIO/S17 | P5.7/S17 | P5.7/S17 |

4.2 Signal Descriptions

Table 4-3 describes the signals for devices in the PEU package. See Table 4-4 for the signals in the PZ package.

Table 4-3. Terminal Functions – PEU Package

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|---------------------------------|------------|--------------------|---|
| NAME | NO. PEU | | |
| XIN | 1 | I/O | Input terminal for crystal oscillator |
| XOUT | 2 | I/O | Output terminal for crystal oscillator |
| AUXVCC3 | 3 | | Auxiliary power supply AUXVCC3 for backup subsystem |
| RTCCAP1 | 4 | I | External time capture pin 1 for RTC_C |
| RTCCAP0 | 5 | I | External time capture pin 0 for RTC_C |
| P1.5/SMCLK/CB0/A5 | 6 | I/O | General-purpose digital I/O with port interrupt SMCLK clock output Comparator_B input CB0 Analog input A5 for 10-bit ADC |
| P1.4/MCLK/CB1/A4 | 7 | I/O | General-purpose digital I/O with port interrupt MCLK clock output Comparator_B input CB1 Analog input A4 for 10-bit ADC |
| P1.3/ADC10CLK/A3 ⁽²⁾ | 8 | I/O | General-purpose digital I/O with port interrupt ADC10_A clock output Analog input A3 for 10-bit ADC |
| P1.2/ACLK/A2 | 9 | I/O | General-purpose digital I/O with port interrupt ACLK clock output Analog input A2 for 10-bit ADC |
| P1.1/TA2.1/VeREF+/A1 | 10 | I/O | General-purpose digital I/O with port interrupt Timer TA2 CCR1 capture: CCI1A input, compare: Out1 output Positive terminal for the ADC reference voltage for an external applied reference voltage Analog input A1 for 10-bit ADC |
| P1.0/TA1.1/VeREF-/A0 | 11 | I/O | General-purpose digital I/O with port interrupt Timer TA1 CCR1 capture: CCI1A input, compare: Out1 output Negative terminal for the ADC reference voltage for an external applied reference voltage Analog input A0 for 10-bit ADC |
| P2.4/PM_TA2.0 | 12 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: Timer TA2 capture CCR0: CCI0A input, compare: Out0 output |
| P2.5/PM_UCB0SOMI/ PM_UCB0SCL | 13 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: eUSCI_B0 SPI slave out master in Default mapping: eUSCI_B0 I ² C clock |
| P2.6/PM_UCB0SIMO/ PM_UCB0SDA | 14 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: eUSCI_B0 SPI slave in master out Default mapping: eUSCI_B0 I ² C data |
| P2.7/PM_UCB0CLK | 15 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: eUSCI_B0 clock input/output |

(1) I = input, O = output

(2) Before enabling the analog function (A3), pull this pin low by setting the port function to output low or to input with the internal pulldown resistor enabled.

Table 4-3. Terminal Functions – PEU Package (continued)

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|---------------------------------|------------|--------------------|--|
| NAME | NO. PEU | | |
| P3.0/PM_UCA0RXD/ PM_UCA0SOMI | 16 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A0 UART receive data Default mapping: eUSCI_A0 SPI slave out master in |
| P3.1/PM_UCA0TXD/ PM_UCA0SIMO | 17 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A0 UART transmit data Default mapping: eUSCI_A0 SPI slave in master out |
| P3.2/PM_UCA0CLK | 18 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A0 clock input/output |
| P3.3/PM_UCA1CLK | 19 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A1 clock input/output |
| P3.4/PM_UCA1RXD/ PM_UCA1SOMI | 20 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A1 UART receive data Default mapping: eUSCI_A1 SPI slave out master in |
| P3.5/PM_UCA1TXD/ PM_UCA1SIMO | 21 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A1 UART transmit data Default mapping: eUSCI_A1 SPI slave in master out |
| COM0 | 22 | O | LCD common output COM0 for LCD backplane |
| COM1 | 23 | O | LCD common output COM1 for LCD backplane |
| P1.6/COM2 | 24 | I/O | General-purpose digital I/O with port interrupt LCD common output COM2 for LCD backplane |
| P1.7/COM3 | 25 | I/O | General-purpose digital I/O with port interrupt LCD common output COM3 for LCD backplane |
| P5.0/COM4 | 26 | I/O | General-purpose digital I/O LCD common output COM4 for LCD backplane |
| P5.1/COM5 | 27 | I/O | General-purpose digital I/O LCD common output COM5 for LCD backplane |
| P5.2/COM6 | 28 | I/O | General-purpose digital I/O LCD common output COM6 for LCD backplane |
| P5.3/COM7 | 29 | I/O | General-purpose digital I/O LCD common output COM7 for LCD backplane |
| LCDCAP/R33 | 30 | I/O | LCD capacitor connection Input/output port of most positive analog LCD voltage (V1) CAUTION: This pin must be connected to DVSS if not used. |
| P5.4/SDCLK/R23 | 31 | I/O | General-purpose digital I/O SD24_B bit-stream clock input/output Input/Output port of second most positive analog LCD voltage (V2) |
| P5.5/SD0DIO/ LCDREF/R13 | 32 | I/O | General-purpose digital I/O SD24_B converter 0 bit-stream data input/output External reference voltage input for regulated LCD voltage Input/output port of third most positive analog LCD voltage (V3 or V4) |
| P5.6/SD1DIO/R03 | 33 | I/O | General-purpose digital I/O SD24_B converter 1 bit-stream data input/output Input/output port of lowest analog LCD voltage (V5) |

Table 4-3. Terminal Functions – PEU Package (continued)

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|---------------------------------|-----|--------------------|--|
| NAME | NO. | | |
| | PEU | | |
| P5.7/SD2DIO/CB2 | 34 | I/O | General-purpose digital I/O SD24_B converter 2 bit-stream data input/output Comparator_B input CB2 |
| P6.0/SD3DIO | 35 | I/O | General-purpose digital I/O SD24_B converter 3 bit-stream data input/output |
| P3.6/PM_UCA2RXD/ PM_UCA2SOMI | 36 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A2 UART receive data Default mapping: eUSCI_A2 SPI slave out master in |
| P3.7/PM_UCA2TXD/ PM_UCA2SIMO | 37 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A2 UART transmit data Default mapping: eUSCI_A2 SPI slave in master out |
| P4.0/PM_UCA2CLK | 38 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A2 clock input/output |
| P4.1/PM_UCA3RXD/ PM_UCA3SOMI | 39 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A3 UART receive data Default mapping: eUSCI_A3 SPI slave out master in |
| P4.2/PM_UCA3TXD/ PM_UCA3SIMO | 40 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A3 UART transmit data Default mapping: eUSCI_A3 SPI slave in master out |
| P4.3/PM_UCA3CLK | 41 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A3 clock input/output |
| P4.4/PM_UCB1SOMI/ PM_UCB1SCL | 42 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_B1 SPI slave out, master in Default mapping: eUSCI_B1 I ² C clock |
| P4.5/PM_UCB1SIMO/ PM_UCB1SDA | 43 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_B1 SPI slave in, master out Default mapping: eUSCI_B1 I ² C data |
| P4.6/PM_UCB1CLK | 44 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_B1 clock input/output |
| P4.7/PM_TA3.0 | 45 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: Timer TA3 capture CCR0: CCI0A input, compare: Out0 output |
| P6.1/SD4DIO/S39 | 46 | I/O | General-purpose digital I/O SD24_B converter 4 bit-stream data input/output (not available in F674xA devices) LCD segment output S39 |
| P6.2/SD5DIO/S38 | 47 | I/O | General-purpose digital I/O SD24_B converter 5 bit-stream data input/output (not available in F674xA devices) LCD segment output S38 |
| P6.3/SD6DIO/S37 | 48 | I/O | General-purpose digital I/O SD24_B converter 6 bit-stream data input/output (not available in F676xA, F674xA devices) LCD segment output S37 |
| P6.4/S36 | 49 | I/O | General-purpose digital I/O LCD segment output S36 |
| P6.5/S35 | 50 | I/O | General-purpose digital I/O LCD segment output S35 |

Table 4-3. Terminal Functions – PEU Package (continued)

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|-----------------------|------------|--------------------|---|
| NAME | NO. PEU | | |
| P6.6/S34 | 51 | I/O | General-purpose digital I/O LCD segment output S34 |
| P6.7/S33 | 52 | I/O | General-purpose digital I/O LCD segment output S33 |
| P7.0/S32 | 53 | I/O | General-purpose digital I/O LCD segment output S32 |
| P7.1/S31 | 54 | I/O | General-purpose digital I/O LCD segment output S31 |
| P7.2/S30 | 55 | I/O | General-purpose digital I/O LCD segment output S30 |
| P7.3/S29 | 56 | I/O | General-purpose digital I/O LCD segment output S29 |
| P7.4/S28 | 57 | I/O | General-purpose digital I/O LCD segment output S28 |
| P7.5/S27 | 58 | I/O | General-purpose digital I/O LCD segment output S27 |
| P7.6/S26 | 59 | I/O | General-purpose digital I/O LCD segment output S26 |
| P7.7/S25 | 60 | I/O | General-purpose digital I/O LCD segment output S25 |
| P8.0/S24 | 61 | I/O | General-purpose digital I/O LCD segment output S24 |
| P8.1/S23 | 62 | I/O | General-purpose digital I/O LCD segment output S23 |
| P8.2/S22 | 63 | I/O | General-purpose digital I/O LCD segment output S22 |
| P8.3/S21 | 64 | I/O | General-purpose digital I/O LCD segment output S21 |
| P8.4/S20 | 65 | I/O | General-purpose digital I/O LCD segment output S20 |
| P8.5/S19 | 66 | I/O | General-purpose digital I/O LCD segment output S19 |
| P8.6/S18 | 67 | I/O | General-purpose digital I/O LCD segment output S18 |
| P8.7/S17 | 68 | I/O | General-purpose digital I/O LCD segment output S17 |
| VDSYS2 ⁽³⁾ | 69 | | Digital power supply for I/Os |
| DVSS2 | 70 | | Digital ground supply |
| P9.0/S16 | 71 | I/O | General-purpose digital I/O LCD segment output S16 |
| P9.1/S15 | 72 | I/O | General-purpose digital I/O LCD segment output S15 |
| P9.2/S14 | 73 | I/O | General-purpose digital I/O LCD segment output S14 |

(3) The pins VDSYS1 and VDSYS2 must be connected externally on board for proper device operation.

Table 4-3. Terminal Functions – PEU Package (continued)

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|----------------------|------------|--------------------|--|
| NAME | NO. PEU | | |
| P9.3/S13 | 74 | I/O | General-purpose digital I/O LCD segment output S13 |
| P9.4/S12 | 75 | I/O | General-purpose digital I/O LCD segment output S12 |
| P9.5/S11 | 76 | I/O | General-purpose digital I/O LCD segment output S11 |
| P9.6/S10 | 77 | I/O | General-purpose digital I/O LCD segment output S10 |
| P9.7/S9 | 78 | I/O | General-purpose digital I/O LCD segment output S9 |
| P10.0/S8 | 79 | I/O | General-purpose digital I/O LCD segment output S8 |
| P10.1/S7 | 80 | I/O | General-purpose digital I/O LCD segment output S7 |
| P10.2/S6 | 81 | I/O | General-purpose digital I/O LCD segment output S6 |
| P10.3/S5 | 82 | I/O | General-purpose digital I/O LCD segment output S5 |
| P10.4/S4 | 83 | I/O | General-purpose digital I/O LCD segment output S4 |
| P10.5/S3 | 84 | I/O | General-purpose digital I/O LCD segment output S3 |
| P10.6/S2 | 85 | I/O | General-purpose digital I/O LCD segment output S2 |
| P10.7/S1 | 86 | I/O | General-purpose digital I/O LCD segment output S1 |
| P11.0/S0 | 87 | I/O | General-purpose digital I/O LCD segment output S0 |
| P11.1/TA3.1/CB3 | 88 | I/O | General-purpose digital I/O Timer TA3 capture CCR1: CCI1A input, compare: Out1 output Comparator_B input CB3 |
| P11.2/TA1.1 | 89 | I/O | General-purpose digital I/O Timer TA1 capture CCR1: CCI1A input, compare: Out1 output |
| P11.3/TA2.1 | 90 | I/O | General-purpose digital I/O Timer TA2 capture CCR1: CCI1A input, compare: Out1 output |
| P11.4/CBOUT | 91 | I/O | General-purpose digital I/O Comparator_B output |
| P11.5/TACLK/RTCCLK | 92 | I/O | General-purpose digital I/O Timer clock input TACLK for TA0, TA1, TA2, TA3 RTCCLK clock output |
| P2.0/PM_TA0.0/BSL_TX | 93 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: Timer TA0 capture CCR0: CCI0A input, compare: Out0 output Bootloader: Data transmit |

Table 4-3. Terminal Functions – PEU Package (continued)

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|-------------------------------------|------------|--------------------|---|
| NAME | NO. PEU | | |
| P2.1/PM_TA0.1/BSL_RX | 94 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: Timer TA0 capture CCR1: CCI1A input, compare: Out1 output Bootloader: Data receive |
| P2.2/PM_TA0.2 | 95 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: Timer TA0 capture CCR2: CCI2A input, compare: Out2 output |
| P2.3/PM_TA1.0 | 96 | I/O | General-purpose digital I/O port interrupt and with mappable secondary function Default mapping: Timer TA1 capture CCR0: CCI0A input, compare: Out0 output |
| TEST/SBWTCK | 97 | I | Test mode pin – select digital I/O on JTAG pins Spy-Bi-Wire input clock |
| PJ.0/TDO | 98 | I/O | General-purpose digital I/O Test data output |
| PJ.1/TDI/TCLK | 99 | I/O | General-purpose digital I/O Test data input Test clock input |
| PJ.2/TMS | 100 | I/O | General-purpose digital I/O Test mode select |
| PJ.3/TCK | 101 | I/O | General-purpose digital I/O Test clock |
| $\overline{\text{RST}}$ /NMI/SBWDIO | 102 | I/O | Reset input, active-low ⁽⁴⁾ Nonmaskable interrupt input Spy-By-Wire data input/output |
| SD0P0 | 103 | I | SD24_B positive analog input for converter 0 ⁽⁵⁾ |
| SD0N0 | 104 | I | SD24_B negative analog input for converter 0 ⁽⁵⁾ |
| SD1P0 | 105 | I | SD24_B positive analog input for converter 1 ⁽⁵⁾ |
| SD1N0 | 106 | I | SD24_B negative analog input for converter 1 ⁽⁵⁾ |
| SD2P0 | 107 | I | SD24_B positive analog input for converter 2 ⁽⁵⁾ |
| SD2N0 | 108 | I | SD24_B negative analog input for converter 2 ⁽⁵⁾ |
| SD3P0 | 109 | I | SD24_B positive analog input for converter 3 ⁽⁵⁾ |
| SD3N0 | 110 | I | SD24_B negative analog input for converter 3 ⁽⁴⁾ |
| VASYS2 | 111 | | Analog power supply selected between AVCC, AUXVCC1, AUXVCC2. Connect recommended capacitor value of C _{VSYS} . |
| AVSS2 | 112 | | Analog ground supply |
| VREF | 113 | I | SD24_B external reference voltage |
| SD4P0 | 114 | I | SD24_B positive analog input for converter 4 ⁽⁵⁾ (not available on F674xA devices) |
| SD4N0 | 115 | I | SD24_B negative analog input for converter 4 ⁽⁵⁾ (not available on F674xA devices) |
| SD5P0 | 116 | I | SD24_B positive analog input for converter 5 ⁽⁵⁾ (not available on F674xA devices) |
| SD5N0 | 117 | I | SD24_B negative analog input for converter 5 ⁽⁵⁾ (not available on F674xA devices) |
| SD6P0 | 118 | I | SD24_B positive analog input for converter 6 ⁽⁵⁾ (not available on F676xA, F674xA devices) |
| SD6N0 | 119 | I | SD24_B negative analog input for converter 6 ⁽⁵⁾ (not available on F676xA, F674xA devices) |
| AVSS1 | 120 | | Analog ground supply |
| AVCC | 121 | | Analog power supply |
| VASYS1 | 122 | | Analog power supply selected between AVCC, AUXVCC1, AUXVCC2. Connect recommended capacitor value of C _{VSYS} . |
| AUXVCC2 | 123 | | Auxiliary power supply AUXVCC2 |

(4) When this pin is configured as reset, the internal pullup resistor is enabled by default.

(5) TI recommends shorting unused analog input pairs and connecting them to analog ground.

Table 4-3. Terminal Functions – PEU Package (continued)

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|-----------------------|-----|--------------------|--|
| NAME | NO. | | |
| | PEU | | |
| AUXVCC1 | 124 | | Auxiliary power supply AUXVCC1 |
| VDSYS1 ⁽³⁾ | 125 | | Digital power supply selected between DVCC, AUXVCC1, AUXVCC2. Connect recommended capacitor value of C _{VSYS} . |
| DVCC | 126 | | Digital power supply |
| DVSS1 | 127 | | Digital ground supply |
| VCORE ⁽⁶⁾ | 128 | | Regulated core power supply (internal use only, no external current loading) |

(6) VCORE is for internal use only. No external current loading is possible. VCORE should only be connected to the recommended capacitor value, C_{VCORE}.

Table 4-4 describes the signals for devices in the PZ package. See Table 4-3 for the signals in the PEU package.

Table 4-4. Terminal Functions – PZ Package

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|-----------------------|-----------|--------------------|---|
| NAME | NO. PZ | | |
| SD0P0 | 1 | I | SD24_B positive analog input for converter 0 ⁽²⁾ |
| SD0N0 | 2 | I | SD24_B negative analog input for converter 0 ⁽²⁾ |
| SD1P0 | 3 | I | SD24_B positive analog input for converter 1 ⁽²⁾ |
| SD1N0 | 4 | I | SD24_B negative analog input for converter 1 ⁽²⁾ |
| SD2P0 | 5 | I | SD24_B positive analog input for converter 2 ⁽²⁾ |
| SD2N0 | 6 | I | SD24_B negative analog input for converter 2 ⁽²⁾ |
| SD3P0 | 7 | I | SD24_B positive analog input for converter 3 ⁽²⁾ |
| SD3N0 | 8 | I | SD24_B negative analog input for converter 3 ⁽²⁾ |
| VASYS2 | 9 | | Analog power supply selected between AVCC, AUXVCC1, AUXVCC2. Connect recommended capacitor value of C _{VSYS} . |
| AVSS2 | 10 | | Analog ground supply |
| VREF | 11 | I | SD24_B external reference voltage |
| SD4P0 | 12 | I | SD24_B positive analog input for converter 4 ⁽²⁾ (not available on F674x devices) |
| SD4N0 | 13 | I | SD24_B negative analog input for converter 4 ⁽²⁾ (not available on F674xA devices) |
| SD5P0 | 14 | I | SD24_B positive analog input for converter 5 ⁽²⁾ (not available on F674xA devices) |
| SD5N0 | 15 | I | SD24_B negative analog input for converter 5 ⁽²⁾ (not available on F674xA devices) |
| SD6P0 | 16 | I | SD24_B positive analog input for converter 6 ⁽²⁾ (not available on F676xA, F674xA devices) |
| SD6N0 | 17 | I | SD24_B negative analog input for converter 6 ⁽²⁾ (not available on F676xA, F674xA devices) |
| AVSS1 | 18 | | Analog ground supply |
| AVCC | 19 | | Analog power supply |
| VASYS1 | 20 | | Analog power supply selected between AVCC, AUXVCC1, AUXVCC2. Connect recommended capacitor value of C _{VSYS} |
| AUXVCC2 | 21 | | Auxiliary power supply AUXVCC2 |
| AUXVCC1 | 22 | | Auxiliary power supply AUXVCC1 |
| VDSYS1 ⁽³⁾ | 23 | | Digital power supply selected between DVCC, AUXVCC1, AUXVCC2. Connect recommended capacitor value of C _{VSYS} . |
| DVCC | 24 | | Digital power supply |
| DVSS1 | 25 | | Digital ground supply |
| VCORE ⁽⁴⁾ | 26 | | Regulated core power supply (internal use only, no external current loading) |
| XIN | 27 | I/O | Input terminal for crystal oscillator |
| XOUT | 28 | I/O | Output terminal for crystal oscillator |
| AUXVCC3 | 29 | | Auxiliary power supply AUXVCC3 for backup subsystem |
| RTCCAP1 | 30 | I | External time capture pin 1 for RTC_C |
| RTCCAP0 | 31 | I | External time capture pin 0 for RTC_C |
| P1.5/SMCLK/CB0/A5 | 32 | I/O | General-purpose digital I/O with port interrupt SMCLK clock output Comparator_B input CB0 Analog input A5 for 10-bit ADC |

(1) I = input, O = output

(2) TI recommends shorting unused analog input pairs and connecting them to analog ground.

(3) The pins VDSYS1 and VDSYS2 must be connected externally on board for proper device operation.

(4) VCORE is for internal use only. No external current loading is possible. VCORE should only be connected to the recommended capacitor value, C_{VCORE}.

Table 4-4. Terminal Functions – PZ Package (continued)

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|--------------------------------|-----------|--------------------|--|
| NAME | NO. PZ | | |
| P1.4/MCLK/CB1/A4 | 33 | I/O | General-purpose digital I/O with port interrupt MCLK clock output Comparator_B input CB1 Analog input A4 for 10-bit ADC |
| P1.3/ADC10CLK/A3 | 34 | I/O | General-purpose digital I/O with port interrupt ADC10_A clock output Analog input A3 for 10-bit ADC |
| P1.2/ACLK/A2 | 35 | I/O | General-purpose digital I/O with port interrupt ACLK clock output Analog input A2 for 10-bit ADC |
| P1.1/TA2.1/CBOUT/ VeREF+/A1 | 36 | I/O | General-purpose digital I/O with port interrupt Timer TA2 CCR1 capture: CCI1A input, compare: Out1 output Comparator_B Output Positive terminal for the ADC reference voltage for an external applied reference voltage Analog input A1 for 10-bit ADC |
| P1.0/TA1.1/VeREF-/A0 | 37 | I/O | General-purpose digital I/O with port interrupt Timer TA1 CCR1 capture: CCI1A input, compare: Out1 output Negative terminal for the ADC reference voltage for an external applied reference voltage Analog input A0 for 10-bit ADC |
| COM0 | 38 | I/O | LCD common output COM0 for LCD backplane |
| COM1 | 39 | I/O | LCD common output COM1 for LCD backplane |
| P1.6/COM2 | 40 | I/O | General-purpose digital I/O with port interrupt LCD common output COM2 for LCD backplane |
| P1.7/COM3 | 41 | I/O | General-purpose digital I/O with port interrupt LCD common output COM3 for LCD backplane |
| P2.0/PM_TA0.0/ BSL_TX/COM4 | 42 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default Mapping: Timer TA0 CCR0 capture: CCI0A input, compare: Out0 output Bootloader: Data transmit LCD common output COM4 for LCD backplane |
| P2.1/PM_TA0.1/ BSL_RX/COM5 | 43 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default Mapping: Timer TA0 CCR1 capture: CCI1A input, compare: Out1 output Bootloader: Data receive LCD common output COM5 for LCD backplane |
| P2.2/PM_TA0.2/COM6 | 44 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default Mapping: Timer TA0 CCR0 capture: CCI2A input, compare: Out2 output LCD common output COM6 for LCD backplane |
| P2.3/PM_TA1.0/COM7 | 45 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default Mapping: Timer TA1 CCR0 capture: CCI0A input, compare: Out0 output LCD common output COM7 for LCD backplane |
| LDCAP/R33 | 46 | I/O | LCD capacitor connection Input/output port of most positive analog LCD voltage (V1) CAUTION: This pin must be connected to DVSS if not used. |
| P2.4/PM_TA2.0/R23 | 47 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default Mapping: Timer TA2 CCR0 capture: CCI0A input, compare: Out0 output Input/output port of second most positive analog LCD voltage (V2) |

Table 4-4. Terminal Functions – PZ Package (continued)

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|--|-----|--------------------|---|
| NAME | NO. | | |
| | PZ | | |
| P2.5/PM_UCB0SOMI/ PM_UCB0SCL/LCDREF/ R13 | 48 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: eUSCI_B0 SPI slave out, master in Default mapping: eUSCI_B0 I ² C clock External reference voltage input for regulated LCD voltage Input/output port of third most positive analog LCD voltage (V3 or V4) |
| P2.6/PM_UCB0SIMO/ PM_UCB0SDA/R03 | 49 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: eUSCI_B0 SPI slave in, master out Default mapping: eUSCI_B0 I ² C data Input/output port of lowest analog LCD voltage (V5) |
| P2.7/PM_UCB0CLK/CB2 | 50 | I/O | General-purpose digital I/O with port interrupt and mappable secondary function Default mapping: eUSCI_B0 clock input/output Comparator_B input CB2 |
| P3.0/PM_UCA0RXD/ PM_UCA0SOMI | 51 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A0 UART receive data Default mapping: eUSCI_A0 SPI slave out, master in |
| P3.1/PM_UCA0TXD/ PM_UCA0SIMO/S39 | 52 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A0 UART transmit data Default mapping: eUSCI_A0 SPI slave in, master out LCD segment output S39 |
| P3.2/PM_UCA0CLK/S38 | 53 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A0 clock input/output LCD segment output S38 |
| P3.3/PM_UCA1CLK/S37 | 54 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A1 clock input/output LCD segment output S37 |
| P3.4/PM_UCA1RXD/ PM_UCA1SOMI/S36 | 55 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A1 UART receive data Default mapping: eUSCI_A1 SPI slave out, master in LCD segment output S36 |
| P3.5/PM_UCA1TXD/ PM_UCA1SIMO/S35 | 56 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A1 UART transmit data Default mapping: eUSCI_A1 SPI slave in, master out LCD segment output S35 |
| P3.6/PM_UCA2RXD/ PM_UCA2SOMI/S34 | 57 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A2 UART receive data Default mapping: eUSCI_A2 SPI slave out, master in LCD segment output S34 |
| P3.7/PM_UCA2TXD/ PM_UCA2SIMO/S33 | 58 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A2 UART transmit data Default mapping: eUSCI_A2 SPI slave in, master out LCD segment output S33 |
| P4.0/PM_UCA2CLK/S32 | 59 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A2 clock input/output LCD segment output S32 |

Table 4-4. Terminal Functions – PZ Package (continued)

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|-------------------------------------|-----|--------------------|--|
| NAME | NO. | | |
| | PZ | | |
| P4.1/PM_UCA3RXD/ PM_UCA3SOMI/S31 | 60 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A3 UART receive data Default mapping: eUSCI_A3 SPI slave out, master in LCD segment output S31 |
| P4.2/PM_UCA3TXD/ PM_UCA3SIMO/S30 | 61 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A3 UART transmit data Default mapping: eUSCI_A3 SPI slave in, master out LCD segment output S30 |
| P4.3/PM_UCA3CLK/S29 | 62 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_A3 clock input/output LCD segment output S29 |
| P4.4/PM_UCB1SOMI/ PM_UCB1SCL/S28 | 63 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_B1 SPI slave out, master in Default mapping: eUSCI_B1 I ² C clock LCD segment output S28 |
| P4.5/PM_UCB1SIMO/ PM_UCB1SDA/S27 | 64 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_B1 SPI slave in, master out Default mapping: eUSCI_B1 I ² C data LCD segment output S27 |
| P4.6/PM_UCB1CLK/S26 | 65 | I/O | General-purpose digital I/O with mappable secondary function Default mapping: eUSCI_B1 clock input/output LCD segment output S26 |
| P4.7/PM_TA3.0/S25 | 66 | I/O | General-purpose digital I/O with mappable secondary function Default Mapping: Timer TA3 CCR0 capture: CCI0A input, compare: Out0 output LCD segment output S25 |
| P5.0/SDCLK/S24 | 67 | I/O | General-purpose digital I/O SD24_B bit-stream clock input/output LCD segment output S24 |
| P5.1/PM_SD0DIO/S23 | 68 | I/O | General-purpose digital I/O Default mapping: SD24_B converter 0 bit-stream data input/output LCD segment output S23 |
| P5.2/PM_SD1DIO/S22 | 69 | I/O | General-purpose digital I/O Default mapping: SD24_B converter 1 bit-stream data input/output LCD segment output S22 |
| P5.3/PM_SD2DIO/S21 | 70 | I/O | General-purpose digital I/O Default mapping: SD24_B converter 2 bit-stream data input/output LCD segment output S21 |
| P5.4/PM_SD3DIO/S20 | 71 | I/O | General-purpose digital I/O Default mapping: SD24_B converter 3 bit-stream data input/output LCD segment output S20 |
| P5.5/PM_SD4DIO/S19 | 72 | I/O | General-purpose digital I/O Default mapping: SD24_B converter 4 bit-stream data input/output (not available on F674xA devices) LCD segment output S19 |

Table 4-4. Terminal Functions – PZ Package (continued)

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|-----------------------|-----------|--------------------|---|
| NAME | NO. PZ | | |
| P5.6/PM_SD5DIO/S18 | 73 | I/O | General-purpose digital I/O Default mapping: SD24_B converter 5 bit-stream data input/output (not available on F674xA devices) LCD segment output S18 |
| P5.7/PM_SD6DIO/S17 | 74 | I/O | General-purpose digital I/O Default mapping: SD24_B converter 6 bit-stream data input/output (not available on F676xA or F674xA devices) LCD segment output S17 |
| VDSYS2 ⁽³⁾ | 75 | | Digital power supply for I/Os |
| DVSS2 | 76 | | Digital ground supply |
| P6.0/S16 | 77 | I/O | General-purpose digital I/O LCD segment output S16 |
| P6.1/S15 | 78 | I/O | General-purpose digital I/O LCD segment output S15 |
| P6.2/S14 | 79 | I/O | General-purpose digital I/O LCD segment output S14 |
| P6.3/S13 | 80 | I/O | General-purpose digital I/O LCD segment output S13 |
| P6.4/S12 | 81 | I/O | General-purpose digital I/O LCD segment output S12 |
| P6.5/S11 | 82 | I/O | General-purpose digital I/O LCD segment output S11 |
| P6.6/S10 | 83 | I/O | General-purpose digital I/O LCD segment output S10 |
| P6.7/S9 | 84 | I/O | General-purpose digital I/O LCD segment output S9 |
| P7.0/S8 | 85 | I/O | General-purpose digital I/O LCD segment output S8 |
| P7.1/S7 | 86 | I/O | General-purpose digital I/O LCD segment output S7 |
| P7.2/S6 | 87 | I/O | General-purpose digital I/O LCD segment output S6 |
| P7.3/S5 | 88 | I/O | General-purpose digital I/O LCD segment output S5 |
| P7.4/S4 | 89 | I/O | General-purpose digital I/O LCD segment output S4 |
| P7.5/S3 | 90 | I/O | General-purpose digital I/O LCD segment output S3 |
| P7.6/S2 | 91 | I/O | General-purpose digital I/O LCD segment output S2 |
| P7.7/S1 | 92 | I/O | General-purpose digital I/O LCD segment output S1 |
| P8.0/S0 | 93 | I/O | General-purpose digital I/O LCD segment output S0 |

Table 4-4. Terminal Functions – PZ Package (continued)

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|-------------------------------------|-----|--------------------|--|
| NAME | NO. | | |
| | PZ | | |
| P8.1/TACLK/RTCCLK/CB3 | 94 | I/O | General-purpose digital I/O Timer clock input TACLK for TA0, TA1, TA2, TA3 RTCCLK clock output Comparator_B input CB3 |
| TEST/SBWTCK | 95 | I | Test mode pin – select digital I/O on JTAG pins Spy-By-Wire input clock |
| PJ.0/TDO | 96 | I/O | General-purpose digital I/O Test data output |
| PJ.1/TDI/TCLK | 97 | I/O | General-purpose digital I/O Test data input or Test clock input |
| PJ.2/TMS | 98 | I/O | General-purpose digital I/O Test mode select |
| PJ.3/TCK | 99 | I/O | General-purpose digital I/O Test clock |
| $\overline{\text{RST}}$ /NMI/SBWDIO | 100 | I/O | Reset input active low ⁽⁵⁾ Nonmaskable interrupt input Spy-By-Wire data input/output |

(5) When this pin is configured as reset, the internal pullup resistor is enabled by default.

4.3 Pin Multiplexing

Pin multiplexing for these devices is controlled by both register settings and operating modes (for example, if the device is in test mode). For details of the settings for each pin and schematics of the multiplexed ports, see [Section 6.12](#).

4.4 Connection of Unused Pins

[Table 4-5](#) lists the correct termination of unused pins.

Table 4-5. Connection of Unused Pins⁽¹⁾

| PIN | POTENTIAL | COMMENT |
|--|-------------------------------------|---|
| AVCC | DV _{CC} | |
| AVSS | DV _{SS} | |
| Px.y | Open | Switched to port function, output direction (PxDIR.n = 1). Px.y represents port x and bit y of port x (for example, P1.0, P1.1, P2.2, PJ.0, PJ.1) |
| XIN | DV _{SS} | For dedicated XIN pins only. XIN pins with shared GPIO functions should be programmed to GPIO and follow Px.y recommendations. |
| XOUT | Open | For dedicated XOUT pins only. XOUT pins with shared GPIO functions should be programmed to GPIO and follow Px.y recommendations. |
| LDCAP | DV _{SS} | |
| $\overline{\text{RST}}$ /NMI | DV _{CC} or V _{CC} | 47-k Ω pullup or internal pullup selected with 10-nF (2.2 nF) pulldown ⁽²⁾ |
| PJ.0/TDO PJ.1/TDI PJ.2/TMS PJ.3/TCK | Open | The JTAG pins are shared with general-purpose I/O function (PJ.x). If not being used, these should be switched to port function, output direction (PJDIR.n = 1). When used as JTAG pins, these pins should remain open. |
| TEST | Open | This pin always has an internal pulldown enabled. |

- (1) Any unused pin with a secondary function that is shared with general-purpose I/O should follow the Px.y unused pin connection guidelines.
- (2) The pulldown capacitor should not exceed 2.2 nF when using devices with Spy-Bi-Wire interface in Spy-Bi-Wire mode or in 4-wire JTAG mode with TI tools such as FET interfaces or GANG programmers.

5 Specifications

All graphs in this section are for typical conditions, unless otherwise noted.

Typical (TYP) values are specified at $V_{CC} = 3.3\text{ V}$ and $T_A = 25^\circ\text{C}$, unless otherwise noted.

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | MIN | MAX | UNIT |
|--|---|------|----------------|------|
| Voltage applied at DVCC to DVSS | | -0.3 | 4.1 | V |
| Voltage applied to pins ⁽²⁾ | All pins except V _{CORE} ⁽³⁾ , SD24_B input pins (SDxN0, SDxP0) ⁽⁴⁾ , AUXVCC1, AUXVCC2, and AUXVCC3 ⁽⁵⁾ | -0.3 | $V_{CC} + 0.3$ | V |
| Diode current at pins | All pins except SD24_B input pins (SDxN0, SDxP0) | ±2 | | mA |
| | SD0N0, SD0P0, SD1N0, SD1P0, SD2N0, SD2P0, SD3N0, SD3P0, SD4N0, SD4P0, SD5N0, SD5P0, SD6N0, SD6P0 ⁽⁶⁾ | 2 | | |
| Maximum junction temperature, T _J | | 95 | | °C |
| Storage temperature, T _{stg} ⁽⁷⁾ | | -55 | 105 | °C |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages referenced to $V_{SS} = V_{DVSS} = V_{AVSS}$.
- (3) V_{CORE} is for internal device use only. No external DC loading or voltage should be applied.
- (4) See [Table 5-39](#) for SD24_B specifications.
- (5) See [Table 5-18](#) for AUX specifications.
- (6) A protection diode is connected to V_{CC} for the SD24_B input pins. No protection diode is connected to V_{SS} .
- (7) Higher temperature may be applied during board soldering according to the current JEDEC J-STD-020 specification with peak reflow temperatures not higher than classified on the device label on the shipping boxes or reels.

5.2 ESD Ratings

| | | VALUE | UNIT |
|--|--|-------|------|
| V _(ESD) Electrostatic discharge | Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾ | ±1000 | V |
| | Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾ | ±250 | |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Pins listed as ±1000 V may actually have higher performance.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Pins listed as ±250 V may actually have higher performance.

5.3 Recommended Operating Conditions

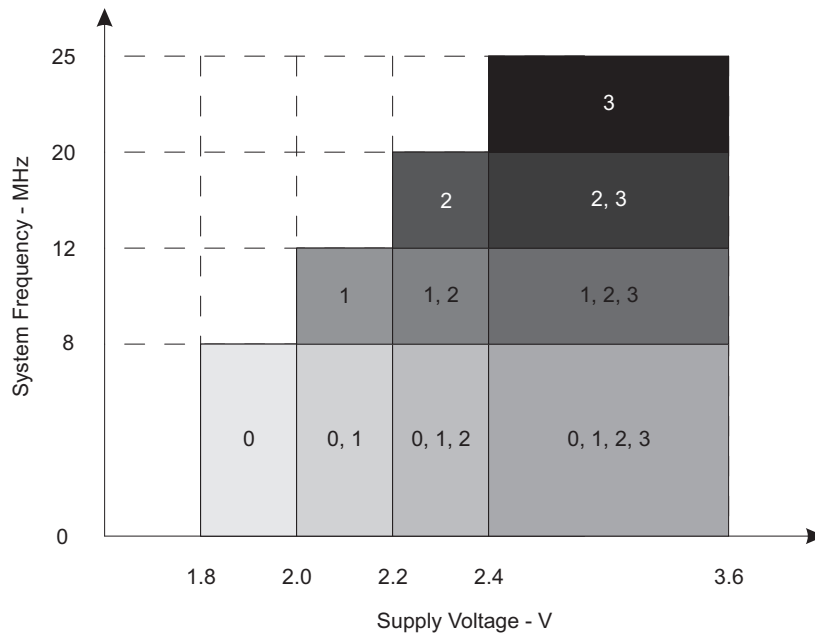
| | | MIN | NOM | MAX | UNIT | |
|---|--|------------------------|-----|-----|------|----|
| V _{CC} | Supply voltage during program execution and flash programming ($V_{AVCC} = V_{DVCC} = V_{CC}$) ⁽¹⁾⁽²⁾ | PMMCOREVx = 0 | 1.8 | 3.6 | V | |
| | | PMMCOREVx = 0, 1 | 2.0 | 3.6 | | |
| | | PMMCOREVx = 0, 1, 3 2 | 2.2 | 3.6 | | |
| | | PMMCOREVx = 0, 1, 2, 3 | 2.4 | 3.6 | | |
| V _{SS} | Supply voltage $V_{AVSS} = V_{DVSS} = V_{SS}$ | 0 | | | V | |
| T _A | Operating free-air temperature | I version | | -40 | 85 | °C |
| T _J | Operating junction temperature | I version | | -40 | 85 | °C |
| C _{VCORE} | Recommended capacitor at V _{CORE} | 470 | | | nF | |
| C _{DVCC} / C _{VCORE} | Capacitor ratio of DVCC to V _{CORE} | 10 | | | | |

- (1) TI recommends powering AVCC and DVCC from the same source. A maximum difference of 0.3 V between $V_{(AVCC)}$ and $V_{(DVCC)}$ can be tolerated during power up and operation.
- (2) The minimum supply voltage is defined by the supervisor SVS levels when it is enabled. See the [Table 5-14](#) threshold parameters for the exact values and further details.

Recommended Operating Conditions (continued)

| | | MIN | NOM | MAX | UNIT |
|--------------------------|---|--|-----|---|------|
| f _{SYSTEM} | Processor frequency (maximum MCLK frequency) ⁽³⁾ (4) (see Figure 5-1) | PMMCOREVx = 0, 1.8 V ≤ V _{CC} ≤ 3.6 V (default condition) | 0 | 8.0 | MHz |
| | | PMMCOREVx = 1, 2 V ≤ V _{CC} ≤ 3.6 V | 0 | 12.0 | |
| | | PMMCOREVx = 2, 2.2 V ≤ V _{CC} ≤ 3.6 V | 0 | 20.0 | |
| | | PMMCOREVx = 3, 2.4 V ≤ V _{CC} ≤ 3.6 V | 0 | 25.0 | |
| I _{LOAD, DVCCD} | Maximum load current that can be drawn from DVCC for core and IO (I _{LOAD} = I _{CORE} + I _{IO}) | | | 20 | mA |
| I _{LOAD, AUX1D} | Maximum load current that can be drawn from AUXVCC1 for core and IO (I _{LOAD} = I _{CORE} + I _{IO}) | | | 20 | mA |
| I _{LOAD, AUX2D} | Maximum load current that can be drawn from AUXVCC2 for core and IO (I _{LOAD} = I _{CORE} + I _{IO}) | | | 20 | mA |
| I _{LOAD, AVCCA} | Maximum load current that can be drawn from AVCC for analog modules (I _{LOAD} = I _{Modules}) | | | 10 | mA |
| I _{LOAD, AUX1A} | Maximum load current that can be drawn from AUXVCC1 for analog modules (I _{LOAD} = I _{Modules}) | | | 5 | mA |
| I _{LOAD, AUX2A} | Maximum load current that can be drawn from AUXVCC2 for analog modules (I _{LOAD} = I _{Modules}) | | | 5 | mA |
| P _{INT} | Internal power dissipation | | | V _{CC} × I _(DVCC) | W |
| P _{IO} | I/O power dissipation of the I/O pins powered by DVCC | | | (V _{CC} - V _{IOH}) × I _{IOH} + V _{IO L} × I _{IO L} | W |
| P _{MAX} | Maximum allowed power dissipation, P _{MAX} > P _{IO} + P _{INT} | | | (T _J - T _A) / θ _{JA} | W |

- (3) The MSP430 CPU is clocked directly with MCLK. Both the high and low phase of MCLK must not exceed the pulse duration of the specified maximum frequency.
- (4) Modules may have a different maximum input clock specification. See the specification of the respective module in this data sheet.



The numbers within the fields denote the supported PMMCOREVx settings.

Figure 5-1. Maximum System Frequency

5.4 Active Mode Supply Current Into V_{CC} Excluding External Current

over recommended operating free-air temperature (unless otherwise noted)⁽¹⁾⁽²⁾⁽³⁾

| PARAMETER | EXECUTION MEMORY | V_{CC} | PMMCOREV _x | FREQUENCY ($f_{DCO} = f_{MCLK} = f_{SMCLK}$) | | | | | | | | UNIT | | |
|-----------------------|------------------|----------|-----------------------|--|------|-------|------|--------|------|--------|-----|------|--------|-----|
| | | | | 1 MHz | | 8 MHz | | 12 MHz | | 20 MHz | | | 25 MHz | |
| | | | | TYP | MAX | TYP | MAX | TYP | MAX | TYP | MAX | | TYP | MAX |
| $I_{AM, Flash}^{(4)}$ | Flash | 3 V | 0 | 0.32 | 0.50 | 2.08 | 2.84 | | | | | | | mA |
| | | | 1 | 0.35 | | 2.35 | | 3.50 | 4.76 | | | | | |
| | | | 2 | 0.39 | | 2.68 | | 3.99 | | 6.61 | 8.3 | | | |
| | | | 3 | 0.41 | | 2.83 | | 4.22 | | 6.98 | | 8.67 | 11.75 | |
| $I_{AM, RAM}^{(5)}$ | RAM | 3 V | 0 | 0.19 | | 1.04 | | | | | | | mA | |
| | | | 1 | 0.21 | | 1.20 | | 1.77 | | | | | | |
| | | | 2 | 0.23 | | 1.38 | | 2.04 | | 3.35 | | | | |
| | | | 3 | 0.24 | | 1.47 | | 2.18 | | 3.58 | | 4.44 | | |

- (1) All inputs are tied to 0 V or to V_{CC} . Outputs do not source or sink any current.
- (2) The currents are characterized with a Micro Crystal MS1 V-T1K crystal with a load capacitance of 12.5 pF. The internal and external load capacitance are chosen to closely match the required 12.5 pF.
- (3) Characterized with program executing typical data processing.
 $f_{ACLK} = 32786$ Hz, $f_{DCO} = f_{MCLK} = f_{SMCLK}$ at specified frequency.
 $XTS = CPUOFF = SCG0 = SCG1 = OSCOFF = SMCLKOFF = 0$.
- (4) Active mode supply current when program executes in flash at a nominal supply voltage of 3.0 V.
- (5) Active mode supply current when program executes in RAM at a nominal supply voltage of 3.0 V.

5.5 Low-Power Mode Supply Currents (Into V_{CC}) Excluding External Current

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾⁽²⁾

| PARAMETER | V_{CC} | PMMCOREVx | TEMPERATURE (T_A) | | | | | | UNIT |
|---|----------|-----------|-----------------------|-----|------|-----|------|------|---------|
| | | | -40°C | | 25°C | | 85°C | | |
| | | | TYP | MAX | TYP | MAX | TYP | MAX | |
| $I_{LPM0,1MHz}$ Low-power mode 0 ^{(3) (4)} | 2.2 V | 0 | 70 | | 75 | | 86 | | μA |
| | 3 V | 3 | 81 | | 87 | 105 | 100 | 130 | |
| I_{LPM2} Low-power mode 2 ^{(5) (4)} | 2.2 V | 0 | 5.9 | | 6.5 | | 12.5 | | μA |
| | 3 V | 3 | 6.7 | | 7.3 | 18 | 13.8 | 30 | |
| $I_{LPM3,XT1LF}$ Low-power mode 3, crystal mode ^{(6) (4)} | 2.2 V | 0 | 1.50 | | 2.0 | | 7.8 | | μA |
| | | 1 | 1.65 | | 2.2 | | 8.3 | | |
| | | 2 | 1.80 | | 2.4 | | 8.6 | | |
| | | 3 | 1.84 | | 2.4 | | 8.6 | | |
| $I_{LPM3,XT1LF}$ Low-power mode 3, crystal mode ^{(6) (4)} | 3 V | 0 | 2.0 | | 2.5 | | 8.5 | | μA |
| | | 1 | 2.1 | | 2.7 | | 9.0 | | |
| | | 2 | 2.3 | | 2.9 | | 9.3 | | |
| | | 3 | 2.3 | | 2.9 | | 9.3 | 25 | |
| $I_{LPM3,VLO}$ Low-power mode 3, VLO mode ^{(7) (4)} | 3 V | 0 | 1.3 | | 1.7 | | 7.5 | | μA |
| | | 1 | 1.3 | | 1.8 | | 7.9 | | |
| | | 2 | 1.4 | | 1.9 | | 8.2 | | |
| | | 3 | 1.4 | | 1.9 | | 8.2 | 25.0 | |
| I_{LPM4} Low-power mode 4 ^{(8) (4)} | 3 V | 0 | 1.2 | | 1.6 | | 7.4 | | μA |
| | | 1 | 1.2 | | 1.7 | | 7.8 | | |
| | | 2 | 1.3 | | 1.7 | | 7.9 | | |
| | | 3 | 1.3 | | 1.7 | | 8.0 | 23.0 | |
| $I_{LPM3.5}$ Low-power mode 3.5, RTC active on AUXVCC3 ⁽⁹⁾ | 2.2 V | | 0.7 | | 0.9 | | 1.4 | | μA |
| | 3 V | | 1.0 | | 1.2 | 1.5 | 1.8 | 3.0 | |
| $I_{LPM4.5}$ Low-power mode 4.5 ⁽¹⁰⁾ | 3 V | | 0.6 | | 0.7 | 1.0 | 1.2 | 2.0 | μA |

(1) All inputs are tied to 0 V or to V_{CC} . Outputs do not source or sink any current.

(2) The currents are characterized with a Micro Crystal MS1 V-T1K crystal with a load capacitance of 12.5 pF. The internal and external load capacitance are chosen to closely match the required 12.5 pF.

(3) Current for watchdog timer clocked by SMCLK included. ACLK = low frequency crystal operation (XTS = 0, XT1DRIVEx = 0). CPUOFF = 1, SCG0 = 0, SCG1 = 0, OSCOFF = 0 (LPM0), f_{ACLK} = 32768 Hz, f_{MCLK} = 0 MHz, f_{SMCLK} = f_{DCO} = 1 MHz

(4) Current for brownout, high-side supervisor (SVSH) normal mode included. Low-side supervisor (SVSL) and low-side monitor (SVM_L) disabled. High-side monitor (SVM_H) disabled. RAM retention enabled.

(5) Current for watchdog timer and RTC clocked by ACLK included. ACLK = low frequency crystal operation (XTS = 0, XT1DRIVEx = 0). CPUOFF = 1, SCG0 = 0, SCG1 = 1, OSCOFF = 0 (LPM2), f_{ACLK} = 32768 Hz, f_{MCLK} = 0 MHz, f_{SMCLK} = f_{DCO} = 0 MHz, DCO setting = 1-MHz operation, DCO bias generator enabled.

(6) Current for watchdog timer and RTC clocked by low-frequency clock included. ACLK = low frequency crystal operation (XTS = 0, XT1DRIVEx = 0).

CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 0 (LPM3), f_{ACLK} = 32768 Hz, f_{MCLK} = f_{SMCLK} = f_{DCO} = 0 MHz

(7) Current for watchdog timer and RTC clocked by low-frequency clock included. ACLK = VLO.

CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 0 (LPM3), f_{ACLK} = f_{VLO} , f_{MCLK} = f_{SMCLK} = f_{DCO} = 0 MHz

(8) CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 1 (LPM4), f_{DCO} = f_{ACLK} = f_{MCLK} = f_{SMCLK} = 0 MHz

(9) f_{DCO} = f_{MCLK} = f_{SMCLK} = 0 MHz, f_{ACLK} = 32768 Hz, PMMREGOFF = 1, RTC active on AUXVCC3 supply

(10) f_{DCO} = f_{MCLK} = f_{SMCLK} = 0 MHz, f_{ACLK} = 0 Hz, PMMREGOFF = 1

5.6 Low-Power Mode With LCD Supply Currents (Into V_{CC}) Excluding External Current

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾⁽²⁾

| PARAMETER | V_{CC} | PMMCOREVx | TEMPERATURE (T_A) | | | | | | UNIT |
|---------------------------------|----------|-----------|-----------------------|-----|------|-----|-----------|---------|------|
| | | | -40°C | | 25°C | | 85°C | | |
| | | | TYP | MAX | TYP | MAX | TYP | MAX | |
| I_{LPM3} LCD, ext. bias | 3 V | 0 | 2.5 | | 3.1 | | 9.1 | μA | |
| | | 1 | 2.6 | | 3.3 | | 9.5 | | |
| | | 2 | 2.8 | | 3.5 | | 9.9 | | |
| | | 3 | 2.8 | | 3.5 | 6.0 | 10.0 25.0 | | |
| I_{LPM3} LCD, int. bias | 3 V | 0 | 2.9 | | 3.5 | | 9.7 | μA | |
| | | 1 | 3.1 | | 3.7 | | 10.1 | | |
| | | 2 | 3.2 | | 4.0 | | 10.5 | | |
| | | 3 | 3.3 | | 4.0 | 5.5 | 10.5 25.0 | | |
| I_{LPM3} LCD,CP | 2.2 V | 0 | 2.2 | | 2.8 | | 8.8 | μA | |
| | | 1 | 2.3 | | 3.0 | | 9.1 | | |
| | | 2 | 2.5 | | 3.2 | | 9.5 | | |
| | 3 V | 0 | 2.6 | | 3.2 | | 9.3 | μA | |
| | | 1 | 2.8 | | 3.4 | | 9.7 | | |
| | | 2 | 2.9 | | 3.6 | | 10.1 | | |
| | | 3 | 3.0 | | 3.7 | | 10.2 | | |

- (1) All inputs are tied to 0 V or to V_{CC} . Outputs do not source or sink any current.
- (2) The currents are characterized with a Micro Crystal MS1 V-T1K crystal with a load capacitance of 12.5 pF. The internal and external load capacitance are chosen to closely match the required 12.5 pF.
- (3) Current for watchdog timer and RTC clocked by ACLK included. ACLK = low frequency crystal operation (XTS = 0, XT1DRIVE_x = 0). CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 0 (LPM3), f_{ACLK} = 32768 Hz, f_{MCLK} = f_{SMCLK} = f_{DCO} = 0 MHz. Current for brownout and high-side supervisor (SVSH) in normal mode included. Low-side supervisor (SVSL) and low-side monitor (SVM_L) disabled. High-side monitor (SVM_H) disabled. RAM retention enabled.
- (4) LCDM_x = 11 (4-mux mode), LCDREXT = 1, LCDEXTBIAS = 1 (external biasing), LCD2B = 0 (1/3 bias), LCDCPEN = 0 (charge pump disabled), LCDSSEL = 0, LCDPREx = 101, LCDDIVx = 00011 (f_{LCD} = 32768 Hz / 32 / 4 = 256 Hz). Current through external resistors not included (voltage levels are supplied by test equipment). Even segments (S0, S2, ...) = 0, and odd segments (S1, S3, ...) = 1. No LCD panel load.
- (5) LCDM_x = 11 (4-mux mode), LCDREXT = 0, LCDEXTBIAS = 0 (internal biasing), LCD2B = 0 (1/3 bias), LCDCPEN = 0 (charge pump disabled), LCDSSEL = 0, LCDPREx = 101, LCDDIVx = 00011 (f_{LCD} = 32768 Hz / 32 / 4 = 256 Hz). Even segments (S0, S2, ...) = 0, and odd segments (S1, S3, ...) = 1. No LCD panel load.
- (6) LCDM_x = 11 (4-mux mode), LCDREXT = 0, LCDEXTBIAS = 0 (internal biasing), LCD2B = 0 (1/3 bias), LCDCPEN = 1 (charge pump enabled), VLCDx = 1000 (V_{LCD} = 3 V typical), LCDSSEL = 0, LCDPREx = 101, LCDDIVx = 00011 (f_{LCD} = 32768 Hz / 32 / 4 = 256 Hz). Even segments (S0, S2, ...) = 0, and odd segments (S1, S3, ...) = 1. No LCD panel load.

5.7 Thermal Resistance Characteristics

| THERMAL METRIC ^{(1) (2)} | | VALUE | UNIT | |
|-----------------------------------|--|----------------|--------------------|------|
| R _{θJA} | Junction-to-ambient thermal resistance, still air | LQFP 128 (PEU) | 44.4 | °C/W |
| | | LQFP 100 (PZ) | 42.9 | |
| R _{θJC(TOP)} | Junction-to-case (top) thermal resistance | LQFP 128 (PEU) | 10.5 | °C/W |
| | | LQFP 100 (PZ) | 9.3 | |
| R _{θJC(BOTTOM)} | Junction-to-case (bottom) thermal resistance | LQFP 128 (PEU) | N/A ⁽³⁾ | °C/W |
| | | LQFP 100 (PZ) | N/A | |
| R _{θJB} | Junction-to-board thermal resistance | LQFP 128 (PEU) | 23.1 | °C/W |
| | | LQFP 100 (PZ) | 20.6 | |
| Ψ _{JT} | Junction-to-package-top thermal characterization parameter | LQFP 128 (PEU) | 0.4 | °C/W |
| | | LQFP 100 (PZ) | 0.3 | |
| Ψ _{JB} | Junction-to-board thermal characterization parameter | LQFP 128 (PEU) | 22.8 | °C/W |
| | | LQFP 100 (PZ) | 20.3 | |

- (1) For more information about traditional and new thermal metrics, see [Semiconductor and IC Package Thermal Metrics](#).
- (2) These values are based on a JEDEC-defined 2S2P system (with the exception of the Theta JC [R_{θJC}] value, which is based on a JEDEC-defined 1S0P system) and will change based on environment as well as application. For more information, see these EIA/JEDEC standards:
- JESD51-2, *Integrated Circuits Thermal Test Method Environmental Conditions - Natural Convection (Still Air)*
 - JESD51-3, *Low Effective Thermal Conductivity Test Board for Leaded Surface Mount Packages*
 - JESD51-7, *High Effective Thermal Conductivity Test Board for Leaded Surface Mount Packages*
 - JESD51-9, *Test Boards for Area Array Surface Mount Package Thermal Measurements*
- (3) N/A = not applicable

5.8 Timing and Switching Characteristics

5.8.1 Reset Timing

Table 5-1 lists the device wake-up times.

Table 5-1. Wake-up Times From Low-Power Modes and Reset

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-----------------------------|---|---|-----------------------------|-----|-----|------|
| t _{WAKE-UP-FAST} | Wake-up time from LPM2, LPM3, or LPM4 to active mode ⁽¹⁾ | PMMCOREV = SVSMLRRL = n (where n = 0, 1, 2, or 3), SVSLFP = 1 | f _{MCLK} ≥ 4.0 MHz | | 5 | μs |
| | | | f _{MCLK} < 4.0 MHz | | 10 | |
| t _{WAKE-UP-SLOW} | Wake-up time from LPM2, LPM3, or LPM4 to active mode ⁽²⁾⁽³⁾ | PMMCOREV = SVSMLRRL = n (where n = 0, 1, 2, or 3), SVSLFP = 0 | | 150 | 165 | μs |
| t _{WAKE-UP-LPM4.5} | Wake-up time from LPM4.5 to active mode ⁽⁴⁾ | | | 2 | 3 | ms |
| t _{WAKE-UP-RESET} | Wake-up time from \overline{RST} or BOR event to active mode ⁽⁴⁾ | | | 2 | 3 | ms |

- (1) This value represents the time from the wake-up event to the first active edge of MCLK. The wake-up time depends on the performance mode of the low-side supervisor (SVS_L) and low-side monitor (SVM_L). t_{WAKE-UP-FAST} is possible with SVS_L and SVM_L in full performance mode or disabled. For specific register settings, see the *Low-Side SVS and SVM Control and Performance Mode Selection* section in the *Power Management Module and Supply Voltage Supervisor* chapter of the [MSP430x5xx and MSP430x6xx Family User's Guide](#).
- (2) This value represents the time from the wake-up event to the first active edge of MCLK. The wake-up time depends on the performance mode of the low-side supervisor (SVS_L) and low-side monitor (SVM_L). t_{WAKE-UP-SLOW} is set with SVS_L and SVM_L in normal mode (low current mode). For specific register settings, see the *Low-Side SVS and SVM Control and Performance Mode Selection* section in the *Power Management Module and Supply Voltage Supervisor* chapter of the [MSP430x5xx and MSP430x6xx Family User's Guide](#).
- (3) The wake-up times from LPM0 and LPM1 to AM are not specified. They are proportional to MCLK cycle time but are not affected by the performance mode settings as for LPM2, LPM3, and LPM4.
- (4) This value represents the time from the wake-up event to the reset vector execution.

5.8.2 Clock Specifications

Table 5-2 lists the characteristics of the crystal oscillator in low-frequency mode.

Table 5-2. Crystal Oscillator, XT1, Low-Frequency Mode⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT | |
|----------------------|--|-----------------|-----|--------|-------|------------|---|
| $\Delta I_{DVCC,LF}$ | Differential XT1 oscillator crystal current consumption from lowest drive setting, LF mode | 3 V | | 0.075 | | μA | |
| | $f_{OSC} = 32768$ Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 1, T _A = 25°C | | | | | | |
| | $f_{OSC} = 32768$ Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 2, T _A = 25°C | | | | | | |
| | $f_{OSC} = 32768$ Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 3, T _A = 25°C | | | 0.290 | | | |
| $f_{XT1,LF0}$ | XT1 oscillator crystal frequency, LF mode | | | 32768 | | Hz | |
| $f_{XT1,LF,SW}$ | XT1 oscillator logic-level square-wave input frequency, LF mode | | 10 | 32.768 | 50 | kHz | |
| OA_{LF} | Oscillation allowance for LF crystals ⁽⁴⁾ | | | 210 | | k Ω | |
| | | | | | | | XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 0, $f_{XT1,LF} = 32768$ Hz, C _{L,eff} = 6 pF |
| | XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 1, $f_{XT1,LF} = 32768$ Hz, C _{L,eff} = 12 pF | | | 300 | | | |
| $C_{L,eff}$ | Integrated effective load capacitance, LF mode ⁽⁵⁾ | | | | | pF | |
| | | | | | | | XTS = 0, XCAP _x = 0 ⁽⁶⁾ |
| | | | | | | | XTS = 0, XCAP _x = 1 |
| | | | | | | | XTS = 0, XCAP _x = 2 |
| | XTS = 0, XCAP _x = 3 | | | 12.0 | | | |
| | Duty cycle, LF mode | | | 30% | 70% | | |
| $f_{Fault,LF}$ | Oscillator fault frequency, LF mode ⁽⁷⁾ | | | 10 | 10000 | Hz | |
| $t_{START,LF}$ | Start-up time, LF mode | 3 V | | 1000 | | ms | |
| | | | | | | | $f_{OSC} = 32768$ Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 0, T _A = 25°C, C _{L,eff} = 6 pF |
| | $f_{OSC} = 32768$ Hz, XTS = 0, XT1BYPASS = 0, XT1DRIVE _x = 3, T _A = 25°C, C _{L,eff} = 12 pF | | | 500 | | | |

- To improve EMI on the XT1 oscillator, the following guidelines should be observed.
 - Keep the trace between the device and the crystal as short as possible.
 - Design a good ground plane around the oscillator pins.
 - Prevent crosstalk from other clock or data lines into oscillator pins XIN and XOUT.
 - Avoid running PCB traces underneath or adjacent to the XIN and XOUT pins.
 - Use assembly materials and processes that avoid any parasitic load on the oscillator XIN and XOUT pins.
 - If conformal coating is used, make sure that it does not induce capacitive or resistive leakage between the oscillator pins.
- When XT1BYPASS is set, XT1 circuits are automatically powered down. Input signal is a digital square wave with parametrics defined in the Schmitt-trigger Inputs section of this data sheet.
- Maximum frequency of operation of the entire device cannot be exceeded.
- Oscillation allowance is based on a safety factor of 5 for recommended crystals. The oscillation allowance is a function of the XT1DRIVE_x settings and the effective load. In general, comparable oscillator allowance can be achieved based on the following guidelines, but should be evaluated based on the actual crystal selected for the application:
 - For XT1DRIVE_x = 0, C_{L,eff} ≤ 6 pF.
 - For XT1DRIVE_x = 1, 6 pF ≤ C_{L,eff} ≤ 9 pF.
 - For XT1DRIVE_x = 2, 6 pF ≤ C_{L,eff} ≤ 10 pF.
 - For XT1DRIVE_x = 3, C_{L,eff} ≥ 6 pF.
- Includes parasitic bond and package capacitance (approximately 2 pF per pin). Because the PCB adds additional capacitance, verify the correct load by measuring the ACLK frequency. For a correct setup, the effective load capacitance should always match the specification of the used crystal.
- Requires external capacitors at both terminals. Values are specified by crystal manufacturers.
- Frequencies below the MIN specification set the fault flag. Frequencies above the MAX specification do not set the fault flag. Frequencies in between might set the flag.
- Measured with logic-level input frequency but also applies to operation with crystals.

Table 5-3 lists the characteristics of the VLO.

Table 5-3. Internal Very-Low-Power Low-Frequency Oscillator (VLO)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT |
|-------------------------------------|------------------------------------|------------------|-----------------|-----|-----|-----|------|
| f _{VLO} | VLO frequency | Measured at ACLK | 1.8 V to 3.6 V | 6 | 9.6 | 15 | kHz |
| df _{VLO} /dT | VLO frequency temperature drift | Measured at ACLK | 1.8 V to 3.6 V | | 0.5 | | %/°C |
| df _{VLO} /dV _{CC} | VLO frequency supply voltage drift | Measured at ACLK | 1.8 V to 3.6 V | | 4 | | %/V |
| | Duty cycle | Measured at ACLK | 1.8 V to 3.6 V | 40% | 50% | 60% | |

Table 5-4 lists the characteristics of the REFO.

Table 5-4. Internal Reference, Low-Frequency Oscillator (REFO)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT |
|--------------------------------------|-------------------------------------|------------------------|-----------------|-------|-------|-------|------|
| I _{REFO} | REFO oscillator current consumption | T _A = 25°C | 1.8 V to 3.6 V | | 3 | | μA |
| f _{REFO} | REFO frequency calibrated | Measured at ACLK | 1.8 V to 3.6 V | | 32768 | | Hz |
| | REFO absolute tolerance calibrated | Full temperature range | 1.8 V to 3.6 V | -3.5% | | +3.5% | |
| | | T _A = 25°C | 3 V | -1.5% | | +1.5% | |
| df _{REFO} /dT | REFO frequency temperature drift | Measured at ACLK | 1.8 V to 3.6 V | | 0.01 | | %/°C |
| df _{REFO} /dV _{CC} | REFO frequency supply voltage drift | Measured at ACLK | 1.8 V to 3.6 V | | 1.0 | | %/V |
| | Duty cycle | Measured at ACLK | 1.8 V to 3.6 V | 40% | 50% | 60% | |
| t _{START} | REFO start-up time | 40%/60% duty cycle | 1.8 V to 3.6 V | | 25 | | μs |

Table 5-5 lists the frequency characteristics of the DCO.

Table 5-5. DCO Frequency

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5-2)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|----------------------|--|--|------|------|-------|
| $f_{DCO(0,0)}$ | DCO frequency (0, 0) ⁽¹⁾ | DCORSELx = 0, DCOx = 0, MODx = 0 | 0.07 | 0.20 | MHz |
| $f_{DCO(0,31)}$ | DCO frequency (0, 31) ⁽¹⁾ | DCORSELx = 0, DCOx = 31, MODx = 0 | 0.70 | 1.70 | MHz |
| $f_{DCO(1,0)}$ | DCO frequency (1, 0) ⁽¹⁾ | DCORSELx = 1, DCOx = 0, MODx = 0 | 0.15 | 0.36 | MHz |
| $f_{DCO(1,31)}$ | DCO frequency (1, 31) ⁽¹⁾ | DCORSELx = 1, DCOx = 31, MODx = 0 | 1.47 | 3.45 | MHz |
| $f_{DCO(2,0)}$ | DCO frequency (2, 0) ⁽¹⁾ | DCORSELx = 2, DCOx = 0, MODx = 0 | 0.32 | 0.75 | MHz |
| $f_{DCO(2,31)}$ | DCO frequency (2, 31) ⁽¹⁾ | DCORSELx = 2, DCOx = 31, MODx = 0 | 3.17 | 7.38 | MHz |
| $f_{DCO(3,0)}$ | DCO frequency (3, 0) ⁽¹⁾ | DCORSELx = 3, DCOx = 0, MODx = 0 | 0.64 | 1.51 | MHz |
| $f_{DCO(3,31)}$ | DCO frequency (3, 31) ⁽¹⁾ | DCORSELx = 3, DCOx = 31, MODx = 0 | 6.07 | 14.0 | MHz |
| $f_{DCO(4,0)}$ | DCO frequency (4, 0) ⁽¹⁾ | DCORSELx = 4, DCOx = 0, MODx = 0 | 1.3 | 3.2 | MHz |
| $f_{DCO(4,31)}$ | DCO frequency (4, 31) ⁽¹⁾ | DCORSELx = 4, DCOx = 31, MODx = 0 | 12.3 | 28.2 | MHz |
| $f_{DCO(5,0)}$ | DCO frequency (5, 0) ⁽¹⁾ | DCORSELx = 5, DCOx = 0, MODx = 0 | 2.5 | 6.0 | MHz |
| $f_{DCO(5,31)}$ | DCO frequency (5, 31) ⁽¹⁾ | DCORSELx = 5, DCOx = 31, MODx = 0 | 23.7 | 54.1 | MHz |
| $f_{DCO(6,0)}$ | DCO frequency (6, 0) ⁽¹⁾ | DCORSELx = 6, DCOx = 0, MODx = 0 | 4.6 | 10.7 | MHz |
| $f_{DCO(6,31)}$ | DCO frequency (6, 31) ⁽¹⁾ | DCORSELx = 6, DCOx = 31, MODx = 0 | 39.0 | 88.0 | MHz |
| $f_{DCO(7,0)}$ | DCO frequency (7, 0) ⁽¹⁾ | DCORSELx = 7, DCOx = 0, MODx = 0 | 8.5 | 19.6 | MHz |
| $f_{DCO(7,31)}$ | DCO frequency (7, 31) ⁽¹⁾ | DCORSELx = 7, DCOx = 31, MODx = 0 | 60 | 135 | MHz |
| $S_{DCORSEL}$ | Frequency step between range DCORSEL and DCORSEL + 1 | $S_{RSEL} = f_{DCO(DCORSEL+1,DCO)}/f_{DCO(DCORSEL,DCO)}$ | 1.2 | 2.3 | ratio |
| S_{DCO} | Frequency step between tap DCO and DCO + 1 | $S_{DCO} = f_{DCO(DCORSEL,DCO+1)}/f_{DCO(DCORSEL,DCO)}$ | 1.02 | 1.12 | ratio |
| | Duty cycle | Measured at SMCLK | 40% | 50% | 60% |
| df_{DCO}/dT | DCO frequency temperature drift | $f_{DCO} = 1 \text{ MHz}$ | 0.1 | | %/°C |
| df_{DCO}/dV_{CORE} | DCO frequency voltage drift | $f_{DCO} = 1 \text{ MHz}$ | 1.9 | | %/V |

- (1) When selecting the proper DCO frequency range (DCORSELx), the target DCO frequency, f_{DCO} , should be set to reside within the range of $f_{DCO(n,0),MAX} \leq f_{DCO} \leq f_{DCO(n,31),MIN}$, where $f_{DCO(n,0),MAX}$ represents the maximum frequency specified for the DCO frequency, range n, tap 0 (DCOx = 0) and $f_{DCO(n,31),MIN}$ represents the minimum frequency specified for the DCO frequency, range n, tap 31 (DCOx = 31). This ensures that the target DCO frequency resides within the range selected. It should also be noted that if the actual f_{DCO} frequency for the selected range causes the FLL or the application to select tap 0 or 31, the DCO fault flag is set to report that the selected range is at its minimum or maximum tap setting.

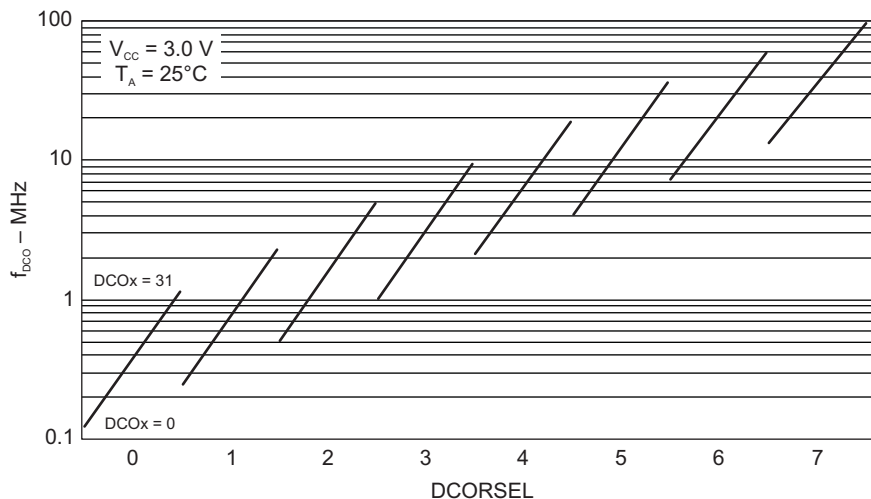


Figure 5-2. Typical DCO Frequency

5.9 Digital I/Os

Table 5-6 lists the input characteristics of the Schmitt-trigger GPIOs.

Table 5-6. Schmitt-Trigger Inputs – General-Purpose I/O

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT |
|-------------------|---|--|-----------------|------|-----|------|------|
| V _{IT+} | Positive-going input threshold voltage | | 1.8 V | 0.80 | | 1.40 | V |
| | | | 3 V | 1.50 | | 2.10 | |
| V _{IT-} | Negative-going input threshold voltage | | 1.8 V | 0.45 | | 1.00 | V |
| | | | 3 V | 0.75 | | 1.65 | |
| V _{hys} | Input voltage hysteresis (V _{IT+} – V _{IT-}) | | 1.8 V | 0.3 | | 0.85 | V |
| | | | 3 V | 0.4 | | 1.0 | |
| R _{Pull} | Pullup or pulldown resistor | For pullup: V _{IN} = V _{SS} , For pulldown: V _{IN} = V _{CC} | | 20 | 35 | 50 | kΩ |
| C _I | Input capacitance | V _{IN} = V _{SS} or V _{CC} | | | 5 | | pF |

Table 5-7 lists the input characteristics of the GPIOs.

Table 5-7. Inputs – Ports P1 and P2⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | MIN | MAX | UNIT |
|--------------------|--|-----------------|-----|-----|------|
| t _(int) | External interrupt timing ⁽²⁾ Port P1, P2: P1.x to P2.x, External trigger pulse duration to set interrupt flag | 2.2 V, 3 V | 20 | | ns |

- (1) Some devices may contain additional ports with interrupts. See the block diagram and terminal function descriptions.
(2) An external signal sets the interrupt flag every time the minimum interrupt pulse duration t_(int) is met. It may be set by trigger signals shorter than t_(int).

Table 5-8 lists the leakage characteristics of the GPIOs.

Table 5-8. Leakage Current – General-Purpose I/O

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | MIN | MAX | UNIT |
|------------------------|--|-----------------|-----|-----|------|
| I _{Ikg(Px.y)} | High-impedance leakage current (1)(2) | 1.8 V, 3 V | -50 | +50 | nA |

- (1) The leakage current is measured with V_{SS} or V_{CC} applied to the corresponding pins, unless otherwise noted.
(2) The leakage of the digital port pins is measured individually. The port pin is selected for input and the pullup or pulldown resistor is disabled.

Table 5-9 lists the output characteristics of the GPIOs in full drive strength mode.

Table 5-9. Outputs – General-Purpose I/O (Full Drive Strength)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Section 5.9.2)

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | MAX | UNIT |
|-----------------|---------------------------|--|-----------------|------|------|------|
| V _{OH} | High-level output voltage | I _(OHmax) = -3 mA ⁽¹⁾ | 1.8 V | 1.55 | 1.80 | V |
| | | I _(OHmax) = -10 mA ⁽¹⁾ | | 1.20 | 1.80 | |
| | | I _(OHmax) = -5 mA ⁽¹⁾ | 3 V | 2.75 | 3.00 | |
| | | I _(OHmax) = -15 mA ⁽¹⁾ | | 2.40 | 3.00 | |
| V _{OL} | Low-level output voltage | I _(OLmax) = 3 mA ⁽²⁾ | 1.8 V | 0.00 | 0.25 | V |
| | | I _(OLmax) = 10 mA ⁽³⁾ | | 0.00 | 0.60 | |
| | | I _(OLmax) = 5 mA ⁽²⁾ | 3 V | 0.00 | 0.25 | |
| | | I _(OLmax) = 15 mA ⁽³⁾ | | 0.00 | 0.60 | |

- (1) The maximum total current, I_(OHmax), for all outputs combined should not exceed ±20 mA to hold the maximum voltage drop specified. See Section 5.3 for more details.
- (2) The maximum total current, I_(OLmax), for all outputs combined should not exceed ±48 mA to hold the maximum voltage drop specified.
- (3) The maximum total current, I_(OLmax), for all outputs combined should not exceed ±100 mA to hold the maximum voltage drop specified.

Table 5-10 lists the output characteristics of the GPIOs in reduced drive strength mode.

Table 5-10. Outputs – General-Purpose I/O (Reduced Drive Strength)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾ (see Section 5.9.1)

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | MAX | UNIT |
|-----------------|---------------------------|---|-----------------|------|------|------|
| V _{OH} | High-level output voltage | I _(OHmax) = -1 mA ⁽²⁾ | 1.8 V | 1.55 | 1.80 | V |
| | | I _(OHmax) = -3 mA ⁽²⁾ | | 1.20 | 1.80 | |
| | | I _(OHmax) = -2 mA ⁽²⁾ | 3 V | 2.75 | 3.00 | |
| | | I _(OHmax) = -6 mA ⁽²⁾ | | 2.40 | 3.00 | |
| V _{OL} | Low-level output voltage | I _(OLmax) = 1 mA ⁽³⁾ | 1.8 V | 0.00 | 0.25 | V |
| | | I _(OLmax) = 3 mA ⁽⁴⁾ | | 0.00 | 0.60 | |
| | | I _(OLmax) = 2 mA ⁽³⁾ | 3 V | 0.00 | 0.25 | |
| | | I _(OLmax) = 6 mA ⁽⁴⁾ | | 0.00 | 0.60 | |

- (1) Selecting reduced drive strength may reduce EMI.
- (2) The maximum total current, I_(OHmax), for all outputs combined should not exceed ±20 mA to hold the maximum voltage drop specified. See Section 5.3 for more details.
- (3) The maximum total current, I_(OLmax), for all outputs combined, should not exceed ±48 mA to hold the maximum voltage drop specified.
- (4) The maximum total current, I_(OLmax), for all outputs combined, should not exceed ±100 mA to hold the maximum voltage drop specified.

Table 5-11 lists the output frequency of the GPIOs.

Table 5-11. Output Frequency – General-Purpose I/O

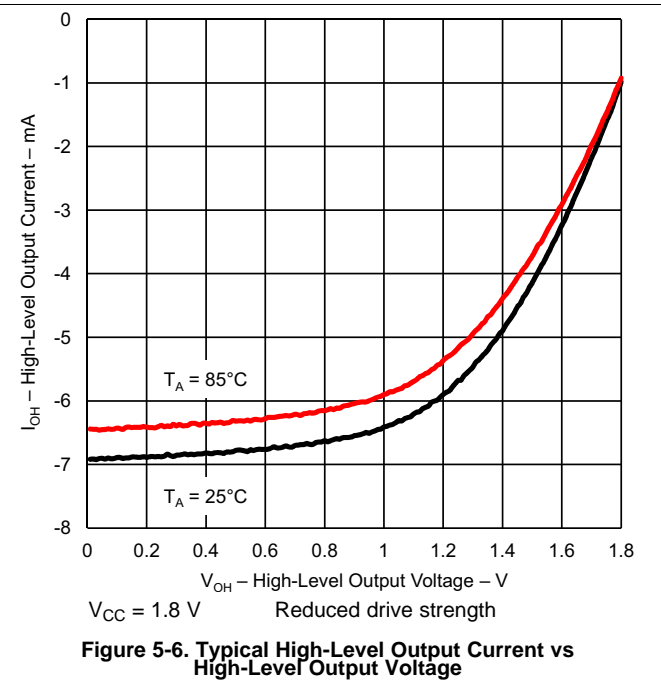
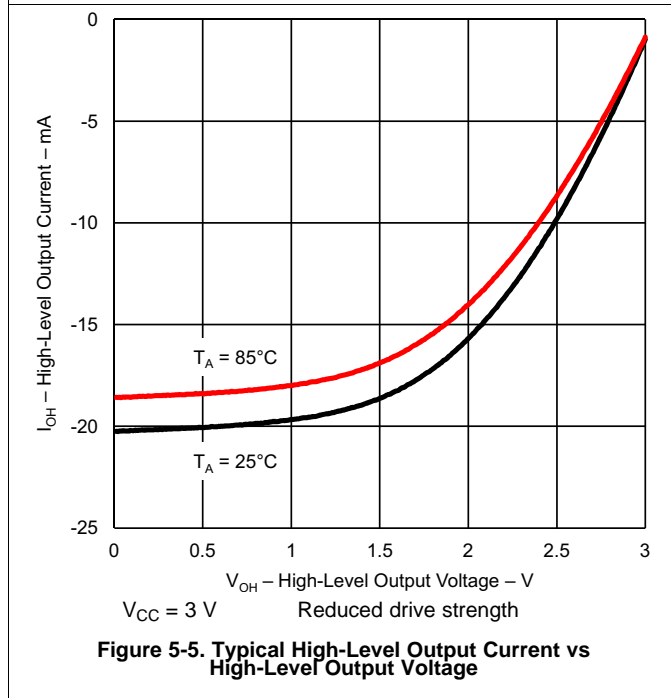
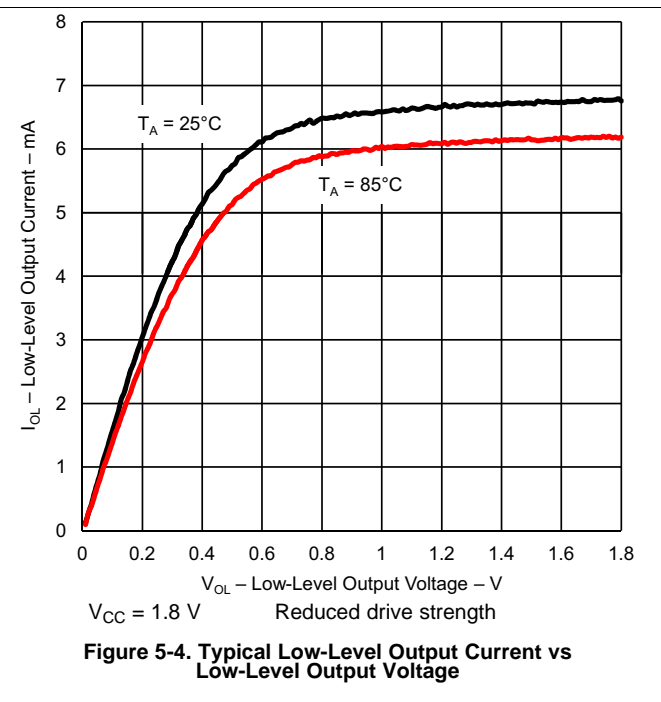
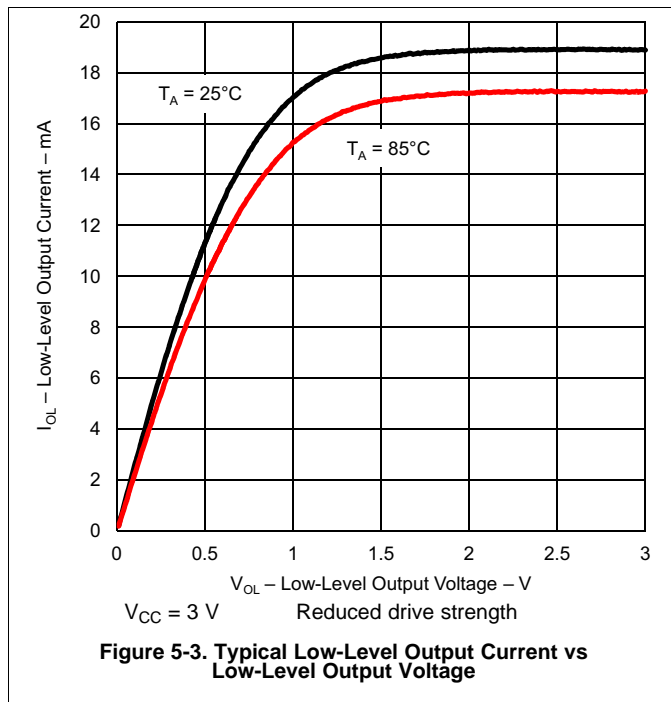
over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | MAX | UNIT |
|-----------------------|-----------------------------------|--|---|-----|------|
| f _{Px,y} | Port output frequency (with load) | See ⁽¹⁾ ⁽²⁾ | V _{CC} = 1.8 V, PMMCOREVx = 0 | 16 | MHz |
| | | | V _{CC} = 3 V, PMMCOREVx = 3 | 25 | |
| f _{Port_CLK} | Clock output frequency | ACLK SMCLK MCLK C _L = 20 pF ⁽²⁾ | V _{CC} = 1.8 V, PMMCOREVx = 0 | 16 | MHz |
| | | | V _{CC} = 3 V, PMMCOREVx = 3 | 25 | |

- (1) A resistive divider with 2 × R1 between V_{CC} and V_{SS} is used as load. The output is connected to the center tap of the divider. For full drive strength, R1 = 550 Ω. For reduced drive strength, R1 = 1.6 kΩ. C_L = 20 pF is connected to the output to V_{SS}.
- (2) The output voltage reaches at least 10% and 90% V_{CC} at the specified toggle frequency.

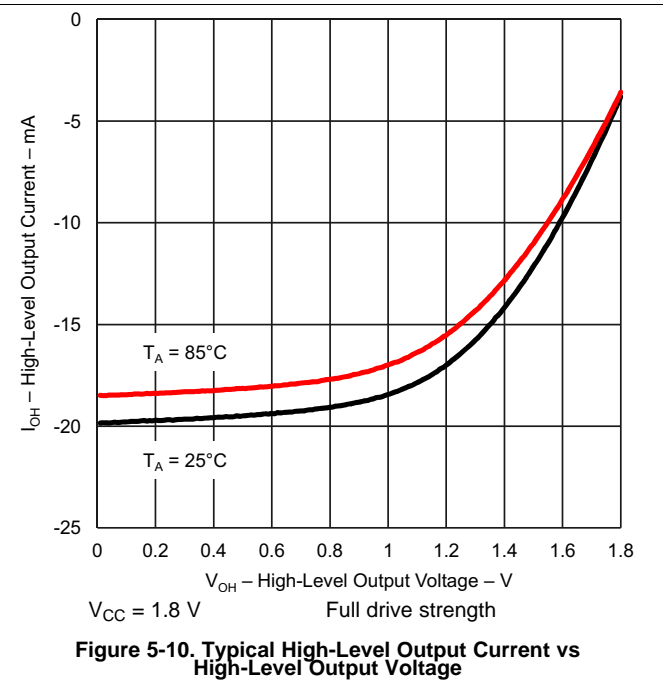
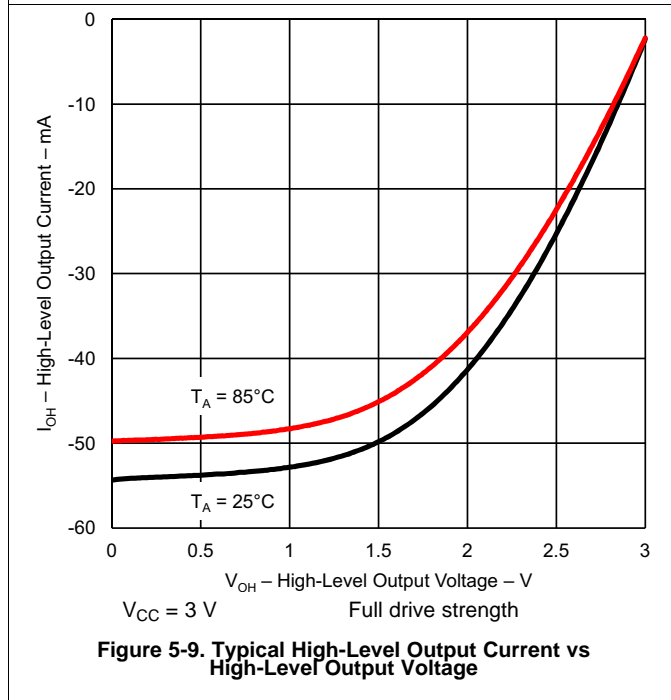
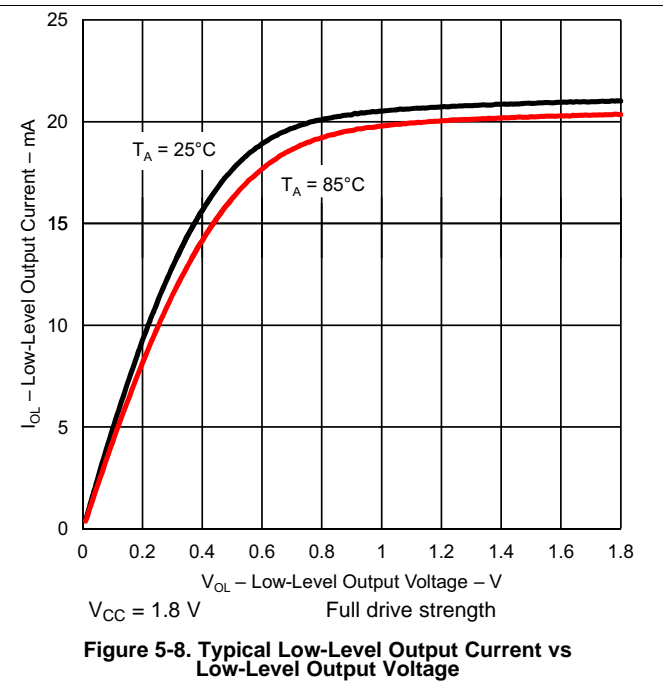
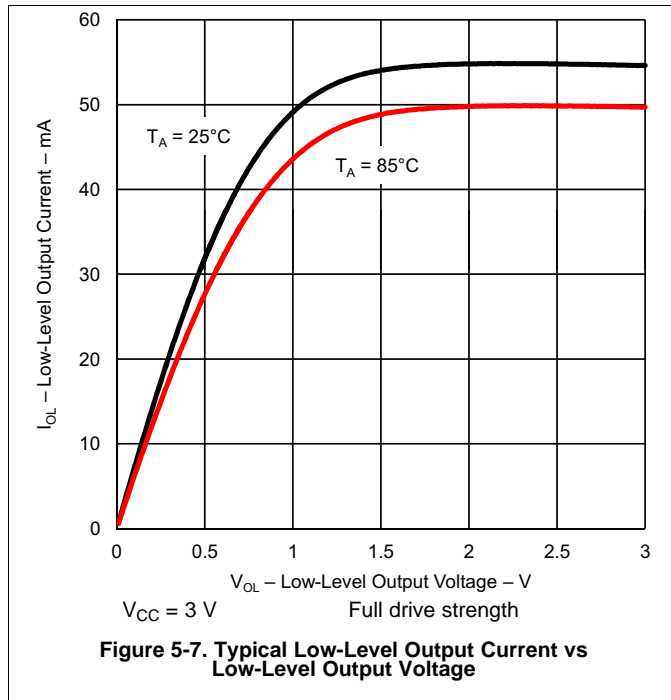
5.9.1 Typical Characteristics – Outputs, Reduced Drive Strength ($P_{xDS.y} = 0$)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)



5.9.2 Typical Characteristics – Outputs, Full Drive Strength ($P_{xDS.y} = 1$)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)



5.10 Power-Management Module (PMM)

Table 5-12 lists the characteristics of the BOR.

Table 5-12. PMM, Brownout Reset (BOR)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------------|---|---------------------------------|------|------|------|------|
| $V_{(DVCC_BOR_IT-)}$ | BOR _H on voltage, DV _{CC} falling level | $ dDV_{CC}/dt < 3 \text{ V/s}$ | | | 1.45 | V |
| $V_{(DVCC_BOR_IT+)}$ | BOR _H off voltage, DV _{CC} rising level | $ dDV_{CC}/dt < 3 \text{ V/s}$ | 0.80 | 1.20 | 1.50 | V |
| $V_{(DVCC_BOR_hys)}$ | BOR _H hysteresis | | 50 | | 250 | mV |
| t_{RESET} | Pulse duration required at \overline{RST}/NMI pin to accept a reset | | 2 | | | μs |

Table 5-13 lists the core voltage characteristics of the PMM.

Table 5-13. PMM, Core Voltage

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------|--|---|-----|------|-----|------|
| $V_{CORE3(AM)}$ | Core voltage, active mode, PMMCOREV = 3 | $2.4 \text{ V} \leq DV_{CC} \leq 3.6 \text{ V}$ | | 1.91 | | V |
| $V_{CORE2(AM)}$ | Core voltage, active mode, PMMCOREV = 2 | $2.2 \text{ V} \leq DV_{CC} \leq 3.6 \text{ V}$ | | 1.81 | | V |
| $V_{CORE1(AM)}$ | Core voltage, active mode, PMMCOREV = 1 | $2 \text{ V} \leq DV_{CC} \leq 3.6 \text{ V}$ | | 1.61 | | V |
| $V_{CORE0(AM)}$ | Core voltage, active mode, PMMCOREV = 0 | $1.8 \text{ V} \leq DV_{CC} \leq 3.6 \text{ V}$ | | 1.41 | | V |
| $V_{CORE3(LPM)}$ | Core voltage, low-current mode, PMMCOREV = 3 | $2.4 \text{ V} \leq DV_{CC} \leq 3.6 \text{ V}$ | | 1.94 | | V |
| $V_{CORE2(LPM)}$ | Core voltage, low-current mode, PMMCOREV = 2 | $2.2 \text{ V} \leq DV_{CC} \leq 3.6 \text{ V}$ | | 1.92 | | V |
| $V_{CORE1(LPM)}$ | Core voltage, low-current mode, PMMCOREV = 1 | $2 \text{ V} \leq DV_{CC} \leq 3.6 \text{ V}$ | | 1.73 | | V |
| $V_{CORE0(LPM)}$ | Core voltage, low-current mode, PMMCOREV = 0 | $1.8 \text{ V} \leq DV_{CC} \leq 3.6 \text{ V}$ | | 1.52 | | V |

Table 5-14 lists the characteristics of the high-side SVS.

Table 5-14. PMM, SVS High Side

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-------------------|---------------------------------------|--|------|------|------|------|
| $I_{(SVSH)}$ | SVS current consumption | SVSHE = 0, DV _{CC} = 3.6 V | | 0 | | nA |
| | | SVSHE = 1, DV _{CC} = 3.6 V, SVSHFP = 0 | | 200 | | |
| | | SVSHE = 1, DV _{CC} = 3.6 V, SVSHFP = 1 | | 1.5 | | μA |
| $V_{(SVSH_IT-)}$ | SVS _H on voltage level | SVSHE = 1, SVSHRVL = 0 | 1.60 | 1.65 | 1.75 | V |
| | | SVSHE = 1, SVSHRVL = 1 | 1.77 | 1.84 | 1.95 | |
| | | SVSHE = 1, SVSHRVL = 2 | 1.93 | 2.00 | 2.12 | |
| | | SVSHE = 1, SVSHRVL = 3 | 2.09 | 2.16 | 2.29 | |
| $V_{(SVSH_IT+)}$ | SVS _H off voltage level | SVSHE = 1, SVSMHRRL = 0 | 1.65 | 1.75 | 1.85 | V |
| | | SVSHE = 1, SVSMHRRL = 1 | 1.85 | 1.95 | 2.05 | |
| | | SVSHE = 1, SVSMHRRL = 2 | 2.05 | 2.15 | 2.25 | |
| | | SVSHE = 1, SVSMHRRL = 3 | 2.15 | 2.25 | 2.35 | |
| | | SVSHE = 1, SVSMHRRL = 4 | 2.30 | 2.40 | 2.55 | |
| | | SVSHE = 1, SVSMHRRL = 5 | 2.57 | 2.70 | 2.83 | |
| | | SVSHE = 1, SVSMHRRL = 6 | 2.90 | 3.05 | 3.20 | |
| | | SVSHE = 1, SVSMHRRL = 7 | 2.90 | 3.05 | 3.20 | |
| $t_{pd(SVSH)}$ | SVS _H propagation delay | SVSHE = 1, dV _{DVCC} /dt = 10 mV/μs, SVSHFP = 1 | | 2.5 | | μs |
| | | SVSHE = 1, dV _{DVCC} /dt = 1 mV/μs, SVSHFP = 0 | | 20 | | |
| $t_{(SVSH)}$ | SVS _H on or off delay time | SVSHE = 0 → 1, dV _{DVCC} /dt = 10 mV/μs, SVSHFP = 1 | | 12.5 | | μs |
| | | SVSHE = 0 → 1, dV _{DVCC} /dt = 1 mV/μs, SVSHFP = 0 | | 100 | | |
| dV_{DVCC}/dt | DVCC rise time | | 0 | | 1000 | V/s |

Table 5-15 lists the characteristics of the high-side SVM.

Table 5-15. PMM, SVM High Side

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|--|------|------|------|------|
| $I_{(SVMH)}$ SVM _H current consumption | SVMHE = 0, DV _{CC} = 3.6 V | | 0 | | nA |
| | SVMHE = 1, DV _{CC} = 3.6 V, SVMHFP = 0 | | 200 | | |
| | SVMHE = 1, DV _{CC} = 3.6 V, SVMHFP = 1 | | 1.5 | | μA |
| $V_{(SVMH)}$ SVM _H on or off voltage level ⁽¹⁾ | SVMHE = 1, SVSMHRRRL = 0 | 1.63 | 1.73 | 1.83 | V |
| | SVMHE = 1, SVSMHRRRL = 1 | 1.83 | 1.93 | 2.03 | |
| | SVMHE = 1, SVSMHRRRL = 2 | 2.03 | 2.13 | 2.23 | |
| | SVMHE = 1, SVSMHRRRL = 3 | 2.13 | 2.23 | 2.33 | |
| | SVMHE = 1, SVSMHRRRL = 4 | 2.28 | 2.40 | 2.53 | |
| | SVMHE = 1, SVSMHRRRL = 5 | 2.55 | 2.70 | 2.81 | |
| | SVMHE = 1, SVSMHRRRL = 6 | 2.88 | 3.02 | 3.18 | |
| | SVMHE = 1, SVSMHRRRL = 7 | 2.88 | 3.02 | 3.18 | |
| $t_{pd(SVMH)}$ SVM _H propagation delay | SVMHE = 1, dV _{DVCC} /dt = 10 mV/μs, SVMHFP = 1 | | 2.5 | | μs |
| | SVMHE = 1, dV _{DVCC} /dt = 1 mV/μs, SVMHFP = 0 | | 20 | | |
| $t_{t(SVMH)}$ SVM _H on or off delay time | SVMHE = 0 → 1, dV _{DVCC} /dt = 10 mV/μs, SVMHFP = 1 | | 12.5 | | μs |
| | SVMHE = 0 → 1, dV _{DVCC} /dt = 1 mV/μs, SVMHFP = 0 | | 100 | | |

(1) The SVM_H settings available depend on the V_{CORE} (PMMCOREV_x) setting. See the *Power Management Module and Supply Voltage Supervisor* chapter in the *MSP430x5xx and MSP430x6xx Family User's Guide* on recommended settings and use.

Table 5-16 lists the characteristics of the low-side SVS.

Table 5-16. PMM, SVS Low Side

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|--|-----|------|-----|------|
| $I_{(SVSL)}$ SVS _L current consumption | SVSLE = 0, PMMCOREV = 2 | | 0 | | nA |
| | SVSLE = 1, PMMCOREV = 2, SVSLFP = 0 | | 200 | | |
| | SVSLE = 1, PMMCOREV = 2, SVSLFP = 1 | | 1.5 | | μA |
| $t_{pd(SVSL)}$ SVS _L propagation delay | SVSLE = 1, dV _{CORE} /dt = 10 mV/μs, SVSLFP = 1 | | 2.5 | | μs |
| | SVSLE = 1, dV _{CORE} /dt = 1 mV/μs, SVSLFP = 0 | | 20 | | |
| $t_{t(SVSL)}$ SVS _L on or off delay time | SVSLE = 0 → 1, dV _{CORE} /dt = 10 mV/μs, SVSLFP = 1 | | 12.5 | | μs |
| | SVSLE = 0 → 1, dV _{CORE} /dt = 1 mV/μs, SVSLFP = 0 | | 100 | | |

Table 5-17 lists the characteristics of the low-side SVM.

Table 5-17. PMM, SVM Low Side

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-----------------|---------------------------------------|--|-----|------|-----|------|
| $I_{(SVM_L)}$ | SVM _L current consumption | SVMLE = 0, PMMCOREV = 2 | | 0 | | nA |
| | | SVMLE = 1, PMMCOREV = 2, SVMLFP = 0 | | 200 | | |
| | | SVMLE = 1, PMMCOREV = 2, SVMLFP = 1 | | 1.5 | | μA |
| $t_{pd(SVM_L)}$ | SVM _L propagation delay | SVMLE = 1, $dV_{CORE}/dt = 10 \text{ mV}/\mu\text{s}$, SVMLFP = 1 | | 2.5 | | μs |
| | | SVMLE = 1, $dV_{CORE}/dt = 1 \text{ mV}/\mu\text{s}$, SVMLFP = 0 | | 20 | | |
| $t_{(SVM_L)}$ | SVM _L on or off delay time | SVMLE = 0 → 1, $dV_{CORE}/dt = 10 \text{ mV}/\mu\text{s}$, SVMLFP = 1 | | 12.5 | | μs |
| | | SVMLE = 0 → 1, $dV_{CORE}/dt = 1 \text{ mV}/\mu\text{s}$, SVMLFP = 0 | | 100 | | |

5.11 Auxiliary Supplies

Table 5-18 lists the recommended operating conditions of the auxiliary supplies.

Table 5-18. Auxiliary Supplies, Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

| | | MIN | NOM | MAX | UNIT |
|-----------------------|--|---------------------------|------|-----|------|
| V_{CC} | Supply voltage range for all supplies at pins DVCC, AVCC, AUXVCC1, AUXVCC2, AUXVCC3 | 1.8 | | 3.6 | V |
| V_{DSYS} | Digital system supply voltage range, $V_{DSYS} = V_{CC} - R_{ON} \times I_{LOAD}$ | PMMCOREV _x = 0 | | 3.6 | V |
| | | PMMCOREV _x = 1 | 2.0 | 3.6 | |
| | | PMMCOREV _x = 2 | 2.2 | 3.6 | |
| | | PMMCOREV _x = 3 | 2.4 | 3.6 | |
| V_{ASYS} | Analog system supply voltage range, $V_{ASYS} = V_{CC} - R_{ON} \times I_{LOAD}$ | See module specifications | | | V |
| T_A | Ambient temperature range | -40 | | 85 | °C |
| $T_{A,HTOL}$ | Ambient temperature during HTOL (module should be functional during HTOL) | | | 150 | °C |
| $C_{VCC}, C_{AUX1/2}$ | Recommended capacitor at pins DVCC, AVCC, AUXVCC1, AUXVCC2 | | 4.7 | | μF |
| C_{VSY} | Recommended capacitor at pins VDSYS1, VDSYS2 and VASYS1, VASYS2 | | 4.7 | | μF |
| C_{VCORE} | Recommended capacitance at pin V _{CORE} | | 0.47 | | μF |
| C_{AUX3} | Recommended capacitor at pin AUXVCC3 | | 0.47 | | μF |

Table 5-19 lists the current consumption of the backup subsystem.

Table 5-19. Auxiliary Supplies, AUXVCC3 (Backup Subsystem) Currents

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V_{CC} | T_A | MIN | MAX | UNIT |
|-------------------|-----------------------------------|----------|-------|-----|------|------|
| $I_{AUX3,RTCOn}$ | AUXVCC3 current with RTC enabled | 3 V | 25°C | | 0.86 | μA |
| | | | 85°C | | 1.2 | |
| $I_{AUX3,RTCOff}$ | AUXVCC3 current with RTC disabled | 3 V | 25°C | | 120 | nA |
| | | | 85°C | | 220 | |

Table 5-20 lists the characteristics of the auxiliary supply monitor.

Table 5-20. Auxiliary Supplies, Auxiliary Supply Monitor

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------------|--|--|--|--|--|---------|
| $I_{CC,Monitor}$ | Average supply current for monitoring circuitry drawn from VDSYS | LOCKAUX = 0, AUXMRx = 0 AUX0MD = 0, AUX1MD = 0, AUX2MD = 1, VDSYS = DVCC, VASYS = AVCC, Current measured at VDSYS | | | 1.10 | μ A |
| $I_{Meas,Monitor}$ | Average current drawn from monitored supply during measurement cycle | LOCKAUX = 0, AUXMRx = 0 AUX0MD = 0, AUX1MD = 0, AUX2MD = 1, VDSYS = DVCC, VASYS = AVCC, Current measured at AUXVCC1 | | | 0.13 | μ A |
| $V_{Monitor}$ | Auxiliary supply threshold level (same as high-side SVM) | General | V_{SVMH} (SVSMHRRL x = AUXLVLx) X - 5% | V_{SVMH} (SVSMHRRL x = AUXLVLx) | V_{SVMH} (SVSMHRRLx = AUXLVLx) X + 5% | V |
| | | AUXLVLx = 0 | 1.65 | 1.75 | 1.85 | |
| | | AUXLVLx = 1 | 1.85 | 1.95 | 2.05 | |
| | | AUXLVLx = 2 | 2.05 | 2.15 | 2.25 | |
| | | AUXLVLx = 3 | 2.15 | 2.25 | 2.35 | |
| | | AUXLVLx = 4 | 2.30 | 2.40 | 2.55 | |
| | | AUXLVLx = 5 | 2.57 | 2.70 | 2.83 | |
| | | AUXLVLx = 6 | 2.90 | 3.00 | 3.20 | |
| AUXLVLx = 7 | 2.90 | 3.00 | 3.20 | | | |

Table 5-21 lists the ON-resistance characteristics of the switches.

Table 5-21. Auxiliary Supplies, Switch ON-Resistance

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | MAX | UNIT |
|----------------|---|---|-----|-----|----------|
| $R_{ON,DVCC}$ | ON-resistance of switch between DVCC and VDSYS | $I_{LOAD} = I_{CORE} + I_{IO} = 10\text{ mA} + 10\text{ mA} = 20\text{ mA}$ | | 5 | Ω |
| $R_{ON,DAUX1}$ | ON-resistance of switch between AUXVCC1 and VDSYS | $I_{LOAD} = I_{CORE} + I_{IO} = 10\text{ mA} + 10\text{ mA} = 20\text{ mA}$ | | 5 | Ω |
| $R_{ON,DAUX2}$ | ON-resistance of switch between AUXVCC2 and VDSYS | $I_{LOAD} = I_{CORE} + I_{IO} = 10\text{ mA} + 10\text{ mA} = 20\text{ mA}$ | | 5 | Ω |
| $R_{ON,AVCC}$ | ON-resistance of switch between AVCC and VASYS | $I_{LOAD} = I_{Modules} = 10\text{ mA}$ | | 5 | Ω |
| $R_{ON,AAUX1}$ | ON-resistance of switch between AUXVCC1 and VASYS | $I_{LOAD} = I_{Modules} = 5\text{ mA}$ | | 20 | Ω |
| $R_{ON,AAUX2}$ | ON-resistance of switch between AUXVCC2 and VASYS | $I_{LOAD} = I_{Modules} = 5\text{ mA}$ | | 20 | Ω |

Table 5-22 lists the switching times of the auxiliary supplies.

Table 5-22. Auxiliary Supplies, Switching Time

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | MIN | MAX | UNIT |
|----------------------|---|-----|-----|---------------|
| t_{Switch} | Time from occurrence of trigger (SVM or software) to "new" supply connected to system supplies | | 100 | ns |
| t_{Recover} | "Recovery time" after a switch over takes place. During this time, another switch cannot occur. | 170 | 480 | μs |

Table 5-23 lists the leakage characteristics of the switch.

Table 5-23. Auxiliary Supplies, Switch Leakage

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---------------------|--|---|-----|-----|------|
| $I_{\text{SW,Lkg}}$ | Current into DVCC, AVCC, AUXVCC1, or AUXVCC2 if not selected | Per supply (but not the highest supply) | | | |
| | | | 75 | 250 | nA |
| I_{Vmax} | Current drawn from highest supply | | 500 | 700 | nA |

Table 5-24 lists the characteristics of the auxiliary supplies to the ADC.

Table 5-24. Auxiliary Supplies, Auxiliary Supplies to ADC10_A

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | V_{CC} | MIN | TYP | MAX | UNIT |
|------------------------|---|--|--------------|-----------------|------|-----|------|------------|
| V_3 | Supply voltage divider $V_3 = V_{\text{Supply}} / 3$ | | | 1.8 V | 0.57 | 0.6 | 0.63 | V |
| | | | | 3 V | 0.95 | 1.0 | 1.05 | |
| | | | | 3.6 V | 1.14 | 1.2 | 1.26 | |
| R_{V3} | Load resistance | AUXADCRx = 0 | | | | | 15 | k Ω |
| | | AUXADCRx = 1 | | | | | 1.5 | |
| | | AUXADCRx = 2 | | | | | 0.6 | |
| $t_{\text{Sample,V3}}$ | Sampling time required if V_3 is selected | Error of conversion result ≤ 1 LSB | AUXADCRx = 0 | | 1000 | | | ns |
| | | | AUXADCRx = 1 | | 1000 | | | |
| | | | AUXADCRx = 2 | | 1000 | | | |

Table 5-25 lists the characteristics of the charge limiting resistor.

Table 5-25. Auxiliary Supplies, Charge Limiting Resistor

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V_{CC} | MIN | TYP | MAX | UNIT |
|---------------------|--------------------------|-----------------|-----------------|-----|-----|-----|------------|
| R_{CHARGE} | Charge limiting resistor | AUXCHCx = 1 | 3 V | | | 5 | k Ω |
| | | AUXCHCx = 2 | | | | 10 | |
| | | AUXCHCx = 3 | | | | 20 | |

5.12 Timer_A

Table 5-26 lists the characteristics of the Timer_A.

Table 5-26. Timer_A

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | MAX | UNIT |
|---------------------|-------------------------------|---|-----------------|-----|-----|------|
| f _{TA} | Timer_A input clock frequency | Internal: SMCLK or ACLK, External: TACLK, Duty cycle = 50% ±10% | 1.8 V, 3 V | | 25 | MHz |
| t _{TA,cap} | Timer_A capture timing | All capture inputs, Minimum pulse duration required for capture | 1.8 V, 3 V | 20 | | ns |

5.13 eUSCI

Table 5-27 lists the supported clock frequencies of the eUSCI in UART mode.

Table 5-27. eUSCI (UART Mode) Clock Frequency

| PARAMETER | | TEST CONDITIONS | MIN | MAX | UNIT |
|---------------------|---|--|-----|---------------------|------|
| f _{eUSCI} | eUSCI input clock frequency | Internal: SMCLK or ACLK, External: UCLK, Duty cycle = 50% ±10% | | f _{SYSTEM} | MHz |
| f _{BITCLK} | BITCLK clock frequency (equals baud rate in MBaud) | | | 5 | MHz |

Table 5-28 lists the switching characteristics of the eUSCI in UART mode.

Table 5-28. eUSCI (UART Mode) Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT |
|----------------|---|-----------------|-----------------|-----|-----|-----|------|
| t _t | UART receive deglitch time ⁽¹⁾ | UCGLITx = 0 | 2 V, 3 V | 10 | 15 | 25 | ns |
| | | UCGLITx = 1 | | 30 | 50 | 85 | |
| | | UCGLITx = 2 | | 50 | 80 | 150 | |
| | | UCGLITx = 3 | | 70 | 120 | 200 | |

(1) Pulses on the UART receive input (UCxRX) shorter than the UART receive deglitch time are suppressed. To make sure that pulses are correctly recognized, their duration should exceed the maximum specification of the deglitch time.

Table 5-29 lists the supported clock frequencies of the eUSCI in SPI master mode.

Table 5-29. eUSCI (SPI Master Mode) Clock Frequency

| PARAMETER | | TEST CONDITIONS | MIN | MAX | UNIT |
|-------------|-----------------------------|--|-----|--------------|------|
| f_{eUSCI} | eUSCI input clock frequency | Internal: SMCLK or ACLK, Duty cycle = 50% \pm 10% | | f_{SYSTEM} | MHZ |

Table 5-30 lists the switching characteristics of the eUSCI in SPI master mode.

Table 5-30. eUSCI (SPI Master Mode) Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | MAX | UNIT |
|----------------|---|---|-----------------|-----|-----|------|
| $t_{STE,LEAD}$ | STE lead time, STE low to clock | UCSTEM = 0, UCMODEx = 01 or 10 | 2 V, 3 V | 150 | | ns |
| | | UCSTEM = 1, UCMODEx = 01 or 10 | | 150 | | |
| $t_{STE,LAG}$ | STE lag time, Last clock to STE high | UCSTEM = 0, UCMODEx = 01 or 10 | 2 V, 3 V | 200 | | ns |
| | | UCSTEM = 1, UCMODEx = 01 or 10 | | 200 | | |
| $t_{STE,ACC}$ | STE access time, STE low to SIMO data out | UCSTEM = 0, UCMODEx = 01 or 10 | 2 V | 50 | | ns |
| | | | 3 V | 30 | | |
| | | UCSTEM = 1, UCMODEx = 01 or 10 | 2 V | 50 | | |
| | | | 3 V | 30 | | |
| $t_{STE,DIS}$ | STE disable time, STE high to SIMO high impedance | UCSTEM = 0, UCMODEx = 01 or 10 | 2 V | 40 | | ns |
| | | | 3 V | 25 | | |
| | | UCSTEM = 1, UCMODEx = 01 or 10 | 2 V | 40 | | |
| | | | 3 V | 25 | | |
| $t_{SU,MI}$ | SOMI input data setup time | | 2 V | 50 | | ns |
| | | | 3 V | 30 | | |
| $t_{HD,MI}$ | SOMI input data hold time | | 2 V | 0 | | ns |
| | | | 3 V | 0 | | |
| $t_{VALID,MO}$ | SIMO output data valid time ⁽²⁾ | UCLK edge to SIMO valid, C _L = 20 pF | 2 V | 9 | | ns |
| | | | 3 V | 5 | | |
| $t_{HD,MO}$ | SIMO output data hold time ⁽³⁾ | C _L = 20 pF | 2 V | 0 | | ns |
| | | | 3 V | 0 | | |

- $f_{UCxCLK} = 1/2t_{LO/HI}$ with $t_{LO/HI} = \max(t_{VALID,MO}(eUSCI) + t_{SU,SI}(Slave), t_{SU,MI}(eUSCI) + t_{VALID,SO}(Slave))$
For the slave parameters $t_{SU,SI}(Slave)$ and $t_{VALID,SO}(Slave)$, see the SPI parameters of the attached slave.
- Specifies the time to drive the next valid data to the SIMO output after the output changing UCLK clock edge. See the timing diagrams in Figure 5-11 and Figure 5-12.
- Specifies how long data on the SIMO output is valid after the output changing UCLK clock edge. Negative values indicate that the data on the SIMO output can become invalid before the output changing clock edge observed on UCLK. See the timing diagrams in Figure 5-11 and Figure 5-12.

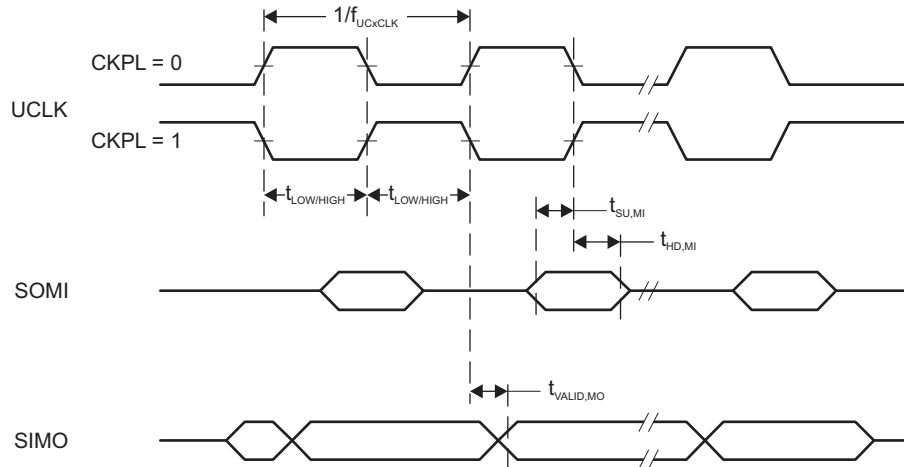


Figure 5-11. SPI Master Mode, CKPH = 0

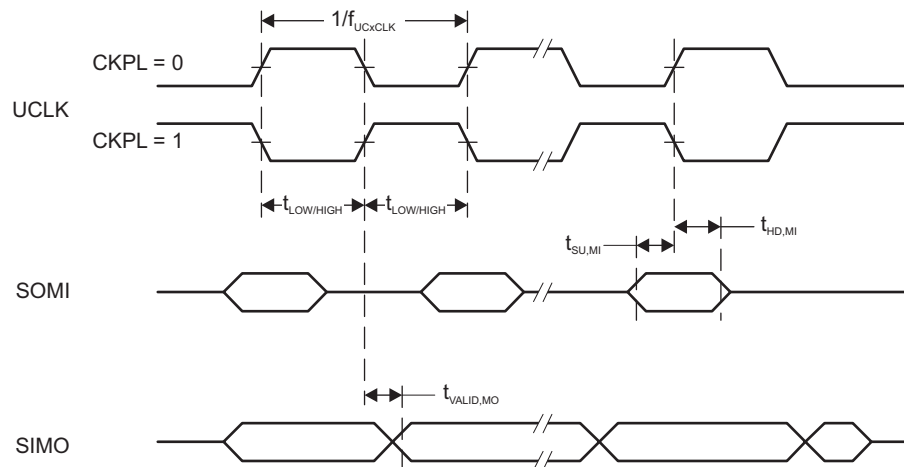


Figure 5-12. SPI Master Mode, CKPH = 1

Table 5-31 lists the characteristics of the eUSCI in SPI slave mode.

Table 5-31. eUSCI (SPI Slave Mode)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT |
|-----------------------|---|--|-----------------|-----|-----|-----|------|
| t _{STE,LEAD} | STE lead time, STE low to clock | | 2 V | 4 | | | ns |
| | | | 3 V | 3 | | | |
| t _{STE,LAG} | STE lag time, Last clock to STE high | | 2 V | 0 | | | ns |
| | | | 3 V | 0 | | | |
| t _{STE,ACC} | STE access time, STE low to SOMI data out | | 2 V | | | 46 | ns |
| | | | 3 V | | | 24 | |
| t _{STE,DIS} | STE disable time, STE high to SOMI high impedance | | 2 V | | | 38 | ns |
| | | | 3 V | | | 25 | |
| t _{SU,SI} | SIMO input data setup time | | 2 V | 2 | | | ns |
| | | | 3 V | 1 | | | |
| t _{HD,SI} | SIMO input data hold time | | 2 V | 2 | | | ns |
| | | | 3 V | 2 | | | |
| t _{VALID,SO} | SOMI output data valid time ⁽²⁾ | UCLK edge to SOMI valid, C _L = 20 pF | 2 V | | | 55 | ns |
| | | | 3 V | | | 32 | |
| t _{HD,SO} | SOMI output data hold time ⁽³⁾ | C _L = 20 pF | 2 V | 24 | | | ns |
| | | | 3 V | 16 | | | |

- (1) $f_{UCxCLK} = 1/2t_{LO/HI}$ with $t_{LO/HI} \geq \max(t_{VALID,MO(Master)} + t_{SU,SI(eUSCI)}, t_{SU,MI(Master)} + t_{VALID,SO(eUSCI)})$
For the master parameters $t_{SU,MI(Master)}$ and $t_{VALID,MO(Master)}$, see the SPI parameters of the attached master.
- (2) Specifies the time to drive the next valid data to the SOMI output after the output changing UCLK clock edge. See the timing diagrams in [Figure 5-13](#) and [Figure 5-14](#).
- (3) Specifies how long data on the SOMI output is valid after the output changing UCLK clock edge. See the timing diagrams in [Figure 5-13](#) and [Figure 5-14](#).

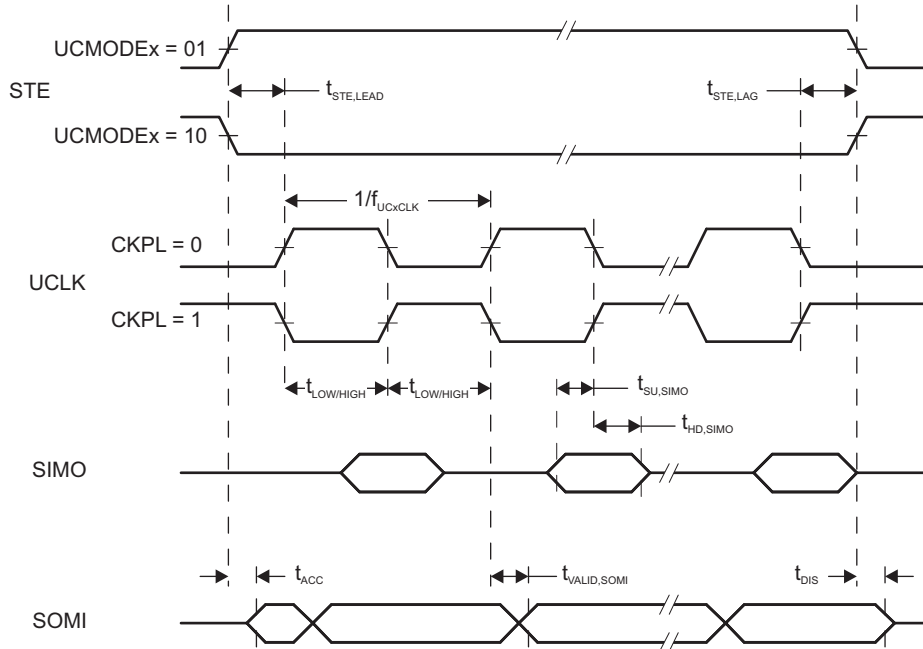


Figure 5-13. SPI Slave Mode, CKPH = 0

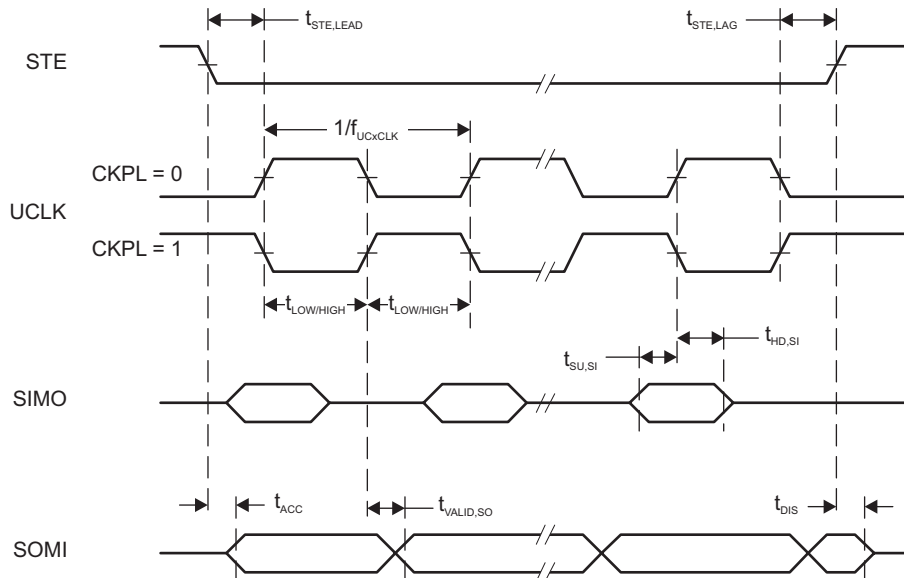


Figure 5-14. SPI Slave Mode, CKPH = 1

Table 5-32 lists the characteristics of the eUSCI in I²C mode.

Table 5-32. eUSCI (I²C Mode) Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5-15)

| PARAMETER | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT |
|----------------------|---|--|----------|----------------------|------------------------|------|
| f _{eUSCI} | eUSCI input clock frequency | | | f _{SYSTEM} | | MHz |
| f _{SCL} | SCL clock frequency | 2 V, 3 V | 0 | | 400 | kHz |
| t _{HD,STA} | Hold time (repeated) START | f _{SCL} = 100 kHz f _{SCL} > 100 kHz | 2 V, 3 V | 5.1 1.5 | | μs |
| t _{SU,STA} | Setup time for a repeated START | f _{SCL} = 100 kHz f _{SCL} > 100 kHz | 2 V, 3 V | 5.1 1.4 | | μs |
| t _{HD,DAT} | Data hold time | | 2 V, 3 V | 0.4 | | μs |
| t _{SU,DAT} | Data setup time | f _{SCL} = 100 kHz f _{SCL} > 100 kHz | 2 V, 3 V | 5.0 1.3 | | μs |
| t _{SU,STO} | Setup time for STOP | f _{SCL} = 100 kHz f _{SCL} > 100 kHz | 2 V, 3 V | 5.2 1.7 | | μs |
| t _{SP} | Pulse duration of spikes suppressed by input filter | UCGLITx = 0 UCGLITx = 1 UCGLITx = 2 UCGLITx = 3 | 2 V, 3 V | 75 35 30 20 | 220 120 60 35 | ns |
| t _{TIMEOUT} | Clock low time-out | UCCLTOx = 1 UCCLTOx = 2 UCCLTOx = 3 | 2 V, 3 V | 30 33 37 | | ms |

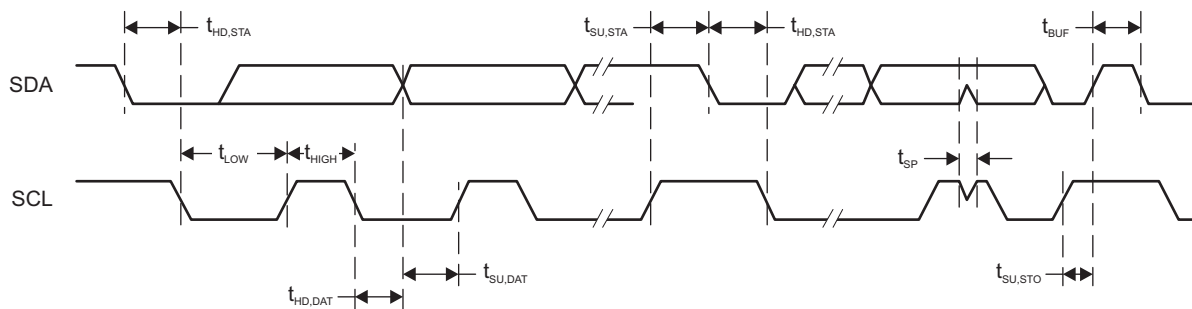


Figure 5-15. I²C Mode Timing

5.14 RTC Tamper Detect Pin

Table 5-33 lists the input characteristics of the tamper detect pin.

Table 5-33. Schmitt-Trigger Inputs, RTC Tamper Detect Pin

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | AUXVCC3 | MIN | TYP | MAX | UNIT |
|--|--|---------|------|-----|------|------|
| V _{IT+} Positive-going input threshold voltage | | 1.8 V | 0.80 | | 1.40 | V |
| | | 3 V | 1.50 | | 2.10 | |
| V _{IT-} Negative-going input threshold voltage | | 1.8 V | 0.45 | | 1.00 | V |
| | | 3 V | 0.75 | | 1.65 | |
| V _{hys} Input voltage hysteresis (V _{IT+} – V _{IT-}) | | 1.8 V | 0.3 | | 0.85 | V |
| | | 3 V | 0.4 | | 1.0 | |
| R _{Pull} Pullup or pulldown resistor | For pullup: V _{IN} = V _{SS} For pulldown: V _{IN} = AUXVCC3 | | 20 | 35 | 50 | kΩ |
| C _I Input capacitance | V _{IN} = V _{SS} or AUXVCC3 | | | 5 | | pF |

Table 5-34 lists the input requirements of the tamper detect pin.

Table 5-34. Inputs, RTC Tamper Detect Pin⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | AUXVCC3 | MIN | MAX | UNIT |
|---|--|------------|-----|-----|------|
| t _(int) External interrupt timing ⁽²⁾ | Port P1, P2: P1.x to P2.x, External trigger pulse duration to set interrupt flag | 2.2 V, 3 V | 20 | | ns |

- (1) Some devices may contain additional ports with interrupts. See the block diagram and terminal function descriptions.
 (2) An external signal sets the interrupt flag every time the minimum interrupt pulse duration t_(int) is met. It may be set by trigger signals shorter than t_(int).

Table 5-35 lists the leakage current of the tamper detect pin.

Table 5-35. Leakage Current, RTC Tamper Detect Pin

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | AUXVCC3 | MIN | MAX | UNIT |
|---|-----------------------------------|------------|-----|-----|------|
| I _{lkg(Px.y)} High-impedance leakage current | See ⁽¹⁾ ⁽²⁾ | 1.8 V, 3 V | -50 | +50 | nA |

- (1) The leakage current is measured with V_{SS} or V_{CC} applied to the corresponding pins, unless otherwise noted.
 (2) The leakage of the digital port pins is measured individually. The port pin is selected for input and the pullup or pulldown resistor is disabled.

Table 5-36 lists the output characteristics of the tamper detect pin.

Table 5-36. Outputs, RTC Tamper Detect Pin

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | AUXVCC3 | MIN | MAX | UNIT |
|---|---|---------|------|------|------|
| V _{OH} High-level output voltage | I _(OHmax) = -100 μA ⁽¹⁾ | 1.8 V | 1.50 | 1.80 | V |
| | I _(OHmax) = -200 μA ⁽¹⁾ | | 1.20 | 1.80 | |
| | I _(OHmax) = -100 μA ⁽¹⁾ | 3 V | 2.70 | 3.00 | |
| | I _(OHmax) = -200 μA ⁽¹⁾ | | 2.40 | 3.00 | |
| V _{OL} Low-level output voltage | I _(OLmax) = 100 μA ⁽²⁾ | 1.8 V | 0.00 | 0.25 | V |
| | I _(OLmax) = 200 μA ⁽²⁾ | | 0.00 | 0.60 | |
| | I _(OLmax) = 100 μA ⁽²⁾ | 3 V | 0.00 | 0.25 | |
| | I _(OLmax) = 200 μA ⁽²⁾ | | 0.00 | 0.60 | |

- (1) The maximum total current, I_(OHmax), for all outputs combined should not exceed ±20 mA to hold the maximum voltage drop specified. See Section 5.3 for more details.
 (2) The maximum total current, I_(OLmax), for all outputs combined should not exceed ±20 mA to hold the maximum voltage drop specified. See Section 5.3 for more details.

5.15 LCD_C

Table 5-37 lists the operating conditions of the LCD controller.

Table 5-37. LCD_C, Operating Conditions

| PARAMETER | TEST CONDITIONS | MIN | NOM | MAX | UNIT | | |
|----------------------------|--|---|-----|-----------|--|----------------|---------------|
| $V_{CC,LCD_C,CP\ en,3.6}$ | Supply voltage range, charge pump enabled, $V_{LCD} \leq 3.6\text{ V}$ | LCDPEN = 1, $0000 < VLC Dx \leq 1111$ (charge pump enabled, $V_{LCD} \leq 3.6\text{ V}$) | | 2.2 | 3.6 | V | |
| $V_{CC,LCD_C,CP\ en,3.3}$ | Supply voltage range, charge pump enabled, $V_{LCD} \leq 3.3\text{ V}$ | LCDPEN = 1, $0000 < VLC Dx \leq 1100$ (charge pump enabled, $V_{LCD} \leq 3.3\text{ V}$) | | 2.0 | 3.6 | V | |
| $V_{CC,LCD_C,int.\ bias}$ | Supply voltage range, internal biasing, charge pump disabled | LCDPEN = 0, VLCDEXT = 0 | | 2.4 | 3.6 | V | |
| $V_{CC,LCD_C,ext.\ bias}$ | Supply voltage range, external biasing, charge pump disabled | LCDPEN = 0, VLCDEXT = 0 | | 2.4 | 3.6 | V | |
| $V_{CC,LCD_C,VLCDEXT}$ | Supply voltage range, external LCD voltage, internal or external biasing, charge pump disabled | LCDPEN = 0, VLCDEXT = 1 | | 2.0 | 3.6 | V | |
| $V_{LDCAP/R33}$ | External LCD voltage at LDCAP/R33, internal or external biasing, charge pump disabled | LCDPEN = 0, VLCDEXT = 1 | | 2.4 | 3.6 | V | |
| C_{LDCAP} | Capacitor on LDCAP when charge pump enabled | LCDPEN = 1, $VLC Dx > 0000$ (charge pump enabled) | | 4.7 | 4.7 | 10 | μF |
| f_{LCD} | LCD frequency range | $f_{FRAME} = 1/(2 \times \text{mux}) \times f_{LCD}$ with mux = 1 (static) to 8 | | 0 | | 1024 | Hz |
| $f_{FRAME,4\text{mux}}$ | LCD frame frequency range | $f_{FRAME,4\text{mux}}(\text{MAX}) = 1/(2 \times 4) \times f_{LCD}(\text{MAX})$ $f_{LCD}(\text{MAX}) = 1/(2 \times 4) \times 1024\text{ Hz}$ | | | | 128 | Hz |
| $f_{FRAME,8\text{mux}}$ | LCD frame frequency range | $f_{FRAME,8\text{mux}}(\text{MAX}) = 1/(2 \times 4) \times f_{LCD}(\text{MAX})$ $f_{LCD}(\text{MAX}) = 1/(2 \times 8) \times 1024\text{ Hz}$ | | | | 64 | Hz |
| $f_{ACLK,in}$ | ACLK input frequency range | | | 30 | 32 | 40 | kHz |
| C_{Panel} | Panel capacitance | 100-Hz frame frequency | | | | 10000 | pF |
| V_{R33} | Analog input voltage at R33 | LCDPEN = 0, VLCDEXT = 1 | | 2.4 | | $V_{CC} + 0.2$ | V |
| $V_{R23,1/3\text{bias}}$ | Analog input voltage at R23 | LCDREXT = 1, LCDEXTBIAS = 1, LCD2B = 0 | | V_{R13} | $V_{R03} + 2/3 \times (V_{R33} - V_{R03})$ | V_{R33} | V |
| $V_{R13,1/3\text{bias}}$ | Analog input voltage at R13 with 1/3 biasing | LCDREXT = 1, LCDEXTBIAS = 1, LCD2B = 0 | | V_{R03} | $V_{R03} + 1/3 \times (V_{R33} - V_{R03})$ | V_{R23} | V |
| $V_{R13,1/2\text{bias}}$ | Analog input voltage at R13 with 1/2 biasing | LCDREXT = 1, LCDEXTBIAS = 1, LCD2B = 1 | | V_{R03} | $V_{R03} + 1/2 \times (V_{R33} - V_{R03})$ | V_{R33} | V |
| V_{R03} | Analog input voltage at R03 | R03EXT = 1 | | V_{SS} | | | V |
| $V_{LCD} - V_{R03}$ | Voltage difference between V_{LCD} and R03 | LCDPEN = 0, R03EXT = 1 | | 2.4 | | $V_{CC} + 0.2$ | V |
| $V_{LCDREF/R13}$ | External LCD reference voltage applied at LCDREF/R13 | VLCDFREFx = 01 | | 0.8 | 1.2 | 1.5 | V |

Table 5-38 lists the characteristics of the LCD controller.

Table 5-38. LCD_C, Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT |
|---------------------------|--|--|-----------------|------|-----------------|-----|------|
| V _{LCD} | LCD voltage | VLCDx = 0000, VLCDxEXT = 0 | 2.4 V to 3.6 V | | V _{CC} | | V |
| | | LCDCPEN = 1, VLCDx = 0001 | 2 V to 3.6 V | | 2.60 | | |
| | | LCDCPEN = 1, VLCDx = 0010 | 2 V to 3.6 V | | 2.66 | | |
| | | LCDCPEN = 1, VLCDx = 0011 | 2 V to 3.6 V | | 2.72 | | |
| | | LCDCPEN = 1, VLCDx = 0100 | 2 V to 3.6 V | | 2.78 | | |
| | | LCDCPEN = 1, VLCDx = 0101 | 2 V to 3.6 V | | 2.84 | | |
| | | LCDCPEN = 1, VLCDx = 0110 | 2 V to 3.6 V | | 2.90 | | |
| | | LCDCPEN = 1, VLCDx = 0111 | 2 V to 3.6 V | | 2.96 | | |
| | | LCDCPEN = 1, VLCDx = 1000 | 2 V to 3.6 V | | 3.02 | | |
| | | LCDCPEN = 1, VLCDx = 1001 | 2 V to 3.6 V | | 3.08 | | |
| | | LCDCPEN = 1, VLCDx = 1010 | 2 V to 3.6 V | | 3.14 | | |
| | | LCDCPEN = 1, VLCDx = 1011 | 2 V to 3.6 V | | 3.20 | | |
| | | LCDCPEN = 1, VLCDx = 1100 | 2 V to 3.6 V | | 3.26 | | |
| | | LCDCPEN = 1, VLCDx = 1101 | 2.2 V to 3.6 V | | 3.32 | | |
| | | LCDCPEN = 1, VLCDx = 1110 | 2.2 V to 3.6 V | | 3.38 | | |
| LCDCPEN = 1, VLCDx = 1111 | 2.2 V to 3.6 V | | 3.50 | 3.72 | | | |
| I _{CC,Peak,CP} | Peak supply currents due to charge pump activities | LCDCPEN = 1, VLCDx = 1111 | 2.2 V | | 200 | | μA |
| t _{LCD,CP,on} | Time to charge C _{LCD} when discharged | C _{LCD} = 4.7 μF, LCDCPEN = 0→1, VLCDx = 1111 | 2.2 V | | 100 | 500 | ms |
| I _{CP,Load} | Maximum charge pump load current | LCDCPEN = 1, VLCDx = 1111 | 2.2 V | 50 | | | μA |
| R _{LCD,Seg} | LCD driver output impedance, segment lines | LCDCPEN = 1, VLCDx = 1000, I _{LOAD} = ±10 μA | 2.2 V | | | 10 | kΩ |
| R _{LCD,COM} | LCD driver output impedance, common lines | LCDCPEN = 1, VLCDx = 1000, I _{LOAD} = ±10 μA | 2.2 V | | | 10 | kΩ |

5.16 SD24_B

Table 5-39 lists the operating conditions of the SD24_B.

Table 5-39. SD24_B, Power Supply and Operating Conditions

| | | | MIN | TYP | MAX | UNIT |
|-------------|---|--|-----------------|------|-----------------|------|
| V_{CC} | Analog supply voltage | $V_{CC} = DV_{CC}, AV_{SS} = DV_{SS} = 0\text{ V}$ | 2.4 | | 3.6 | V |
| T_A | Ambient temperature | | -40 | | 85 | °C |
| f_{SD} | Modulator clock frequency | | 0.03 | | 2.3 | MHz |
| V_I | Absolute input voltage | | $AV_{SS} - 1$ | | AV_{CC} | V |
| V_{IC} | Common-mode input voltage | | $AV_{SS} - 1$ | | AV_{CC} | V |
| $V_{ID,FS}$ | Differential full-scale input voltage | Bipolar mode, $V_{ID} = V_{I,A+} - V_{I,A-}$ | $-V_{REF}/GAIN$ | | $+V_{REF}/GAIN$ | mV |
| V_{ID} | Differential input voltage for specified performance ⁽¹⁾ | REFON = 1 | SD24GAINx = 1 | ±900 | ±930 | mV |
| | | | SD24GAINx = 2 | ±450 | ±460 | |
| | | | SD24GAINx = 4 | ±225 | ±230 | |
| | | | SD24GAINx = 8 | ±112 | ±120 | |
| | | | SD24GAINx = 16 | ±56 | ±60 | |
| | | | SD24GAINx = 32 | ±28 | ±30 | |
| | | | SD24GAINx = 64 | ±14 | ±14 | |
| | SD24GAINx = 128 | ±7 | ±7.25 | | | |
| C_{REF} | VREF load capacitance ⁽²⁾ | SD24REFS = 1 | | 100 | | nF |

- (1) The full-scale range (FSR) is defined by $V_{FS+} = +V_{REF}/GAIN$ and $V_{FS-} = -V_{REF}/GAIN$; $FSR = V_{FS+} - V_{FS-} = 2 \times V_{REF}/GAIN$. If V_{REF} is sourced externally, the analog input range should not exceed 80% of V_{FS+} or V_{FS-} , that is, $V_{ID} = 0.8 V_{FS-}$ to $0.8 V_{FS+}$. If V_{REF} is sourced internally, the given V_{ID} ranges apply. MIN values are calculated based on a V_{REF} of 1.125 V. TYP values are calculated based on a V_{REF} of 1.16 V.
- (2) There is no capacitance required on VREF. However, TI recommends using a capacitance of 100 nF to reduce any reference voltage noise.

Table 5-40 lists the analog input characteristics of the SD24_B.

Table 5-40. SD24_B, Analog Inputs ⁽¹⁾

Also see Figure 5-16

| PARAMETER | | TEST CONDITIONS | | V_{CC} | MIN | TYP | MAX | UNIT |
|-----------|--|---------------------------|----------------|----------|-----|-----|-----|------|
| C_I | Input capacitance | SD24GAINx = 1 | | 3 V | | 5.0 | | pF |
| | | SD24GAINx = 2 | | | | 5.0 | | |
| | | SD24GAINx = 4 | | | | 5.0 | | |
| | | SD24GAINx = 8 | | | | 5.0 | | |
| | | SD24GAINx = 16 | | | | 5.0 | | |
| | | SD24GAINx = 32, 64, 128 | | | | 5.0 | | |
| Z_I | Input impedance (pin A+ or A- to AV_{SS}) | $f_{SD24} = 1\text{ MHz}$ | SD24GAINx = 1 | 3 V | | 200 | | kΩ |
| | | | SD24GAINx = 8 | | | 200 | | |
| | | | SD24GAINx = 32 | | | 200 | | |
| Z_{ID} | Differential input impedance (pin A+ to pin A-) | $f_{SD24} = 1\text{ MHz}$ | SD24GAINx = 1 | 3 V | 300 | 400 | | kΩ |
| | | | SD24GAINx = 8 | | | 400 | | |
| | | | SD24GAINx = 32 | | | 300 | 400 | |

- (1) All parameters pertain to each SD24_B converter.

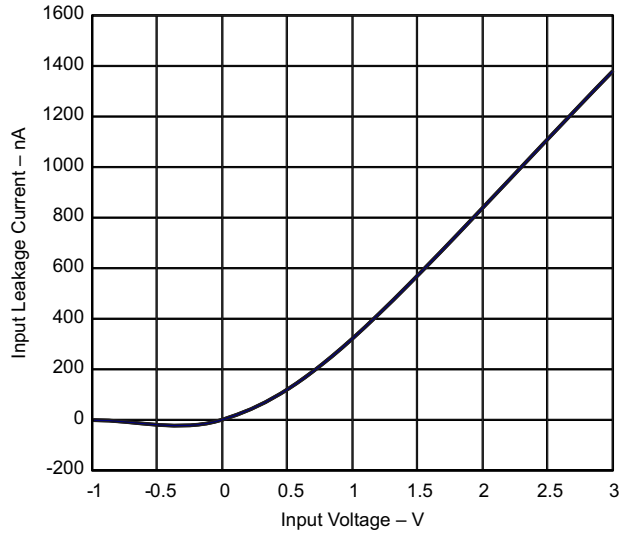


Figure 5-16. Input Leakage Current vs Input Voltage (Modulator OFF)

Table 5-41 lists the supply currents of the SD24_B.

Table 5-41. SD24_B, Supply Currents

| PARAMETER | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT | | | |
|--|--|--|-----|-----|-----|------|---------------|-----|-----|
| I _{SD,256} Analog plus digital supply current per converter (reference not included) | f _{SD24} = 1 MHz, SD24OSR = 256 | 3 V | | | | μA | SD24GAIN: 1 | 490 | 600 |
| | | | | | | | SD24GAIN: 2 | 490 | 600 |
| | | | | | | | SD24GAIN: 4 | 490 | 600 |
| | | | | | | | SD24GAIN: 8 | 559 | 700 |
| | | | | | | | SD24GAIN: 16 | 559 | 700 |
| | | | | | | | SD24GAIN: 32 | 627 | 800 |
| | | | | | | | SD24GAIN: 64 | 627 | 800 |
| | | | | | | | SD24GAIN: 128 | 627 | 800 |
| I _{SD,512} Analog plus digital supply current per converter (reference not included) | f _{SD24} = 2 MHz, SD24OSR = 512 | 3 V | | | | μA | SD24GAIN: 1 | 600 | 700 |
| | | | | | | | SD24GAIN: 8 | 677 | 800 |
| | | | | | | | SD24GAIN: 32 | 740 | 900 |
| I _{SD24REFonly} | Current of internal SD24 reference and buffers (includes shared reference) | No converter is active, (SD24REFS = 1, SD24BCCTLx.SD24SC = 0) | 3 V | | 147 | 190 | μA | | |
| I _{SD24REF,Conv0} | Current of internal SD24 reference and buffers (includes shared reference) | Converter 0 is active, (SD24REFS = 1, SD24BCCTL0.SD24SC = 1) | 3 V | | 75 | 110 | μA | | |
| I _{SD24REF,notConv0} | Current of internal SD24 reference and buffers (includes shared reference) | Any converter other than converter 0 is active, (SD24REFS = 1, SD24BCCTL0.SD24SC = 0, SD24BCCTLx.SD24SC = 1) | 3 V | | 137 | 175 | μA | | |

Table 5-42 lists the performance characteristics of the SD24_B.

Table 5-42. SD24_B, Performance

$f_{SD24} = 1$ MHz, SD24OSRx = 256, SD24REFON = 1

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT |
|-----------------------------------|--|---|-----------------|-------|------|-------|----------|
| INL | Integral nonlinearity, end-point fit | SD24GAIN: 1 | 3 V | -0.01 | | +0.01 | % of FSR |
| | | SD24GAIN: 8 | | -0.01 | | +0.01 | |
| | | SD24GAIN: 32 | | -0.01 | | +0.01 | |
| G _{nom} | Nominal gain | SD24GAIN: 1 | 3 V | | 1 | | |
| | | SD24GAIN: 2 | | | 2 | | |
| | | SD24GAIN: 4 | | | 4 | | |
| | | SD24GAIN: 8 | | | 8 | | |
| | | SD24GAIN: 16 | | | 16 | | |
| | | SD24GAIN: 32 | | | 32 | | |
| | | SD24GAIN: 64 | | | 64 | | |
| | | SD24GAIN: 128 | | | 128 | | |
| E _G | Gain error ⁽¹⁾ | SD24GAIN: 1, with external reference (1.2 V) | 3 V | -1% | | +1% | |
| | | SD24GAIN: 8, with external reference (1.2 V) | | -2% | | +2% | |
| | | SD24GAIN: 32, with external reference (1.2 V) | | -2% | | +2% | |
| ΔE _G /ΔT | Gain error temperature coefficient ⁽²⁾ , internal reference | SD24GAIN: 1, 8, or 32 (with internal reference) | 3 V | | | 80 | ppm/°C |
| ΔE _G /ΔT | Gain error temperature coefficient ⁽²⁾ , external reference | SD24GAIN: 1 (with external reference) | 3 V | | | 15 | ppm/°C |
| | | SD24GAIN: 8 (with external reference) | | | | 15 | |
| | | SD24GAIN: 32 (with external reference) | | | | 15 | |
| ΔE _G /ΔV _{CC} | Gain error vs V _{CC} ⁽³⁾ | SD24GAIN: 1 | 3 V | | 0.1 | | %V |
| | | SD24GAIN: 8 | | | 0.1 | | |
| | | SD24GAIN: 32 | | | 0.4 | | |
| E _{OS} [V] | Offset error ⁽⁴⁾ | SD24GAIN: 1 (with V _{diff} = 0 V) | 3 V | | | 2.3 | mV |
| | | SD24GAIN: 8 | | | | 1 | |
| | | SD24GAIN: 32 | | | | 0.5 | |
| E _{OS} [FS] | Offset error ⁽⁴⁾ | SD24GAIN: 1 (with V _{diff} = 0 V) | 3 V | -0.2 | | +0.2 | % FS |
| | | SD24GAIN: 8 | | -0.7 | | +0.7 | |
| | | SD24GAIN: 32 | | -1.4 | | +1.4 | |
| ΔE _{OS} /ΔT | Offset error temperature coefficient ⁽⁵⁾ | SD24GAIN: 1 | 3 V | | 2 | | μV/°C |
| | | SD24GAIN: 8 | | | 0.25 | | |
| | | SD24GAIN: 32 | | | 0.1 | | |

- The gain error E_G specifies the deviation of the actual gain G_{act} from the nominal gain G_{nom}: E_G = (G_{act} - G_{nom})/G_{nom}. It covers process, temperature, and supply voltage variations.
- The gain error temperature coefficient ΔE_G/ΔT specifies the variation of the gain error E_G over temperature (E_G(T) = (G_{act}(T) - G_{nom})/G_{nom}) using the box method (that is, minimum and maximum values):

$$\Delta E_G / \Delta T = (\text{MAX}(E_G(T)) - \text{MIN}(E_G(T))) / (\text{MAX}(T) - \text{MIN}(T)) = (\text{MAX}(G_{act}(T)) - \text{MIN}(G_{act}(T))) / G_{nom} / (\text{MAX}(T) - \text{MIN}(T))$$
 with T ranging from -40°C to 85°C.
- The gain error vs V_{CC} coefficient ΔE_G/ΔV_{CC} specifies the variation of the gain error E_G over supply voltage (E_G(V_{CC}) = (G_{act}(V_{CC}) - G_{nom})/G_{nom}) using the box method (that is, minimum and maximum values):

$$\Delta E_G / \Delta V_{CC} = (\text{MAX}(E_G(V_{CC})) - \text{MIN}(E_G(V_{CC}))) / (\text{MAX}(V_{CC}) - \text{MIN}(V_{CC})) = (\text{MAX}(G_{act}(V_{CC})) - \text{MIN}(G_{act}(V_{CC}))) / G_{nom} / (\text{MAX}(V_{CC}) - \text{MIN}(V_{CC}))$$
 with V_{CC} ranging from 2.4 V to 3.6 V.
- The offset error E_{OS} is measured with shorted inputs in 2s-complement mode with +100% FS = V_{REF}/G and -100% FS = -V_{REF}/G. Conversion between E_{OS} [FS] and E_{OS} [V] is as follows: E_{OS} [FS] = E_{OS} [V] × G/V_{REF}, E_{OS} [V] = E_{OS} [FS] × V_{REF}/G.
- The offset error temperature coefficient ΔE_{OS}/ΔT specifies the variation of the offset error E_{OS} over temperature using the box method (that is, minimum and maximum values):

$$\Delta E_{OS} / \Delta T = (\text{MAX}(E_{OS}(T)) - \text{MIN}(E_{OS}(T))) / (\text{MAX}(T) - \text{MIN}(T))$$
 with T ranging from -40°C to 85°C.

Table 5-42. SD24_B, Performance (continued)
 $f_{SD24} = 1 \text{ MHz}$, $SD24OSRx = 256$, $SD24REFON = 1$

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT |
|-------------------------------|--|--|-----------------|-----|------|-----|-----------------|
| $\Delta E_{OS}/\Delta V_{CC}$ | Offset error vs V _{CC} ⁽⁶⁾ | SD24GAIN: 1 | 3 V | | 500 | | $\mu\text{V/V}$ |
| | | SD24GAIN: 8 | | | 125 | | |
| | | SD24GAIN: 32 | | | 50 | | |
| CMRR,DC | Common-mode rejection at DC ⁽⁷⁾ | SD24GAIN: 1 | 3 V | | -120 | | dB |
| | | SD24GAIN: 8 | | | -110 | | |
| | | SD24GAIN: 32 | | | -100 | | |
| CMRR,50Hz | Common-mode rejection at 50 Hz ⁽⁸⁾ | SD24GAIN: 1, $f_{CM} = 50 \text{ Hz}$, $V_{CM} = 930 \text{ mV}$ | 3 V | | -120 | | dB |
| | | SD24GAIN: 8, $f_{CM} = 50 \text{ Hz}$, $V_{CM} = 120 \text{ mV}$ | | | -110 | | |
| | | SD24GAIN: 32, $f_{CM} = 50 \text{ Hz}$, $V_{CM} = 30 \text{ mV}$ | | | -100 | | |
| AC PSRR, ext | AC power supply rejection ratio, external reference ⁽⁹⁾ | SD24GAIN: 1, $V_{CC} = 3 \text{ V} + 50 \text{ mV} \times \sin(2\pi \times f_{VCC} \times t)$, $f_{VCC} = 50 \text{ Hz}$ | | | -61 | | dB |
| | | SD24GAIN: 8, $V_{CC} = 3 \text{ V} + 50 \text{ mV} \times \sin(2\pi \times f_{VCC} \times t)$, $f_{VCC} = 50 \text{ Hz}$ | | | -75 | | |
| | | SD24GAIN: 32, $V_{CC} = 3 \text{ V} + 50 \text{ mV} \times \sin(2\pi \times f_{VCC} \times t)$, $f_{VCC} = 50 \text{ Hz}$ | | | -79 | | |
| AC PSRR, int | AC power supply rejection ratio, internal reference ⁽⁹⁾ | SD24GAIN: 1, $V_{CC} = 3 \text{ V} + 50 \text{ mV} \times \sin(2\pi \times f_{VCC} \times t)$, $f_{VCC} = 50 \text{ Hz}$ | | | -61 | | dB |
| | | SD24GAIN: 8, $V_{CC} = 3 \text{ V} + 50 \text{ mV} \times \sin(2\pi \times f_{VCC} \times t)$, $f_{VCC} = 50 \text{ Hz}$ | | | -75 | | |
| | | SD24GAIN: 32, $V_{CC} = 3 \text{ V} + 50 \text{ mV} \times \sin(2\pi \times f_{VCC} \times t)$, $f_{VCC} = 50 \text{ Hz}$ | | | -79 | | |
| XT | Crosstalk between converters ⁽¹⁰⁾ | Crosstalk source: SD24GAIN: 1, Sine-wave with maximum possible V _{pp} , $f_{IN} = 50 \text{ Hz}$ or 100 Hz , Converter under test: SD24GAIN: 1 | 3 V | | -120 | | dB |
| | | Crosstalk source: SD24GAIN: 1, Sine-wave with maximum possible V _{pp} , $f_{IN} = 50 \text{ Hz}$ or 100 Hz , Converter under test: SD24GAIN: 8 | | | -115 | | |
| | | Crosstalk source: SD24GAIN: 1, Sine-wave with maximum possible V _{pp} , $f_{IN} = 50 \text{ Hz}$ or 100 Hz , Converter under test: SD24GAIN: 32 | | | -110 | | |

- (6) The offset error vs V_{CC} $\Delta E_{OS}/\Delta V_{CC}$ specifies the variation of the offset error E_{OS} over supply voltage using the box method (that is, minimum and maximum values):

$$\Delta E_{OS}/\Delta V_{CC} = (\text{MAX}(E_{OS}(V_{CC})) - \text{MIN}(E_{OS}(V_{CC})) / (\text{MAX}(V_{CC}) - \text{MIN}(V_{CC}))$$
 with V_{CC} ranging from 2.4 V to 3.6 V.
- (7) The DC CMRR specifies the change in the measured differential input voltage value when the common-mode voltage varies:
 DC CMRR = $-20\log(\Delta_{MAX}/FSR)$ with Δ_{MAX} being the difference between the minimum value and the maximum value measured when sweeping the common-mode voltage.
 The DC CMRR is measured with both inputs connected to the common-mode voltage (that is, no differential input signal is applied), and the common-mode voltage is swept from -1 V to V_{CC}.
- (8) The AC CMRR is the difference between a hypothetical signal with the amplitude and frequency of the applied common-mode ripple applied to the inputs of the ADC and the actual common-mode signal spur visible in the FFT spectrum:
 AC CMRR = Error Spur [dBFS] - $20\log(V_{CM} / 1.2 \text{ V} / G)$ [dBFS] with a common-mode signal of $V_{CM} \times \sin(2\pi \times f_{CM} \times t)$ applied to the analog inputs.
 The AC CMRR is measured with the both inputs connected to the common-mode signal; that is, no differential input signal is applied. With the specified typical values the error spur is within the noise floor (as specified by the SINAD values).
- (9) The AC PSRR is the difference between a hypothetical signal with the amplitude and frequency of the applied supply voltage ripple applied to the inputs of the ADC and the actual supply ripple spur visible in the FFT spectrum:
 AC PSRR = Error Spur [dBFS] - $20\log(50 \text{ mV} / 1.2 \text{ V} / G)$ [dBFS] with a signal of $50 \text{ mV} \times \sin(2\pi \times f_{VCC} \times t)$ added to V_{CC}.
 The AC PSRR is measured with the inputs grounded; that is, no analog input signal is applied. With the specified typical values the error spur is within the noise floor (as specified by the SINAD values).
 SD24GAIN: 1 → Hypothetical signal: $20\log(50 \text{ mV} / 1.2 \text{ V} / 1) = -27.6 \text{ dBFS}$
 SD24GAIN: 8 → Hypothetical signal: $20\log(50 \text{ mV} / 1.2 \text{ V} / 8) = -9.5 \text{ dBFS}$
 SD24GAIN: 32 → Hypothetical signal: $20\log(50 \text{ mV} / 1.2 \text{ V} / 32) = 2.5 \text{ dBFS}$
- (10) The crosstalk XT is specified as the tone level of the signal applied to the crosstalk source seen in the spectrum of the converter under test. It is measured with the inputs of the converter under test being grounded.

Table 5-43 lists the AC performance characteristics of the SD24_B.

Table 5-43. SD24_B, AC Performance

$f_{SD24} = 1 \text{ MHz}$, $SD24OSRx = 256$, $SD24REFON = 1$

| PARAMETER | | TEST CONDITIONS | | V_{CC} | MIN | TYP | MAX | UNIT |
|-----------|------------------------------------|-----------------|--------------------------------|----------|-----|-----|-----|------|
| SINAD | Signal-to-noise + distortion ratio | SD24GAIN: 1 | $f_{IN} = 50 \text{ Hz}^{(1)}$ | 3 V | 82 | 86 | | dB |
| | | SD24GAIN: 2 | | | | 85 | | |
| | | SD24GAIN: 4 | | | | 84 | | |
| | | SD24GAIN: 8 | | | | 81 | 83 | |
| | | SD24GAIN: 16 | | | | 80 | | |
| | | SD24GAIN: 32 | | | | 71 | 73 | |
| | | SD24GAIN: 64 | | | | 67 | | |
| | | SD24GAIN: 128 | | | | 61 | | |
| THD | Total harmonic distortion | SD24GAIN: 1 | $f_{IN} = 50 \text{ Hz}^{(1)}$ | 3 V | | 95 | | dB |
| | | SD24GAIN: 8 | | | | 90 | | |
| | | SD24GAIN: 32 | | | | 86 | | |

(1) The following voltages were applied to the SD24_B inputs: $V_{I,A+}(t) = 0 \text{ V} + V_{PP} / 2 \times \sin(2\pi \times f_{IN} \times t)$ and $V_{I,A-}(t) = 0 \text{ V} - V_{PP}/2 \times \sin(2\pi \times f_{IN} \times t)$ resulting in a differential voltage of $V_{ID} = V_{I,A+}(t) - V_{I,A-}(t) = V_{PP} \times \sin(2\pi \times f_{IN} \times t)$ with V_{PP} being selected as the maximum value allowed for a given range (according to SD24_B recommended operating conditions).

Table 5-44 lists the AC performance characteristics of the SD24_B.

Table 5-44. SD24_B, AC Performance

$f_{SD24} = 2 \text{ MHz}$, $SD24OSRx = 512$, $SD24REFON = 1$

| PARAMETER | | TEST CONDITIONS | | V_{CC} | MIN | TYP | MAX | UNIT |
|-----------|------------------------------------|-----------------|--------------------------------|----------|-----|-----|-----|------|
| SINAD | Signal-to-noise + distortion ratio | SD24GAIN: 1 | $f_{IN} = 50 \text{ Hz}^{(1)}$ | 3 V | | 87 | | dB |
| | | SD24GAIN: 2 | | | | 85 | | |
| | | SD24GAIN: 4 | | | | 84 | | |
| | | SD24GAIN: 8 | | | | 83 | | |
| | | SD24GAIN: 16 | | | | 81 | | |
| | | SD24GAIN: 32 | | | | 76 | | |
| | | SD24GAIN: 64 | | | | 71 | | |
| | | SD24GAIN: 128 | | | | 65 | | |

(1) The following voltages were applied to the SD24_B inputs: $V_{I,A+}(t) = 0 \text{ V} + V_{PP} / 2 \times \sin(2\pi \times f_{IN} \times t)$ and $V_{I,A-}(t) = 0 \text{ V} - V_{PP}/2 \times \sin(2\pi \times f_{IN} \times t)$ resulting in a differential voltage of $V_{ID} = V_{I,A+}(t) - V_{I,A-}(t) = V_{PP} \times \sin(2\pi \times f_{IN} \times t)$ with V_{PP} being selected as the maximum value allowed for a given range (according to SD24_B recommended operating conditions).

Table 5-45 lists the AC performance characteristics of the SD24_B.

Table 5-45. SD24_B, AC Performance

$f_{SD24} = 32$ kHz, SD24OSRx = 512, SD24REFON = 1 (see Figure 5-17 and Figure 5-18)

| PARAMETER | | TEST CONDITIONS | V_{CC} | MIN | TYP | MAX | UNIT |
|-----------|------------------------------------|-----------------|----------|-----|-----|-----|------|
| SINAD | Signal-to-noise + distortion ratio | SD24GAIN: 1 | 3 V | | 89 | | dB |
| | | SD24GAIN: 2 | | | | | |
| | | SD24GAIN: 4 | | | | | |
| | | SD24GAIN: 8 | | | | | |
| | | SD24GAIN: 16 | | | | | |
| | | SD24GAIN: 32 | | | | | |
| | | SD24GAIN: 64 | | | | | |
| | | SD24GAIN: 128 | | | | | |

(1) The following voltages were applied to the SD24_B inputs: $V_{I,A+}(t) = 0 V + V_{PP} / 2 \times \sin(2\pi \times f_{IN} \times t)$ and $V_{I,A-}(t) = 0 V - V_{PP}/2 \times \sin(2\pi \times f_{IN} \times t)$ resulting in a differential voltage of $V_{ID} = V_{I,A+}(t) - V_{I,A-}(t) = V_{PP} \times \sin(2\pi \times f_{IN} \times t)$ with V_{PP} being selected as the maximum value allowed for a given range (according to SD24_B recommended operating conditions).

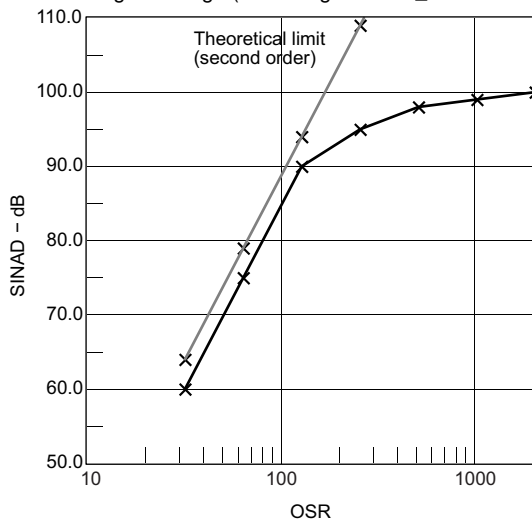


Figure 5-17. SINAD vs OSR
($f_{SD24} = 1$ MHz, SD24REFON = 1, SD24GAIN = 1)

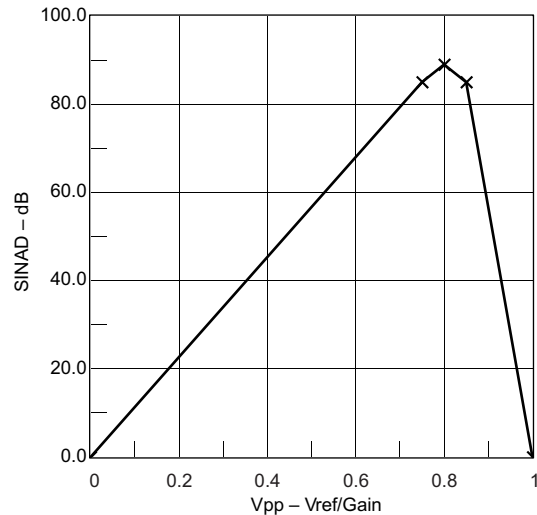


Figure 5-18. SINAD vs V_{PP}

Table 5-46 lists the external reference requirements of the SD24_B.

Table 5-46. SD24_B External Reference Input

ensure correct input voltage range according to V_{REF}

| PARAMETER | | TEST CONDITIONS | V_{CC} | MIN | TYP | MAX | UNIT |
|--------------|---------------|-----------------|----------|-----|------|-----|------|
| $V_{REF(I)}$ | Input voltage | SD24REFS = 0 | 3 V | 1.0 | 1.20 | 1.5 | V |
| $I_{REF(I)}$ | Input current | SD24REFS = 0 | 3 V | | | 50 | nA |

5.17 ADC10_A

Table 5-47 lists the input requirements of the ADC.

Table 5-47. 10-Bit ADC, Power Supply and Input Range Conditions

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT |
|---|---|---|-----------------|-----|-----|------------------|------|
| AV _{CC} | Analog supply voltage | AV _{CC} and DV _{CC} are connected together, AV _{SS} and DV _{SS} are connected together, V _(AVSS) = V _(DVSS) = 0 V | | 1.8 | | 3.6 | V |
| V _(Ax) | Analog input voltage range ⁽¹⁾ | All ADC10_A pins | | 0 | | AV _{CC} | V |
| I _{ADC10_A} | Operating supply current into AV _{CC} terminal, REF module and reference buffer off | f _{ADC10CLK} = 5 MHz, ADC10ON = 1, REFON = 0, SHT0 = 0, SHT1 = 0, ADC10DIV = 0, ADC10SREF = 00 | 2.2 V | | 68 | 100 | μA |
| | | | 3 V | | 78 | 110 | |
| | Operating supply current into AV _{CC} terminal, REF module on, reference buffer on | f _{ADC10CLK} = 5 MHz, ADC10ON = 1, REFON = 1, SHT0 = 0, SHT1 = 0, ADC10DIV = 0, ADC10SREF = 01 | 3 V | | 124 | 180 | |
| | | f _{ADC10CLK} = 5 MHz, ADC10ON = 1, REFON = 0, SHT0 = 0, SHT1 = 0, ADC10DIV = 0, ADC10SREF = 10, VREF = 2.5 V | 3 V | | 105 | 160 | |
| Operating supply current into AV _{CC} terminal, REF module off, reference buffer off | f _{ADC10CLK} = 5 MHz, ADC10ON = 1, REFON = 0, SHT0 = 0, SHT1 = 0, ADC10DIV = 0, ADC10SREF = 11, VREF = 2.5 V | 3 V | | 72 | 110 | | |
| | | | | | | | |
| C _I | Input capacitance | Only one terminal Ax can be selected at one time from the pad to the ADC10_A capacitor array including wiring and pad | 2.2 V | | 3.5 | | pF |
| R _I | Input MUX ON resistance | AV _{CC} > 2.0 V, 0 V ≤ V _{Ax} ≤ AV _{CC} | | | | 36 | kΩ |
| | | 1.8 V < AV _{CC} < 2.0 V, 0 V ≤ V _{Ax} ≤ AV _{CC} | | | | 96 | |

(1) The analog input voltage range must be within the selected reference voltage range V_{R+} to V_{R-} for valid conversion results. The external reference voltage requires decoupling capacitors. Connect two decoupling capacitors, 10 μF and 100 nF, to VREF to decouple the dynamic current required for an external reference source if it is used for the ADC10_A. Also see the [MSP430x5xx and MSP430x6xx Family User's Guide](#).

Table 5-48 lists the switching characteristics of the ADC.

Table 5-48. 10-Bit ADC, Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT |
|-----------------------|--|---|-----------------|------|-----------------------------------|-----|------|
| f _{ADC10CLK} | | For specified performance of ADC10_A linearity parameters | 2.2 V, 3 V | 0.45 | 5 | 5.5 | MHz |
| f _{ADC10OSC} | Internal ADC10_A oscillator ⁽¹⁾ | ADC10DIV = 0, f _{ADC10CLK} = f _{ADC10OSC} | 2.2 V, 3 V | 4.4 | 4.9 | 5.6 | MHz |
| t _{CONVERT} | Conversion time | REFON = 0, Internal oscillator, 12 ADC10CLK cycles, 10-bit mode, f _{ADC10OSC} = 4 MHz to 5 MHz | 2.2 V, 3 V | 2.4 | | 3.0 | μs |
| | | External f _{ADC10CLK} from ACLK, MCLK, or SMCLK, ADC10SSEL ≠ 0 | | | 12 × 1 / f _{ADC10CLK} | | |
| t _{ADC10ON} | Turn-on settling time of the ADC | See ⁽²⁾ | | | | 100 | ns |
| t _{Sample} | Sampling time | R _S = 1000 Ω, R _I = 96 kΩ, C _I = 3.5 pF ⁽³⁾ | 1.8 V | 3 | | | μs |
| | | R _S = 1000 Ω, R _I = 36 kΩ, C _I = 3.5 pF ⁽³⁾ | 3 V | 1 | | | |

(1) The ADC10OSC is sourced directly from MODOSC inside the UCS.

(2) The condition is that the error in a conversion started after t_{ADC10ON} is less than ±0.5 LSB. The reference and input signal are already settled.

(3) Approximately 8 Tau (τ) are needed to get an error of less than ±0.5 LSB

Table 5-49 lists the linearity parameters of the ADC.

Table 5-49. 10-Bit ADC, Linearity Parameters

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | MIN | MAX | UNIT |
|---|--|-----------------|------|------|------|
| E _I Integral linearity error | 1.4 V ≤ (V _{eREF+} - V _{eREF-}) ≤ 1.6 V, C _{VeREF+} = 20 pF | 2.2 V, 3 V | -1.0 | +1.0 | LSB |
| | 1.6 V < (V _{eREF+} - V _{eREF-}) ≤ V _{AVCC} , C _{VeREF+} = 20 pF | | -1.0 | +1.0 | |
| E _D Differential linearity error | 1.4 V ≤ (V _{eREF+} - V _{eREF-}), C _{VeREF+} = 20 pF | 2.2 V, 3 V | -1.0 | +1.0 | LSB |
| E _O Offset error | 1.4 V ≤ (V _{eREF+} - V _{eREF-}), C _{VeREF+} = 20 pF Internal impedance of source R _S < 100 Ω | 2.2 V, 3 V | -1.0 | +1.0 | LSB |
| E _G Gain error | 1.4 V ≤ (V _{eREF+} - V _{eREF-}), C _{VeREF+} = 20 pF, ADC10SREFX = 11b | 2.2 V, 3 V | -1.0 | +1.0 | LSB |
| E _T Total unadjusted error | 1.4 V ≤ (V _{eREF+} - V _{eREF-}), C _{VeREF+} = 20 pF, ADC10SREFX = 11b | 2.2 V, 3 V | -2.0 | +2.0 | LSB |

Table 5-50 lists the requirement for the ADC external reference.

Table 5-50. 10-Bit ADC, External Reference

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾

| PARAMETER | TEST CONDITIONS | V _{CC} | MIN | MAX | UNIT |
|--|---|-----------------|-----|------------------|------|
| V _{eREF+} Positive external reference voltage input | V _{eREF+} > V _{eREF-} ⁽²⁾ | | 1.4 | AV _{CC} | V |
| V _{eREF-} Negative external reference voltage input | V _{eREF+} > V _{eREF-} ⁽³⁾ | | 0 | 1.2 | V |
| (V _{eREF+} - V _{eREF-}) Differential external reference voltage input | V _{eREF+} > V _{eREF-} ⁽⁴⁾ | | 1.4 | AV _{CC} | V |
| I _{VeREF+} , I _{VeREF-} Static input current | 1.4 V ≤ V _{eREF+} ≤ V _{AVCC} , V _{eREF-} = 0 V, f _{ADC10CLK} = 5 MHz, ADC10SHTX = 0x0001, Conversion rate 200 ksp/s | 2.2 V, 3 V | -26 | +26 | μA |
| | 1.4 V ≤ V _{eREF+} ≤ V _{AVCC} , V _{eREF-} = 0 V, f _{ADC10CLK} = 5 MHz, ADC10SHTX = 0x1000, Conversion rate 20 ksp/s | | -1 | +1 | |
| C _{VeREF+} Capacitance at VREF+ terminal | See ⁽⁵⁾ | | 10 | | μF |

- (1) The external reference is used during ADC conversion to charge and discharge the capacitance array. The input capacitance, C_I, is also the dynamic load for an external reference during conversion. The dynamic impedance of the reference supply should follow the recommendations on analog-source impedance to allow the charge to settle for 10-bit accuracy.
- (2) The accuracy limits the minimum positive external reference voltage. Lower reference voltage levels may be applied with reduced accuracy requirements.
- (3) The accuracy limits the maximum negative external reference voltage. Higher reference voltage levels may be applied with reduced accuracy requirements.
- (4) The accuracy limits minimum external differential reference voltage. Lower differential reference voltage levels may be applied with reduced accuracy requirements.
- (5) Connect two decoupling capacitors, 10 μF and 100 nF, to VREF to decouple the dynamic current required for an external reference source if it is used for the ADC10_A. Also see the [MSP430x5xx and MSP430x6xx Family User's Guide](#).

5.18 REF

Table 5-51 lists the characteristics of the REF.

Table 5-51. REF Built-In Reference

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT | |
|-----------------------------|--|--|------------|-------|--------|---------|----|
| V _{REF+} | Positive built-in reference voltage | REFVSEL = {2} for 2.5 V, REFON = 1 | 3 V | 2.47 | 2.51 | 2.55 | V |
| | | REFVSEL = {1} for 2 V, REFON = 1 | | 1.96 | 1.99 | 2.02 | |
| | | REFVSEL = {0} for 1.5 V, REFON = 1 | 2.2 V, 3 V | 1.48 | 1.5 | 1.52 | |
| AV _{CC(min)} | AV _{CC} minimum voltage, Positive built-in reference active | REFVSEL = {0} for 1.5 V | | 1.8 | | V | |
| | | REFVSEL = {1} for 2 V | | 2.2 | | | |
| | | REFVSEL = {2} for 2.5 V | | 2.7 | | | |
| I _{REF+} | Operating supply current into AV _{CC} terminal ⁽¹⁾ | f _{ADC10CLK} = 5.0 MHz, REFON = 1, REFBURST = 0, REFVSEL = {2} for 2.5 V | 3 V | | 18 | 24 | μA |
| | | f _{ADC10CLK} = 5.0 MHz, REFON = 1, REFBURST = 0, REFVSEL = {1} for 2 V | | | 16.1 | 21 | |
| | | f _{ADC10CLK} = 5.0 MHz, REFON = 1, REFBURST = 0, REFVSEL = {0} for 1.5 V | | | 14.4 | 21 | |
| TC _{REF+} | Temperature coefficient of built-in reference ⁽²⁾ | I _{VREF+} = 0 A, REFVSEL = {0, 1, 2}, REFON = 1 | | < 18 | 50 | ppm/ °C | |
| I _{SENSOR} | Operating supply current into AV _{CC} terminal ⁽³⁾ | REFON = 0, INCH = 0Ah, ADC10ON = N/A, T _A = 30°C | 2.2 V | | 17 | 22 | μA |
| | | | 3 V | | 17 | 22 | |
| V _{SENSOR} | See ⁽⁴⁾ | ADC10ON = 1, INCH = 0Ah, T _A = 30°C | 2.2 V | | 770 | | mV |
| | | | 3 V | | 770 | | |
| V _{MID} | AV _{CC} divider at channel 11 | ADC10ON = 1, INCH = 0Bh, V _{MID} ≈ 0.5 × V _{AVCC} | 2.2 V | 1.06 | 1.1 | 1.14 | V |
| | | | 3 V | 1.46 | 1.5 | 1.54 | |
| t _{SENSOR(sample)} | Sample time required if channel 10 is selected ⁽⁵⁾ | ADC10ON = 1, INCH = 0Ah, Error of conversion result ≤ 1 LSB | | 30 | | μs | |
| t _{VMID(sample)} | Sample time required if channel 11 is selected ⁽⁶⁾ | ADC10ON = 1, INCH = 0Bh, Error of conversion result ≤ 1 LSB | | 1 | | μs | |
| PSRR _{DC} | Power supply rejection ratio (DC) | AV _{CC} = AV _{CC (min)} to AV _{CC(max)} , T _A = 25°C, REFVSEL = {0, 1, 2}, REFON = 1 | | 120 | | μV/V | |
| PSRR _{AC} | Power supply rejection ratio (AC) | AV _{CC} = AV _{CC (min)} to AV _{CC(max)} , T _A = 25°C, f = 1 kHz, ΔV _{pp} = 100 mV, REFVSEL = {0, 1, 2}, REFON = 1 | | 6.4 | | mV/V | |
| t _{SETTLE} | Settling time of reference voltage ⁽⁷⁾ | AV _{CC} = AV _{CC (min)} to AV _{CC(max)} , REFVSEL = {0, 1, 2}, REFON = 0 → 1 | | 75 | | μs | |
| V _{SD24REF} | SD24_B internal reference voltage | SD24REFS = 1 | 3 V | 1.151 | 1.1623 | 1.174 | V |
| t _{ON} | SD24_B internal reference turnon time | SD24REFS = 0 → 1, C _{REF} = 100 nF | 3 V | | 200 | | μs |

- (1) The internal reference current is supplied from the AV_{CC} terminal. Consumption is independent of the ADC10ON control bit, unless a conversion is active. The REFON bit enables to settle the built-in reference before starting an analog-to-digital conversion.
- (2) Calculated using the box method: (MAX(−40°C to 85°C) − MIN(−40°C to 85°C)) / MIN(−40°C to 85°C)/(85°C − (−40°C)).
- (3) The sensor current I_{SENSOR} is consumed if (ADC10ON = 1 and REFON = 1) or (ADC10ON = 1 and INCH = 0Ah and sample signal is high). When REFON = 1, I_{SENSOR} is already included in I_{REF+}.
- (4) The temperature sensor offset can be significant. TI recommends a single-point calibration to minimize the offset error of the built-in temperature sensor.
- (5) The typical equivalent impedance of the sensor is 51 kΩ. The sample time required includes the sensor-on time t_{SENSOR(on)}.
- (6) The on-time t_{VMID(on)} is included in the sampling time t_{VMID(sample)}; no additional on time is needed.
- (7) The condition is that the error in a conversion started after t_{REFON} is less than ±0.5 LSB.

5.19 Comparator_B

Table 5-52 lists the characteristics of the comparator.

Table 5-52. Comparator_B

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | V _{CC} | MIN | TYP | MAX | UNIT |
|------------------------|---|---|-----------------|----------------------------------|--------------------------------|----------------------------------|--------|
| V _{CC} | Supply voltage | | | 1.8 | | 3.6 | V |
| I _{AVCC_COMP} | Comparator operating supply current into AVCC, excludes reference resistor ladder | CBPWRMD = 00, CBON = 1, CBRs _x = 00 | 1.8 V | | | 40 | μA |
| | | | 2.2 V | | 22 | 50 | |
| | | | 3 V | | 32 | 65 | |
| | | 2.2 V, 3 V | | 10 | 30 | | |
| | | | | 0.2 | 0.85 | | |
| I _{AVCC_REF} | Quiescent current of resistor ladder into AVCC, includes REF module current | CBREFACC = 1, CBREFL _x = 01, CBRs _x = 10, REFON = 0, CBON = 0 | 2.2 V, 3 V | | 10 | 22 | μA |
| | | | | | | 33 | |
| V _{IC} | Common-mode input range | | | 0 | | V _{CC} – 1 | V |
| V _{OFFSET} | Input offset voltage | CBPWRMD = 00 | | –20 | | 20 | mV |
| | | CBPWRMD = 01 or 10 | | –20 | | 20 | |
| C _{IN} | Input capacitance | | | | 5 | | pF |
| R _{SIN} | Series input resistance | On (switch closed) | | | 3 | 4 | kΩ |
| | | Off (switch open) | | 50 | | | MΩ |
| t _{PD} | Propagation delay, response time | CBPWRMD = 00, CBF = 0 | | | | 450 | ns |
| | | CBPWRMD = 01, CBF = 0 | | | | 600 | |
| | | CBPWRMD = 10, CBF = 0 | | | | | 50 |
| t _{PD,filter} | Propagation delay with filter active | CBPWRMD = 00, CBON = 1, CBF = 1, CBF _{DLY} = 00 | | 0.30 | 0.6 | 1.5 | μs |
| | | CBPWRMD = 00, CBON = 1, CBF = 1, CBF _{DLY} = 01 | | 0.5 | 1.0 | 1.8 | |
| | | CBPWRMD = 00, CBON = 1, CBF = 1, CBF _{DLY} = 10 | | 0.8 | 1.8 | 3.4 | |
| | | CBPWRMD = 00, CBON = 1, CBF = 1, CBF _{DLY} = 11 | | 1.5 | 3.4 | 6.5 | |
| t _{EN_CMP} | Comparator enable time | CBON = 0 to CBON = 1, CBPWRMD = 00 or 01 | | | 1 | 2 | μs |
| | | CBON = 0 to CBON = 1, CBPWRMD = 10 | | | | 100 | |
| t _{EN_REF} | Resistor reference enable time | CBON = 0 to CBON = 1 | | | 1.0 | 1.5 | μs |
| TC _{REF} | Temperature coefficient reference | | | | | 50 | ppm/°C |
| V _{CB_REF} | Reference voltage for a given tap | V _{IN} = reference into resistor ladder, n = 0 to 31 | | V _{IN} × (n + 1.5) / 32 | V _{IN} × (n + 1) / 32 | V _{IN} × (n + 0.5) / 32 | V |

5.20 Flash

Table 5-53 lists the characteristics of the flash memory.

Table 5-53. Flash Memory

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | T _J | MIN | TYP | MAX | UNIT |
|--|--|----------------|-----------------|-----------------|-----|--------|
| DV _{CC(PGM/ERASE)} | Program and erase supply voltage | | 1.8 | | 3.6 | V |
| I _{PGM} | Average supply current from DVCC during program | | | 3 | 5 | mA |
| I _{ERASE} | Average supply current from DVCC during erase | | | 6 | 15 | mA |
| I _{MERASE} , I _{BANK} | Average supply current from DVCC during mass erase or bank erase | | | 6 | 15 | mA |
| t _{CPT} | Cumulative program time ⁽¹⁾ | | | | 16 | ms |
| | Program and erase endurance | | 10 ⁴ | 10 ⁵ | | cycles |
| t _{Retention} | Data retention duration | 25°C | 100 | | | years |
| t _{Word} | Word or byte program time ⁽²⁾ | | 64 | | 85 | μs |
| t _{Block, 0} | Block program time for first byte or word ⁽²⁾ | | 49 | | 65 | μs |
| t _{Block, 1–(N–1)} | Block program time for each additional byte or word, except for last byte or word ⁽²⁾ | | 37 | | 49 | μs |
| t _{Block, N} | Block program time for last byte or word ⁽²⁾ | | 55 | | 73 | μs |
| t _{Erase} | Erase time for segment erase, mass erase, and bank erase when available ⁽²⁾ | | 23 | | 32 | ms |
| f _{MCLK,MGR} | MCLK frequency in marginal read mode (FCTL4.MGR0 = 1 or FCTL4.MGR1 = 1) | | 0 | | 1 | MHz |

(1) The cumulative program time must not be exceeded when writing to a 128-byte flash block. This parameter applies to all programming methods: individual word or byte write and block write modes.

(2) These values are hardwired into the state machine of the flash controller.

5.21 Emulation and Debug

Table 5-54 lists the characteristics of the JTAG and SBW interface.

Table 5-54. JTAG and Spy-Bi-Wire (SBW) Interface

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | V _{CC} | MIN | TYP | MAX | UNIT |
|-----------------------|--|-----------------|-------|-----|-----|------|
| f _{SBW} | Spy-Bi-Wire input frequency | 2.2 V, 3 V | 0 | | 20 | MHz |
| t _{SBW,Low} | Spy-Bi-Wire low clock pulse duration | 2.2 V, 3 V | 0.025 | | 15 | μs |
| t _{SBW,En} | Spy-Bi-Wire enable time (TEST high to acceptance of first clock edge) ⁽¹⁾ | 2.2 V, 3 V | | | 1 | μs |
| t _{SBW,Rst} | Spy-Bi-Wire return to normal operation time | | 15 | | 100 | μs |
| f _{TCK} | TCK input frequency for 4-wire JTAG ⁽²⁾ | 2.2 V | 0 | | 5 | MHz |
| | | 3 V | 0 | | 10 | MHz |
| R _{internal} | Internal pulldown resistance on TEST | 2.2 V, 3 V | 45 | 60 | 80 | kΩ |

(1) Tools that access the Spy-Bi-Wire interface must wait for the minimum t_{SBW,En} time after pulling the TEST/SBWTCK pin high before applying the first SBWTCK clock edge.

(2) f_{TCK} may be restricted to meet the timing requirements of the module selected.

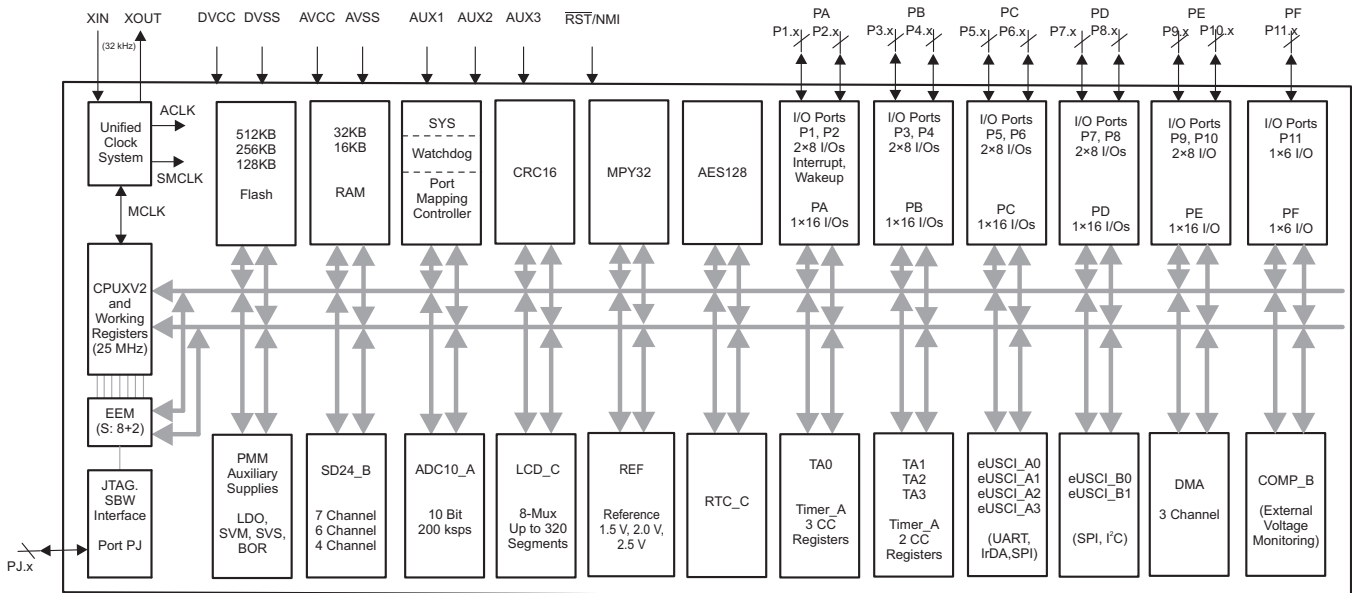
6 Detailed Description

6.1 Overview

The TI MSP430F67xxA family of polyphase metering SoCs are powerful highly-integrated solutions for revenue meters that offer accuracy and low system cost with few external components. The MSP430F67xxA uses the low-power MSP430 CPU with a 32-bit multiplier to perform all energy calculations, metering applications such as tariff rate management, and communications with AMR and AMI modules.

6.2 Functional Block Diagrams

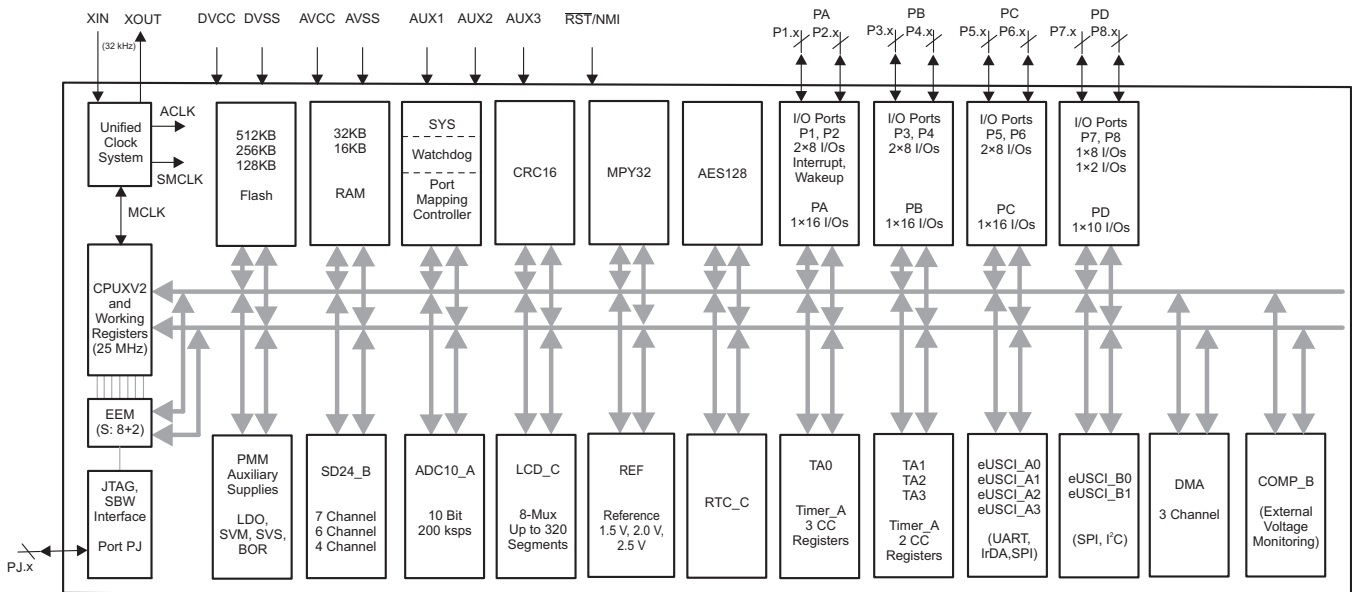
Figure 6-1 shows the functional block diagram for the MSP430F677xA, MSP430F676xA, and MSP430F674xA devices in the PEU package.



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Figure 6-1. Functional Block Diagram – PEU Package

Figure 6-2 shows the functional block diagram for the MSP430F677xA, MSP430F676xA, and MSP430F674xA devices in the PZ package.



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Figure 6-2. Functional Block Diagram – PZ Package

6.3 CPU ([Link to User's Guide](#))

The MSP430 CPU has a 16-bit RISC architecture that is highly transparent to the application. All operations, other than program-flow instructions, are performed as register operations in conjunction with seven addressing modes for source operand and four addressing modes for destination operand.

The CPU is integrated with 16 registers that provide reduced instruction execution time. The register-to-register operation execution time is one cycle of the CPU clock. Four of the registers, R0 to R3, are dedicated as program counter, stack pointer, status register, and constant generator, respectively. The remaining registers are general-purpose registers (see [Figure 6-3](#)).

Peripherals are connected to the CPU using data, address, and control buses. Peripherals can be managed with all instructions.

| | |
|--------------------------|-----------|
| Program Counter | PC/R0 |
| Stack Pointer | SP/R1 |
| Status Register | SR/CG1/R2 |
| Constant Generator | CG2/R3 |
| General-Purpose Register | R4 |
| General-Purpose Register | R5 |
| General-Purpose Register | R6 |
| General-Purpose Register | R7 |
| General-Purpose Register | R8 |
| General-Purpose Register | R9 |
| General-Purpose Register | R10 |
| General-Purpose Register | R11 |
| General-Purpose Register | R12 |
| General-Purpose Register | R13 |
| General-Purpose Register | R14 |
| General-Purpose Register | R15 |

Figure 6-3. CPU Registers

6.4 Instruction Set

The instruction set consists of the original 51 instructions with three formats and seven address modes and additional instructions for the expanded address range. Each instruction can operate on word and byte data. [Table 6-1](#) lists examples of the three types of instruction formats. [Table 6-2](#) lists the address modes.

Table 6-1. Instruction Word Formats

| INSTRUCTION WORD FORMAT | EXAMPLE | OPERATION |
|---|-----------|-----------------------|
| Dual operands, source and destination | ADD R4,R5 | R4 + R5 → R5 |
| Single operands, destination only | CALL R8 | PC → (TOS), R8 → PC |
| Relative jump, conditional or unconditional | JNE | Jump-on-equal bit = 0 |

Table 6-2. Address Mode Descriptions

| ADDRESS MODE | S ⁽¹⁾ | D ⁽¹⁾ | SYNTAX | EXAMPLE | OPERATION |
|------------------------|------------------|------------------|--------------------|------------------|-------------------------------|
| Register | ✓ | ✓ | MOV Rs,Rd | MOV R10,R11 | R10 → R11 |
| Indexed | ✓ | ✓ | MOV X(Rn),Y(Rm) | MOV 2(R5),6(R6) | M(2+R5) → M(6+R6) |
| Symbolic (PC relative) | ✓ | ✓ | MOV EDE,TONI | | M(EDE) → M(TONI) |
| Absolute | ✓ | ✓ | MOV & MEM, & TCDAT | | M(MEM) → M(TCDAT) |
| Indirect | ✓ | | MOV @Rn,Y(Rm) | MOV @R10,Tab(R6) | M(R10) → M(Tab+R6) |
| Indirect autoincrement | ✓ | | MOV @Rn+,Rm | MOV @R10+,R11 | M(R10) → R11 R10 + 2 → R10 |
| Immediate | ✓ | | MOV #X,TONI | MOV #45,TONI | #45 → M(TONI) |

(1) S = source, D = destination

6.5 Operating Modes

These microcontrollers have one active mode and six software-selectable low-power modes of operation. An interrupt event can wake up the device from any of the five low-power modes, service the request, and restore back to the low-power mode on return from the interrupt program.

Software can configure the following operating modes:

- Active mode (AM)
 - All clocks are active
- Low-power mode 0 (LPM0)
 - CPU is disabled
 - ACLK and SMCLK remain active, MCLK is disabled
 - FLL loop control remains active
- Low-power mode 1 (LPM1)
 - CPU is disabled
 - FLL loop control is disabled
 - ACLK and SMCLK remain active, MCLK is disabled
- Low-power mode 2 (LPM2)
 - CPU is disabled
 - MCLK and FLL loop control and DCOCLK are disabled
 - DC generator of the DCO remains enabled
 - ACLK remains active
- Low-power mode 3 (LPM3)
 - CPU is disabled
 - MCLK, FLL loop control, and DCOCLK are disabled
 - DC generator of the DCO is disabled
 - ACLK remains active
- Low-power mode 4 (LPM4)
 - CPU is disabled
 - ACLK is disabled
 - MCLK, FLL loop control, and DCOCLK are disabled
 - DC generator of the DCO is disabled
 - Crystal oscillator is stopped
 - Complete data retention
- Low-power mode 3.5 (LPM3.5)
 - Internal regulator disabled
 - No RAM retention, backup RAM retained
 - I/O pad state retention
 - RTC clocked by low-frequency oscillator
 - Wake-up input from $\overline{\text{RST/NMI}}$, RTC_C events, port P1, or port P2
- Low-power mode 4.5 (LPM4.5)
 - Internal regulator disabled
 - No RAM retention, backup RAM retained
 - RTC is disabled
 - I/O pad state retention
 - Wake-up input from $\overline{\text{RST/NMI}}$, port P1, or port P2

6.6 Interrupt Vector Addresses

The interrupt vectors and the power-up start address are in the address range 0FFFFh to 0FF80h (see [Table 6-3](#)). The vector contains the 16-bit address of the appropriate interrupt-handler instruction sequence.

Table 6-3. Interrupt Sources, Flags, and Vectors

| INTERRUPT SOURCE | INTERRUPT FLAG | SYSTEM INTERRUPT | WORD ADDRESS | PRIORITY |
|---|---|------------------|--------------|-------------|
| System Reset Power up External reset Watchdog time-out, key violation Flash memory key violation | WDTIFG, KEYV (SYSRSTIV) ^{(1) (2)} | Reset | 0FFFEh | 63, highest |
| System NMI PMM Vacant memory access JTAG mailbox | SVMLIFG, SVMHIFG, DLYLIFG, DLYHIFG, VLRIFG, VLRHIFG, VMAIFG, JMBINIFG, JMBOUTIFG (SYSSNIV) ^{(1) (3)} | (Non)maskable | 0FFFCh | 62 |
| User NMI NMI Oscillator fault Flash memory access violation Supply switched | NMIIFG, OFIFG, ACCVIFG, AUXSWGIFG (SYSUNIV) ^{(1) (3)} | (Non)maskable | 0FFFAh | 61 |
| Watchdog Timer_A interval timer mode | WDTIFG | Maskable | 0FFF8h | 60 |
| eUSCI_A0 receive or transmit | UCA0RXIFG, UCA0TXIFG (UCA0IV) ^{(1) (4)} | Maskable | 0FFF6h | 59 |
| eUSCI_B0 receive or transmit | UCB0RXIFG, UCB0TXIFG (UCB0IV) ^{(1) (4)} | Maskable | 0FFF4h | 58 |
| ADC10_A | ADC10IFG0, ADC10INIFG, ADC10LOIFG, ADC10HIIFG, ADC10TOVIFG, ADC10OVIFG (ADC10IV) ^{(1) (4)} | Maskable | 0FFF2h | 57 |
| SD24_B | SD24_B Interrupt Flags (SD24IV) ^{(1) (4)} | Maskable | 0FFF0h | 56 |
| Timer TA0 | TA0CCR0 CCIFG0 ⁽⁴⁾ | Maskable | 0FFEEh | 55 |
| Timer TA0 | TA0CCR1 CCIFG1, TA0CCR2 CCIFG2, TA0IFG (TA0IV) ^{(1) (4)} | Maskable | 0FFECCh | 54 |
| eUSCI_A1 receive or transmit | UCA1RXIFG, UCA1TXIFG (UCA1IV) ^{(1) (4)} | Maskable | 0FFEAh | 53 |
| eUSCI_A2 receive or transmit | UCA2RXIFG, UCA2TXIFG (UCA2IV) ^{(1) (4)} | Maskable | 0FFE8h | 52 |
| Auxiliary supplies | AUXSWGIFG, AUXIFG0, AUXIFG1, AUXIFG2 (AUXIV) ^{(1) (4)} | Maskable | 0FFE6h | 51 |
| DMA | DMA0IFG, DMA1IFG, DMA2IFG (DMAIV) ^{(1) (4)} | Maskable | 0FFE4h | 50 |
| Timer TA1 | TA1CCR0 CCIFG0 ⁽⁴⁾ | Maskable | 0FFE2h | 49 |
| Timer TA1 | TA1CCR1 CCIFG1, TA1IFG (TA1IV) ^{(1) (4)} | Maskable | 0FFE0h | 48 |
| eUSCI_A3 receive or transmit | UCA3RXIFG, UCA3TXIFG (UCA3IV) ^{(1) (4)} | Maskable | 0FFDEh | 47 |
| eUSCI_B1 receive or transmit | UCB1RXIFG, UCB1TXIFG (UCB1IV) ^{(1) (4)} | Maskable | 0FFDCh | 46 |
| I/O port P1 | P1IFG.0 to P1IFG.7 (P1IV) ^{(1) (4)} | Maskable | 0FFDAh | 45 |
| Timer TA2 | TA2CCR0 CCIFG0 ⁽⁴⁾ | Maskable | 0FFD8h | 44 |
| Timer TA2 | TA2CCR1 CCIFG1, TA2IFG (TA2IV) ^{(1) (4)} | Maskable | 0FFD6h | 43 |
| I/O port P2 | P2IFG.0 to P2IFG.7 (P2IV) ^{(1) (4)} | Maskable | 0FFD4h | 42 |
| Timer TA3 | TA3CCR0 CCIFG0 ⁽⁴⁾ | Maskable | 0FFD2h | 41 |
| Timer TA3 | TA3CCR1 CCIFG1, TA3IFG (TA3IV) ^{(1) (4)} | Maskable | 0FFD0h | 40 |
| LCD_C | LCD_C Interrupt Flags (LCDCIV) ^{(1) (4)} | Maskable | 0FFCEh | 39 |

(1) Multiple source flags

(2) A reset is generated if the CPU tries to fetch instructions from within peripheral space or vacant memory space.

(3) (Non)maskable: the individual interrupt enable bit can disable an interrupt event, but the general interrupt enable bit cannot disable it.

(4) Interrupt flags are in the module.

Table 6-3. Interrupt Sources, Flags, and Vectors (continued)

| INTERRUPT SOURCE | INTERRUPT FLAG | SYSTEM INTERRUPT | WORD ADDRESS | PRIORITY |
|------------------|--|------------------|--------------|-----------|
| RTC_C | RTCOFIFG, RTCRDYIFG, RTCTEVIFG, RTCAIFG, RT0PSIFG, RT1PSIFG (RTCIV) ^{(1) (4)} | Maskable | 0FFCCh | 38 |
| Comparator_B | Comparator_B Interrupt Flags (CBIV) ⁽¹⁾ | Maskable | 0FFCAh | 37 |
| AES | AESRDYIFG | Maskable | 0FFC8h | 36 |
| Reserved | Reserved ⁽⁵⁾ | | 0FFC6h | 35 |
| | | | : | : |
| | | | 0FF80h | 0, lowest |

(5) Reserved interrupt vectors at addresses are not used in this device and can be used for regular program code if necessary. To maintain compatibility with other devices, TI recommends reserving these locations.

6.7 Special Function Registers (SFRs)

The SFRs are in the lowest address space and can be accessed in word or byte formats.

Legend

| | |
|----------------|---|
| rw | Bit can be read and written. |
| rw-0, rw-1 | Bit can be read and written. It is reset or set by PUC. |
| rw-(0), rw-(1) | Bit can be read and written. It is reset or set by POR. |
| rw-[0], rw-[1] | Bit can be read and written. It is reset or set by BOR. |
| – | SFR bit is not present in device. |

Figure 6-4. Interrupt Enable 1 Register

| 15 | 14 | 13 | 12 | 11 | 10 | 9 | 8 |
|----------|---------|--------|-------|-------|----|-----------|-------|
| – | – | – | – | – | – | AUXSWNMIE | – |
| rw-0 | | | | | | | |
| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| JMBOUTIE | JMBINIE | ACCVIE | NMIIE | VMAIE | – | OFIE | WDTIE |
| rw-0 | rw-0 | rw-0 | rw-0 | rw-0 | | rw-0 | rw-0 |

Table 6-4. Interrupt Enable 1 Register Description

| Bit | Field | Type | Reset | Description |
|-----|-----------|------|-------|--|
| 9 | AUXSWNMIE | RW | 0h | Supply switched nonmaskable interrupt enable |
| 7 | JMBOUTIE | RW | 0h | JTAG mailbox output interrupt enable |
| 6 | JMBINIE | RW | 0h | JTAG mailbox input interrupt enable |
| 5 | ACCVIE | RW | 0h | Flash access violation interrupt enable |
| 4 | NMIIE | RW | 0h | Nonmaskable interrupt enable |
| 3 | VMAIE | RW | 0h | Vacant memory access interrupt enable |
| 1 | OFIE | RW | 0h | Oscillator fault interrupt enable |
| 0 | WDTIE | RW | 0h | Watchdog timer interrupt enable. Inactive if watchdog mode is selected. Active if watchdog timer is configured as a general-purpose timer. |

Figure 6-5. Interrupt Flag 1 Register

| | | | | | | | |
|-----------|----------|----|--------|--------|----|-------|--------|
| 15 | 14 | 13 | 12 | 11 | 10 | 9 | 8 |
| – | – | – | – | – | – | – | – |
| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| JMBOUTIFG | JMBINIFG | – | NMIIFG | VMAIFG | – | OFIFG | WDTIFG |
| rw-[0] | rw-[0] | | rw-0 | rw-0 | | rw-0 | rw-0 |

Table 6-5. Interrupt Flag 1 Register Description

| Bit | Field | Type | Reset | Description |
|-----|-----------|------|-------|---|
| 7 | JMBOUTIFG | RW | 0h | Set on JTAG mailbox output register ready for next message |
| 6 | JMBINIFG | RW | 0h | Set on JTAG mailbox input message |
| 4 | NMIIFG | RW | 0h | Set by $\overline{\text{RST}}/\text{NMI}$ pin |
| 3 | VMAIFG | RW | 0h | Set on vacant memory access |
| 1 | OFIFG | RW | 0h | Flag set on oscillator fault |
| 0 | WDTIFG | RW | 0h | Set on watchdog timer overflow (in watchdog mode) or security key violation. Reset on V_{CC} power-on or a reset condition at the $\overline{\text{RST}}/\text{NMI}$ pin in reset mode. |

6.8 Bootloader (BSL)

The BSL enables users to program the flash memory or RAM using various serial interfaces. Table 6-6 lists the BSL interface pin requirements. Access to the device memory by the BSL is protected by a user-defined password. BSL entry requires a specific entry sequence on the $\overline{\text{RST}}/\text{NMI}/\text{SBWTDIO}$ and $\text{TEST}/\text{SBWTCK}$ pins. For a complete description of the features of the BSL and its implementation, see the *MSP430™ Flash Device Bootloader (BSL) User's Guide*.

Table 6-6. UART BSL Pin Requirements and Functions

| DEVICE SIGNAL | BSL FUNCTION |
|---|-----------------------|
| $\overline{\text{RST}}/\text{NMI}/\text{SBWTDIO}$ | Entry sequence signal |
| $\text{TEST}/\text{SBWTCK}$ | Entry sequence signal |
| P2.0 | Data transmit |
| P2.1 | Data receive |
| DVCC | Power supply |
| DVSS | Ground supply |

6.9 JTAG Operation

6.9.1 JTAG Standard Interface

The MSP430 family supports the standard JTAG interface which requires four signals for sending and receiving data. The JTAG signals are shared with general-purpose I/O. The TEST/SBWTCK pin is used to enable the JTAG signals. In addition to these signals, the $\overline{\text{RST}}/\text{NMI}/\text{SBWTDIO}$ is required to interface with MSP430 development tools and device programmers. [Table 6-7](#) lists the JTAG interface pin requirements. For further details on interfacing to development tools and device programmers, see the [MSP430 Hardware Tools User's Guide](#). For a complete description of the features of the JTAG interface and its implementation, see [MSP430 Programming With the JTAG Interface](#).

Table 6-7. JTAG Pin Requirements and Functions

| DEVICE SIGNAL | DIRECTION | FUNCTION |
|---|-----------|-----------------------------|
| PJ.3/TCK | IN | JTAG clock input |
| PJ.2/TMS | IN | JTAG state control |
| PJ.1/TDI/TCLK | IN | JTAG data input, TCLK input |
| PJ.0/TDO | OUT | JTAG data output |
| TEST/SBWTCK | IN | Enable JTAG pins |
| $\overline{\text{RST}}/\text{NMI}/\text{SBWTDIO}$ | IN | External reset |
| DVCC | | Power supply |
| DVSS | | Ground supply |

6.9.2 Spy-Bi-Wire Interface

In addition to the standard JTAG interface, the MSP430 family supports the 2-wire Spy-Bi-Wire interface. Spy-Bi-Wire can be used to interface with MSP430 development tools and device programmers. [Table 6-8](#) lists the Spy-Bi-Wire interface pin requirements. For further details on interfacing to development tools and device programmers, see the [MSP430 Hardware Tools User's Guide](#). For a complete description of the features of the JTAG interface and its implementation, see [MSP430 Programming With the JTAG Interface](#).

Table 6-8. Spy-Bi-Wire Pin Requirements and Functions

| DEVICE SIGNAL | DIRECTION | FUNCTION |
|---|-----------|-----------------------------------|
| TEST/SBWTCK | IN | Spy-Bi-Wire clock input |
| $\overline{\text{RST}}/\text{NMI}/\text{SBWTDIO}$ | IN, OUT | Spy-Bi-Wire data input and output |
| DVCC | | Power supply |
| DVSS | | Ground supply |

6.10 Memory

6.10.1 Memory Organization

Table 6-9 summarizes the memory map of the MSP430F67x9A, MSP430F67x8A, and MSP430F67x7A devices.

Table 6-9. Memory Organization – MSP430F67x9A, MSP430F67x8A, and MSP430F67x7A

| | | MSP430F6779A MSP430F6769A MSP430F6749A | MSP430F6778A MSP430F6768A MSP430F6748A | MSP430F6777A MSP430F6767A MSP430F6747A |
|---------------------------------|------------|--|--|--|
| Main memory (flash) | Total Size | 512KB | 512KB | 256KB |
| Main: interrupt vector | | 00FFFFh to 00FF80h | 00FFFFh to 00FF80h | 00FFFFh to 00FF80h |
| Main: code memory | Bank 3 | 128KB 08BFFFh to 06C000h | 128KB 08BFFFh to 06C000h | Not available |
| | Bank 2 | 128KB 06BFFFh to 04C000h | 128KB 06BFFFh to 04C000h | Not available |
| | Bank 1 | 128KB 04BFFFh to 02C000h | 128KB 04BFFFh to 02C000h | 128KB 04BFFFh to 02C000h |
| | Bank 0 | 128KB 02BFFFh to 00C000h | 128KB 02BFFFh to 00C000h | 128KB 02BFFFh to 00C000h |
| RAM | Total Size | 32KB | 16KB | 32KB |
| | Sector 7 | 4KB 009BFFh to 008C00h | Not available | 4KB 009BFFh to 008C00h |
| | Sector 6 | 4KB 008BFFh to 007C00h | Not available | 4KB 008BFFh to 007C00h |
| | Sector 5 | 4KB 007BFFh to 006C00h | Not available | 4KB 007BFFh to 006C00h |
| | Sector 4 | 4KB 006BFFh to 005C00h | Not available | 4KB 006BFFh to 005C00h |
| | Sector 3 | 4KB 005BFFh to 004C00h | 4KB 005BFFh to 004C00h | 4KB 005BFFh to 004C00h |
| | Sector 2 | 4KB 004BFFh to 003C00h | 4KB 004BFFh to 003C00h | 4KB 004BFFh to 003C00h |
| | Sector 1 | 4KB 003BFFh to 002C00h | 4KB 003BFFh to 002C00h | 4KB 003BFFh to 002C00h |
| | Sector 0 | 4KB 002BFFh to 001C00h | 4KB 002BFFh to 001C00h | 4KB 002BFFh to 001C00h |
| Device descriptor | | 128 B 001AFFh to 001A80h | 128 B 001AFFh to 001A80h | 128 B 001AFFh to 001A80h |
| | | 128 B 001A7Fh to 001A00h | 128 B 001A7Fh to 001A00h | 128 B 001A7Fh to 001A00h |
| Information memory (flash) | Info A | 128 B 0019FFh to 001980h | 128 B 0019FFh to 001980h | 128 B 0019FFh to 001980h |
| | Info B | 128 B 00197Fh to 001900h | 128 B 00197Fh to 001900h | 128 B 00197Fh to 001900h |
| | Info C | 128 B 0018FFh to 001880h | 128 B 0018FFh to 001880h | 128 B 0018FFh to 001880h |
| | Info D | 128 B 00187Fh to 001800h | 128 B 00187Fh to 001800h | 128 B 00187Fh to 001800h |
| Bootloader (BSL) memory (flash) | BSL 3 | 512 B 0017FFh to 001600h | 512 B 0017FFh to 001600h | 512 B 0017FFh to 001600h |
| | BSL 2 | 512 B 0015FFh to 001400h | 512 B 0015FFh to 001400h | 512 B 0015FFh to 001400h |
| | BSL 1 | 512 B 0013FFh to 001200h | 512 B 0013FFh to 001200h | 512 B 0013FFh to 001200h |
| | BSL 0 | 512 B 0011FFh to 001000h | 512 B 0011FFh to 001000h | 512 B 0011FFh to 001000h |

Table 6-9. Memory Organization – MSP430F67x9A, MSP430F67x8A, and MSP430F67x7A (continued)

| | | MSP430F6779A MSP430F6769A MSP430F6749A | MSP430F6778A MSP430F6768A MSP430F6748A | MSP430F6777A MSP430F6767A MSP430F6747A |
|-------------|--|--|--|--|
| Peripherals | | 4KB 000FFFh to 0h | 4KB 000FFFh to 0h | 4KB 000FFFh to 0h |

Table 6-10 summarizes the memory map of the MSP430F67x6A and MSP430F67x5A devices.

Table 6-10. Memory Organization – MSP430F67x6A and MSP430F67x5A

| | | MSP430F6776A MSP430F6766A MSP430F6746A | MSP430F6775A MSP430F6765A MSP430F6745A |
|---------------------------------|------------|--|--|
| Main memory (flash) | Total Size | 256KB | 128KB |
| Main: interrupt vector | | 00FFFFh to 00FF80h | 00FFFFh to 00FF80h |
| Main: code memory | Bank 3 | Not available | Not available |
| | Bank 2 | Not available | Not available |
| | Bank 1 | 128KB 04BFFFh to 02C000h | Not available |
| | Bank 0 | 128KB 02BFFFh to 00C000h | 128KB 02BFFFh to 00C000h |
| RAM | Total Size | 16KB | 16KB |
| | Sector 7 | Not available | Not available |
| | Sector 6 | Not available | Not available |
| | Sector 5 | Not available | Not available |
| | Sector 4 | Not available | Not available |
| | Sector 3 | 4KB 005BFFFh to 004C00h | 4KB 005BFFFh to 004C00h |
| | Sector 2 | 4KB 004BFFFh to 003C00h | 4KB 004BFFFh to 003C00h |
| | Sector 1 | 4KB 003BFFFh to 002C00h | 4KB 003BFFFh to 002C00h |
| Device descriptor | | 128 B 001AFFh to 001A80h | 128 B 001AFFh to 001A80h |
| | | 128 B 001A7Fh to 001A00h | 128 B 001A7Fh to 001A00h |
| Information memory (flash) | Info A | 128 B 0019FFh to 001980h | 128 B 0019FFh to 001980h |
| | Info B | 128 B 00197Fh to 001900h | 128 B 00197Fh to 001900h |
| | Info C | 128 B 0018FFh to 001880h | 128 B 0018FFh to 001880h |
| | Info D | 128 B 00187Fh to 001800h | 128 B 00187Fh to 001800h |
| Bootloader (BSL) memory (flash) | BSL 3 | 512 B 0017FFh to 001600h | 512 B 0017FFh to 001600h |
| | BSL 2 | 512 B 0015FFh to 001400h | 512 B 0015FFh to 001400h |
| | BSL 1 | 512 B 0013FFh to 001200h | 512 B 0013FFh to 001200h |
| | BSL 0 | 512 B 0011FFh to 001000h | 512 B 0011FFh to 001000h |
| Peripherals | | 4KB 000FFFh to 0h | 4KB 000FFFh to 0h |

6.10.2 Flash Memory ([Link to User's Guide](#))

The flash memory can be programmed through the JTAG port, Spy-Bi-Wire (SBW), the BSL, or in-system by the CPU. The CPU can perform single-byte, single-word, and long-word writes to the flash memory. Features of the flash memory include:

- Flash memory has n segments of main memory and four segments of information memory (A to D) of 128 bytes each. Each segment in main memory is 512 bytes in size.
- Segments 0 to n may be erased in one step, or each segment may be individually erased.
- Segments A to D can be erased individually, or as a group with segments 0 to n. Segments A to D are also called *information memory*.
- Segment A can be locked separately.

6.10.3 RAM ([Link to User's Guide](#))

The RAM is made up of n sectors. Each sector can be completely powered down to save leakage; however, all data are lost in the sector that is powered down. Features of the RAM include:

- RAM has n sectors of 4KB each.
- Each sector 0 to n can be completely disabled; however, data retention is lost in the disabled sector.
- Each sector 0 to n automatically enters low-power retention mode when possible.

6.10.4 Backup RAM ([Link to User's Guide](#))

The backup RAM provides a limited number of bytes of RAM that are retained during LPM3.5. This backup RAM is part of the backup subsystem that operates on dedicated power supply AUXVCC3. Eight bytes of backup RAM are available in this device. The backup RAM can be word-wise accessed using the registers BAKMEM0, BAKMEM1, BAKMEM2, and BAKMEM3. The backup RAM registers cannot be accessed by CPU when the high-side SVS is disabled by the user application.

6.11 Peripherals

Peripherals are connected to the CPU through data, address, and control buses. Peripherals can be controlled using all instructions. For complete module descriptions, see the [MSP430x5xx and MSP430x6xx Family User's Guide](#).

6.11.1 Oscillator and System Clock ([Link to User's Guide](#))

The Unified Clock System (UCS) module includes support for a 32768-Hz watch crystal oscillator, an internal very-low-power low-frequency oscillator (VLO), an internal trimmed low-frequency oscillator (REFO), and an integrated internal digitally controlled oscillator (DCO). The UCS module is designed to meet the requirements of both low system cost and low power consumption. The UCS module features digital frequency-locked loop (FLL) hardware that, in conjunction with a digital modulator, stabilizes the DCO frequency to a programmable multiple of the selected FLL reference frequency. The internal DCO provides a fast turnon clock source and stabilizes in less than 5 μ s. The UCS module provides the following clock signals:

- Auxiliary clock (ACLK), sourced from a 32768-Hz watch crystal, the internal low-frequency oscillator (VLO), or the trimmed low-frequency oscillator (REFO).
- Main clock (MCLK), the system clock used by the CPU. MCLK can be sourced by same sources made available to ACLK.
- Sub-Main clock (SMCLK), the subsystem clock used by the peripheral modules. SMCLK can be sourced by same sources made available to ACLK.
- ACLK/n, the buffered output of ACLK, ACLK/2, ACLK/4, ACLK/8, ACLK/16, ACLK/32.

6.11.2 Power-Management Module (PMM) ([Link to User's Guide](#))

The PMM includes an integrated voltage regulator that supplies the core voltage to the device and contains programmable output levels to provide for power optimization. The PMM also includes supply voltage supervisor (SVS) and supply voltage monitoring (SVM) circuitry, as well as brownout protection. The brownout circuit is implemented to provide the proper internal reset signal to the device during power on and power off. The SVS and SVM circuitry detects if the supply voltage drops below a user-selectable level and supports both supply voltage supervision (the device is automatically reset) and supply voltage monitoring (the device is not automatically reset). SVS and SVM circuitry is available on the primary supply and core supply.

6.11.3 Auxiliary-Supply System ([Link to User's Guide](#))

The auxiliary supply system provides the option to operate the device from auxiliary supplies when the primary supply fails. There are two auxiliary supplies (AUXVCC1 and AUXVCC2) supported in MSP430F67xx. This module supports automatic and manual switching from primary supply to auxiliary supplies while maintaining full functionality. The auxiliary supply system allows threshold-based monitoring of primary and auxiliary supplies. The device can be started from primary supply or AUXVCC1, whichever is higher. Auxiliary supply system enables internal monitoring of voltage levels on primary and auxiliary supplies using ADC10_A. This module also implements a simple charger for backup capacitors.

6.11.4 Backup Subsystem

The backup subsystem operates on a dedicated power supply AUXVCC3. This subsystem includes low-frequency oscillator, real-time clock module, and backup RAM. The functionality of the backup subsystem is retained during LPM3.5. The backup subsystem module registers cannot be accessed by CPU when the high-side SVS is disabled by user.

6.11.5 Digital I/O ([Link to User's Guide](#))

Up to eleven 8-bit I/O ports are implemented. For 128-pin options, ports P1 to P10 are complete, and port P11 is 6 bits wide. For 100-pin options, ports P1 to P7 are complete, port P8 is 2 bits wide, and ports P9, P10, and P11 are completely removed. Port PJ contains four individual I/O pins, common to all devices. All I/O bits are individually programmable.

- Any combination of input, output, and interrupt conditions is possible.
- Programmable pullup or pulldown on all ports.
- Programmable drive strength on all ports.
- Edge-selectable interrupt and LPM3.5, LPM4.5 wake-up input capability available for all bits of ports P1 and P2.
- Read-write access to port-control registers is supported by all instructions.
- Ports can be accessed byte-wise (P1 to P11) or word-wise in pairs (PA to PF).

6.11.6 Port Mapping Controller ([Link to User's Guide](#))

The port mapping controller allows flexible and reconfigurable mapping of digital functions to ports P2, P3, and P4 (see [Table 6-11](#)). [Table 6-12](#) lists the default settings for all pins that support port mapping.

Table 6-11. Port Mapping Mnemonics and Functions

| VALUE | PxMAPy MNEMONIC | INPUT PIN FUNCTION | OUTPUT PIN FUNCTION |
|-------|-----------------|--|---------------------|
| 0 | PM_NONE | None | DVSS |
| 1 | PM_UCA0RXD | eUSCI_A0 UART RXD (direction controlled by eUSCI – Input) | |
| | PM_UCA0SOMI | eUSCI_A0 SPI slave out master in (direction controlled by eUSCI) | |
| 2 | PM_UCA0TXD | eUSCI_A0 UART TXD (direction controlled by eUSCI – Output) | |
| | PM_UCA0SIMO | eUSCI_A0 SPI slave in master out (direction controlled by eUSCI) | |
| 3 | PM_UCA0CLK | eUSCI_A0 clock input/output (direction controlled by eUSCI) | |
| 4 | PM_UCA0STE | eUSCI_A0 SPI slave transmit enable (direction controlled by eUSCI) | |
| 5 | PM_UCA1RXD | eUSCI_A1 UART RXD (direction controlled by eUSCI – Input) | |
| | PM_UCA1SOMI | eUSCI_A1 SPI slave out master in (direction controlled by eUSCI) | |
| 6 | PM_UCA1TXD | eUSCI_A1 UART TXD (direction controlled by eUSCI – Output) | |
| | PM_UCA1SIMO | eUSCI_A1 SPI slave in master out (direction controlled by eUSCI) | |
| 7 | PM_UCA1CLK | eUSCI_A1 clock input/output (direction controlled by eUSCI) | |
| 8 | PM_UCA1STE | eUSCI_A1 SPI slave transmit enable (direction controlled by eUSCI) | |
| 9 | PM_UCA2RXD | eUSCI_A2 UART RXD (direction controlled by eUSCI – Input) | |
| | PM_UCA2SOMI | eUSCI_A2 SPI slave out master in (direction controlled by eUSCI) | |
| 10 | PM_UCA2TXD | eUSCI_A2 UART TXD (direction controlled by eUSCI – Output) | |
| | PM_UCA2SIMO | eUSCI_A2 SPI slave in master out (direction controlled by eUSCI) | |
| 11 | PM_UCA2CLK | eUSCI_A2 clock input/output (direction controlled by eUSCI) | |
| 12 | PM_UCA2STE | eUSCI_A2 SPI slave transmit enable (direction controlled by eUSCI) | |
| 13 | PM_UCA3RXD | eUSCI_A3 UART RXD (direction controlled by eUSCI – Input) | |
| | PM_UCA3SOMI | eUSCI_A3 SPI slave out master in (direction controlled by eUSCI) | |
| 14 | PM_UCA3TXD | eUSCI_A3 UART TXD (direction controlled by eUSCI – Output) | |
| | PM_UCA3SIMO | eUSCI_A3 SPI slave in master out (direction controlled by eUSCI) | |
| 15 | PM_UCA3CLK | eUSCI_A3 clock input/output (direction controlled by eUSCI) | |
| 16 | PM_UCA3STE | eUSCI_A3 SPI slave transmit enable (direction controlled by eUSCI) | |
| 17 | PM_UCB0SIMO | eUSCI_B0 SPI slave in master out (direction controlled by eUSCI) | |
| | PM_UCB0SDA | eUSCI_B0 I2C data (open drain and direction controlled by eUSCI) | |
| 18 | PM_UCB0SOMI | eUSCI_B0 SPI slave out master in (direction controlled by eUSCI) | |
| | PM_UCB0SCL | eUSCI_B0 I2C clock (open drain and direction controlled by eUSCI) | |
| 19 | PM_UCB0CLK | eUSCI_B0 clock input/output (direction controlled by eUSCI) | |
| 20 | PM_UCB0STE | eUSCI_B0 SPI slave transmit enable (direction controlled by eUSCI) | |

Table 6-11. Port Mapping Mnemonics and Functions (continued)

| VALUE | PxMAPy MNEMONIC | INPUT PIN FUNCTION | OUTPUT PIN FUNCTION |
|--------------------------|-----------------|--|------------------------------|
| 21 | PM_UCB1SIMO | eUSCI_B1 SPI slave in master out (direction controlled by eUSCI) | |
| | PM_UCB1SDA | eUSCI_B1 I2C data (open drain and direction controlled by eUSCI) | |
| 22 | PM_UCB1SOMI | eUSCI_B1 SPI slave out master in (direction controlled by eUSCI) | |
| | PM_UCB1SCL | eUSCI_B1 I2C clock (open drain and direction controlled by eUSCI) | |
| 23 | PM_UCB1CLK | eUSCI_B1 clock input/output (direction controlled by eUSCI) | |
| 24 | PM_UCB1STE | eUSCI_B1 SPI slave transmit enable (direction controlled by eUSCI) | |
| 25 | PM_TA0.0 | TA0 CCR0 capture input CCI0A | TA0 CCR0 compare output Out0 |
| 26 | PM_TA0.1 | TA0 CCR1 capture input CCI1A | TA0 CCR1 compare output Out1 |
| 27 | PM_TA0.2 | TA0 CCR2 capture input CCI2A | TA0 CCR2 compare output Out2 |
| 28 | PM_TA1.0 | TA1 CCR0 capture input CCI0A | TA1 CCR0 compare output Out0 |
| 29 | PM_TA2.0 | TA2 CCR0 capture input CCI0A | TA2 CCR0 compare output Out0 |
| 30 | PM_TA3.0 | TA3 CCR0 capture input CCI0A | TA3 CCR0 compare output Out0 |
| 31 (0FFh) ⁽¹⁾ | PM_ANALOG | Disables the output driver and the input Schmitt trigger to prevent parasitic cross currents when applying analog signals. | |

(1) The value of the PM_ANALOG mnemonic is set to 0FFh. The port mapping registers are only 5 bits wide, and the upper bits are ignored, which results in a read value of 31.

Table 6-12. Default Port Mapping

| PIN NAME | | PxMAPy MNEMONIC | INPUT PIN FUNCTION | OUTPUT PIN FUNCTION |
|----------------------------------|-------------------------------------|----------------------------|--|------------------------------|
| PEU | PZ | | | |
| P2.0/PM_TA0.0 | P2.0/PM_TA0.0/COM4 | PM_TA0.0 | TA0 CCR0 capture input CCI0A | TA0 CCR0 compare output Out0 |
| P2.1/PM_TA0.1 | P2.1/PM_TA0.1/COM5 | PM_TA0.1 | TA0 CCR1 capture input CCI1A | TA0 CCR1 compare output Out1 |
| P2.2/PM_TA0.2 | P2.2/PM_TA0.2/COM6 | PM_TA0.2 | TA0 CCR2 capture input CCI2A | TA0 CCR2 compare output Out2 |
| P2.3/PM_TA1.0 | P2.3/PM_TA1.0/COM7 | PM_TA1.0 | TA1 CCR0 capture input CCI0A | TA1 CCR0 compare output Out0 |
| P2.4/PM_TA2.0 | P1.1/PM_TA2.0/R23 | PM_TA2.0 | TA2 CCR0 capture input CCI0A | TA2 CCR0 compare output Out0 |
| P2.5/PM_UCB0SOMI/ PM_UCB0SCL | P2.0/PM_UCB0SOMI/ PM_UCB0SCL/R13 | PM_UCB0SOMI/ PM_UCB0SCL | eUSCI_B0 SPI slave out master in (direction controlled by eUSCI), eUSCI_B0 I2C clock (open drain and direction controlled by eUSCI) | |
| P2.6/PM_UCB0SIMO/ PM_UCB0SDA | P2.6/PM_UCB0SIMO/ PM_UCB0SDA/R03 | PM_UCB0SIMO/ PM_UCB0SDA | eUSCI_B0 SPI slave in master out (direction controlled by eUSCI), eUSCI_B0 I2C data (open drain and direction controlled by eUSCI) | |
| P2.7/PM_UCB0CLK | P2.7/PM_UCB0CLK/CB2 | PM_UCB0CLK | eUSCI_B0 clock input/output (direction controlled by eUSCI) | |
| P3.0/PM_UCA0RXD/ PM_UCA0SOMI | P3.0/PM_UCA0RXD/ PM_UCA0SOMI | PM_UCA0RXD/ PM_UCA0SOMI | eUSCI_A0 UART RXD (direction controlled by eUSCI – input), eUSCI_A0 SPI slave out master in (direction controlled by eUSCI) | |
| P3.1/PM_UCA0TXD/ PM_UCA0SIMO | P3.1/PM_UCA0TXD/ PM_UCA0SIMO/S39 | PM_UCA0TXD/ PM_UCA0SIMO | eUSCI_A0 UART TXD (direction controlled by eUSCI – output), eUSCI_A0 SPI slave in master out (direction controlled by eUSCI) | |
| P3.2/PM_UCA0CLK | P3.2/PM_UCA0CLK/S38 | PM_UCA0CLK | eUSCI_A0 clock input/output (direction controlled by eUSCI) | |
| P3.3/PM_UCA1CLK | P3.3/PM_UCA1CLK/S37 | PM_UCA1CLK | eUSCI_A1 clock input/output (direction controlled by eUSCI) | |
| P3.4/PM_UCA1RXD/ PM_UCA1SOMI/ | P3.4/PM_UCA1RXD/ PM_UCA1SOMI/S36 | PM_UCA1RXD/ PM_UCA1SOMI | eUSCI_A1 UART RXD (direction controlled by eUSCI – input), eUSCI_A1 SPI slave out master in (direction controlled by eUSCI) | |
| P3.5/PM_UCA1TXD/ PM_UCA1SIMO | P3.5/PM_UCA1TXD/ PM_UCA1SIMO/S35 | PM_UCA1TXD/ PM_UCA1SIMO | eUSCI_A1 UART TXD (direction controlled by eUSCI – output), eUSCI_A1 SPI slave in master out (direction controlled by eUSCI) | |
| P3.6/PM_UCA2RXD/ PM_UCA2SOMI/ | P3.6/PM_UCA2RXD/ PM_UCA2SOMI/S34 | PM_UCA2RXD/ PM_UCA2SOMI | eUSCI_A2 UART RXD (direction controlled by eUSCI – input), eUSCI_A2 SPI slave out master in (direction controlled by eUSCI) | |
| P3.7/PM_UCA2TXD/ PM_UCA2SIMO | P3.7/PM_UCA2TXD/ PM_UCA2SIMO/S33 | PM_UCA2TXD/ PM_UCA2SIMO | eUSCI_A2 UART TXD (direction controlled by eUSCI – output), eUSCI_A2 SPI slave in master out (direction controlled by eUSCI) | |
| P4.0/PM_UCA2CLK | P4.0/PM_UCA2CLK/S32 | PM_UCA2CLK | eUSCI_A2 clock input/output (direction controlled by eUSCI) | |
| P4.1/PM_UCA3RXD/ PM_UCA3SOMI/ | P4.1/PM_UCA3RXD/ PM_UCA3SOMI/S31 | PM_UCA3RXD/ PM_UCA3SOMI | eUSCI_A3 UART RXD (direction controlled by eUSCI – input), eUSCI_A3 SPI slave out master in (direction controlled by eUSCI) | |
| P4.2/PM_UCA3TXD/ PM_UCA3SIMO | P4.2/PM_UCA3TXD/ PM_UCA3SIMO/S30 | PM_UCA3TXD/ PM_UCA3SIMO | eUSCI_A3 UART TXD (direction controlled by eUSCI – output), eUSCI_A3 SPI slave in master out (direction controlled by eUSCI) | |
| P4.3/PM_UCA3CLK | P4.3/PM_UCA3CLK/S29 | PM_UCA3CLK | eUSCI_A3 clock input/output (direction controlled by eUSCI) | |
| P4.4/PM_UCB1SOMI/ PM_UCB1SCL | P4.4/PM_UCB1SOMI/ PM_UCB1SCL/S28 | PM_UCB1SOMI/ PM_UCB1SCL | eUSCI_B1 SPI slave out master in (direction controlled by eUSCI), eUSCI_B1 I2C clock (open drain and direction controlled by eUSCI) | |
| P4.5/PM_UCB1SIMO/ PM_UCB1SDA | P4.5/PM_UCB1SIMO/ PM_UCB1SDA/S27 | PM_UCB1SIMO/ PM_UCB1SDA | eUSCI_B1 SPI slave in master out (direction controlled by eUSCI), eUSCI_B1 I2C data (open drain and direction controlled by eUSCI) | |
| P4.6/PM_UCB1CLK | P4.6/PM_UCB1CLK/S26 | PM_UCB1CLK | eUSCI_B1 clock input/output (direction controlled by eUSCI) | |
| P4.7/PM_TA3.0 | P4.7/PM_TA3.0/S25 | PM_TA3.0 | TA3 CCR0 capture input CCI0A | TA3 CCR0 compare output Out0 |

6.11.7 System Module (SYS) [\(Link to User's Guide\)](#)

The SYS module handles many of the system functions within the device. These include power-on reset (POR) and power-up clear (PUC) handling, NMI source selection and management, reset interrupt vector generators, bootloader entry mechanisms, and configuration management (device descriptors). The SYS module also includes a data exchange mechanism using JTAG called a JTAG mailbox that can be used in the application. [Table 6-13](#) lists the SYS module interrupt vector registers.

Table 6-13. System Module Interrupt Vector Registers

| INTERRUPT VECTOR REGISTER | ADDRESS | INTERRUPT EVENT | VALUE | PRIORITY |
|---------------------------|------------|--------------------------------|------------|----------------------|
| SYSRSTIV, System Reset | 019Eh | No interrupt pending | 00h | |
| | | Brownout (BOR) | 02h | Highest |
| | | RST/NMI (POR) | 04h | |
| | | DoBOR (BOR) | 06h | |
| | | Wake up from LPMx.5 | 08h | |
| | | Security violation (BOR) | 0Ah | |
| | | SVSL (POR) | 0Ch | |
| | | SVSH (POR) | 0Eh | |
| | | SVML_OVP (POR) | 10h | |
| | | SVMH_OVP (POR) | 12h | |
| | | DoPOR (POR) | 14h | |
| | | WDT time-out (PUC) | 16h | |
| | | WDT key violation (PUC) | 18h | |
| | | KEYV flash key violation (PUC) | 1Ah | |
| | | Reserved | 1Ch | |
| | | Peripheral area fetch (PUC) | 1Eh | |
| | | PMM key violation (PUC) | 20h | |
| Reserved | 22h to 3Eh | Lowest | | |
| SYSSNIV, System NMI | 019Ch | No interrupt pending | 00h | |
| | | SVMLIFG | 02h | Highest |
| | | SVMHIFG | 04h | |
| | | DLYLIFG | 06h | |
| | | DLYHIFG | 08h | |
| | | VMAIFG | 0Ah | |
| | | JMBINIFG | 0Ch | |
| | | JMBOUTIFG | 0Eh | |
| | | VLRLIFG | 10h | |
| | | VLRHIFG | 12h | |
| | | Reserved | 14h to 1Eh | Lowest |
| | | SYSUNIV, User NMI | 019Ah | No interrupt pending |
| NMIIFG | 02h | | | Highest |
| OFIFG | 04h | | | |
| ACCVIFG | 06h | | | |
| AUXSWGIFG | 08h | | | |
| Reserved | 0Ah to 1Eh | | | Lowest |

6.11.8 Watchdog Timer (WDT_A) [\(Link to User's Guide\)](#)

The primary function of the WDT_A is to perform a controlled system restart after a software problem occurs. If the selected time interval expires, a system reset is generated. If the watchdog function is not needed in an application, the timer can be configured as an interval timer and can generate interrupts at selected time intervals.

6.11.9 DMA Controller ([Link to User's Guide](#))

The DMA controller allows movement of data from one memory address to another without CPU intervention. For example, the DMA controller can be used to move data from the ADC10_A conversion memory to RAM. Using the DMA controller can increase the throughput of peripheral modules. The DMA controller reduces system power consumption by allowing the CPU to remain in sleep mode, without having to awaken to move data to or from a peripheral. [Table 6-14](#) lists the available DMA triggers.

Table 6-14. DMA Trigger Assignments⁽¹⁾

| TRIGGER | CHANNEL | | |
|---------|---------------|---------------|---------------|
| | 0 | 1 | 2 |
| 0 | DMAREQ | DMAREQ | DMAREQ |
| 1 | TA0CCR0 CCIFG | TA0CCR0 CCIFG | TA0CCR0 CCIFG |
| 2 | TA0CCR2 CCIFG | TA0CCR2 CCIFG | TA0CCR2 CCIFG |
| 3 | TA1CCR0 CCIFG | TA1CCR0 CCIFG | TA1CCR0 CCIFG |
| 4 | Reserved | Reserved | Reserved |
| 5 | TA2CCR0 CCIFG | TA2CCR0 CCIFG | TA2CCR0 CCIFG |
| 6 | Reserved | Reserved | Reserved |
| 7 | TA3CCR0 CCIFG | TA3CCR0 CCIFG | TA3CCR0 CCIFG |
| 8 | Reserved | Reserved | Reserved |
| 9 | Reserved | Reserved | Reserved |
| 10 | Reserved | Reserved | Reserved |
| 11 | Reserved | Reserved | Reserved |
| 12 | Reserved | Reserved | Reserved |
| 13 | SD24IFG | SD24IFG | SD24IFG |
| 14 | Reserved | Reserved | Reserved |
| 15 | Reserved | Reserved | Reserved |
| 16 | UCA0RXIFG | UCA0RXIFG | UCA0RXIFG |
| 17 | UCA0TXIFG | UCA0TXIFG | UCA0TXIFG |
| 18 | UCA1RXIFG | UCA1RXIFG | UCA1RXIFG |
| 19 | UCA1TXIFG | UCA1TXIFG | UCA1TXIFG |
| 20 | UCA2RXIFG | UCA2RXIFG | UCA2RXIFG |
| 21 | UCA2TXIFG | UCA2TXIFG | UCA2TXIFG |
| 22 | UCB0RXIFG0 | UCB0RXIFG0 | UCB0RXIFG0 |
| 23 | UCB0TXIFG0 | UCB0TXIFG0 | UCB0TXIFG0 |
| 24 | ADC10IFG0 | ADC10IFG0 | ADC10IFG0 |
| 25 | UCA3RXIFG | UCA3RXIFG | UCA3RXIFG |
| 26 | UCA3TXIFG | UCA3TXIFG | UCA3TXIFG |
| 27 | UCB1RXIFG0 | UCB1RXIFG0 | UCB1RXIFG0 |
| 28 | UCB1TXIFG0 | UCB1TXIFG0 | UCB1TXIFG0 |
| 29 | MPY ready | MPY ready | MPY ready |
| 30 | DMA2IFG | DMA0IFG | DMA1IFG |
| 31 | Reserved | Reserved | Reserved |

(1) Reserved DMA triggers may be used by other devices in the family. Reserved DMA triggers do not cause any DMA trigger event when selected.

6.11.10 CRC16 ([Link to User's Guide](#))

The CRC16 module produces a signature based on a sequence of entered data values and can be used for data checking purposes. The CRC16 module signature is based on the CRC-CCITT standard.

6.11.11 Hardware Multiplier ([Link to User's Guide](#))

The multiplication operation is supported by a dedicated peripheral module. The module performs operations with 32-, 24-, 16-, and 8-bit operands. The module supports signed and unsigned multiplication as well as signed and unsigned multiply-and-accumulate operations.

6.11.12 AES128 Accelerator ([Link to User's Guide](#))

The AES accelerator module performs encryption and decryption of 128-bit data with 128-bit keys according to the Advanced Encryption Standard (AES) (FIPS PUB 197) in hardware.

6.11.13 Enhanced Universal Serial Communication Interface (eUSCI) ([Links to User's Guide: UART Mode, SPI Mode, I²C Mode](#))

The eUSCI module is used for serial data communication. The eUSCI module supports synchronous communication protocols such as SPI (3- or 4-pin) and I²C, and asynchronous communication protocols such as UART, enhanced UART with automatic baud-rate detection, and IrDA.

The eUSCI_An module provides support for SPI (3- or 4-pin), UART, enhanced UART, and IrDA.

The eUSCI_Bn module provides support for SPI (3- or 4-pin) and I²C.

Four eUSCI_A and two eUSCI_B module are implemented in the MSP430F67xxA MCUs.

6.11.14 ADC10_A ([Link to User's Guide](#))

The ADC10_A module supports fast, 10-bit analog-to-digital conversions. The module implements a 10-bit SAR core, sample select control, reference generator and a conversion results buffer. A window comparator with a lower and upper limit allows CPU independent result monitoring with three window comparator interrupt flags.

6.11.15 SD24_B ([Link to User's Guide](#))

The SD24_B module integrates up to seven independent 24-bit sigma-delta ADCs. Each converter is designed with a fully differential analog input pair and programmable gain amplifier input stage. Also the converters are based on second-order oversampling sigma-delta modulators and digital decimation filters. The decimation filters are comb filters with selectable oversampling ratios of up to 1024.

6.11.16 TA0 [\(Link to User's Guide\)](#)

TA0 is a 16-bit timer/counter (Timer_A type) with three capture/compare registers. TA0 can support multiple capture/compares, PWM outputs, and interval timing (see [Table 6-15](#)). TA0 also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each of the capture/compare registers.

Table 6-15. TA0 Signal Connections

| DEVICE INPUT SIGNAL | MODULE INPUT NAME | MODULE BLOCK | MODULE OUTPUT SIGNAL | DEVICE OUTPUT SIGNAL |
|---------------------|-------------------|--------------|----------------------|----------------------|
| PM_TACLK | TACLK | Timer | NA | NA |
| ACLK (internal) | ACLK | | | |
| SMCLK (internal) | SMCLK | | | |
| PM_TACLK | INCLK | CCR0 | TA0 | PM_TA0.0 |
| PM_TA0.0 | CCI0A | | | |
| CBOU (internal) | CCI0B | | | |
| DVSS | GND | | | |
| DVCC | VCC | CCR1 | TA1 | PM_TA0.1 |
| PM_TA0.1 | CCI1A | | | |
| ACLK (internal) | CCI1B | | | |
| DVSS | GND | | | |
| DVCC | VCC | CCR2 | TA2 | PM_TA0.2 |
| PM_TA0.2 | CCI2A | | | |
| DVSS | CCI2B | | | |
| DVSS | GND | | | |
| DVCC | VCC | | | |

6.11.17 TA1 [\(Link to User's Guide\)](#)

TA1 is a 16-bit timer/counter (Timer_A type) with two capture/compare registers (see [Table 6-16](#)). TA1 can support multiple capture/compares, PWM outputs, and interval timing. TA1 also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each of the capture/compare registers.

Table 6-16. TA1 Signal Connections

| DEVICE INPUT SIGNAL | MODULE INPUT NAME | MODULE BLOCK | MODULE OUTPUT SIGNAL | DEVICE OUTPUT SIGNAL |
|---------------------|-------------------|--------------|----------------------|----------------------|
| PM_TACLK | TACLK | Timer | NA | NA |
| ACLK (internal) | ACLK | | | |
| SMCLK (internal) | SMCLK | | | |
| PM_TACLK | INCLK | CCR0 | TA0 | PM_TA1.0 |
| PM_TA1.0 | CCI0A | | | |
| CBOU (internal) | CCI0B | | | |
| DVSS | GND | | | |
| DVCC | VCC | CCR1 | TA1 | PM_TA1.1 |
| PM_TA1.1 | CCI1A | | | |
| ACLK (internal) | CCI1B | | | |
| DVSS | GND | | | |
| DVCC | VCC | | | |

6.11.18 TA2 [\(Link to User's Guide\)](#)

TA2 is a 16-bit timer/counter (Timer_A type) with two capture/compare registers. TA2 can support multiple capture/compares, PWM outputs, and interval timing (see [Table 6-17](#)). TA2 also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each of the capture/compare registers.

Table 6-17. TA2 Signal Connections

| DEVICE INPUT SIGNAL | MODULE INPUT NAME | MODULE BLOCK | MODULE OUTPUT SIGNAL | DEVICE OUTPUT SIGNAL |
|---------------------|-------------------|--------------|----------------------|--|
| PM_TACLK | TACLK | Timer | NA | NA |
| ACLK (internal) | ACLK | | | |
| SMCLK (internal) | SMCLK | | | |
| PM_TACLK | INCLK | CCR0 | TA0 | PM_TA2.0 |
| PM_TA2.0 | CCI0A | | | |
| CBOU (internal) | CCI0B | | | |
| DVSS | GND | | | |
| DVCC | VCC | CCR1 | TA1 | PM_TA2.1 |
| PM_TA2.1 | CCI1A | | | |
| ACLK (internal) | CCI1B | | | |
| DVSS | GND | | | |
| DVCC | VCC | | | SD24_B (internal) SD24CHx.SD24SCSx = 010b |

6.11.19 TA3 [\(Link to User's Guide\)](#)

TA3 is a 16-bit timer/counter (Timer_A type) with two capture/compare registers. TA3 can support multiple capture/compares, PWM outputs, and interval timing (see [Table 6-18](#)). TA3 also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each of the capture/compare registers.

Table 6-18. TA3 Signal Connections

| DEVICE INPUT SIGNAL | MODULE INPUT NAME | MODULE BLOCK | MODULE OUTPUT SIGNAL | DEVICE OUTPUT SIGNAL |
|---------------------|-------------------|--------------|----------------------|--|
| PM_TACLK | TACLK | Timer | NA | |
| ACLK (internal) | ACLK | | | |
| SMCLK (internal) | SMCLK | | | |
| PM_TACLK | INCLK | CCR0 | TA0 | PM_TA3.0 |
| PM_TA3.0 | CCI0A | | | |
| CBOU (internal) | CCI0B | | | |
| DVSS | GND | | | |
| DVCC | VCC | CCR1 | TA1 | PM_TA3.1 |
| PM_TA3.1 | CCI1A | | | |
| ACLK (internal) | CCI1B | | | |
| DVSS | GND | | | |
| DVCC | VCC | | | SD24_B (internal) SD24CHx.SD24SCSx = 011b |

6.11.20 SD24_B Triggers

Table 6-19 lists the input trigger connections to SD24_B converters from Timer_A modules and output trigger pulse connection from SD24_B to ADC10_A.

Table 6-19. SD24_B Input/Output Trigger Connections

| DEVICE INPUT SIGNAL | MODULE INPUT SIGNAL | MODULE BLOCK | MODULE OUTPUT SIGNAL | DEVICE OUTPUT SIGNAL |
|---------------------|-----------------------------------|--------------|----------------------|--|
| TA0.1 (internal) | SD24_B SD24CHx.SD24SCSx = 001b | SD24_B | Trigger Pulse | ADC10_A (internal) ADC10SHSx = 011b |
| TA2.1 (internal) | SD24_B SD24CHx.SD24SCSx = 010b | | | |
| TA3.1 (internal) | SD24_B SD24CHx.SD24SCSx = 011b | | | |

6.11.21 ADC10_A Triggers

Table 6-20 lists the input trigger connections to ADC10_A from Timer_A modules and SD24_B.

Table 6-20. ADC10_A Input Trigger Connections

| DEVICE INPUT SIGNAL | MODULE INPUT SIGNAL | MODULE BLOCK |
|------------------------------------|-----------------------------|--------------|
| TA0.1 (internal) | ADC10_A ADC10SHSx = 001b | ADC10_A |
| TA3.0 (internal) | ADC10_A ADC10SHSx = 010b | |
| SD24_B trigger pulse (internal) | ADC10_A ADC10SHSx = 011b | |

6.11.22 Real-Time Clock (RTC_C) [\(Link to User's Guide\)](#)

The RTC_C module can be configured for calendar mode providing seconds, hours, day of week, day of month, month, and year. The RTC_C control and configuration registers are password protected to ensure clock integrity against runaway code. Calendar mode integrates an internal calendar that compensates for months with less than 31 days and includes leap year correction. The RTC_C also supports flexible alarm functions, offset calibration, temperature compensation, and time capture on two external events. The RTC_C on this device operates on dedicated AUXVCC3 supply and supports operation in LPM3.5.

6.11.23 Reference (REF) Module Voltage Reference [\(Link to User's Guide\)](#)

The REF module generates all of the critical reference voltages that can be used by the various analog peripherals in the device. The analog peripherals include the ADC10_A, LCD_C, and SD24_B modules.

6.11.24 LCD_C [\(Link to User's Guide\)](#)

The LCD_C driver generates the segment and common signals required to drive a liquid crystal display (LCD). The LCD_C controller has dedicated data memories to hold segment drive information. Common and segment signals are generated as defined by the mode. Static, 2-mux, 3-mux, 4-mux, up to 8-mux LCDs are supported. The module can provide a LCD voltage independent of the supply voltage with its integrated charge pump. It is possible to control the level of the LCD voltage, and thus contrast, by software. The module also provides an automatic blinking capability for individual segments in static, 2-mux, 3-mux, and 4-mux modes.

6.11.25 Comparator_B [\(Link to User's Guide\)](#)

The primary function of the Comparator_B module is to support precision slope analog-to-digital conversions, battery voltage supervision, and monitoring of external analog signals.

6.11.26 Embedded Emulation Module (EEM) [\(Link to User's Guide\)](#)

The EEM supports real-time in-system debugging. The L version of the EEM has the following features:

- Eight hardware triggers or breakpoints on memory access
- Two hardware triggers or breakpoints on CPU register write access
- Up to 10 hardware triggers that can be combined to form complex triggers or breakpoints
- Two cycle counters
- Sequencer
- State storage
- Clock control on module level

6.11.27 Peripheral File Map

Table 6-21 shows the base address for the registers of each supported peripheral. Table 6-22 through Table 6-64 show the offset addresses for each register. For complete description of these registers, see the [MSP430x5xx and MSP430x6xx Family User's Guide](#).

Table 6-21. Peripherals

| MODULE NAME | BASE ADDRESS | OFFSET ADDRESS RANGE |
|--|--------------|----------------------|
| Special Functions (see Table 6-22) | 0100h | 000h to 01Fh |
| PMM (see Table 6-23) | 0120h | 000h to 01Fh |
| Flash Control (see Table 6-24) | 0140h | 000h to 00Fh |
| CRC16 (see Table 6-25) | 0150h | 000h to 007h |
| RAM Control (see Table 6-26) | 0158h | 000h to 001h |
| Watchdog (see Table 6-27) | 015Ch | 000h to 001h |
| UCS (see Table 6-28) | 0160h | 000h to 01Fh |
| SYS (see Table 6-29) | 0180h | 000h to 01Fh |
| Shared Reference (see Table 6-30) | 01B0h | 000h to 001h |
| Port Mapping Control (see Table 6-31) | 01C0h | 000h to 007h |
| Port Mapping Port P2 (see Table 6-32) | 01D0h | 000h to 007h |
| Port Mapping Port P3 (see Table 6-33) | 01D8h | 000h to 007h |
| Port Mapping Port P4 (see Table 6-34) | 01E0h | 000h to 007h |
| Port P1, P2 (see Table 6-35) | 0200h | 000h to 01Fh |
| Port P3, P4 (see Table 6-36) | 0220h | 000h to 00Bh |
| Port P5, P6 (see Table 6-37) | 0240h | 000h to 00Bh |
| Port P7, P8 (see Table 6-38) | 0260h | 000h to 00Bh |
| Port P9, P10 (see Table 6-39) (Ports P9 and P10 not available in PZ package) | 0280h | 000h to 00Bh |
| Port P11 (see Table 6-40) (Port P11 not available in PZ package) | 02A0h | 000h to 00Bh |
| Port PJ (see Table 6-41) | 0320h | 000h to 01Fh |
| Timer TA0 (see Table 6-42) | 0340h | 000h to 03Fh |
| Timer TA1 (see Table 6-43) | 0380h | 000h to 03Fh |
| Timer TA2 (see Table 6-44) | 0400h | 000h to 03Fh |
| Timer TA3 (see Table 6-45) | 0440h | 000h to 03Fh |
| Backup Memory (see Table 6-46) | 0480h | 000h to 00Fh |
| 32-Bit Hardware Multiplier (see Table 6-48) | 04C0h | 000h to 02Fh |
| DMA General Control (see Table 6-49) | 0500h | 000h to 00Fh |
| DMA Channel 0 (see Table 6-50) | 0500h | 010h to 01Fh |
| DMA Channel 1 (see Table 6-51) | 0500h | 020h to 02Fh |

Table 6-21. Peripherals (continued)

| MODULE NAME | BASE ADDRESS | OFFSET ADDRESS RANGE |
|--|--------------|----------------------|
| DMA Channel 2 (see Table 6-52) | 0500h | 030h to 03Fh |
| RTC_C (see Table 6-47) | 0C80h | 000h to 03Fh |
| eUSCI_A0 (see Table 6-53) | 05C0h | 000h to 01Fh |
| eUSCI_A1 (see Table 6-54) | 05E0h | 000h to 01Fh |
| eUSCI_A2 (see Table 6-55) | 0600h | 000h to 01Fh |
| eUSCI_A3 (see Table 6-56) | 0620h | 000h to 01Fh |
| eUSCI_B0 (see Table 6-57) | 0640h | 000h to 02Fh |
| eUSCI_B1 (see Table 6-58) | 0680h | 000h to 02Fh |
| ADC10_A (see Table 6-59) | 0740h | 000h to 01Fh |
| SD24_B (see Table 6-60) | 0800h | 000h to 06Fh |
| Comparator_B (see Table 6-61) | 08C0h | 000h to 00Fh |
| AES Accelerator (see Table 6-62) | 09C0h | 000h to 00Fh |
| Auxiliary Supply (see Table 6-63) | 09E0h | 000h to 01Fh |
| LCD_C (see Table 6-64) | 0A00h | 000h to 05Fh |

Table 6-22. Special Function Registers (Base Address: 0100h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|-----------------------|----------|--------|
| SFR interrupt enable | SFRIE1 | 00h |
| SFR interrupt flag | SFRIFG1 | 02h |
| SFR reset pin control | SFRRPCR | 04h |

Table 6-23. PMM Registers (Base Address: 0120h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|----------------------------|----------|--------|
| PMM control 0 | PMMCTL0 | 00h |
| PMM control 1 | PMMCTL1 | 02h |
| SVS high-side control | SVSMHCTL | 04h |
| SVS low-side control | SVSMLCTL | 06h |
| PMM interrupt flags | PMMIFG | 0Ch |
| PMM interrupt enable | PMMIE | 0Eh |
| PMM power mode 5 control 0 | PM5CTL0 | 10h |

Table 6-24. Flash Control Registers (Base Address: 0140h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|----------------------|----------|--------|
| Flash control 1 | FCTL1 | 00h |
| Flash control 3 | FCTL3 | 04h |
| Flash control 4 | FCTL4 | 06h |

Table 6-25. CRC16 Registers (Base Address: 0150h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|----------------------|-----------|--------|
| CRC data input | CRC16DI | 00h |
| CRC result | CRCINIRES | 04h |

Table 6-26. RAM Control Registers (Base Address: 0158h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|----------------------|----------|--------|
| RAM control 0 | RCCTL0 | 00h |

Table 6-27. Watchdog Registers (Base Address: 015Ch)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|------------------------|----------|--------|
| Watchdog timer control | WDTCTL | 00h |

Table 6-28. UCS Registers (Base Address: 0160h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|----------------------|----------|--------|
| UCS control 0 | UCSCTL0 | 00h |
| UCS control 1 | UCSCTL1 | 02h |
| UCS control 2 | UCSCTL2 | 04h |
| UCS control 3 | UCSCTL3 | 06h |
| UCS control 4 | UCSCTL4 | 08h |
| UCS control 5 | UCSCTL5 | 0Ah |
| UCS control 6 | UCSCTL6 | 0Ch |
| UCS control 7 | UCSCTL7 | 0Eh |
| UCS control 8 | UCSCTL8 | 10h |

Table 6-29. SYS Registers (Base Address: 0180h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|-------------------------------|-----------|--------|
| System control | SYSCCTL | 00h |
| Bootloader configuration area | SYSBSLC | 02h |
| JTAG mailbox control | SYSJMBC | 06h |
| JTAG mailbox input 0 | SYSJMBI0 | 08h |
| JTAG mailbox input 1 | SYSJMBI1 | 0Ah |
| JTAG mailbox output 0 | SYSJMBO0 | 0Ch |
| JTAG mailbox output 1 | SYSJMBO1 | 0Eh |
| Bus Error vector generator | SYSBERRIV | 18h |
| User NMI vector generator | SYSUNIV | 1Ah |
| System NMI vector generator | SYSSNIV | 1Ch |
| Reset vector generator | SYSRSTIV | 1Eh |

Table 6-30. Shared Reference Registers (Base Address: 01B0h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|--------------------------|----------|--------|
| Shared reference control | REFCTL | 00h |

Table 6-31. Port Mapping Controller (Base Address: 01C0h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|-----------------------|----------|--------|
| Port mapping password | PMAPPWD | 00h |
| Port mapping control | PMAPCTL | 02h |

Table 6-32. Port Mapping for Port P2 (Base Address: 01D0h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|----------------------|----------|--------|
| Port P2.0 mapping | P2MAP0 | 00h |
| Port P2.1 mapping | P2MAP1 | 01h |
| Port P2.2 mapping | P2MAP2 | 02h |
| Port P2.3 mapping | P2MAP3 | 03h |
| Port P2.4 mapping | P2MAP4 | 04h |
| Port P2.5 mapping | P2MAP5 | 05h |
| Port P2.6 mapping | P2MAP6 | 06h |
| Port P2.7 mapping | P2MAP7 | 07h |

Table 6-33. Port Mapping for Port P3 (Base Address: 01D8h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|----------------------|----------|--------|
| Port P3.0 mapping | P3MAP0 | 00h |
| Port P3.1 mapping | P3MAP1 | 01h |
| Port P3.2 mapping | P3MAP2 | 02h |
| Port P3.3 mapping | P3MAP3 | 03h |
| Port P3.4 mapping | P3MAP4 | 04h |
| Port P3.5 mapping | P3MAP5 | 05h |
| Port P3.6 mapping | P3MAP6 | 06h |
| Port P3.7 mapping | P3MAP7 | 07h |

Table 6-34. Port Mapping for Port P4 (Base Address: 01E0h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|----------------------|----------|--------|
| Port P4.0 mapping | P4MAP0 | 00h |
| Port P4.1 mapping | P4MAP1 | 01h |
| Port P4.2 mapping | P4MAP2 | 02h |
| Port P4.3 mapping | P4MAP3 | 03h |
| Port P4.4 mapping | P4MAP4 | 04h |
| Port P4.5 mapping | P4MAP5 | 05h |
| Port P4.6 mapping | P4MAP6 | 06h |
| Port P4.7 mapping | P4MAP7 | 07h |

Table 6-35. Port P1, P2 Registers (Base Address: 0200h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|------------------------------------|----------|--------|
| Port P1 input | P1IN | 00h |
| Port P1 output | P1OUT | 02h |
| Port P1 direction | P1DIR | 04h |
| Port P1 resistor enable | P1REN | 06h |
| Port P1 drive strength | P1DS | 08h |
| Port P1 selection 0 | P1SEL0 | 0Ah |
| Port P1 selection 1 | P1SEL1 | 0Ch |
| Port P1 interrupt vector word | P1IV | 0Eh |
| Port P1 interrupt edge select | P1IES | 18h |
| Port P1 interrupt enable | P1IE | 1Ah |
| Port P1 interrupt flag | P1IFG | 1Ch |
| Port P2 input | P2IN | 01h |
| Port P2 output | P2OUT | 03h |
| Port P2 direction | P2DIR | 05h |
| Port P2 resistor enable | P2REN | 07h |
| Port P2 drive strength | P2DS | 09h |
| Port P2 selection 0 | P2SEL0 | 0Bh |
| Port P2 selection 1 ⁽¹⁾ | P2SEL1 | 0Dh |
| Port P2 interrupt vector word | P2IV | 1Eh |
| Port P2 interrupt edge select | P2IES | 19h |
| Port P2 interrupt enable | P2IE | 1Bh |
| Port P2 interrupt flag | P2IFG | 1Dh |

(1) P2SEL1 is an empty control register to be consistent with P1SEL1 in 16-bit access.

Table 6-36. Port P3, P4 Registers (Base Address: 0220h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|-------------------------|----------|--------|
| Port P3 input | P3IN | 00h |
| Port P3 output | P3OUT | 02h |
| Port P3 direction | P3DIR | 04h |
| Port P3 resistor enable | P3REN | 06h |
| Port P3 drive strength | P3DS | 08h |
| Port P3 selection 0 | P3SEL0 | 0Ah |
| Port P4 input | P4IN | 01h |
| Port P4 output | P4OUT | 03h |
| Port P4 direction | P4DIR | 05h |
| Port P4 resistor enable | P4REN | 07h |
| Port P4 drive strength | P4DS | 09h |
| Port P4 selection 0 | P4SEL0 | 0Bh |

Table 6-37. Port P5, P6 Registers (Base Address: 0240h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|------------------------------------|----------|--------|
| Port P5 input | P5IN | 00h |
| Port P5 output | P5OUT | 02h |
| Port P5 direction | P5DIR | 04h |
| Port P5 resistor enable | P5REN | 06h |
| Port P5 drive strength | P5DS | 08h |
| Port P5 selection 0 | P5SEL0 | 0Ah |
| Port P5 selection 1 | P5SEL1 | 0Ch |
| Port P6 input | P6IN | 01h |
| Port P6 output | P6OUT | 03h |
| Port P6 direction | P6DIR | 05h |
| Port P6 resistor enable | P6REN | 07h |
| Port P6 drive strength | P6DS | 09h |
| Port P6 selection 0 | P6SEL0 | 0Bh |
| Port P6 selection 1 ⁽¹⁾ | P6SEL1 | 0Dh |

(1) P6SEL1 is an empty control register to be consistent with P5SEL1 in 16-bit access.

Table 6-38. Port P7, P8 Registers (Base Address: 0260h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|-------------------------|----------|--------|
| Port P7 input | P7IN | 00h |
| Port P7 output | P7OUT | 02h |
| Port P7 direction | P7DIR | 04h |
| Port P7 resistor enable | P7REN | 06h |
| Port P7 drive strength | P7DS | 08h |
| Port P7 selection 0 | P7SEL0 | 0Ah |
| Port P8 input | P8IN | 01h |
| Port P8 output | P8OUT | 03h |
| Port P8 direction | P8DIR | 05h |
| Port P8 resistor enable | P8REN | 07h |
| Port P8 drive strength | P8DS | 09h |
| Port P8 selection 0 | P8SEL0 | 0Bh |

Table 6-39. Port P9, P10 Registers (Base Address: 0280h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|--------------------------|----------|--------|
| Port P9 input | P9IN | 00h |
| Port P9 output | P9OUT | 02h |
| Port P9 direction | P9DIR | 04h |
| Port P9 resistor enable | P9REN | 06h |
| Port P9 drive strength | P9DS | 08h |
| Port P9 selection 0 | P9SELO | 0Ah |
| Port P10 input | P10IN | 01h |
| Port P10 output | P10OUT | 03h |
| Port P10 direction | P10DIR | 05h |
| Port P10 resistor enable | P10REN | 07h |
| Port P10 drive strength | P10DS | 09h |
| Port P10 selection 0 | P10SELO | 0Bh |

Table 6-40. Port 11 Registers (Base Address: 02A0h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|--------------------------|----------|--------|
| Port P11 input | P11IN | 00h |
| Port P11 output | P11OUT | 02h |
| Port P11 direction | P11DIR | 04h |
| Port P11 resistor enable | P11REN | 06h |
| Port P11 drive strength | P11DS | 08h |
| Port P11 selection 0 | P11SELO | 0Ah |

Table 6-41. Port J Registers (Base Address: 0320h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|-------------------------|----------|--------|
| Port PJ input | PJIN | 00h |
| Port PJ output | PJOUT | 02h |
| Port PJ direction | PJDIR | 04h |
| Port PJ resistor enable | PJREN | 06h |
| Port PJ drive strength | PJDS | 08h |
| Port PJ selection | PJSEL | 0Ah |

Table 6-42. TA0 Registers (Base Address: 0340h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|---------------------------|----------|--------|
| TA0 control | TAOCTL | 00h |
| Capture/compare control 0 | TAOCTL0 | 02h |
| Capture/compare control 1 | TAOCTL1 | 04h |
| Capture/compare control 2 | TAOCTL2 | 06h |
| TA0 counter | TAOR | 10h |
| Capture/compare 0 | TAOCCR0 | 12h |
| Capture/compare 1 | TAOCCR1 | 14h |
| Capture/compare 2 | TAOCCR2 | 16h |
| TA0 expansion 0 | TAOEX0 | 20h |
| TA0 interrupt vector | TAOIV | 2Eh |

Table 6-43. TA1 Registers (Base Address: 0380h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|---------------------------|----------|--------|
| TA1 control | TA1CTL | 00h |
| Capture/compare control 0 | TA1CCTL0 | 02h |
| Capture/compare control 1 | TA1CCTL1 | 04h |
| TA1 counter | TA1R | 10h |
| Capture/compare 0 | TA1CCR0 | 12h |
| Capture/compare 1 | TA1CCR1 | 14h |
| TA1 expansion 0 | TA1EX0 | 20h |
| TA1 interrupt vector | TA1IV | 2Eh |

Table 6-44. TA2 Registers (Base Address: 0400h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|---------------------------|----------|--------|
| TA2 control | TA2CTL | 00h |
| Capture/compare control 0 | TA2CCTL0 | 02h |
| Capture/compare control 1 | TA2CCTL1 | 04h |
| TA2 counter | TA2R | 10h |
| Capture/compare 0 | TA2CCR0 | 12h |
| Capture/compare 1 | TA2CCR1 | 14h |
| TA2 expansion 0 | TA2EX0 | 20h |
| TA2 interrupt vector | TA2IV | 2Eh |

Table 6-45. TA3 Registers (Base Address: 0440h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|---------------------------|----------|--------|
| TA3 control | TA3CTL | 00h |
| Capture/compare control 0 | TA3CCTL0 | 02h |
| Capture/compare control 1 | TA3CCTL1 | 04h |
| TA3 counter | TA3R | 10h |
| Capture/compare 0 | TA3CCR0 | 12h |
| Capture/compare 1 | TA3CCR1 | 14h |
| TA3 expansion 0 | TA3EX0 | 20h |
| TA3 interrupt vector | TA3IV | 2Eh |

Table 6-46. Backup Memory Registers (Base Address: 0480h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|----------------------|----------|--------|
| Backup memory 0 | BAKMEM0 | 00h |
| Backup memory 1 | BAKMEM1 | 02h |
| Backup memory 2 | BAKMEM2 | 04h |
| Backup memory 3 | BAKMEM3 | 06h |

Table 6-47. RTC_C Registers (Base Address: 0C80h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|--------------------------------------|-------------|--------|
| RTC control 0 | RTCCTL0 | 00h |
| RTC password | RTCPWD | 01h |
| RTC control 1 | RTCCTL1 | 02h |
| RTC control 3 | RTCCTL3 | 03h |
| RTC offset calibration | RTCOCAL | 04h |
| RTC temperature compensation | RTCTCMP | 06h |
| RTC prescaler 0 control | RTCP0CTL | 08h |
| RTC prescaler 1 control | RTCP1CTL | 0Ah |
| RTC prescaler 0 | RTCP0 | 0Ch |
| RTC prescaler 1 | RTCP1 | 0Dh |
| RTC interrupt vector word | RTCIV | 0Eh |
| RTC seconds | RTCSEC | 10h |
| RTC minutes | RTCMIN | 11h |
| RTC hours | RTCHOUR | 12h |
| RTC day of week | RTCDOW | 13h |
| RTC days | RTCDAY | 14h |
| RTC month | RTCMON | 15h |
| RTC year | RTCYEAR | 16h |
| RTC alarm minutes | RTCAMIN | 18h |
| RTC alarm hours | RTCAHOUR | 19h |
| RTC alarm day of week | RTCADOW | 1Ah |
| RTC alarm days | RTCADAY | 1Bh |
| Binary-to-BCD conversion | BIN2BCD | 1Ch |
| BCD-to-binary conversion | BCD2BIN | 1Eh |
| Real-time clock time capture control | RTCTCCTL | 20h |
| Tamper detect pin 0 control | RTCCAP0CTL | 21h |
| Tamper detect pin 1 control | RTCCAP1CTL | 22h |
| RTC seconds backup 0 | RTCSECBAK0 | 30h |
| RTC minutes backup 0 | RTCMINBAK0 | 31h |
| RTC hours backup 0 | RTCHOURBAK0 | 32h |
| RTC days backup 0 | RTCDAYBAK0 | 33h |
| RTC month backup 0 | RTCMONBAK0 | 34h |
| RTC year backup 0 | RTCYEARBAK0 | 36h |
| RTC seconds backup 1 | RTCSECBAK1 | 38h |
| RTC minutes backup 1 | RTCMINBAK1 | 39h |
| RTC hours backup 1 | RTCHOURBAK1 | 3Ah |
| RTC days backup 1 | RTCDAYBAK1 | 3Bh |
| RTC month backup 1 | RTCMONBAK1 | 3Ch |
| RTC year backup 1 | RTCYEARBAK1 | 3Eh |

Table 6-48. 32-Bit Hardware Multiplier Registers (Base Address: 04C0h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|---|-----------|--------|
| 16-bit operand 1 – multiply | MPY | 00h |
| 16-bit operand 1 – signed multiply | MPYS | 02h |
| 16-bit operand 1 – multiply accumulate | MAC | 04h |
| 16-bit operand 1 – signed multiply accumulate | MACS | 06h |
| 16-bit operand 2 | OP2 | 08h |
| 16 × 16 result low word | RESLO | 0Ah |
| 16 × 16 result high word | RESHI | 0Ch |
| 16 × 16 sum extension | SUMEXT | 0Eh |
| 32-bit operand 1 – multiply low word | MPY32L | 10h |
| 32-bit operand 1 – multiply high word | MPY32H | 12h |
| 32-bit operand 1 – signed multiply low word | MPYS32L | 14h |
| 32-bit operand 1 – signed multiply high word | MPYS32H | 16h |
| 32-bit operand 1 – multiply accumulate low word | MAC32L | 18h |
| 32-bit operand 1 – multiply accumulate high word | MAC32H | 1Ah |
| 32-bit operand 1 – signed multiply accumulate low word | MACS32L | 1Ch |
| 32-bit operand 1 – signed multiply accumulate high word | MACS32H | 1Eh |
| 32-bit operand 2 – low word | OP2L | 20h |
| 32-bit operand 2 – high word | OP2H | 22h |
| 32 × 32 result 0 – least significant word | RES0 | 24h |
| 32 × 32 result 1 | RES1 | 26h |
| 32 × 32 result 2 | RES2 | 28h |
| 32 × 32 result 3 – most significant word | RES3 | 2Ah |
| MPY32 control 0 | MPY32CTL0 | 2Ch |

Table 6-49. DMA General Control Registers (Base Address: 0500h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|----------------------|----------|--------|
| DMA module control 0 | DMACTL0 | 00h |
| DMA module control 1 | DMACTL1 | 02h |
| DMA module control 2 | DMACTL2 | 04h |
| DMA module control 3 | DMACTL3 | 06h |
| DMA module control 4 | DMACTL4 | 08h |
| DMA interrupt vector | DMAIV | 0Eh |

Table 6-50. DMA Channel 0 Registers (Base Address: 0500h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|--|----------|--------|
| DMA channel 0 control | DMA0CTL | 10h |
| DMA channel 0 source address low | DMA0SAL | 12h |
| DMA channel 0 source address high | DMA0SAH | 14h |
| DMA channel 0 destination address low | DMA0DAL | 16h |
| DMA channel 0 destination address high | DMA0DAH | 18h |
| DMA channel 0 transfer size | DMA0SZ | 1Ah |

Table 6-51. DMA Channel 1 Registers (Base Address: 0500h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|--|----------|--------|
| DMA channel 1 control | DMA1CTL | 20h |
| DMA channel 1 source address low | DMA1SAL | 22h |
| DMA channel 1 source address high | DMA1SAH | 24h |
| DMA channel 1 destination address low | DMA1DAL | 26h |
| DMA channel 1 destination address high | DMA1DAH | 28h |
| DMA channel 1 transfer size | DMA1SZ | 2Ah |

Table 6-52. DMA Channel 2 Registers (Base Address: 0500h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|--|----------|--------|
| DMA channel 2 control | DMA2CTL | 30h |
| DMA channel 2 source address low | DMA2SAL | 32h |
| DMA channel 2 source address high | DMA2SAH | 34h |
| DMA channel 2 destination address low | DMA2DAL | 36h |
| DMA channel 2 destination address high | DMA2DAH | 38h |
| DMA channel 2 transfer size | DMA2SZ | 3Ah |

Table 6-53. eUSCI_A0 Registers (Base Address: 05C0h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|------------------------------|------------|--------|
| USCI_A control word 0 | UCA0CTLW0 | 00h |
| USCI_A control word 1 | UCA0CTLW1 | 02h |
| USCI_A baud rate 0 | UCA0BR0 | 06h |
| USCI_A baud rate 1 | UCA0BR1 | 07h |
| USCI_A modulation control | UCA0MCTLW | 08h |
| USCI_A status | UCA0STAT | 0Ah |
| USCI_A receive buffer | UCA0RXBUF | 0Ch |
| USCI_A transmit buffer | UCA0TXBUF | 0Eh |
| USCI_A LIN control | UCA0ABCTL | 10h |
| USCI_A IrDA transmit control | UCA0IRTCTL | 12h |
| USCI_A IrDA receive control | UCA0IRRCTL | 13h |
| USCI_A interrupt enable | UCA0IE | 1Ah |
| USCI_A interrupt flags | UCA0IFG | 1Ch |
| USCI_A interrupt vector word | UCA0IV | 1Eh |

Table 6-54. eUSCI_A1 Registers (Base Address:05E0h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|------------------------------|------------|--------|
| USCI_A control word 0 | UCA1CTLW0 | 00h |
| USCI_A control word 1 | UCA1CTLW1 | 02h |
| USCI_A baud rate 0 | UCA1BR0 | 06h |
| USCI_A baud rate 1 | UCA1BR1 | 07h |
| USCI_A modulation control | UCA1MCTLW | 08h |
| USCI_A status | UCA1STAT | 0Ah |
| USCI_A receive buffer | UCA1RXBUF | 0Ch |
| USCI_A transmit buffer | UCA1TXBUF | 0Eh |
| USCI_A LIN control | UCA1ABCTL | 10h |
| USCI_A IrDA transmit control | UCA1IRTCTL | 12h |
| USCI_A IrDA receive control | UCA1IRRCTL | 13h |
| USCI_A interrupt enable | UCA1IE | 1Ah |
| USCI_A interrupt flags | UCA1IFG | 1Ch |
| USCI_A interrupt vector word | UCA1IV | 1Eh |

Table 6-55. eUSCI_A2 Registers (Base Address:0600h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|------------------------------|------------|--------|
| USCI_A control word 0 | UCA2CTLW0 | 00h |
| USCI_A control word 1 | UCA2CTLW1 | 02h |
| USCI_A baud rate 0 | UCA2BR0 | 06h |
| USCI_A baud rate 1 | UCA2BR1 | 07h |
| USCI_A modulation control | UCA2MCTLW | 08h |
| USCI_A status | UCA2STAT | 0Ah |
| USCI_A receive buffer | UCA2RXBUF | 0Ch |
| USCI_A transmit buffer | UCA2TXBUF | 0Eh |
| USCI_A LIN control | UCA2ABCTL | 10h |
| USCI_A IrDA transmit control | UCA2IRTCTL | 12h |
| USCI_A IrDA receive control | UCA2IRRCTL | 13h |
| USCI_A interrupt enable | UCA2IE | 1Ah |
| USCI_A interrupt flags | UCA2IFG | 1Ch |
| USCI_A interrupt vector word | UCA2IV | 1Eh |

Table 6-56. eUSCI_A3 Registers (Base Address: 0620h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|------------------------------|------------|--------|
| USCI_A control word 0 | UCA3CTLW0 | 00h |
| USCI_A control word 1 | UCA3CTLW1 | 02h |
| USCI_A baud rate 0 | UCA3BR0 | 06h |
| USCI_A baud rate 1 | UCA3BR1 | 07h |
| USCI_A modulation control | UCA3MCTLW | 08h |
| USCI_A status | UCA3STAT | 0Ah |
| USCI_A receive buffer | UCA3RXBUF | 0Ch |
| USCI_A transmit buffer | UCA3TXBUF | 0Eh |
| USCI_A LIN control | UCA3ABCTL | 10h |
| USCI_A IrDA transmit control | UCA3IRTCTL | 12h |
| USCI_A IrDA receive control | UCA3IRRCTL | 13h |
| USCI_A interrupt enable | UCA3IE | 1Ah |
| USCI_A interrupt flags | UCA3IFG | 1Ch |
| USCI_A interrupt vector word | UCA3IV | 1Eh |

Table 6-57. eUSCI_B0 Registers (Base Address: 0640h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|-------------------------------|-------------|--------|
| USCI_B control word 0 | UCB0CTLW0 | 00h |
| USCI_B control word 1 | UCB0CTLW1 | 02h |
| USCI_B bit rate 0 | UCB0BR0 | 06h |
| USCI_B bit rate 1 | UCB0BR1 | 07h |
| USCI_B status word | UCB0STATW | 08h |
| USCI_B byte counter threshold | UCB0TBCNT | 0Ah |
| USCI_B receive buffer | UCB0RXBUF | 0Ch |
| USCI_B transmit buffer | UCB0TXBUF | 0Eh |
| USCI_B I2C own address 0 | UCB0I2COA0 | 14h |
| USCI_B I2C own address 1 | UCB0I2COA1 | 16h |
| USCI_B I2C own address 2 | UCB0I2COA2 | 18h |
| USCI_B I2C own address 3 | UCB0I2COA3 | 1Ah |
| USCI_B received address | UCB0ADDRX | 1Ch |
| USCI_B address mask | UCB0ADDMASK | 1Eh |
| USCI I2C slave address | UCB0I2CSA | 20h |
| USCI interrupt enable | UCB0IE | 2Ah |
| USCI interrupt flags | UCB0IFG | 2Ch |
| USCI interrupt vector word | UCB0IV | 2Eh |

Table 6-58. eUSCI_B1 Registers (Base Address: 0680h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|-------------------------------|-------------|--------|
| USCI_B control word 0 | UCB1CTLW0 | 00h |
| USCI_B control word 1 | UCB1CTLW1 | 02h |
| USCI_B bit rate 0 | UCB1BR0 | 06h |
| USCI_B bit rate 1 | UCB1BR1 | 07h |
| USCI_B status word | UCB1STATW | 08h |
| USCI_B byte counter threshold | UCB1TBCNT | 0Ah |
| USCI_B receive buffer | UCB1RXBUF | 0Ch |
| USCI_B transmit buffer | UCB1TXBUF | 0Eh |
| USCI_B I2C own address 0 | UCB1I2COA0 | 14h |
| USCI_B I2C own address 1 | UCB1I2COA1 | 16h |
| USCI_B I2C own address 2 | UCB1I2COA2 | 18h |
| USCI_B I2C own address 3 | UCB1I2COA3 | 1Ah |
| USCI_B received address | UCB1ADDRX | 1Ch |
| USCI_B address mask | UCB1ADDMASK | 1Eh |
| USCI I2C slave address | UCB1I2CSA | 20h |
| USCI interrupt enable | UCB1IE | 2Ah |
| USCI interrupt flags | UCB1IFG | 2Ch |
| USCI interrupt vector word | UCB1IV | 2Eh |

Table 6-59. ADC10_A Registers (Base Address: 0740h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|--|------------|--------|
| ADC10_A control 0 | ADC10CTL0 | 00h |
| ADC10_A control 1 | ADC10CTL1 | 02h |
| ADC10_A control 2 | ADC10CTL2 | 04h |
| ADC10_A window comparator low threshold | ADC10LO | 06h |
| ADC10_A window comparator high threshold | ADC10HI | 08h |
| ADC10_A memory control 0 | ADC10MCTL0 | 0Ah |
| ADC10_A conversion memory | ADC10MCTL0 | 12h |
| ADC10_A interrupt enable | ADC10IE | 1Ah |
| ADC10_A interrupt flags | ADC10IGH | 1Ch |
| ADC10_A interrupt vector word | ADC10IV | 1Eh |

Table 6-60. SD24_B Registers (Base Address: 0800h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|--|-------------|--------|
| SD24_B control 0 | SD24BCTL0 | 00h |
| SD24_B control 1 | SD24BCTL1 | 02h |
| SD24_B trigger control | SD24BTRGCTL | 04h |
| SD24_B trigger OSR control | SD24BTRGOSR | 06h |
| SD24_B trigger preload | SD24BTRGPRE | 08h |
| SD24_B interrupt flag | SD24BIFG | 0Ah |
| SD24_B interrupt enable | SD24BIE | 0Ch |
| SD24_B interrupt vector | SD24BIV | 0Eh |
| SD24_B converter 0 control | SD24BCCTL0 | 10h |
| SD24_B converter 0 input control | SD24BINCTL0 | 12h |
| SD24_B converter 0 OSR control | SD24BOSR0 | 14h |
| SD24_B converter 0 preload | SD24BPRE0 | 16h |
| SD24_B converter 1 control | SD24BCCTL1 | 18h |
| SD24_B converter 1 input control | SD24BINCTL1 | 1Ah |
| SD24_B converter 1 OSR control | SD24BOSR1 | 1Ch |
| SD24_B converter 1 preload | SD24BPRE1 | 1Eh |
| SD24_B converter 2 control | SD24BCCTL2 | 20h |
| SD24_B converter 2 input control | SD24BINCTL2 | 22h |
| SD24_B converter 2 OSR control | SD24BOSR2 | 24h |
| SD24_B converter 2 preload | SD24BPRE2 | 26h |
| SD24_B converter 3 control | SD24BCCTL3 | 28h |
| SD24_B converter 3 input control | SD24BINCTL3 | 2Ah |
| SD24_B converter 3 OSR control | SD24BOSR3 | 2Ch |
| SD24_B converter 3 preload | SD24BPRE3 | 2Eh |
| SD24_B converter 4 control | SD24BCCTL4 | 30h |
| SD24_B converter 4 input control | SD24BINCTL4 | 32h |
| SD24_B converter 4 OSR control | SD24BOSR4 | 34h |
| SD24_B converter 4 preload | SD24BPRE4 | 36h |
| SD24_B converter 5 control | SD24BCCTL5 | 38h |
| SD24_B converter 5 Input control | SD24BINCTL5 | 3Ah |
| SD24_B converter 5 OSR control | SD24BOSR5 | 3Ch |
| SD24_B converter 5 preload | SD24BPRE5 | 3Eh |
| SD24_B converter 6 control | SD24BCCTL6 | 40h |
| SD24_B converter 6 Input control | SD24BINCTL6 | 42h |
| SD24_B converter 6 OSR control | SD24BOSR6 | 44h |
| SD24_B converter 6 preload | SD24BPRE6 | 46h |
| SD24_B converter 0 conversion memory low word | SD24BMEML0 | 50h |
| SD24_B converter 0 conversion memory high word | SD24BMEMH0 | 52h |
| SD24_B converter 1 conversion memory low word | SD24BMEML1 | 54h |
| SD24_B converter 1 conversion memory high word | SD24BMEMH1 | 56h |
| SD24_B converter 2 conversion memory low word | SD24BMEML2 | 58h |
| SD24_B converter 2 conversion memory high word | SD24BMEMH2 | 5Ah |
| SD24_B converter 3 conversion memory low word | SD24BMEML3 | 5Ch |
| SD24_B converter 3 conversion memory high word | SD24BMEMH3 | 5Eh |
| SD24_B converter 4 conversion memory low word | SD24BMEML4 | 60h |
| SD24_B converter 4 conversion memory high word | SD24BMEMH4 | 62h |
| SD24_B converter 5 conversion memory low word | SD24BMEML5 | 64h |

Table 6-60. SD24_B Registers (Base Address: 0800h) (continued)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|--|------------|--------|
| SD24_B converter 5 conversion memory high word | SD24BMEMH5 | 66h |
| SD24_B converter 6 conversion memory low word | SD24BMEML6 | 68h |
| SD24_B converter 6 conversion memory high word | SD24BMEMH6 | 6Ah |

Table 6-61. Comparator_B Register (Base Address: 08C0h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|------------------------------|----------|--------|
| Comp_B control 0 | CBCTL0 | 00h |
| Comp_B control 1 | CBCTL1 | 02h |
| Comp_B control 2 | CBCTL2 | 04h |
| Comp_B control 3 | CBCTL3 | 06h |
| Comp_B interrupt | CBINT | 0Ch |
| Comp_B interrupt vector word | CBIV | 0Eh |

Table 6-62. AES Accelerator Registers (Base Address: 09C0h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|---------------------------|----------|--------|
| AES accelerator control 0 | AESACTL0 | 00h |
| AES accelerator status | AESASTAT | 04h |
| AES accelerator key | AESAKEY | 06h |
| AES accelerator data in | AESADIN | 08h |
| AES accelerator data out | AESADOUT | 0Ah |

Table 6-63. Auxiliary Supply Registers (Base Address: 09E0h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|----------------------------|-----------|--------|
| Auxiliary supply control 0 | AUXCTL0 | 00h |
| Auxiliary supply control 1 | AUXCTL1 | 02h |
| Auxiliary supply control 2 | AUXCTL2 | 04h |
| AUX2 charger control | AUX2CHCTL | 12h |
| AUX3 charger control | AUX3CHCTL | 14h |
| AUX ADC control | AUXADCCTL | 16h |
| AUX interrupt flag | AUXIFG | 1Ah |
| AUX interrupt enable | AUXIE | 1Ch |
| AUX interrupt vector word | AUXIV | 1Eh |

Table 6-64. LCD_C Registers (Base Address: 0A00h)

| REGISTER DESCRIPTION | REGISTER | OFFSET |
|-------------------------------------|------------|--------|
| LCD_C control 0 | LCDCCTL0 | 000h |
| LCD_C control 1 | LCDCCTL1 | 002h |
| LCD_C blinking control | LCDCBLKCTL | 004h |
| LCD_C memory control | LCDCMEMCTL | 006h |
| LCD_C voltage control | LCDCVCTL | 008h |
| LCD_C port control 0 | LCDCPCTL0 | 00Ah |
| LCD_C port control 1 | LCDCPCTL1 | 00Ch |
| LCD_C port control 2 | LCDCPCTL2 | 00Eh |
| LCD_C charge pump control | LCDCCPCTL | 012h |
| LCD_C interrupt vector | LCDCIV | 01Eh |
| Static and 2- to 4-mux modes | | |
| LCD_C memory 1 | LCDM1 | 020h |
| LCD_C memory 2 | LCDM2 | 021h |
| ⋮ | ⋮ | ⋮ |
| LCD_C memory 20 | LCDM20 | 033h |
| LCD_C blinking memory 1 | LCDBM1 | 040h |
| LCD_C blinking memory 2 | LCDBM2 | 041h |
| ⋮ | ⋮ | ⋮ |
| LCD_C blinking memory 20 | LCDBM20 | 053h |
| 5- to 8-mux modes | | |
| LCD_C memory 1 | LCDM1 | 020h |
| LCD_C memory 2 | LCDM2 | 021h |
| ⋮ | ⋮ | ⋮ |
| LCD_C memory 40 | LCDM40 | 047h |

6.12 Input/Output Diagrams

6.12.1 Port P1 (P1.0 to P1.3) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-6 shows the port diagram. Table 6-65 summarizes the selection of the pin functions.

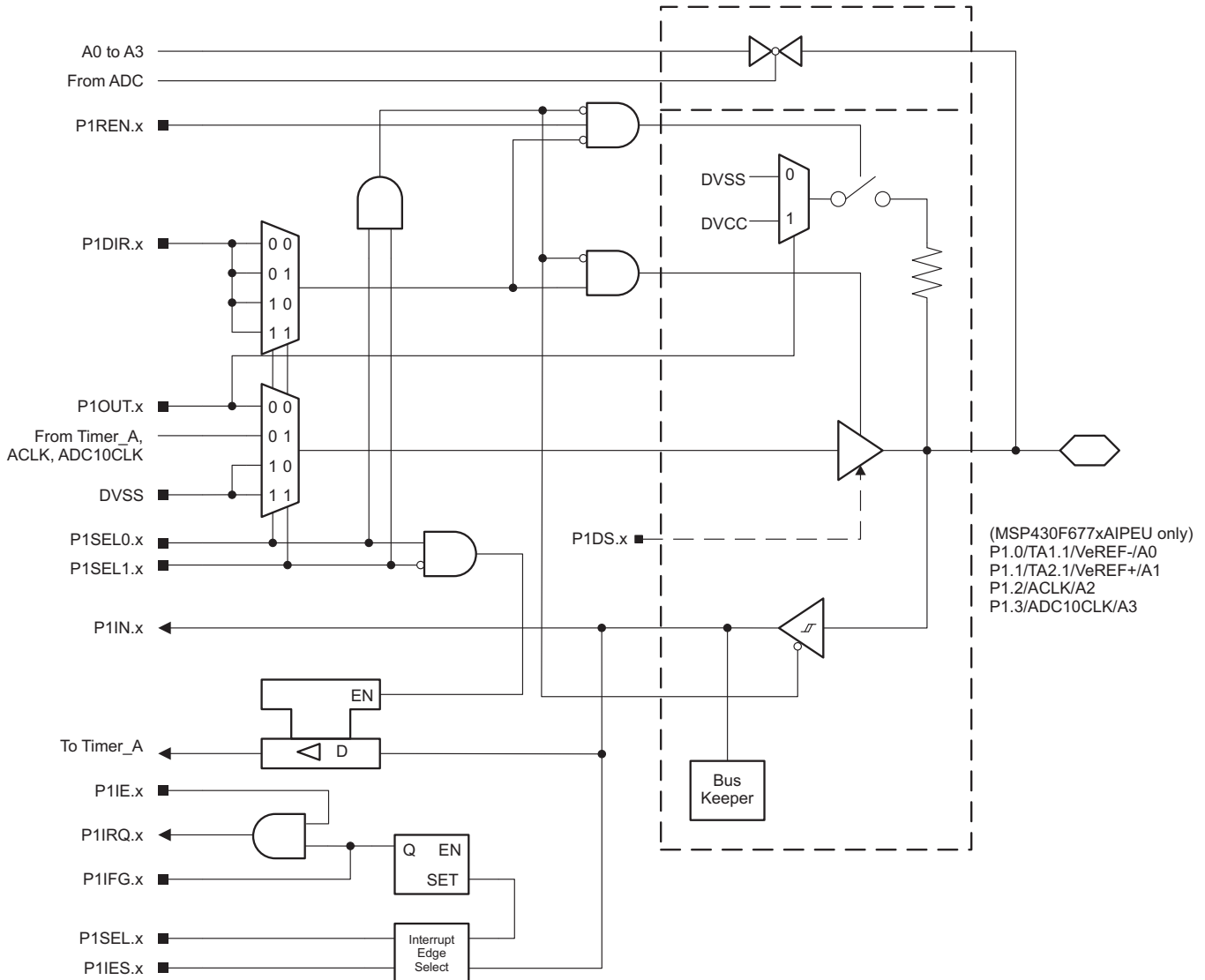


Figure 6-6. Port P1 (P1.0 to P1.3) Diagram (PEU Package Only)

Table 6-65. Port P1 (P1.0 to P1.3) Pin Functions (PEU Package Only)

| PIN NAME (P1.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|----------------------|---|------------|--|----------|----------|
| | | | P1DIR.x | P1SEL1.x | P1SEL0.x |
| P1.0/TA1.1/VeREF-/A0 | 0 | P1.0 (I/O) | I:0; O:1 | 0 | 0 |
| | | TA1.CCI1A | 0 | 0 | 1 |
| | | TA1.1 | 1 | 0 | 1 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | VeREF-/A0 | X | 1 | 1 |
| P1.1/TA2.1/VeREF+/A1 | 1 | P1.1 (I/O) | I:0; O:1 | 0 | 0 |
| | | TA2.CCI1A | 0 | 0 | 1 |
| | | TA2.1 | 1 | 0 | 1 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | VeREF+/A1 | X | 1 | 1 |
| P1.2/ACLK/A2 | 2 | P1.2 (I/O) | I:0; O:1 | 0 | 0 |
| | | ACLK | 1 | 0 | 1 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | A2 | X | 1 | 1 |
| P1.3/ADC10CLK/A3 | 3 | P1.3 (I/O) | I:0; O:1 | 0 | 0 |
| | | ADC10CLK | 1 | 0 | 1 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | A3 | X | 1 | 1 |

(1) X = don't care

6.12.2 Port P1 (P1.0 to P1.3) Input/Output With Schmitt Trigger (PZ Package Only)

Figure 6-7 shows the port diagram. Table 6-66 summarizes the selection of the pin functions.

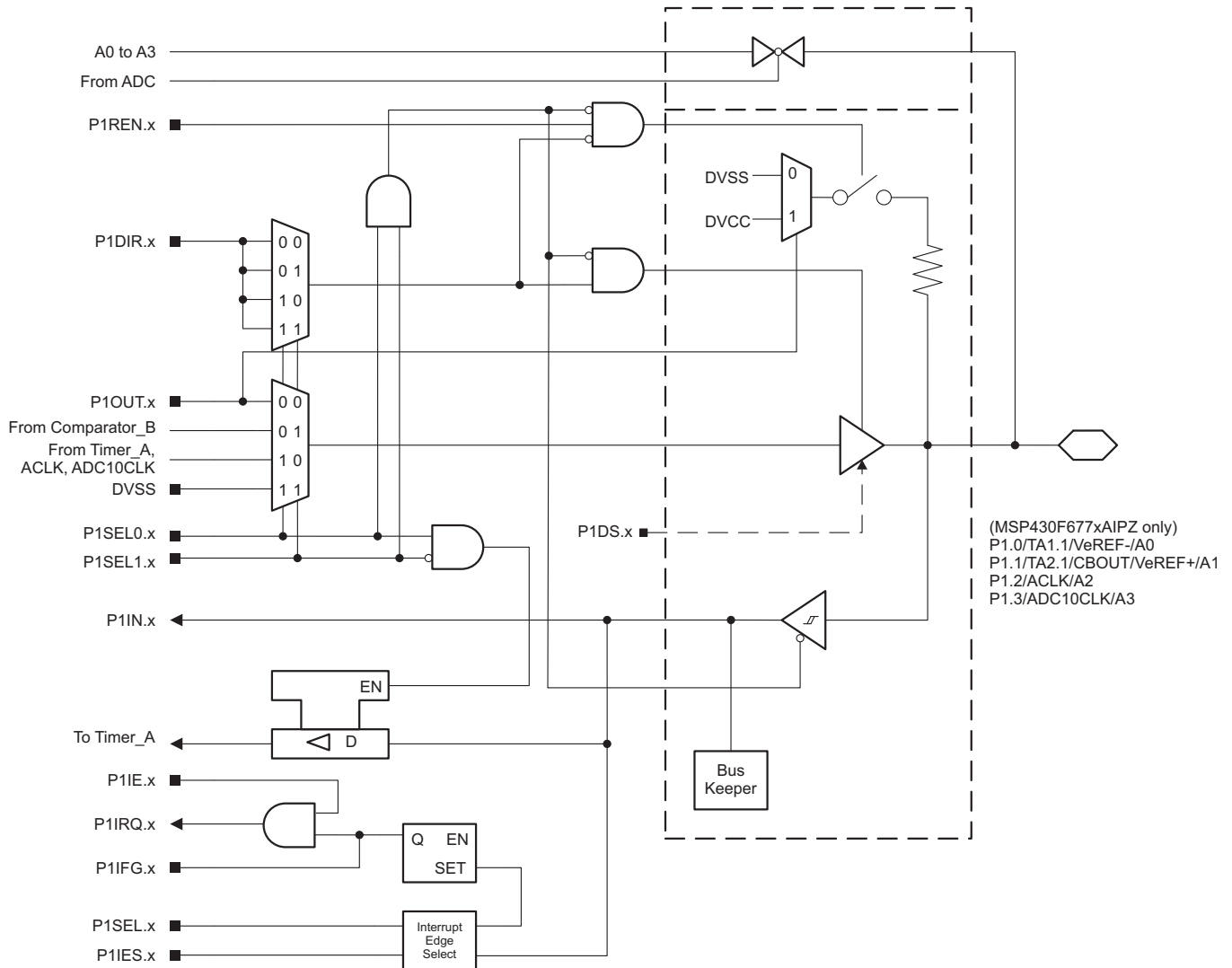


Figure 6-7. Port P1 (P1.0 to P1.3) Diagram (PZ Package Only)

Table 6-66. Port P1 (P1.0 to P1.3) Pin Functions (PZ Package Only)

| PIN NAME (P1.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|----------------------------|---|------------|--|----------|----------|
| | | | P1DIR.x | P1SEL1.x | P1SEL0.x |
| P1.0/TA1.1/VeREF-/A0 | 0 | P1.0 (I/O) | I:0; O:1 | 0 | 0 |
| | | TA1.CCI1A | 0 | 0 | 1 |
| | | TA1.1 | 1 | 0 | 1 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | VeREF-/A0 | X | 1 | 1 |
| P1.1/TA2.1/CBOUT/VeREF+/A1 | 1 | P1.1 (I/O) | I:0; O:1 | 0 | 0 |
| | | TA2.CCI1A | 0 | 0 | 1 |
| | | TA2.1 | 1 | 0 | 1 |
| | | N/A | 0 | 1 | 0 |
| | | CBOUT | 1 | 1 | 0 |
| | | VeREF+/A1 | X | 1 | 1 |
| P1.2/ACLK/A2 | 2 | P1.2 (I/O) | I:0; O:1 | 0 | 0 |
| | | ACLK | 1 | 0 | 1 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | A2 | X | 1 | 1 |
| P1.3/ADC10CLK/A3 | 3 | P1.3 (I/O) | I:0; O:1 | 0 | 0 |
| | | ADC10CLK | 1 | 0 | 1 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | A3 | X | 1 | 1 |

(1) X = don't care

6.12.3 Port P1 (P1.4 and P1.5) Input/Output With Schmitt Trigger

Figure 6-8 shows the port diagram. Table 6-67 summarizes the selection of the pin functions.

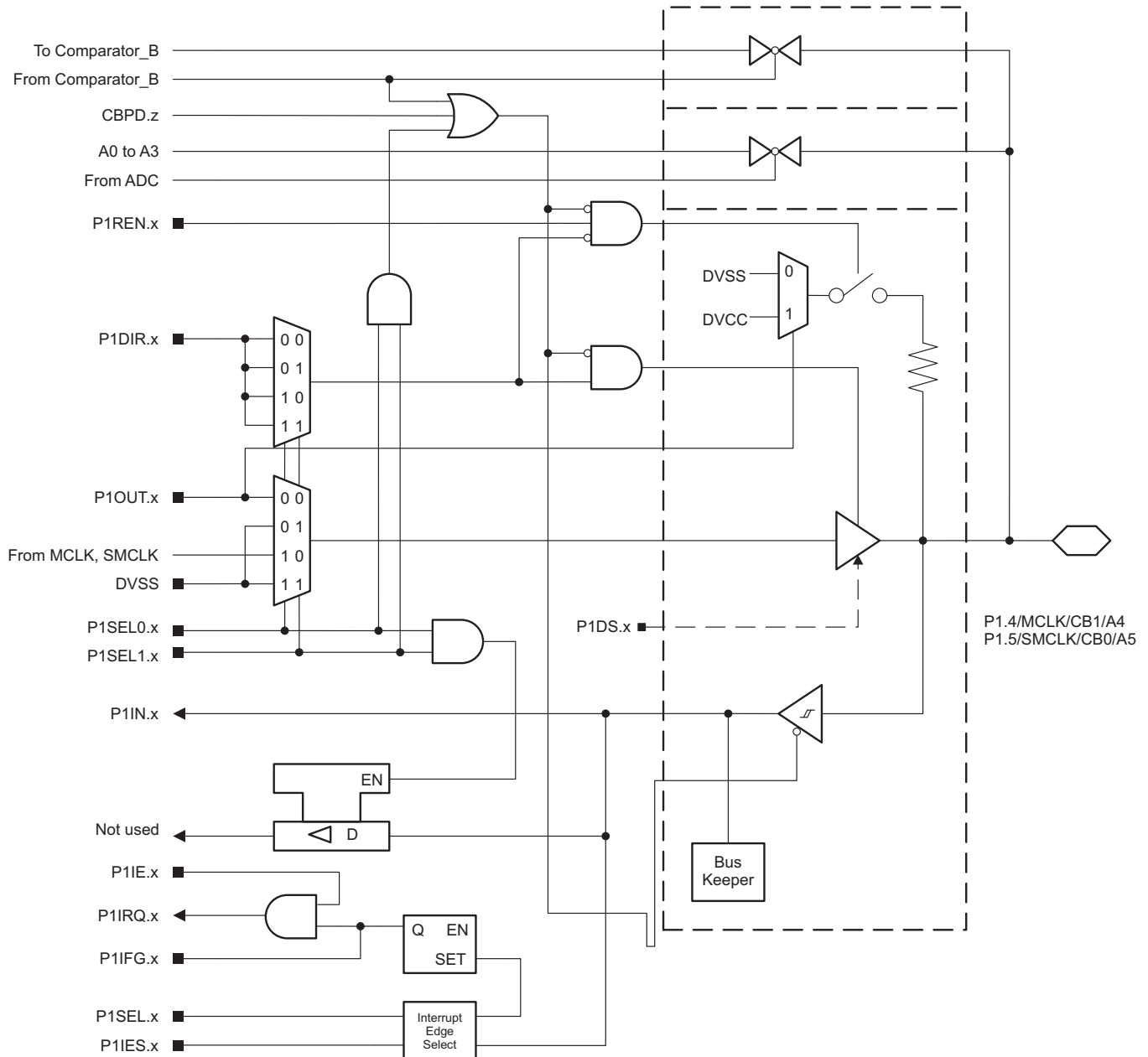


Figure 6-8. Port P1 (P1.4 and P1.5) Diagram

Table 6-67. Port P1 (P1.4 and P1.5) Pin Functions

| PIN NAME (P1.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | | |
|-------------------|---|------------|--|----------|----------|-----------|
| | | | P1DIR.x | P1SEL1.x | P1SEL0.x | CPBD.z |
| P1.4/MCLK/CB1/A4 | 4 | P1.4 (I/O) | I:0; O:1 | 0 | 0 | 0 |
| | | MCLK | 1 | 0 | 1 | 0 |
| | | N/A | 0 | 1 | 0 | 0 |
| | | DVSS | 1 | 1 | 0 | 0 |
| | | A4 | X | 1 | 1 | 0 |
| | | CB1 | X | X | X | 1 (z = 1) |
| P1.5/SMCLK/CB0/A5 | 5 | P1.5 (I/O) | I:0; O:1 | 0 | 0 | 0 |
| | | SMCLK | 1 | 0 | 1 | 0 |
| | | N/A | 0 | 1 | 0 | 0 |
| | | DVSS | 1 | 1 | 0 | 0 |
| | | A5 | X | 1 | 1 | 0 |
| | | CB0 | X | X | X | 1 (z = 0) |

(1) X = don't care

6.12.4 Port P1 (P1.6 and P1.7) Input/Output With Schmitt Trigger

Figure 6-9 shows the port diagram. Table 6-68 summarizes the selection of the pin functions.

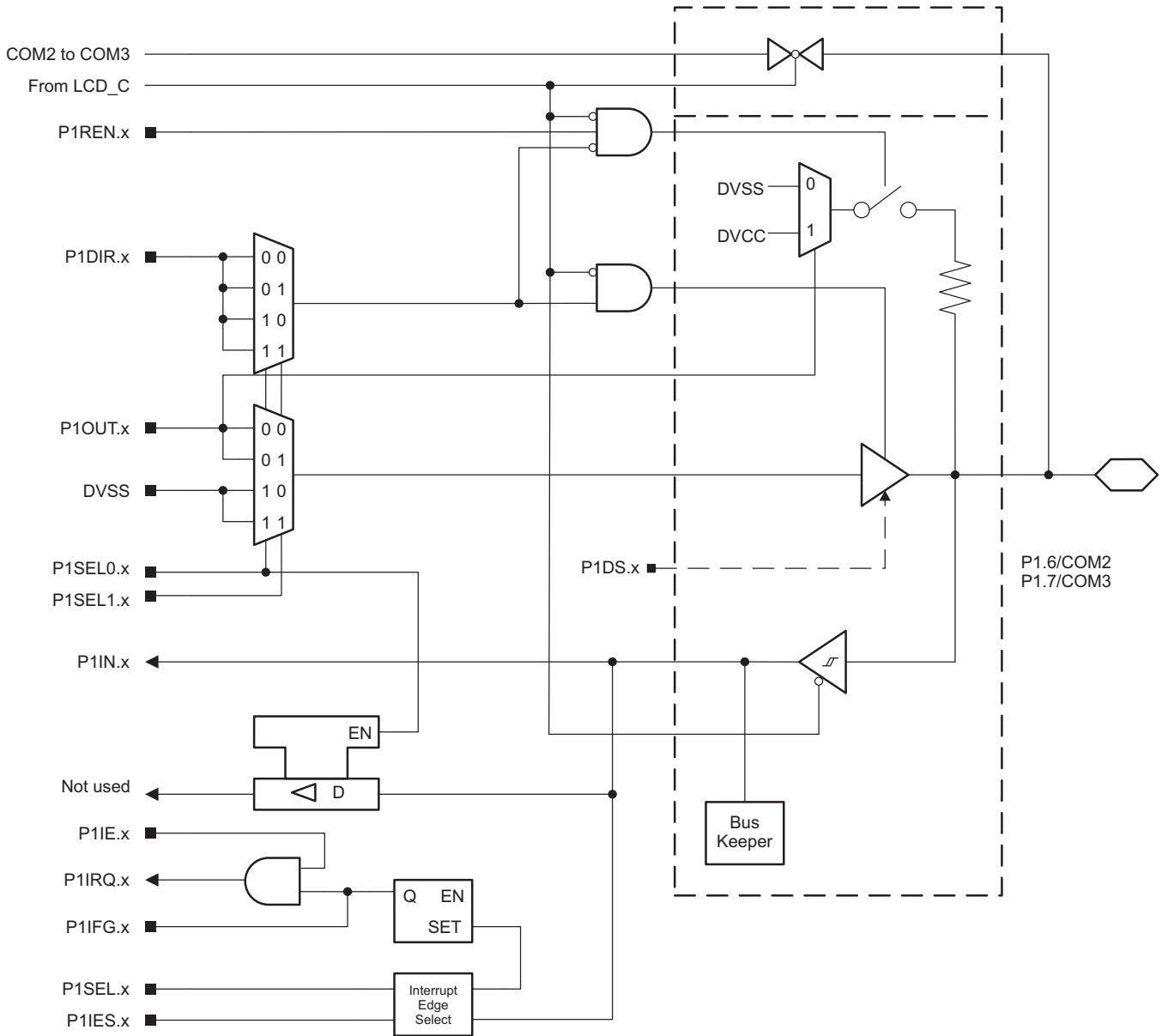


Figure 6-9. Port P1 (P1.6 and P1.7) Diagram

Table 6-68. Port P1 (P1.6 and P1.7) Pin Functions

| PIN NAME (P1.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | | |
|-----------------|---|------------|--|----------|----------|------------|
| | | | P1DIR.x | P1SEL1.x | P1SEL0.x | COM Enable |
| P1.6/COM2 | 6 | P1.6 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | N/A | 0 | X | 1 | 0 |
| | | DVSS | 1 | X | 1 | 0 |
| | | COM2 | X | X | X | 1 |
| P1.7/COM3 | 7 | P1.7 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | N/A | 0 | X | 1 | 0 |
| | | DVSS | 1 | X | 1 | 0 |
| | | COM3 | X | X | X | 1 |

(1) X = don't care

6.12.5 Port P2 (P2.0 to P2.7) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-10 shows the port diagram. Table 6-69 summarizes the selection of the pin functions.

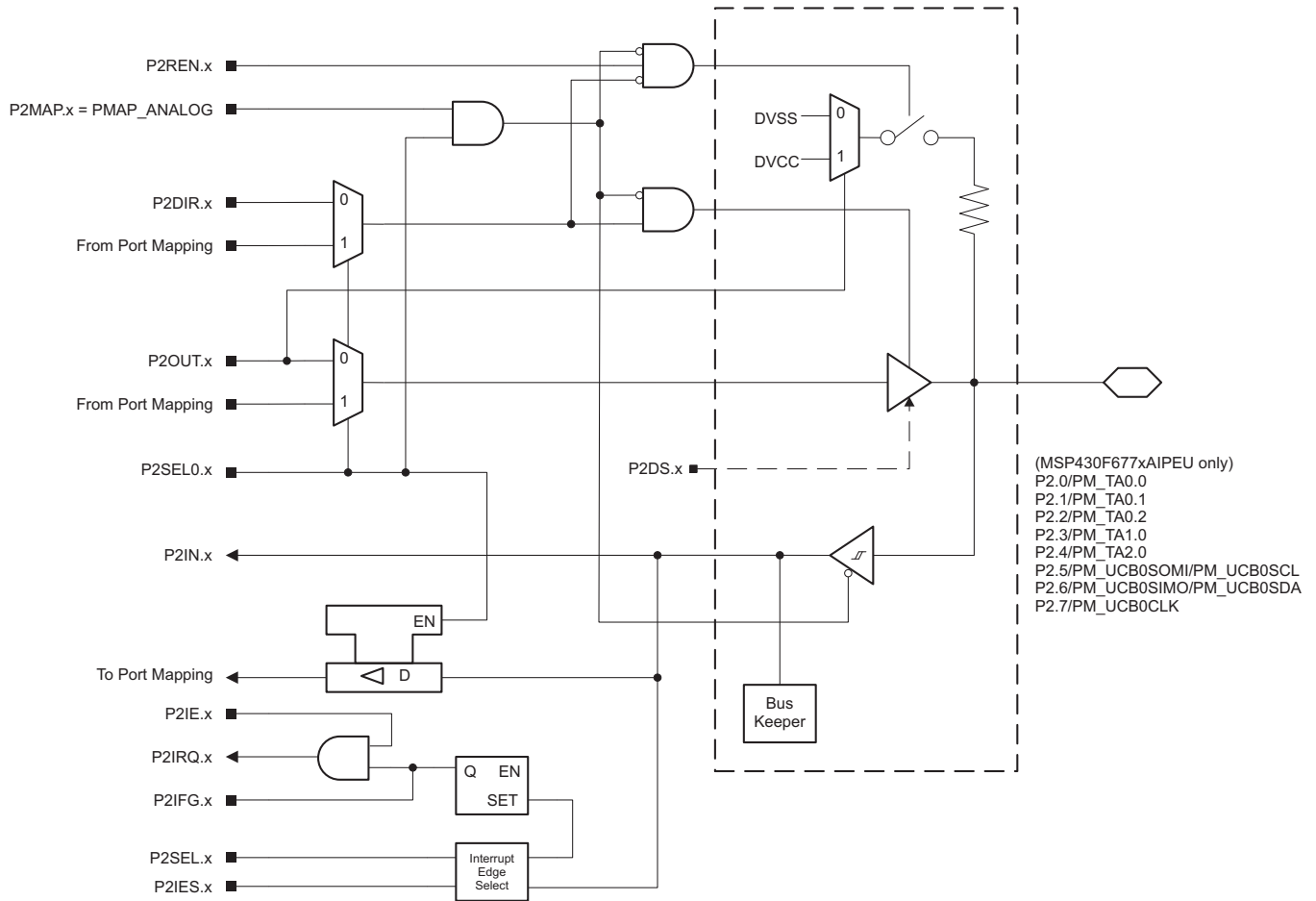


Figure 6-10. Port P2 (P2.0 to P2.7) Diagram (PEU Package Only)

Table 6-69. Port P2 (P2.0 to P2.7) Pin Functions (PEU Package Only)

| PIN NAME (P2.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|---------------------------------|---|--|--|----------|---------|
| | | | P2DIR.x | P2SEL0.x | P2MAP.x |
| P2.0/PM_TA0.0 | 0 | P2.0 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P2.1/PM_TA0.1 | 1 | P2.1 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P2.2/PM_TA0.2 | 2 | P2.2 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P2.3/PM_TA1.0 | 3 | P2.3 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P2.4/PM_TA2.0 | 4 | P2.4 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P2.5/PM_UCB0SOMI/ PM_UCB0SCL | 5 | P2.5 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P2.6/PM_UCB0SIMO/ PM_UCB0SDA | 6 | P2.6 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P2.7/PM_UCB0CLK | 7 | P2.7 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |

(1) X = don't care

6.12.6 Port P2 (P2.0 to P2.3) Input/Output With Schmitt Trigger (PZ Package Only)

Figure 6-11 shows the port diagram. Table 6-70 summarizes the selection of the pin functions.

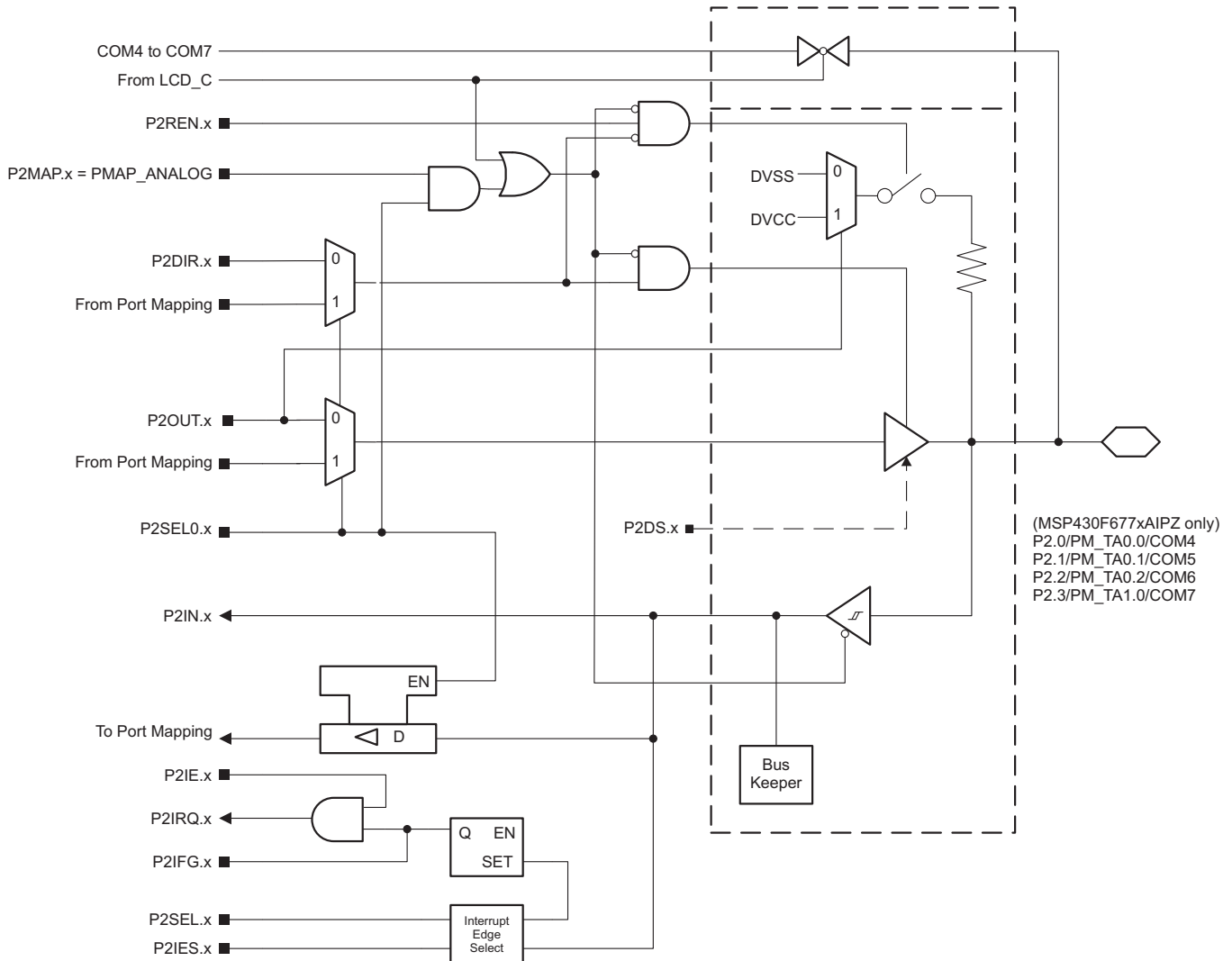


Figure 6-11. Port P2 (P2.0 to P2.3) Diagram (PZ Package Only)

Table 6-70. Port P2 (P2.0 to P2.3) Pin Functions (PZ Package Only)

| PIN NAME (P2.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | | |
|---------------------|---|--|--|----------|---------|------------|
| | | | P2DIR.x | P2SEL0.x | P2MAP.x | COM Enable |
| P2.0/PM_TA0.0/ COM4 | 0 | P2.0 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | COM4 | X | X | X | 1 |
| P2.1/PM_TA0.1/ COM5 | 1 | P2.1 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | COM5 | X | X | X | 1 |
| P2.2/PM_TA0.2/ COM6 | 2 | P2.2 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | COM6 | X | X | X | 1 |
| P2.3/PM_TA1.0/ COM7 | 3 | P2.3 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | COM7 | X | X | X | 1 |

(1) X = don't care

6.12.7 Port P2 (P2.4 to P2.6) Input/Output With Schmitt Trigger (PZ Package Only)

Figure 6-12 shows the port diagram. Table 6-71 summarizes the selection of the pin functions.

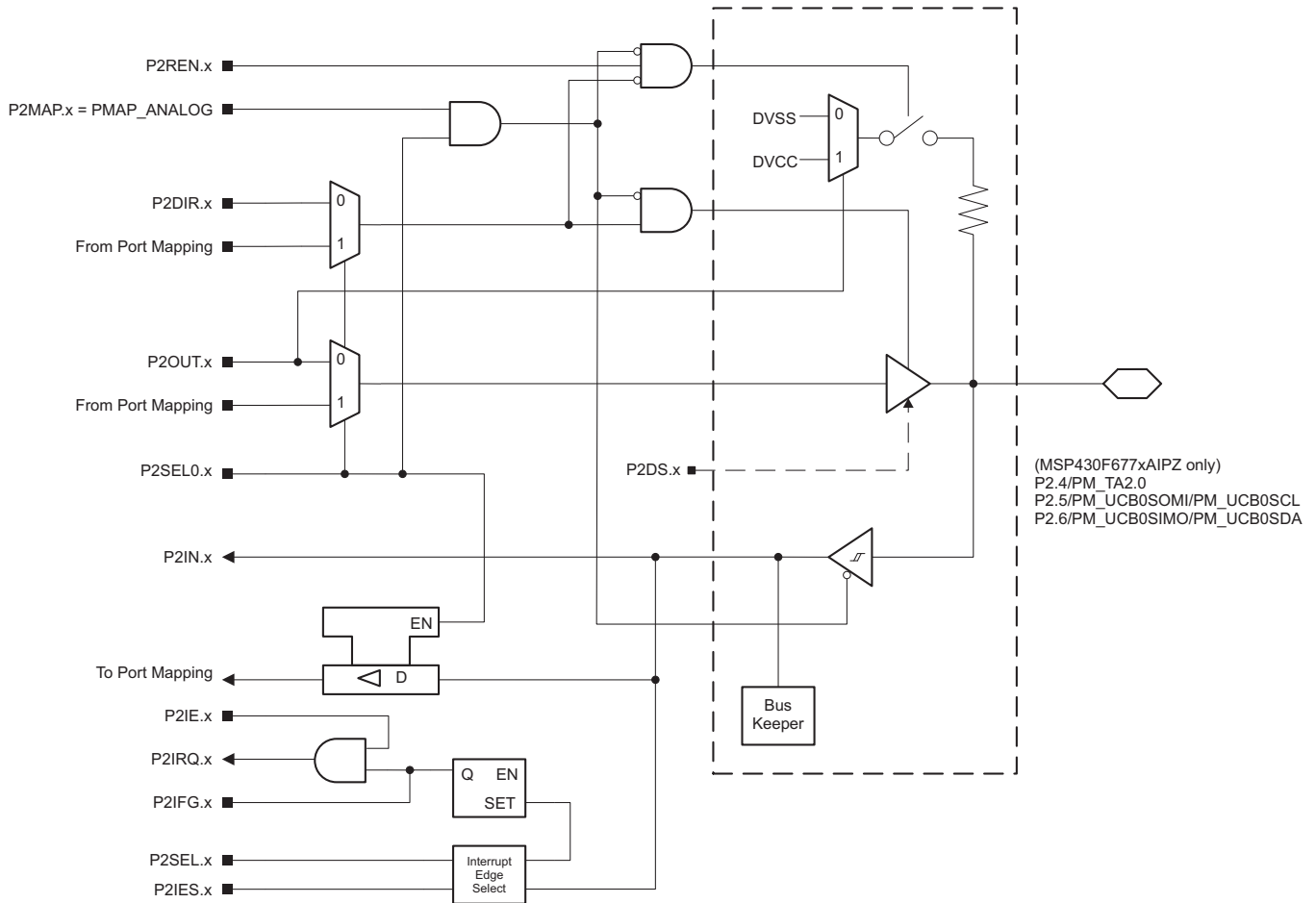


Figure 6-12. Port P2 (P2.4 to P2.6) Diagram (PZ Package Only)

Table 6-71. Port P2 (P2.4 to P2.6) Pin Functions (PZ Package Only)

| PIN NAME (P2.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|---------------------------------|---|-----------------------------------|--|----------|---------|
| | | | P2DIR.x | P2SEL0.x | P2MAP.x |
| P2.4/PM_TA2.0/R23 | 4 | P2.4 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | R23 | X | 1 | = 31 |
| P2.5/PM_UCB0SOMI/PM_UCB0SCL/R13 | 5 | P2.5 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | R13 | X | 1 | = 31 |
| P2.6/PM_UCB0SIMO/PM_UCB0SDA/R03 | 6 | P2.6 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | R03 | X | 1 | = 31 |

(1) X = don't care

6.12.8 Port P2 (P2.7) Input/Output With Schmitt Trigger (PZ Package Only)

Figure 6-13 shows the port diagram. Table 6-72 summarizes the selection of the pin functions.

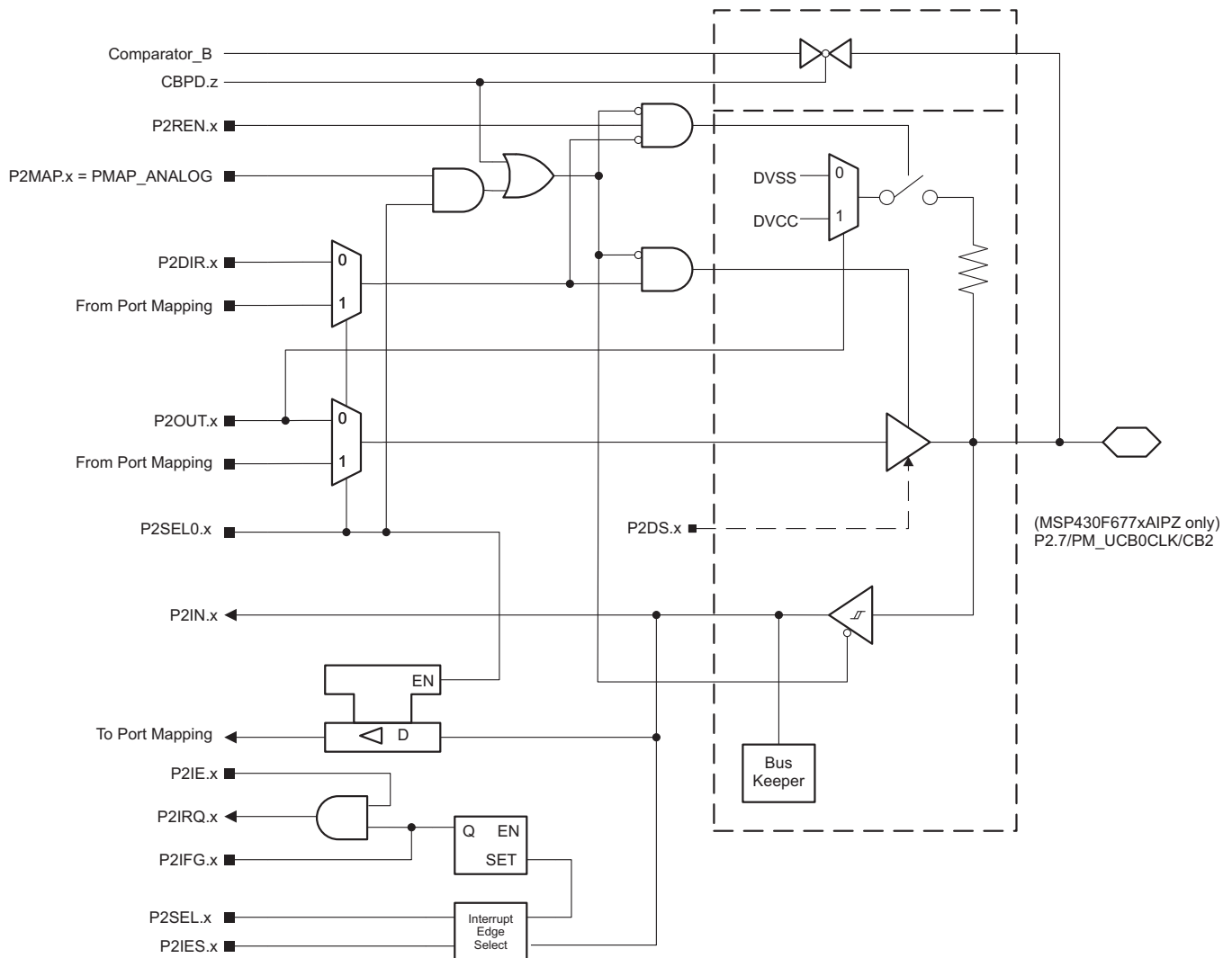


Figure 6-13. Port P2 (P2.7) Diagram (PZ Package Only)

Table 6-72. Port P2 (P2.7) Pin Functions (PZ Package Only)

| PIN NAME (P2.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | | |
|-------------------------|---|--|--|----------|---------|-----------|
| | | | P2DIR.x | P2SEL0.x | P2MAP.x | CBPD.z |
| P2.7/PM_UCB0CLK/ CB2 | 7 | P2.7 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | CB2 | X | X | X | 1 (z = 2) |

(1) X = don't care

6.12.9 Ports P3 (P3.0 to P3.7) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-14 shows the port diagram. Table 6-73 summarizes the selection of the pin functions.

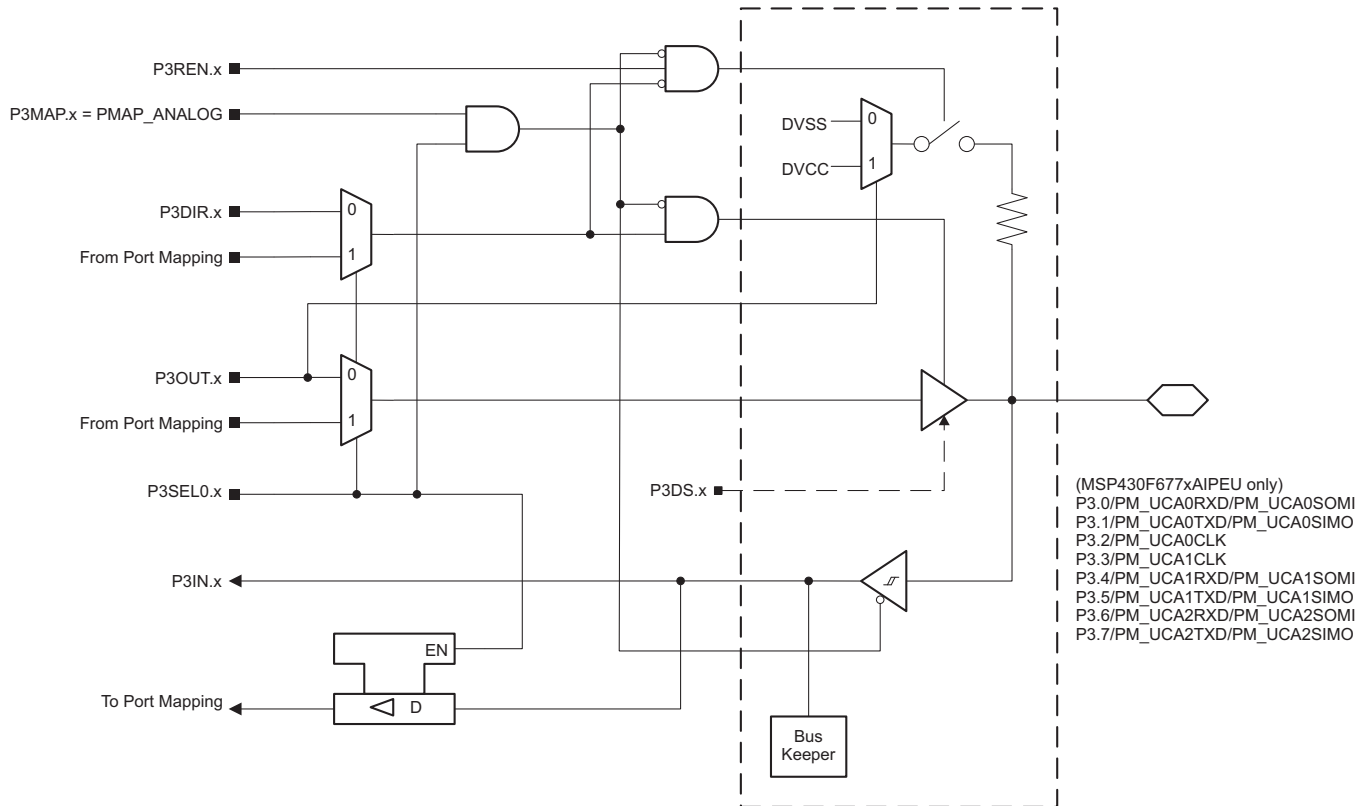


Figure 6-14. Ports P3 (P3.0 to P3.7) Diagram (PEU Package Only)

Table 6-73. Ports P3 (P3.0 to P3.7) Pin Functions (PEU Package Only)

| PIN NAME (P3.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|---------------------------------|---|--|--|----------|---------|
| | | | P3DIR.x | P3SEL0.x | P3MAP.x |
| P3.0/PM_UCA0RXD/ PM_UCA0SOMI | 0 | P3.0 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P3.1/PM_UCA0TXD/ PM_UCA0SIMO | 1 | P3.1 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P3.2/PM_UCA0CLK | 2 | P3.2 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P3.3/PM_UCA1CLK | 3 | P3.3 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P3.4/PM_UCA1RXD/ PM_UCA1SOMI | 4 | P3.4 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P3.5/PM_UCA1TXD/ PM_UCA1SIMO | 5 | P3.5 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P3.6/PM_UCA2RXD/ PM_UCA2SOMI | 6 | P3.6 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P3.7/PM_UCA2TXD/ PM_UCA2SIMO | 7 | P3.7 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |

(1) X = don't care

6.12.10 Ports P3 (P3.0) Input/Output With Schmitt Trigger (PZ Package Only)

Figure 6-15 shows the port diagram. Table 6-74 summarizes the selection of the pin functions.

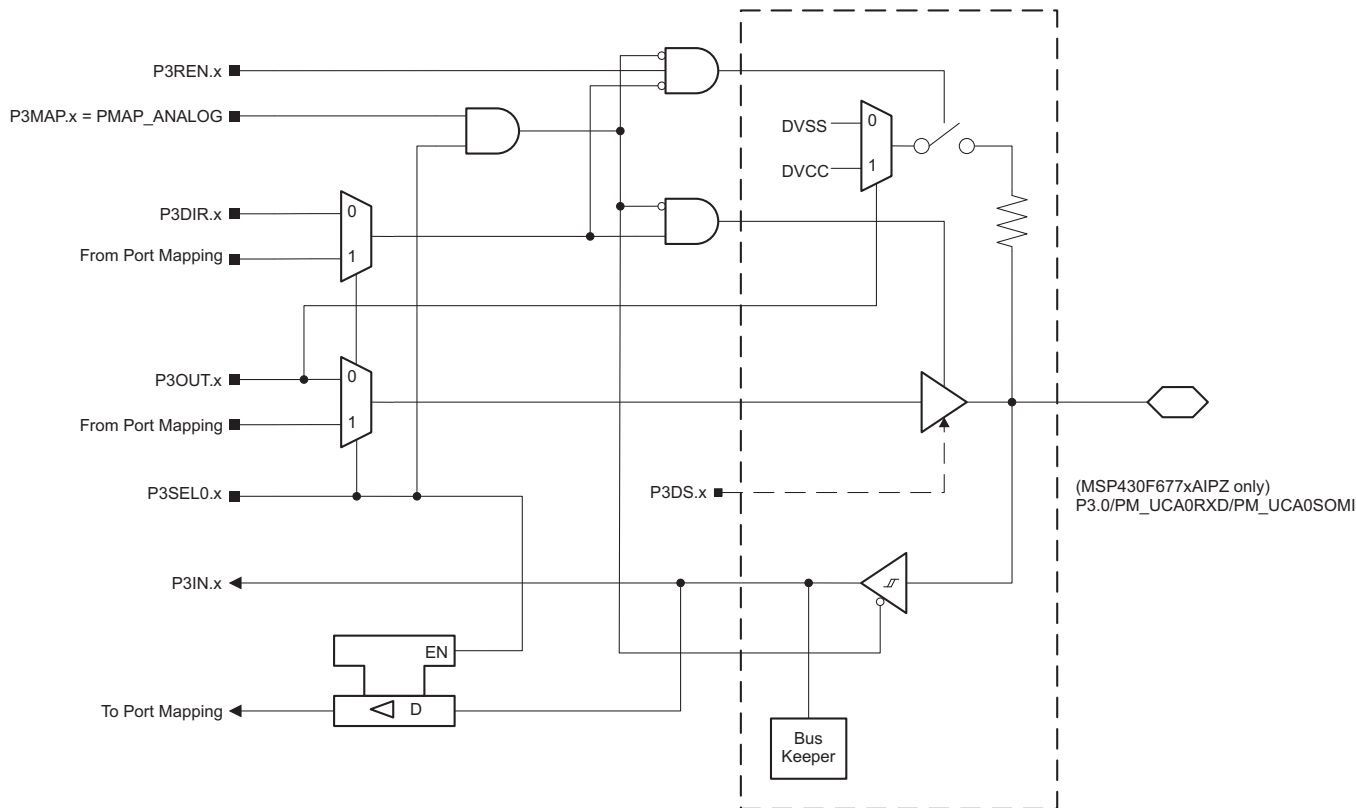


Figure 6-15. Ports P3 (P3.0) Diagram (PZ Package Only)

Table 6-74. Ports P3 (P3.0) Pin Functions (PZ Package Only)

| PIN NAME (P3.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|---------------------------------|---|--|--|----------|---------|
| | | | P3DIR.x | P3SEL0.x | P3MAP.x |
| P3.0/PM_UCA0RXD/ PM_UCA0SOMI | 0 | P3.0 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |

(1) X = don't care

6.12.11 Ports P3 (P3.1 to P3.7) Input/Output With Schmitt Trigger (PZ Package Only)

Figure 6-16 shows the port diagram. Table 6-75 summarizes the selection of the pin functions.

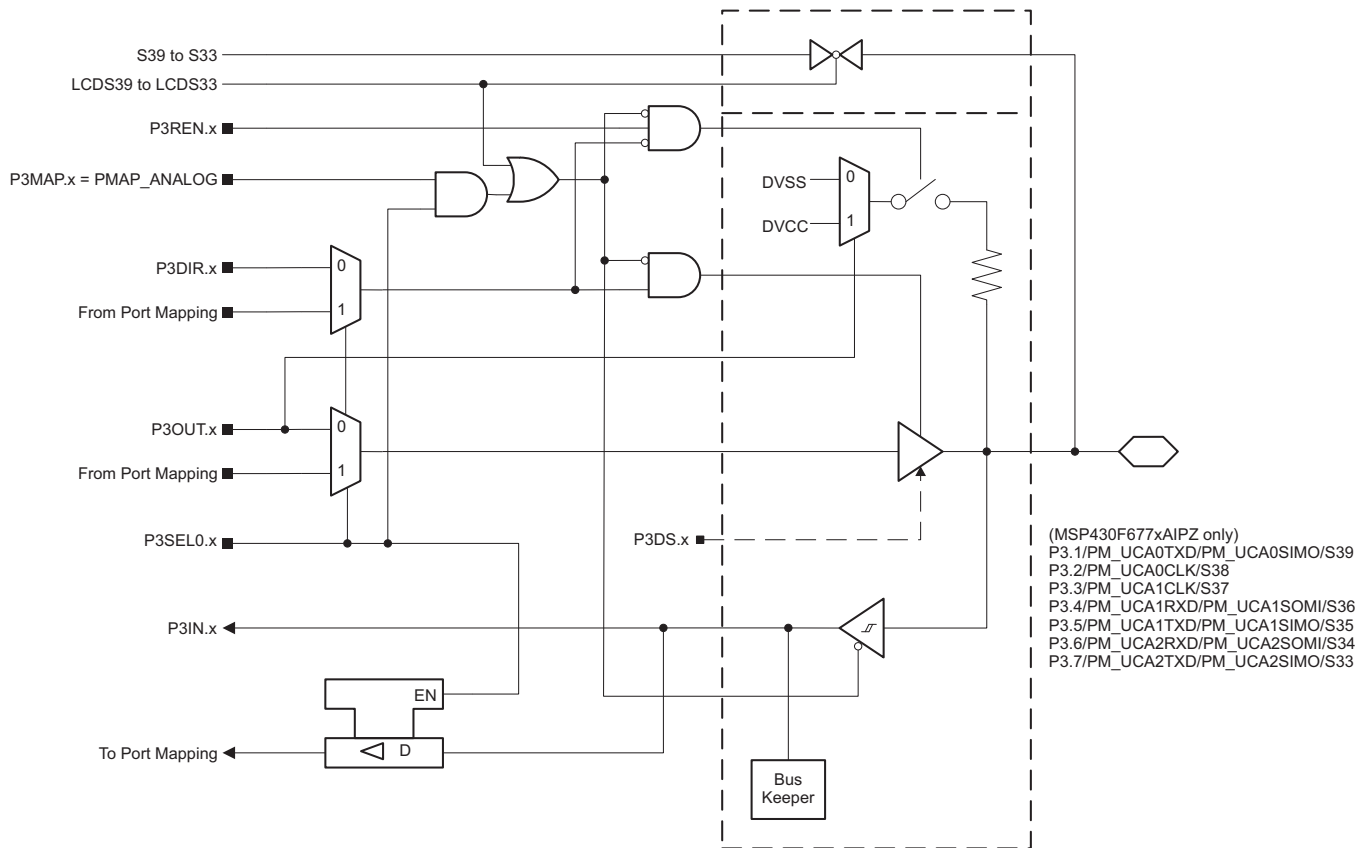


Figure 6-16. Ports P3 (P3.1 to P3.7) Diagram (PZ Package Only)

Table 6-75. Ports P3 (P3.1 to P3.7) Pin Functions (PZ Package Only)

| PIN NAME (P3.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | | |
|-------------------------------------|---|--|--|----------|---------|------------------|
| | | | P3DIR.x | P3SEL0.x | P3MAP.x | LCDS39 to LCDS33 |
| P3.1/PM_UCA0TXD/ PM_UCA0SIMO/S39 | 1 | P3.1 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S39 | X | X | X | 1 |
| P3.2/PM_UCA0CLK/ S38 | 2 | P3.2 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S38 | X | X | X | 1 |
| P3.3/PM_UCA1CLK/ S37 | 3 | P3.3 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S37 | X | X | X | 1 |
| P3.4/PM_UCA1RXD/ PM_UCA1SOMI/S36 | 4 | P3.4 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S36 | X | X | X | 1 |
| P3.5/PM_UCA1TXD/ PM_UCA1SIMO/S35 | 5 | P3.5 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S35 | X | X | X | 1 |
| P3.6/PM_UCA2RXD/ PM_UCA2SOMI/S34 | 6 | P3.6 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S34 | X | X | X | 1 |
| P3.7/PM_UCA2TXD/ PM_UCA2SIMO/S33 | 7 | P3.7 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S33 | X | X | X | 1 |

(1) X = don't care

6.12.12 Port P4 (P4.0 to P4.7) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-17 shows the port diagram. Table 6-76 summarizes the selection of the pin functions.

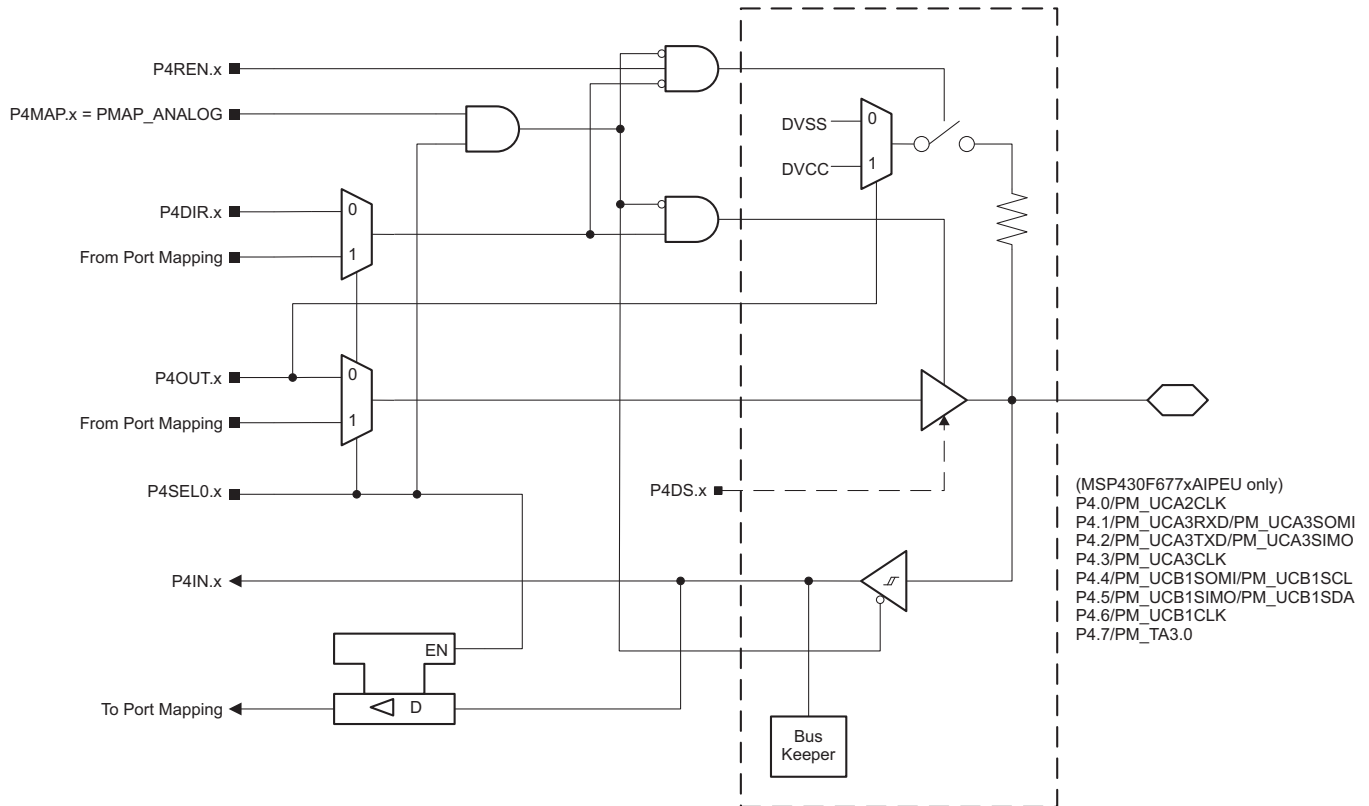


Figure 6-17. Port P4 (P4.0 to P4.7) Diagram (PEU Package Only)

Table 6-76. Port P4 (P4.0 to P4.7) Pin Functions (PEU Package Only)

| PIN NAME (P4.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|---------------------------------|---|--|--|----------|---------|
| | | | P4DIR.x | P4SEL0.x | P4MAP.x |
| P4.0/PM_UCA2CLK | 0 | P4.0 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P4.1/PM_UCA3RXD/ PM_UCA3SOMI | 1 | P4.1 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P4.2/PM_UCA3TXD/ PM_UCA3SIMO | 2 | P4.2 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P4.3/PM_UCA3CLK | 3 | P4.3 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P4.4/PM_UCB1SOMI/ PM_UCB1SCL | 4 | P4.4 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P4.5/PM_UCB1SIMO/ PM_UCB1SDA | 5 | P4.5 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P4.6/PM_UCB1CLK | 6 | P4.6 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |
| P4.7/PM_TA3.0 | 7 | P4.7 (I/O) | I:0; O:1 | 0 | X |
| | | Mapped secondary digital function | X | 1 | ≤ 30 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 |

(1) X = don't care

6.12.13 Port P4 (P4.0 to P4.7) Input/Output With Schmitt Trigger (PZ Package Only)

Figure 6-18 shows the port diagram. Table 6-77 summarizes the selection of the pin functions.

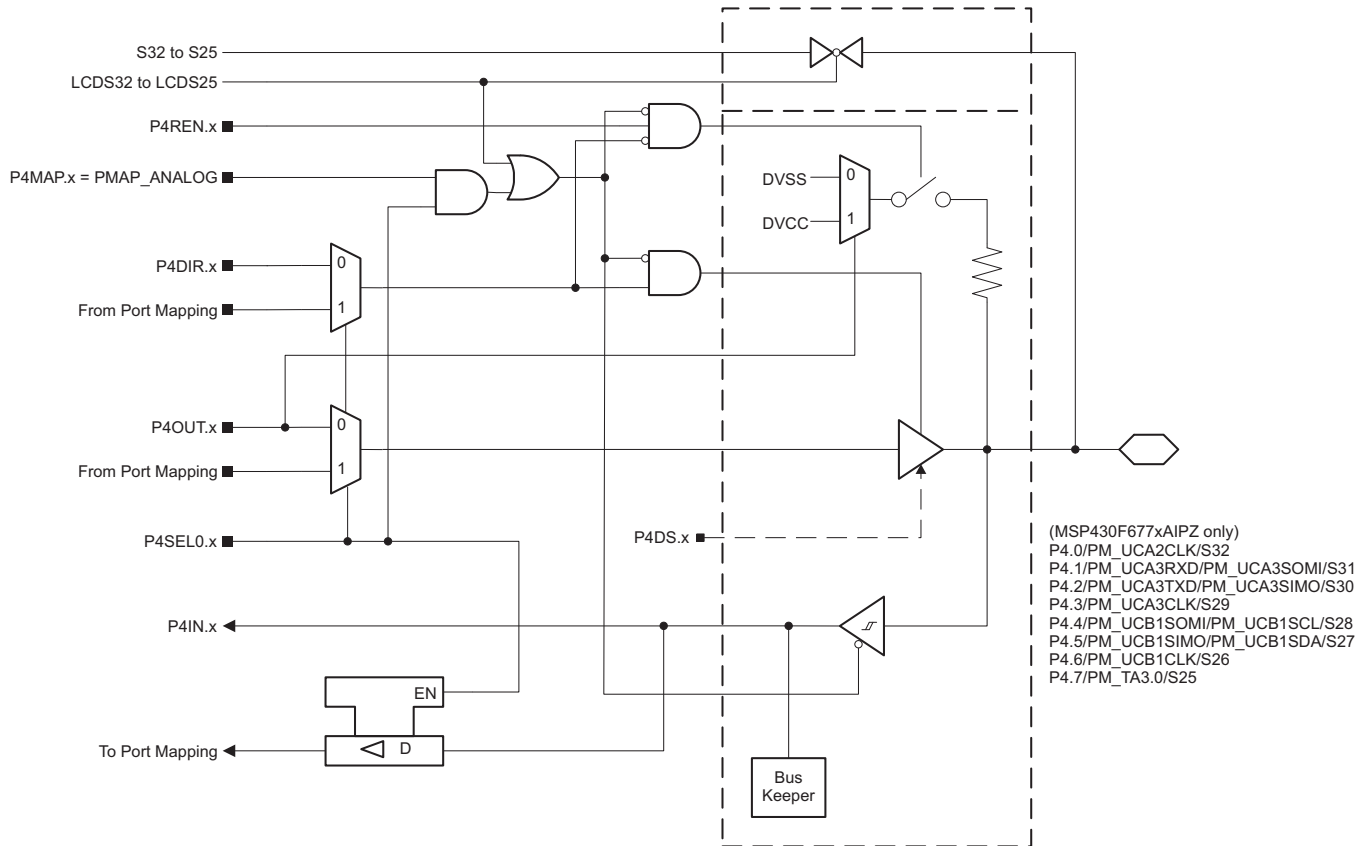


Figure 6-18. Port P4 (P4.0 to P4.7) Diagram (PZ Package Only)

Table 6-77. Port P4 (P4.0 to P4.7) Pin Functions (PZ Package Only)

| PIN NAME (P4.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | | |
|--------------------------------------|---|--|--|----------|---------|-----------------|
| | | | P4DIR.x | P4SEL0.x | P4MAP.x | LCD32 to LCDS25 |
| P4.0/PM_UCA2CLK/ S32 | 0 | P4.0 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S32 | X | X | X | 1 |
| P4.1/PM_UCA3RXD/ PM_UCA3SOMI/S31 | 1 | P4.1 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S31 | X | X | X | 1 |
| P4.2/PM_UCA3TXD/ PM_UCA3SIMO/S30 | 2 | P4.2 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S30 | X | X | X | 1 |
| P4.3/PM_UCA3CLK/ S29 | 3 | P4.3 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S29 | X | X | X | 1 |
| P4.4/ PM_UCB1SOMI/ PM_UCB1SCL/S28 | 4 | P4.4 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S28 | X | X | X | 1 |
| P4.5/ PM_UCB1SIMO/ PM_UCB1SDA/S27 | 5 | P4.5 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S27 | X | X | X | 1 |
| P4.6/PM_UCB1CLK/ S26 | 6 | P4.6 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S26 | X | X | X | 1 |
| P4.7/PM_TA3.0/S25 | 7 | P4.7 (I/O) | I:0; O:1 | 0 | X | 0 |
| | | Mapped secondary digital function | X | 1 | ≤ 30 | 0 |
| | | Output driver and input Schmitt trigger disabled | X | 1 | = 31 | 0 |
| | | S25 | X | X | X | 1 |

(1) X = don't care

6.12.14 Port P5 (P5.0 to P5.3) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-19 shows the port diagram. Table 6-78 summarizes the selection of the pin functions.

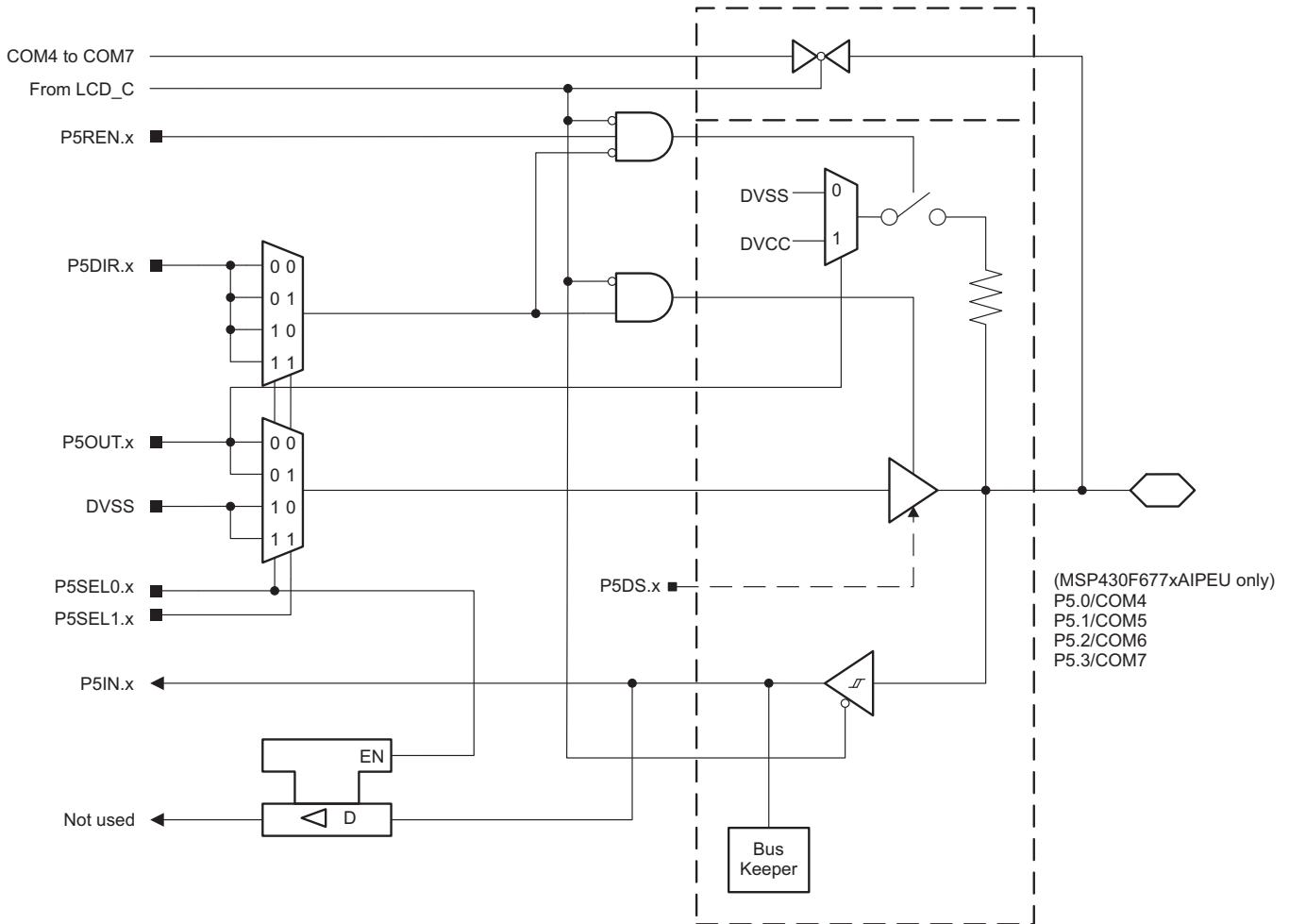


Figure 6-19. Port P5 (P5.0 to P5.3) Diagram (PEU Package Only)

Table 6-78. Port P5 (P5.0 to P5.3) Pin Functions (PEU Package Only)

| PIN NAME (P5.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | | |
|-----------------|---|------------|--|----------|----------|------------|
| | | | P5DIR.x | P5SEL1.x | P5SEL0.x | COM Enable |
| P5.0/COM4 | 0 | P5.0 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | N/A | 0 | X | 1 | 0 |
| | | DVSS | 1 | X | 1 | 0 |
| | | COM4 | X | X | X | 1 |
| P5.1/COM5 | 1 | P5.1 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | N/A | 0 | X | 1 | 0 |
| | | DVSS | 1 | X | 1 | 0 |
| | | COM5 | X | X | X | 1 |
| P5.2/COM6 | 2 | P5.2 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | N/A | 0 | X | 1 | 0 |
| | | DVSS | 1 | X | 1 | 0 |
| | | COM6 | X | X | X | 1 |
| P5.3/COM7 | 3 | P5.3 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | N/A | 0 | X | 1 | 0 |
| | | DVSS | 1 | X | 1 | 0 |
| | | COM7 | X | X | X | 1 |

(1) X = don't care

6.12.15 Port P5 (P5.4 to P5.6) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-20 shows the port diagram. Table 6-79 summarizes the selection of the pin functions.

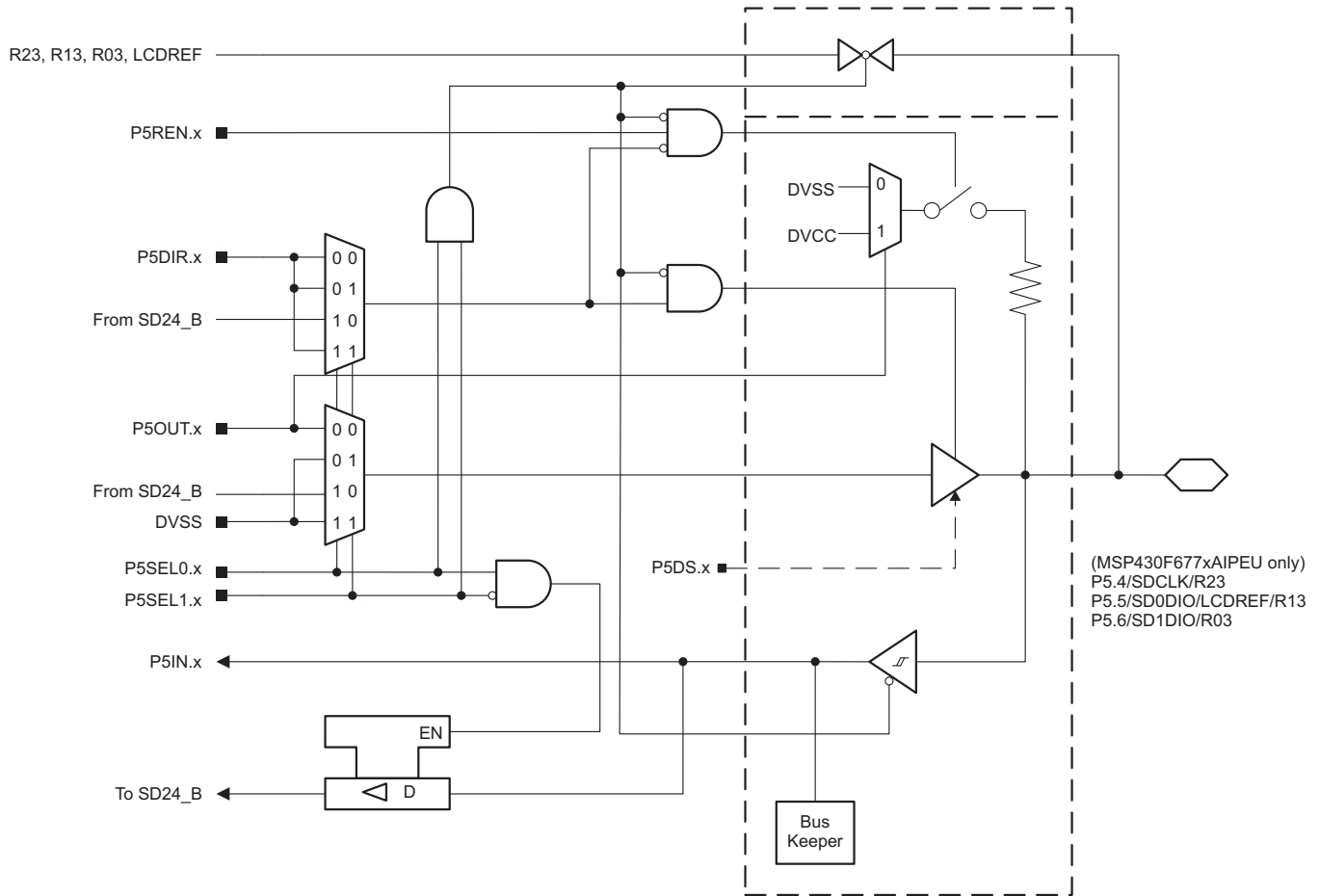


Figure 6-20. Port P5 (P5.4 to P5.6) Diagram (PEU Package Only)

Table 6-79. Port P5 (P5.4 to P5.6) Pin Functions (PEU Package Only)

| PIN NAME (P5.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|------------------------|---|----------------------------|--|----------|----------|
| | | | P5DIR.x | P5SEL1.x | P5SEL0.x |
| P5.4/SDCLK/R23 | 4 | P5.4 (I/O) | I:0; O:1 | 0 | 0 |
| | | Secondary digital function | X | 0 | 1 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | R23 | X | 1 | 1 |
| P5.5/SD0DIO/LCDREF/R13 | 5 | P5.5 (I/O) | I:0; O:1 | 0 | 0 |
| | | Secondary digital function | X | 0 | 1 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | LCDREF/R13 | X | 1 | 1 |
| PT.6/SD1DIO/R03 | 6 | P5.6 (I/O) | I:0; O:1 | 0 | 0 |
| | | Secondary digital function | X | 0 | 1 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | R03 | X | 1 | 1 |

(1) X = don't care

6.12.16 Port P5 (P5.7) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-21 shows the port diagram. Table 6-80 summarizes the selection of the pin functions.

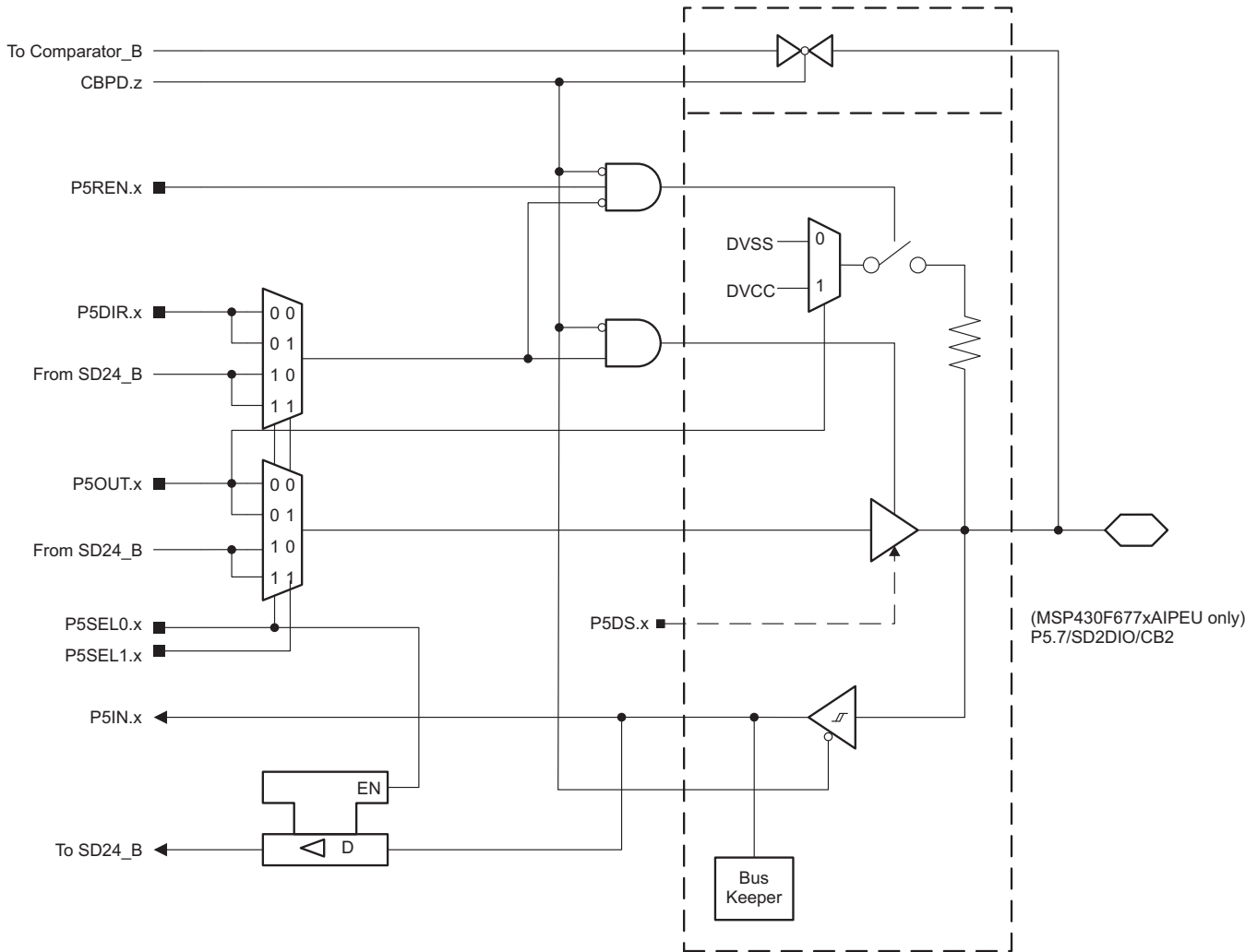


Figure 6-21. Port P5 (P5.7) Diagram (PEU Package Only)

Table 6-80. Port P5 (P5.7) Pin Function (PEU Package Only)

| PIN NAME (P5.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | | |
|-----------------|---|----------------------------|--|----------|----------|-----------|
| | | | P5DIR.x | P5SEL1.x | P5SEL0.x | CBPD.z |
| P5.7/SD2DIO/CB2 | 7 | P5.7 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | Secondary digital function | X | X | 1 | 0 |
| | | CB2 | X | X | X | 1 (z = 2) |

(1) X = don't care

6.12.17 Port P5 (P5.0 to P5.7) Input/Output With Schmitt Trigger (PZ Package Only)

Figure 6-22 shows the port diagram. Table 6-81 summarizes the selection of the pin functions.

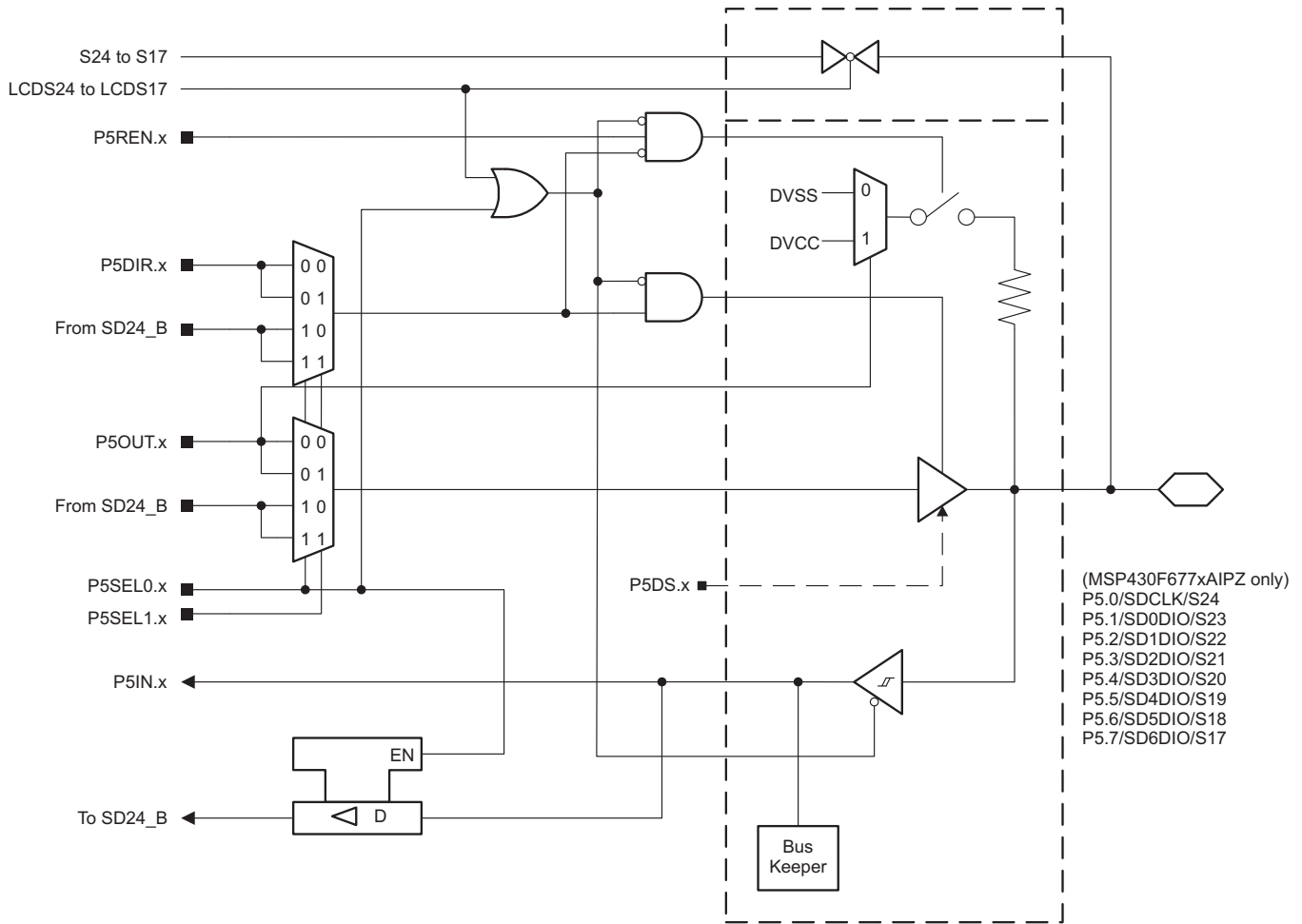


Figure 6-22. Port P5 (P5.0 to P5.7) Diagram (PZ Package Only)

Table 6-81. Port P5 (P5.0 to P5.7) Pin Function (PZ Package Only)

| PIN NAME (P5.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | | |
|-----------------|---|----------------------------|--|----------|----------|------------------|
| | | | P5DIR.x | P5SEL1.x | P5SEL0.x | LCDS24 to LCDS17 |
| P5.0/SDCLK/S24 | 0 | P5.0 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | Secondary digital function | X | X | 1 | 0 |
| | | S24 | X | X | X | 1 |
| P5.1/SD0DIO/S23 | 1 | P5.1 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | Secondary digital function | X | X | 1 | 0 |
| | | S23 | X | X | X | 1 |
| P5.2/SD1DIO/S22 | 2 | P5.2 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | Secondary digital function | X | X | 1 | 0 |
| | | S22 | X | X | X | 1 |
| P5.3/SD2DIO/S21 | 3 | P5.3 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | Secondary digital function | X | X | 1 | 0 |
| | | S21 | X | X | X | 1 |
| P5.4/SD3DIO/S20 | 4 | P5.4 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | Secondary digital function | X | X | 1 | 0 |
| | | S20 | X | X | X | 1 |
| P5.5/SD4DIO/S19 | 5 | P5.5 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | Secondary digital function | X | X | 1 | 0 |
| | | S19 | X | X | X | 1 |
| P5.6/SD5DIO/S18 | 6 | P5.6 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | Secondary digital function | X | X | 1 | 0 |
| | | S18 | X | X | X | 1 |
| P5.7/SD6DIO/S17 | 7 | P5.7 (I/O) | I:0; O:1 | X | 0 | 0 |
| | | Secondary digital function | X | X | 1 | 0 |
| | | S17 | X | X | X | 1 |

(1) X = don't care

6.12.18 Port P6 (P6.0) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-23 shows the port diagram. Table 6-82 summarizes the selection of the pin functions.

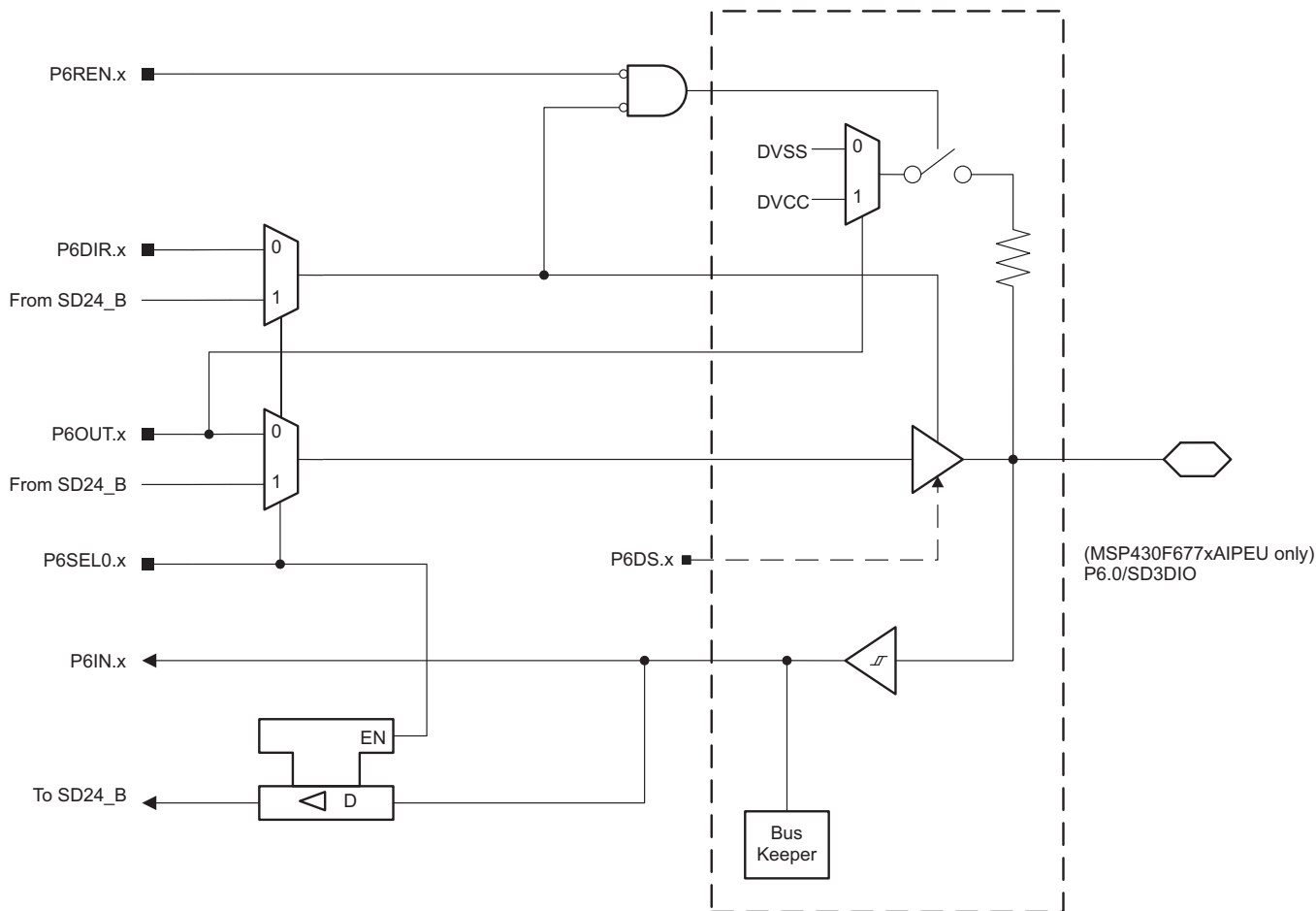


Figure 6-23. Port P6 (P6.0) Diagram (PEU Package Only)

Table 6-82. Port P6 (P6.0) Pin Functions (PEU Package Only)

| PIN NAME (P6.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | |
|-----------------|---|----------------------------|--|----------|
| | | | P6DIR.x | P6SEL0.x |
| P6.0/SD3DIO | 0 | P6.0 (I/O) | I:0; O:1 | 0 |
| | | Secondary digital function | X | 1 |

(1) X = don't care

6.12.19 Port P6 (P6.1 to P6.3) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-24 shows the port diagram. Table 6-83 summarizes the selection of the pin functions.

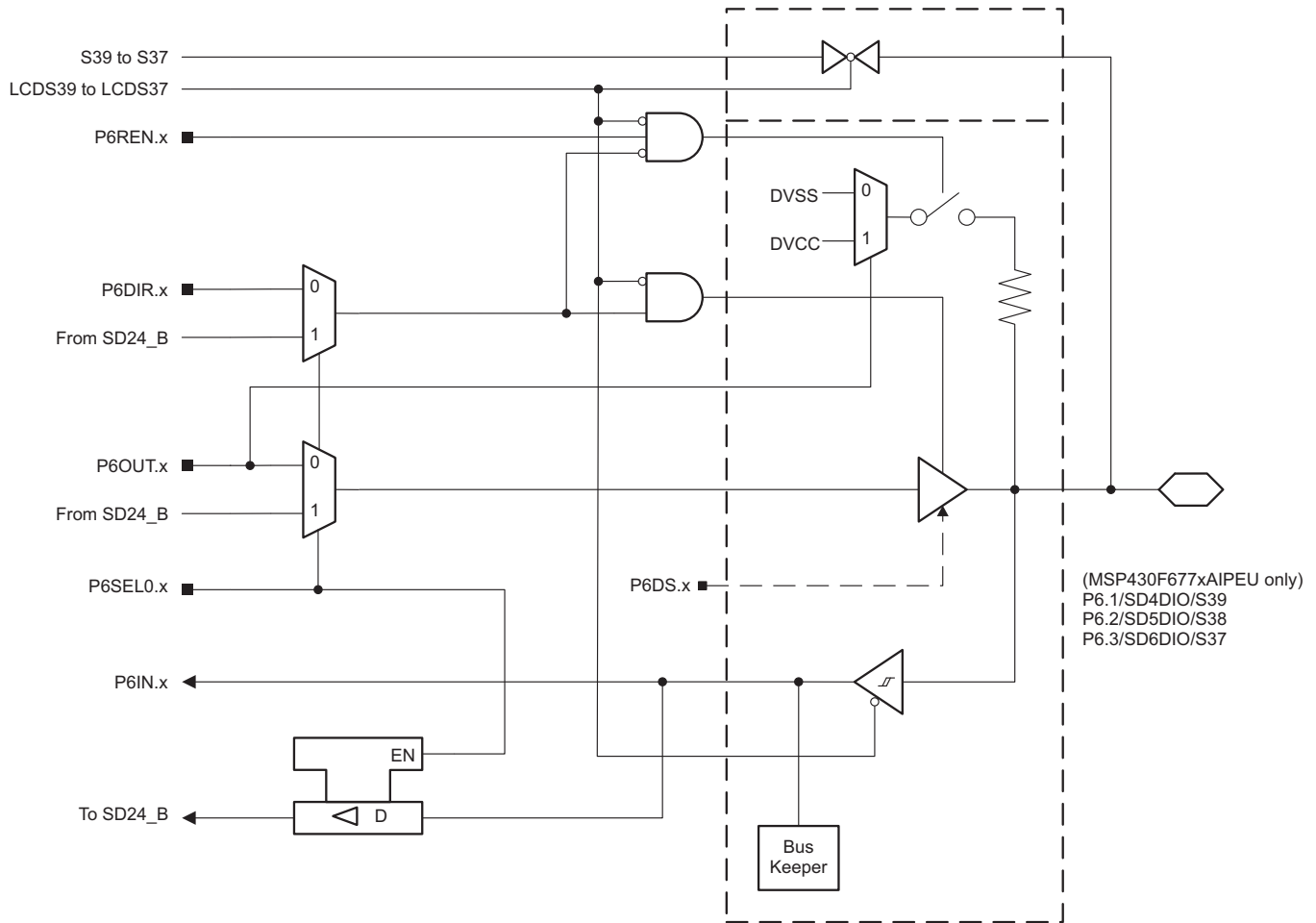


Figure 6-24. Port P6 (P6.1 to P6.3) Diagram (PEU Package Only)

Table 6-83. Port P6 (P6.1 to P6.3) Pin Functions (PEU Package Only)

| PIN NAME (P6.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|-----------------|---|----------------------------|--|----------|-----------------|
| | | | P6DIR.x | P6SEL0.x | LCD39 to LCDS37 |
| P6.1/SD4DIO/S39 | 1 | P6.1 (I/O) | I:0; O:1 | 0 | 0 |
| | | Secondary digital function | X | 1 | 0 |
| | | S39 | X | X | 1 |
| P6.2/SD5DIO/S38 | 2 | P6.2 (I/O) | I:0; O:1 | 0 | 0 |
| | | Secondary digital function | X | 1 | 0 |
| | | S38 | X | X | 1 |
| P6.3/SD6DIO/S37 | 3 | P6.3 (I/O) | I:0; O:1 | 0 | 0 |
| | | Secondary digital function | X | 1 | 0 |
| | | S37 | X | X | 1 |

(1) X = don't care

6.12.20 Port P6 (P6.4 to P6.7) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-25 shows the port diagram. Table 6-84 summarizes the selection of the pin functions.

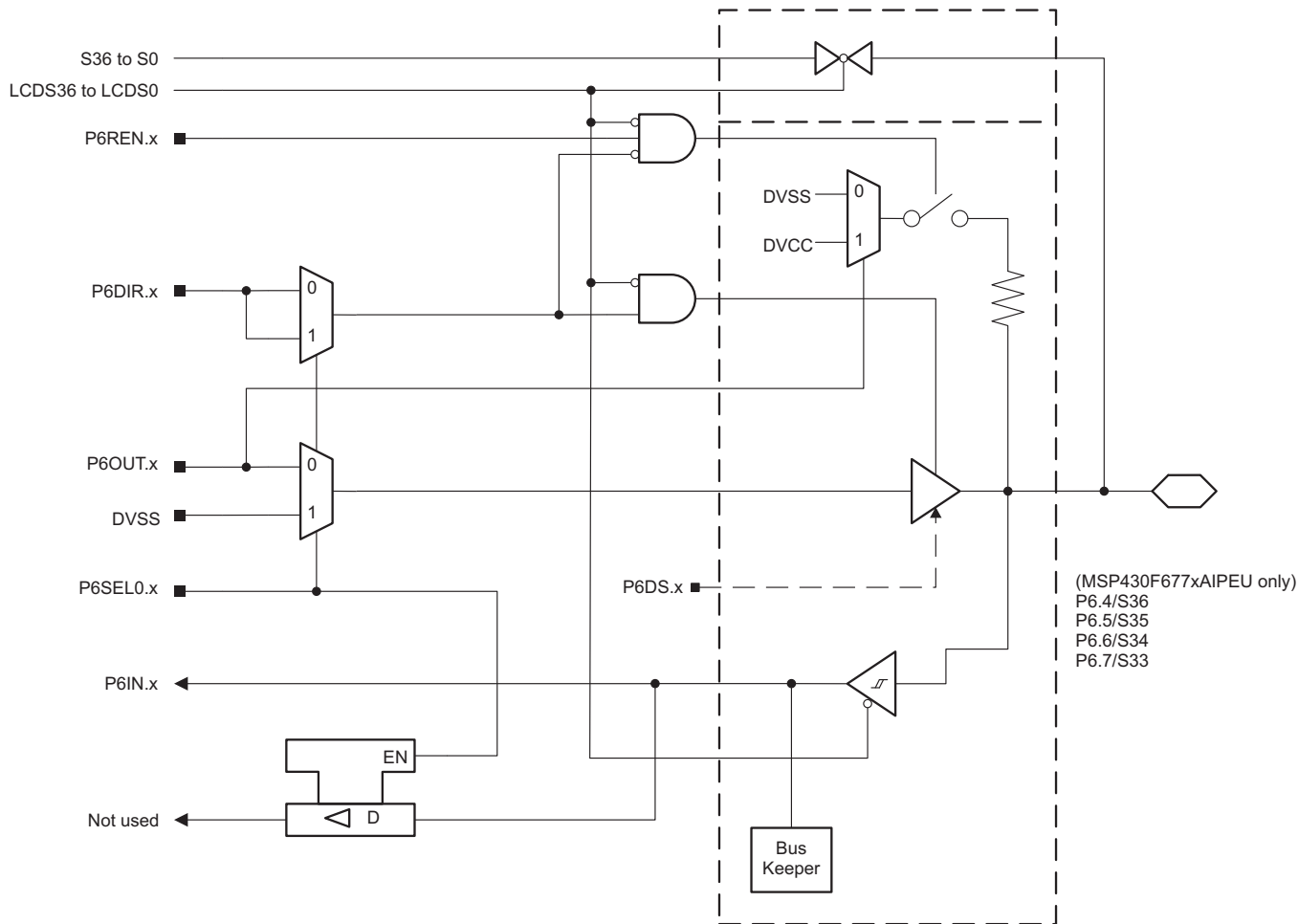


Figure 6-25. Port P6 (P6.4 to P6.7) Diagram (PEU Package Only)

Table 6-84. Port P6 (P6.4 to P6.7) Pin Functions (PEU Package Only)

| PIN NAME (P6.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|-----------------|---|------------|--|----------|------------------|
| | | | P6DIR.x | P6SEL0.x | LCDS36 to LCDS33 |
| P6.4/S36 | 4 | P6.4 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S36 | X | X | 1 |
| P6.5/S35 | 5 | P6.5 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S35 | X | X | 1 |
| P6.6/S34 | 6 | P6.6 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S34 | X | X | 1 |
| P6.7/S33 | 7 | P6.7 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S33 | X | X | 1 |

(1) X = don't care

6.12.21 Port P6 (P6.0 to P6.7) Input/Output With Schmitt Trigger (PZ Package Only)

Figure 6-26 shows the port diagram. Table 6-85 summarizes the selection of the pin functions.

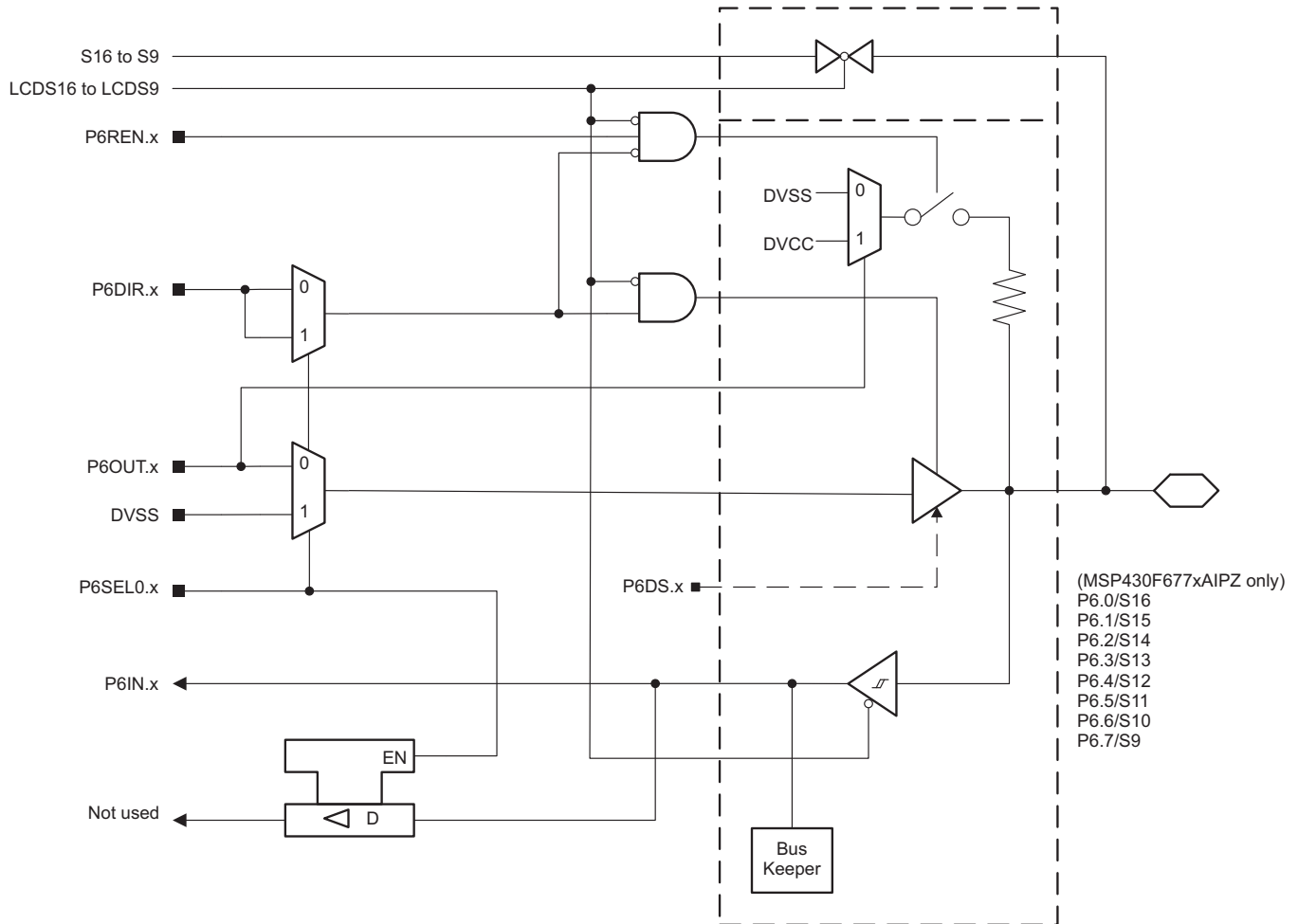


Figure 6-26. Port P6 (P6.0 to P6.7) Diagram (PZ Package Only)

Table 6-85. Port P6 (P6.0 to P6.7) Pin Functions (PZ Package Only)

| PIN NAME (P6.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|-----------------|---|------------|--|----------|-----------------|
| | | | P6DIR.x | P6SEL0.x | LCDS16 to LCDS9 |
| P6.0/S16 | 0 | P6.0 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S16 | X | X | 1 |
| P6.1/S15 | 1 | P6.1 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S15 | X | X | 1 |
| P6.2/S14 | 2 | P6.2 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S14 | X | X | 1 |
| P6.3/S13 | 3 | P6.3 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S13 | X | X | 1 |
| P6.4/S12 | 4 | P6.4 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S12 | X | X | 1 |
| P6.5/S11 | 5 | P6.5 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S11 | X | X | 1 |
| P6.6/S10 | 6 | P6.6 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S10 | X | X | 1 |
| P6.7/S9 | 7 | P6.7 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S9 | X | X | 1 |

(1) X = don't care

6.12.22 Port P7 (P7.0 to P7.7) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-27 shows the port diagram. Table 6-86 summarizes the selection of the pin functions.

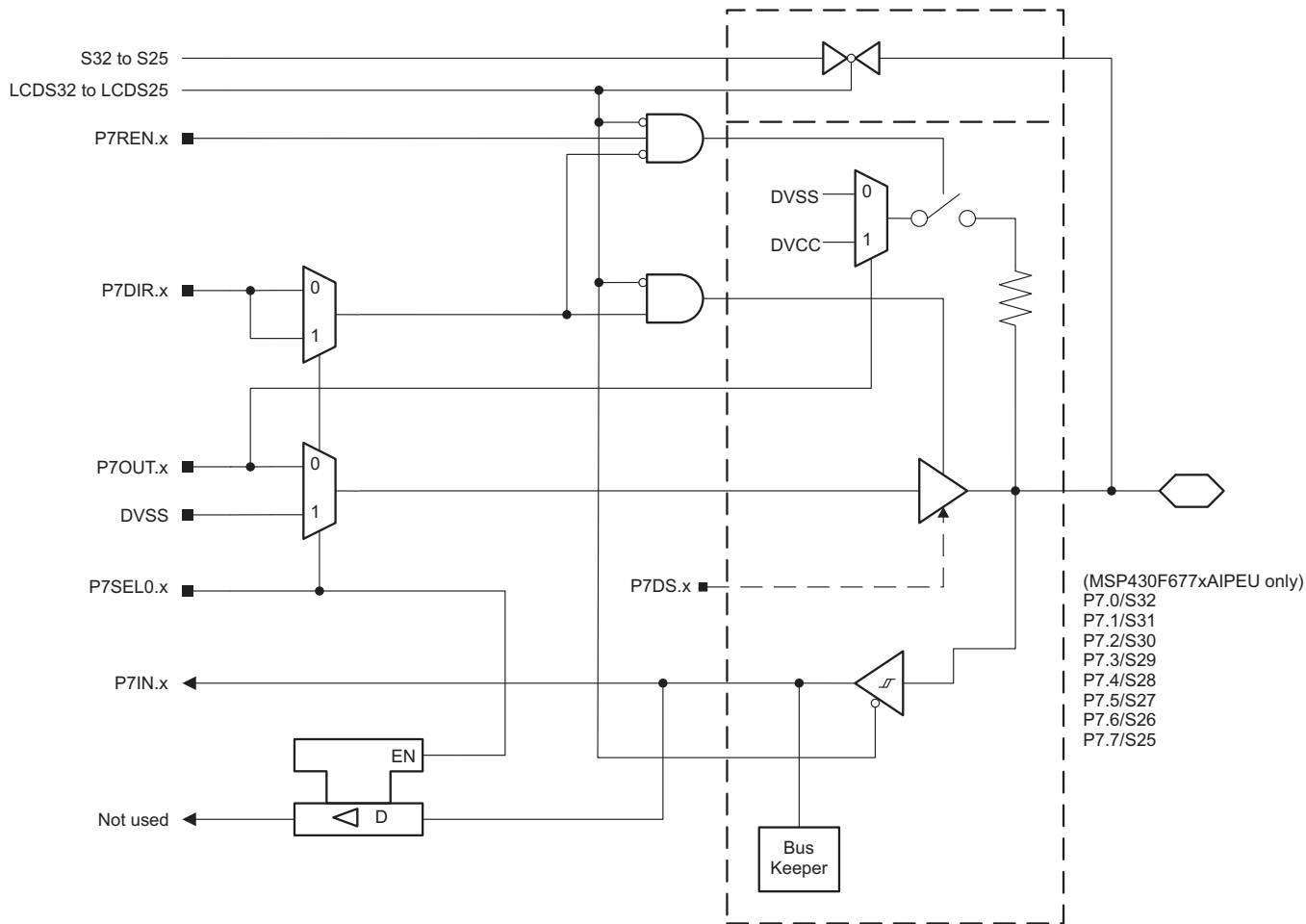


Figure 6-27. Port P7 (P7.0 to P7.7) Diagram (PEU Package Only)

Table 6-86. Port P7 (P7.0 to P7.7) Pin Functions (PEU Package Only)

| PIN NAME (P7.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|-----------------|---|------------|--|----------|------------------|
| | | | P7DIR.x | P7SEL0.x | LCDS32 to LCDS25 |
| P7.0/S32 | 0 | P7.0 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S32 | X | X | 1 |
| P7.1/S31 | 1 | P7.1 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S31 | X | X | 1 |
| P7.2/S30 | 2 | P7.2 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S30 | X | X | 1 |
| P7.3/S29 | 3 | P7.3 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S29 | X | X | 1 |
| P7.4/S28 | 4 | P7.4 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S28 | X | X | 1 |
| P7.5/S27 | 5 | P7.5 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S27 | X | X | 1 |
| P7.6/S26 | 6 | P7.6 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S26 | X | X | 1 |
| P7.7/S25 | 7 | P7.7 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S25 | X | X | 1 |

(1) X = don't care

6.12.23 Port P7 (P7.0 to P7.7) Input/Output With Schmitt Trigger (PZ Package Only)

Figure 6-28 shows the port diagram. Table 6-87 summarizes the selection of the pin functions.

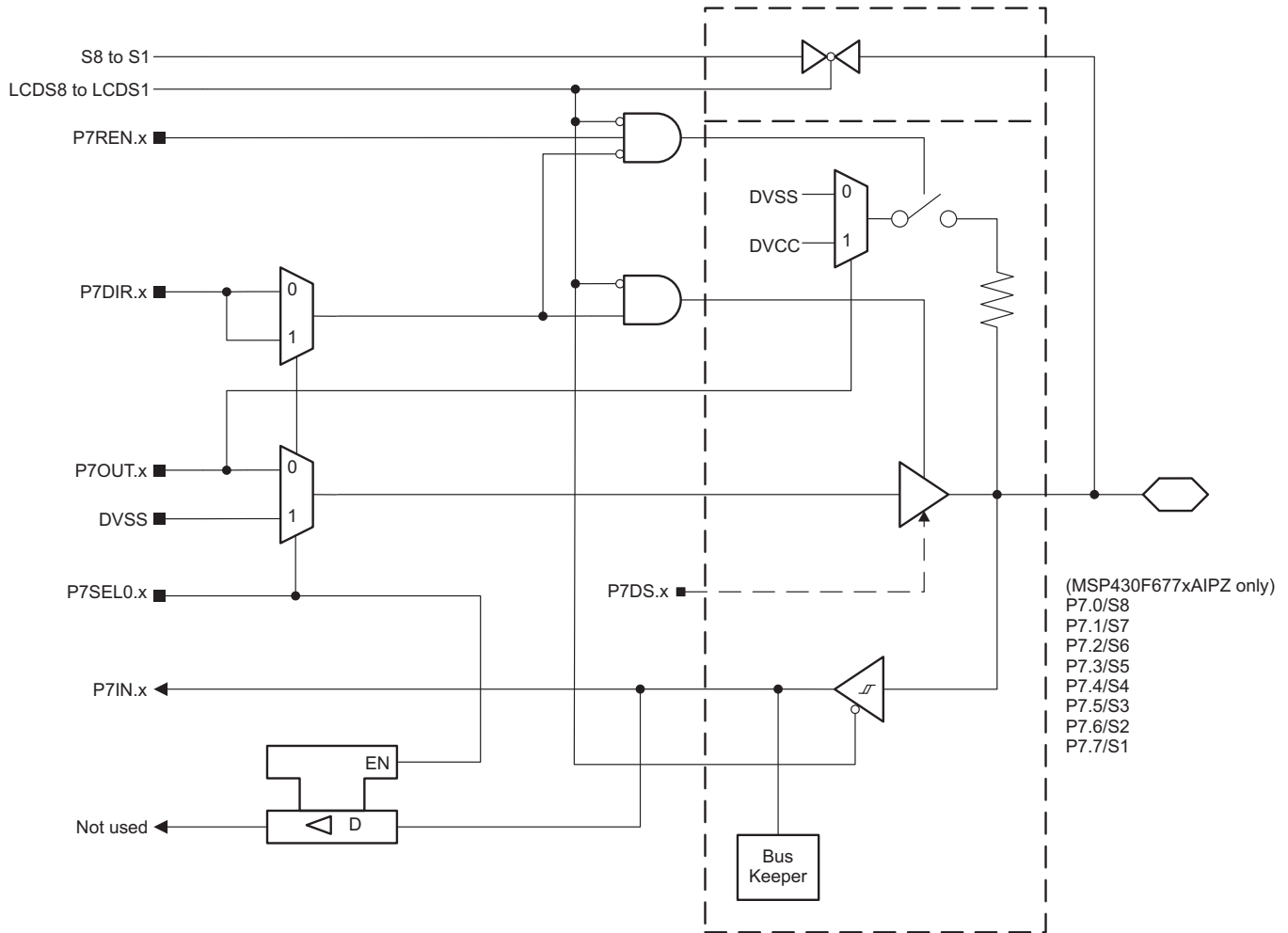


Figure 6-28. Port P7 (P7.0 to P7.7) Diagram (PZ Package Only)

Table 6-87. Port P7 (P7.0 to P7.7) Pin Functions (PZ Package Only)

| PIN NAME (P7.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|-----------------|---|------------|--|----------|----------------|
| | | | P7DIR.x | P7SEL0.x | LCDS8 to LCDS1 |
| P7.0/S8 | 0 | P7.0 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S8 | X | X | 1 |
| P7.1/S7 | 1 | P7.1 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S7 | X | X | 1 |
| P7.2/S6 | 2 | P7.2 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S6 | X | X | 1 |
| P7.3/S5 | 3 | P7.3 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S5 | X | X | 1 |
| P7.4/S4 | 4 | P7.4 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S4 | X | X | 1 |
| P7.5/S3 | 5 | P7.5 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S3 | X | X | 1 |
| P7.6/S2 | 6 | P7.6 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S2 | X | X | 1 |
| P7.7/S1 | 7 | P7.7 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S1 | X | X | 1 |

(1) X = don't care

6.12.24 Port P8 (P8.0 to P8.7) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-29 shows the port diagram. Table 6-88 summarizes the selection of the pin functions.

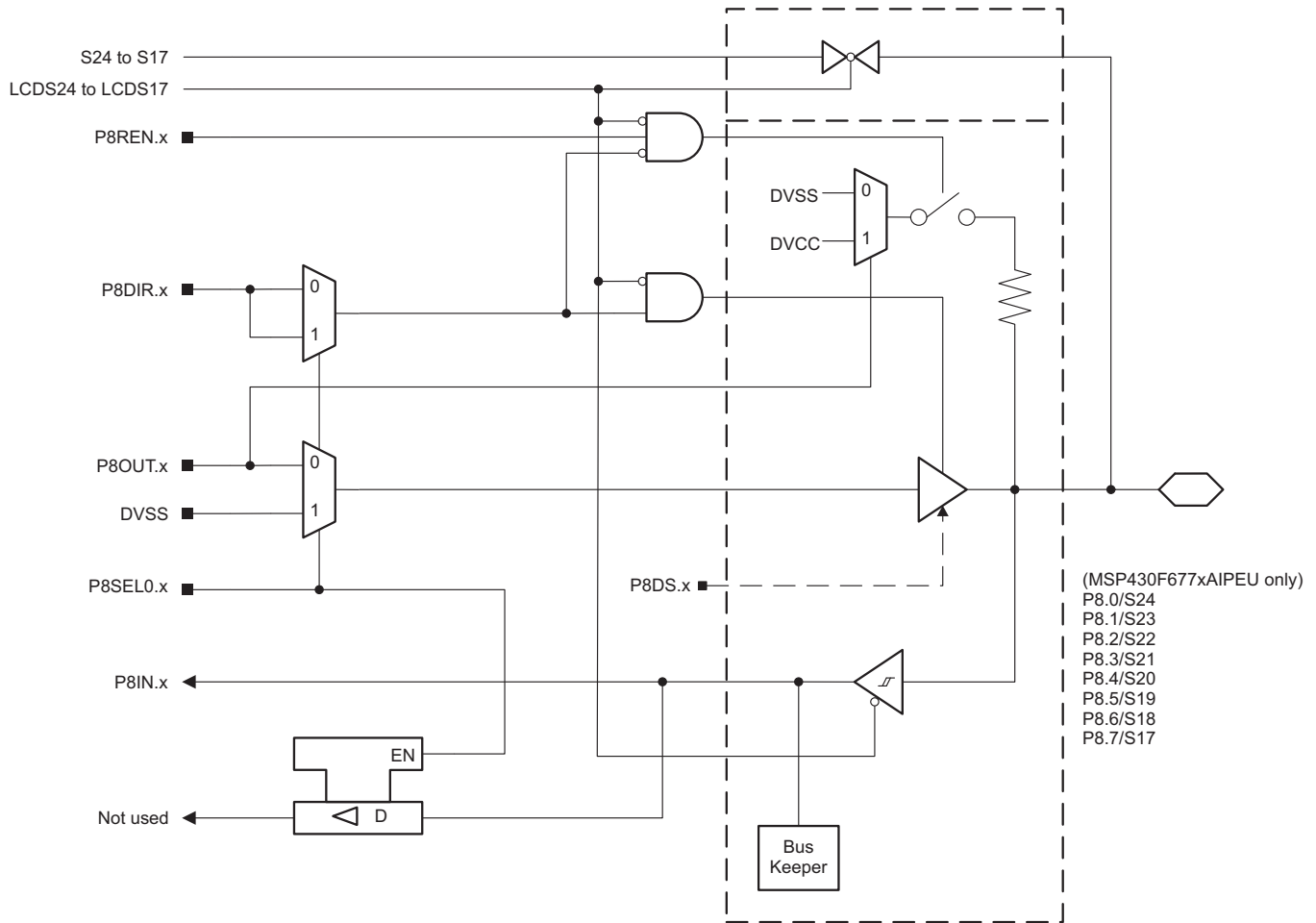


Figure 6-29. Port P8 (P8.0 to P8.7) Diagram (PEU Package Only)

Table 6-88. Port P8 (P8.0 to P8.7) Pin Functions (PEU Package Only)

| PIN NAME (P8.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|-----------------|---|------------|--|----------|------------------|
| | | | P8DIR.x | P8SEL0.x | LCDS24 to LCDS17 |
| P8.0/S24 | 0 | P8.0 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S24 | X | X | 1 |
| P8.1/S23 | 1 | P8.1 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S23 | X | X | 1 |
| P8.2/S22 | 2 | P8.2 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S22 | X | X | 1 |
| P8.3/S21 | 3 | P8.3 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S21 | X | X | 1 |
| P8.4/S20 | 4 | P8.4 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S20 | X | X | 1 |
| P8.5/S19 | 5 | P8.5 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S19 | X | X | 1 |
| P8.6/S18 | 6 | P8.6 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S18 | X | X | 1 |
| P8.7/S17 | 7 | P8.7 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S17 | X | X | 1 |

(1) X = don't care

6.12.25 Port P8 (P8.0) Input/Output With Schmitt Trigger (PZ Package Only)

Figure 6-30 shows the port diagram. Table 6-89 summarizes the selection of the pin functions.

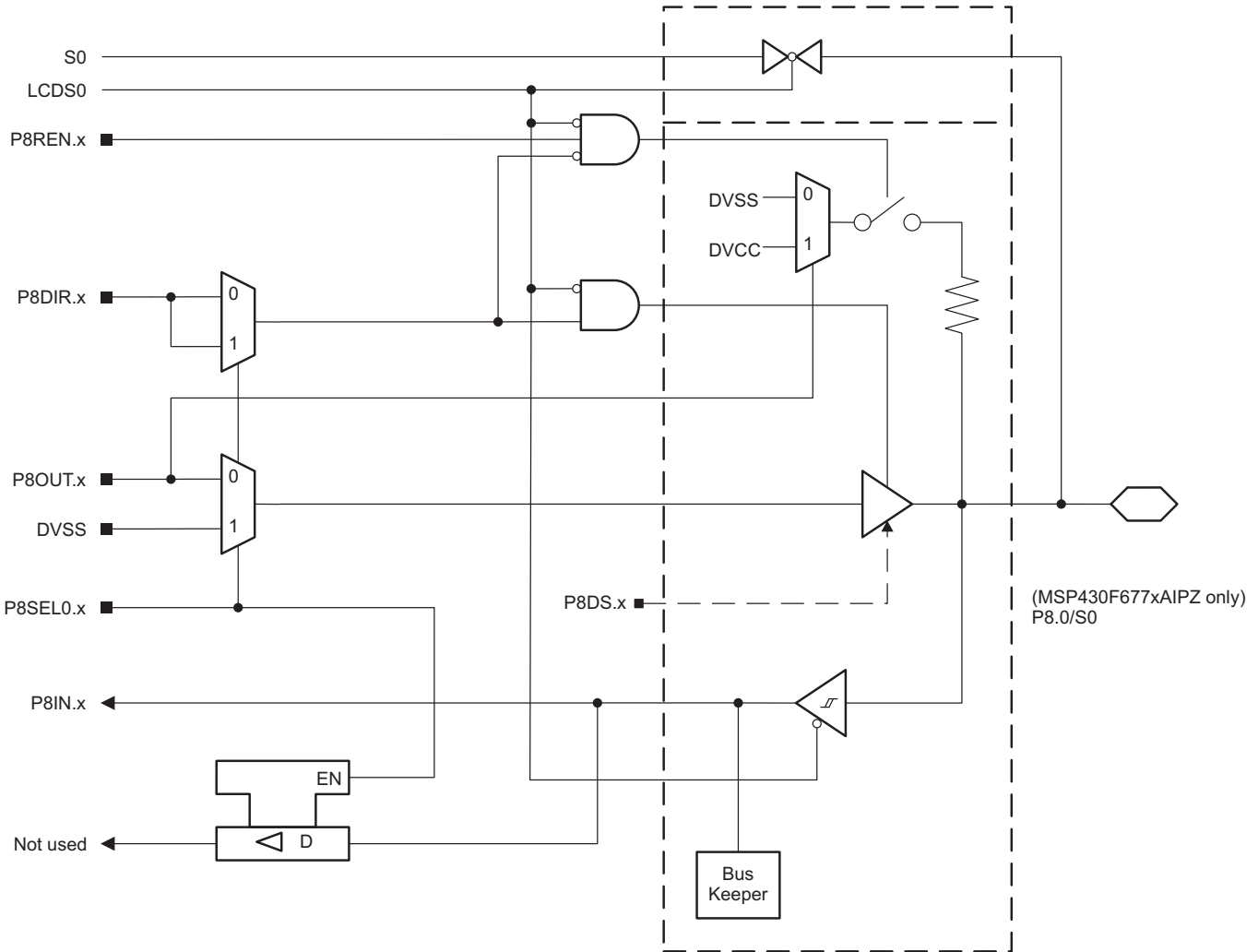


Figure 6-30. Port P8 (P8.0) Diagram (PZ Package Only)

Table 6-89. Port P8 (P8.0) Pin Functions (PZ Package Only)

| PIN NAME (P8.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|-----------------|---|------------|--|----------|-------|
| | | | P8DIR.x | P8SEL0.x | LCDS0 |
| P8.0/S0 | 0 | P8.0 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S0 | X | X | 1 |

(1) X = don't care

6.12.26 Port P8 (P8.1) Input/Output With Schmitt Trigger (PZ Package Only)

Figure 6-31 shows the port diagram. Table 6-90 summarizes the selection of the pin functions.

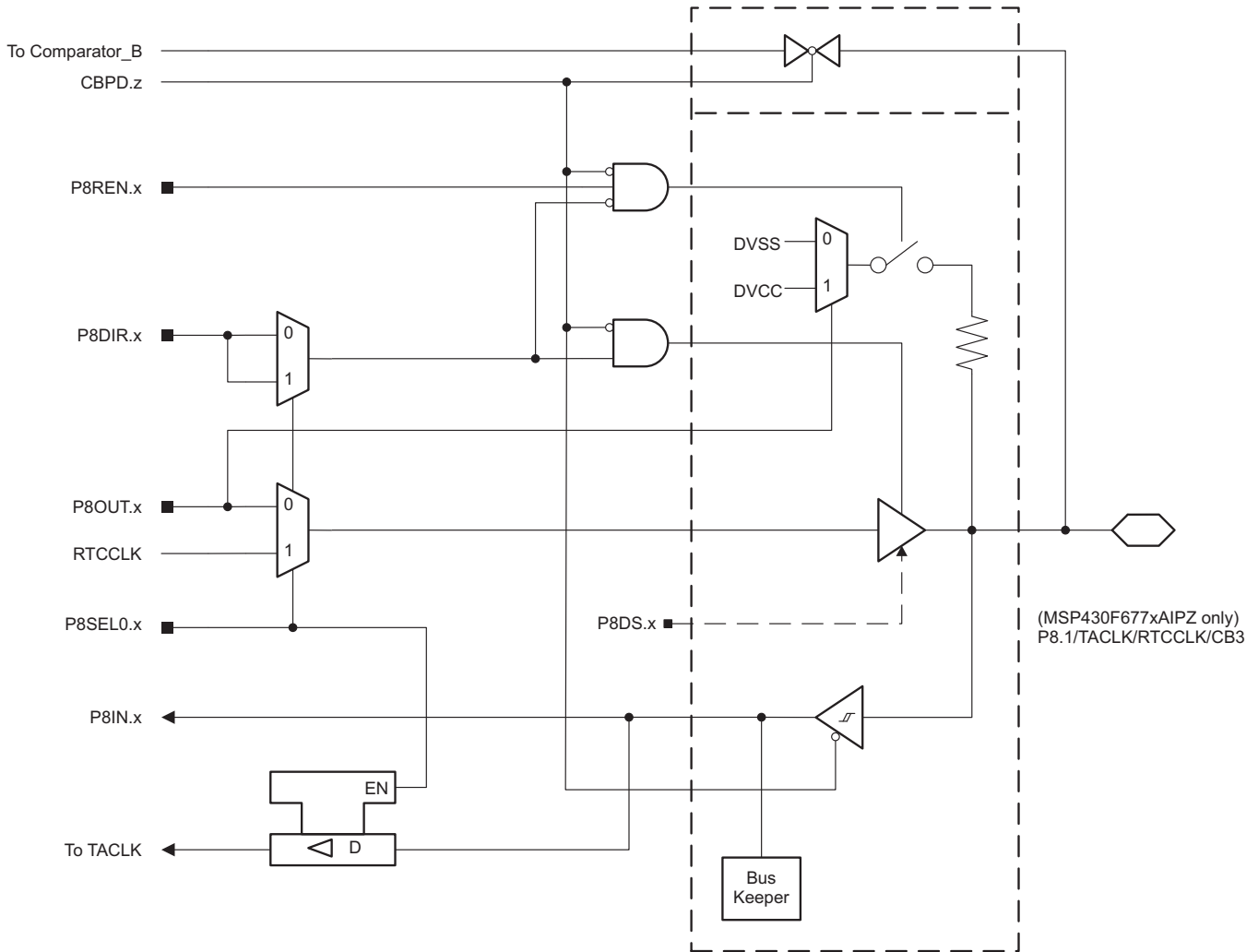


Figure 6-31. Port P8 (P8.1) Diagram (PZ Package Only)

Table 6-90. Port P8 (P8.1) Pin Functions (PZ Package Only)

| PIN NAME (P8.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|-----------------------|---|------------|--|----------|-----------|
| | | | P8DIR.x | P8SEL0.x | CBPD.z |
| P8.1/TACLK/RTCCLK/CB3 | 1 | P8.1 (I/O) | I:0; O:1 | 0 | 0 |
| | | TACLK | 0 | 1 | 0 |
| | | RTCCLK | 1 | 1 | 0 |
| | | CB3 | X | X | 1 (z = 3) |

(1) X = don't care

6.12.27 Port P9 (P9.0 to P9.7) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-32 shows the port diagram. Table 6-91 summarizes the selection of the pin functions.

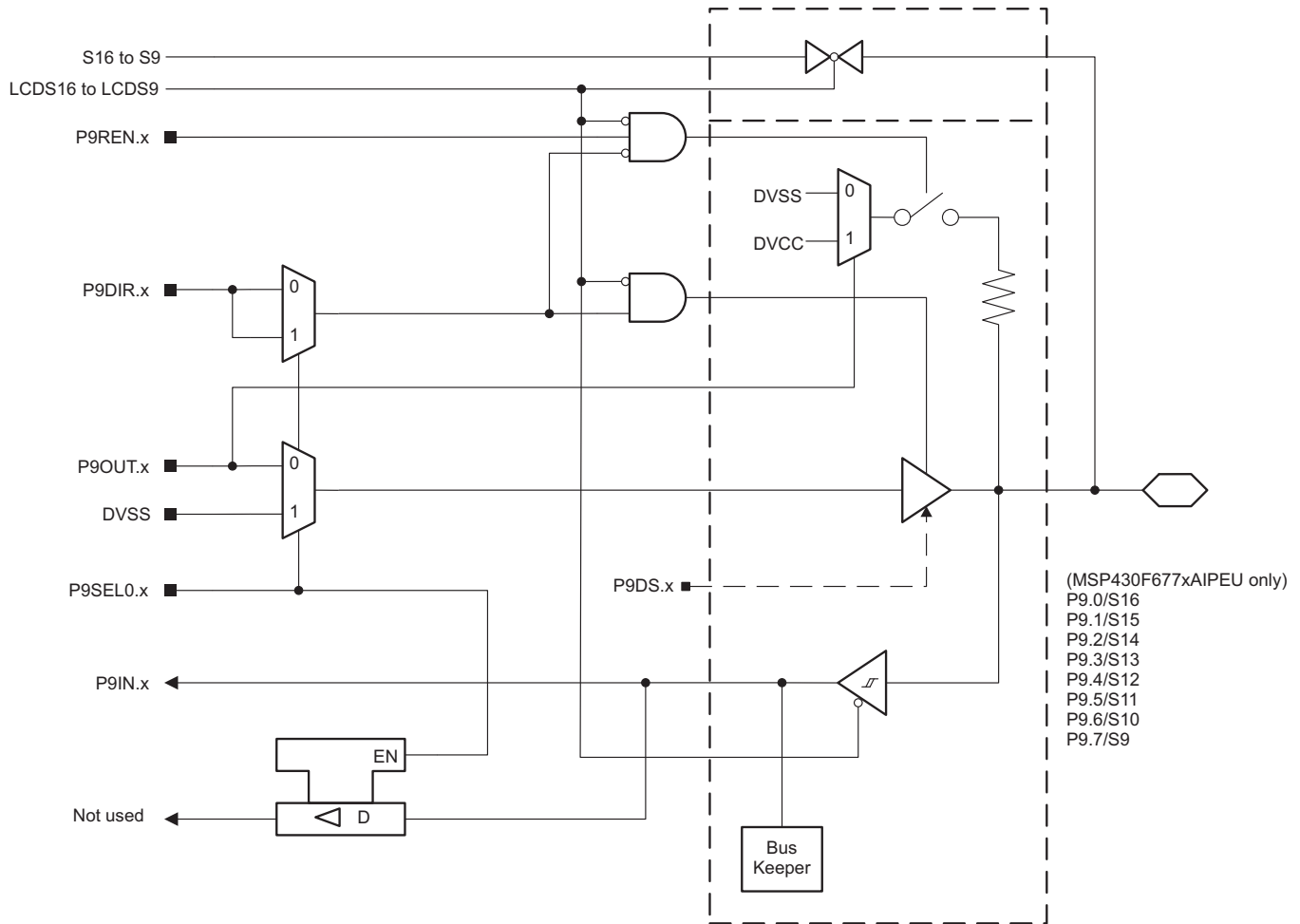


Figure 6-32. Port P9 (P9.0 to P9.7) Diagram (PEU Package Only)

Table 6-91. Port P9 (P9.0 to P9.7) Pin Functions (PEU Package Only)

| PIN NAME (P9.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|-----------------|---|------------|--|----------|-----------------|
| | | | P9DIR.x | P9SEL0.x | LCDS16 to LCDS9 |
| P9.0/S16 | 0 | P9.0 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S16 | X | X | 1 |
| P9.1/S15 | 1 | P9.1 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S15 | X | X | 1 |
| P9.2/S14 | 2 | P9.2 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S14 | X | X | 1 |
| P9.3/S13 | 3 | P9.3 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S13 | X | X | 1 |
| P9.4/S12 | 4 | P9.4 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S12 | X | X | 1 |
| P9.5/S11 | 5 | P9.5 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S11 | X | X | 1 |
| P9.6/S10 | 6 | P9.6 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S10 | X | X | 1 |
| P9.7/S9 | 7 | P9.7 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S9 | X | X | 1 |

(1) X = don't care

6.12.28 Port P10 (P10.0 to P10.7) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-33 shows the port diagram. Table 6-92 summarizes the selection of the pin functions.

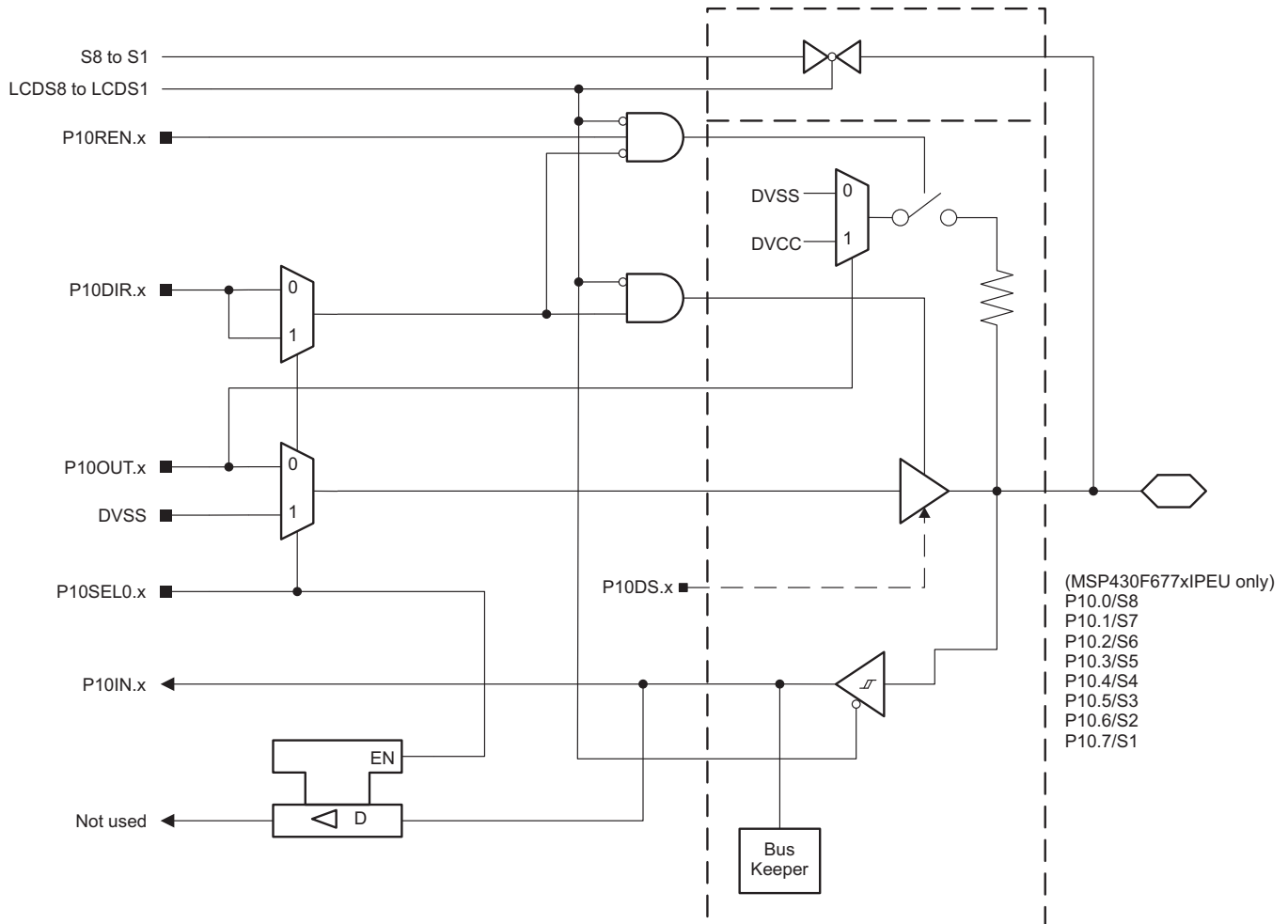


Figure 6-33. Port P10 (P10.0 to P10.7) Diagram (PEU Package Only)

Table 6-92. Port P10 (P10.0 to P10.7) Pin Functions (PEU Package Only)

| PIN NAME (P10.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|------------------|---|-------------|--|-----------|----------------|
| | | | P10DIR.x | P10SEL0.x | LCDS8 to LCDS1 |
| P10.0/S8 | 0 | P10.0 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S8 | X | X | 1 |
| P10.1/S7 | 1 | P10.1 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S7 | X | X | 1 |
| P10.2/S6 | 2 | P10.2 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S6 | X | X | 1 |
| P10.3/S5 | 3 | P10.3 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S5 | X | X | 1 |
| P10.4/S4 | 4 | P10.4 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S4 | X | X | 1 |
| P10.5/S3 | 5 | P10.5 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S3 | X | X | 1 |
| P10.6/S2 | 6 | P10.6 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S2 | X | X | 1 |
| P10.7/S1 | 7 | P10.7 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S1 | X | X | 1 |

(1) X = don't care

6.12.29 Port P11 (P11.0) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-34 shows the port diagram. Table 6-93 summarizes the selection of the pin functions.

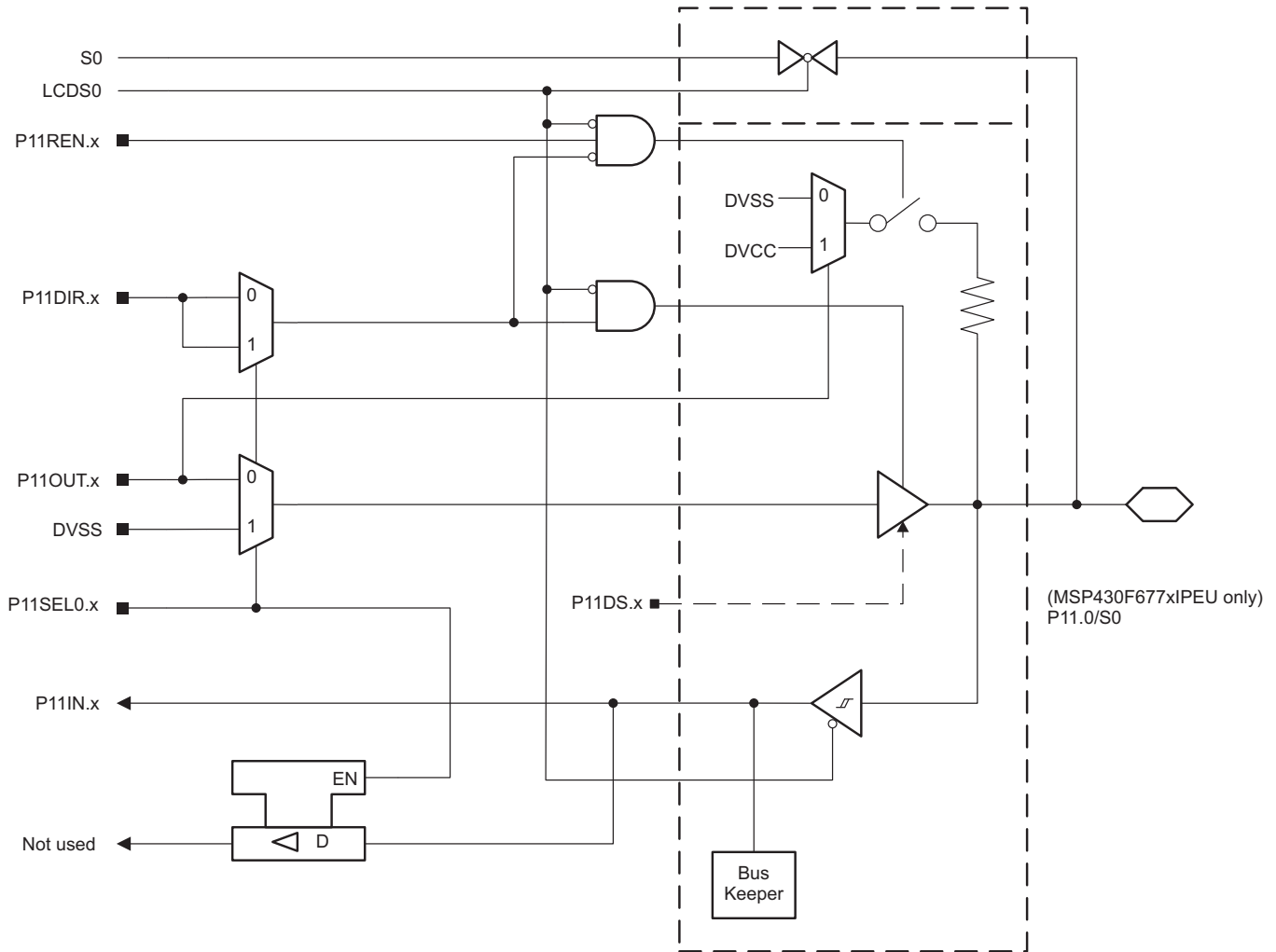


Figure 6-34. Port P11 (P11.0) Diagram (PEU Package Only)

Table 6-93. Port P11 (P11.0) Pin Functions (PEU Package Only)

| PIN NAME (P11.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|------------------|---|-------------|--|-----------|-------|
| | | | P11DIR.x | P11SEL0.x | LCDS0 |
| P11.0/S0 | 0 | P11.0 (I/O) | I:0; O:1 | 0 | 0 |
| | | N/A | 0 | 1 | 0 |
| | | DVSS | 1 | 1 | 0 |
| | | S0 | X | X | 1 |

(1) X = don't care

6.12.30 Port P11 (P11.1) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-35 shows the port diagram. Table 6-94 summarizes the selection of the pin functions.

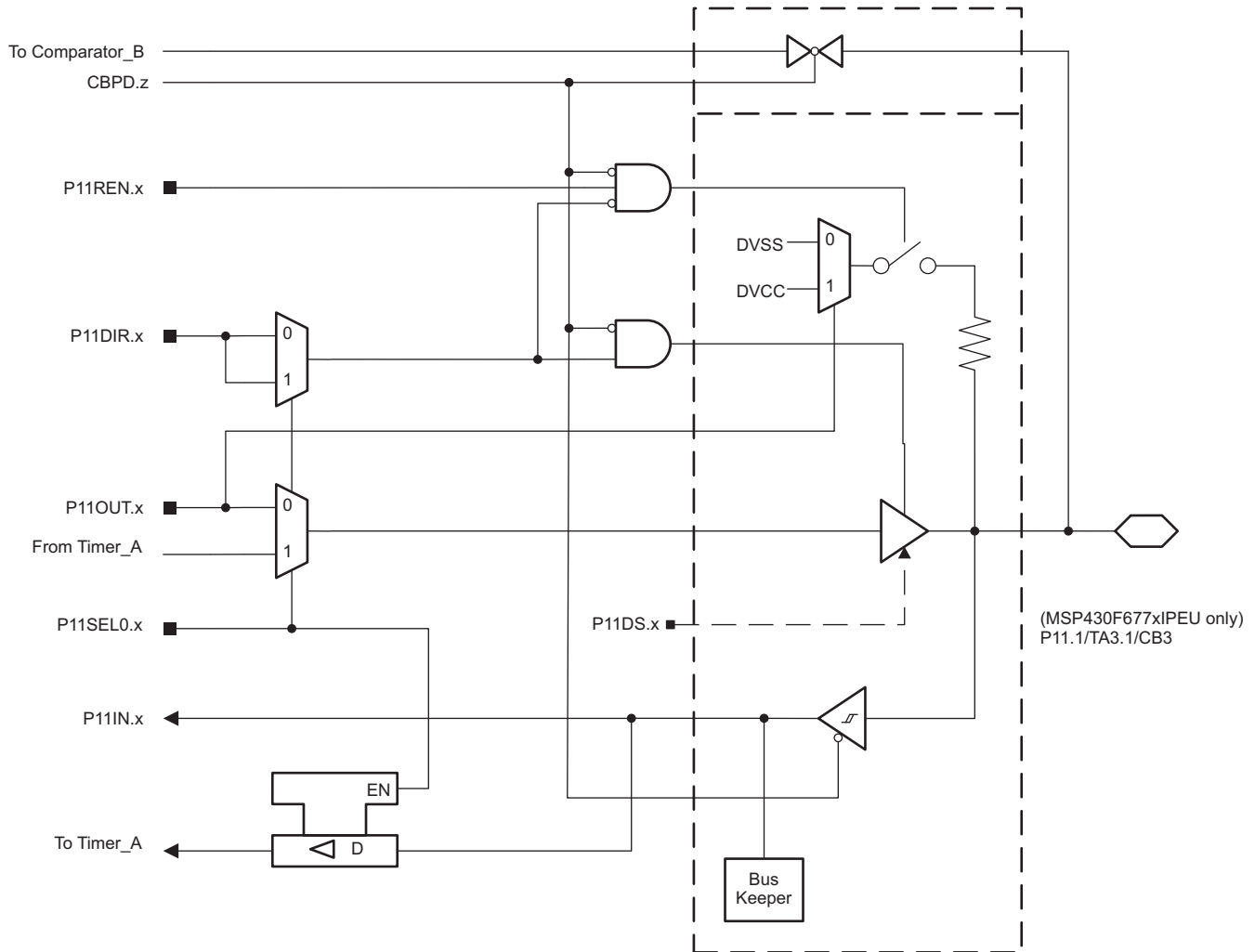


Figure 6-35. Port P11 (P11.1) Diagram (PEU Package Only)

Table 6-94. Port P11 (P11.1) Pin Functions (PEU Package Only)

| PIN NAME (P11.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|------------------|---|-------------|--|-----------|--------|
| | | | P11DIR.x | P11SEL0.x | CBPD.z |
| P11.1/TA3.1/CB3 | 1 | P11.1 (I/O) | I:0; O:1 | 0 | 0 |
| | | TA3.CCI1A | 0 | 1 | 0 |
| | | TA3.1 | 1 | 1 | 0 |
| | | CB3 | X | X | 1 |

(1) X = don't care

6.12.31 Port P11 (P11.2 and P11.3) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-36 shows the port diagram. Table 6-95 summarizes the selection of the pin functions.

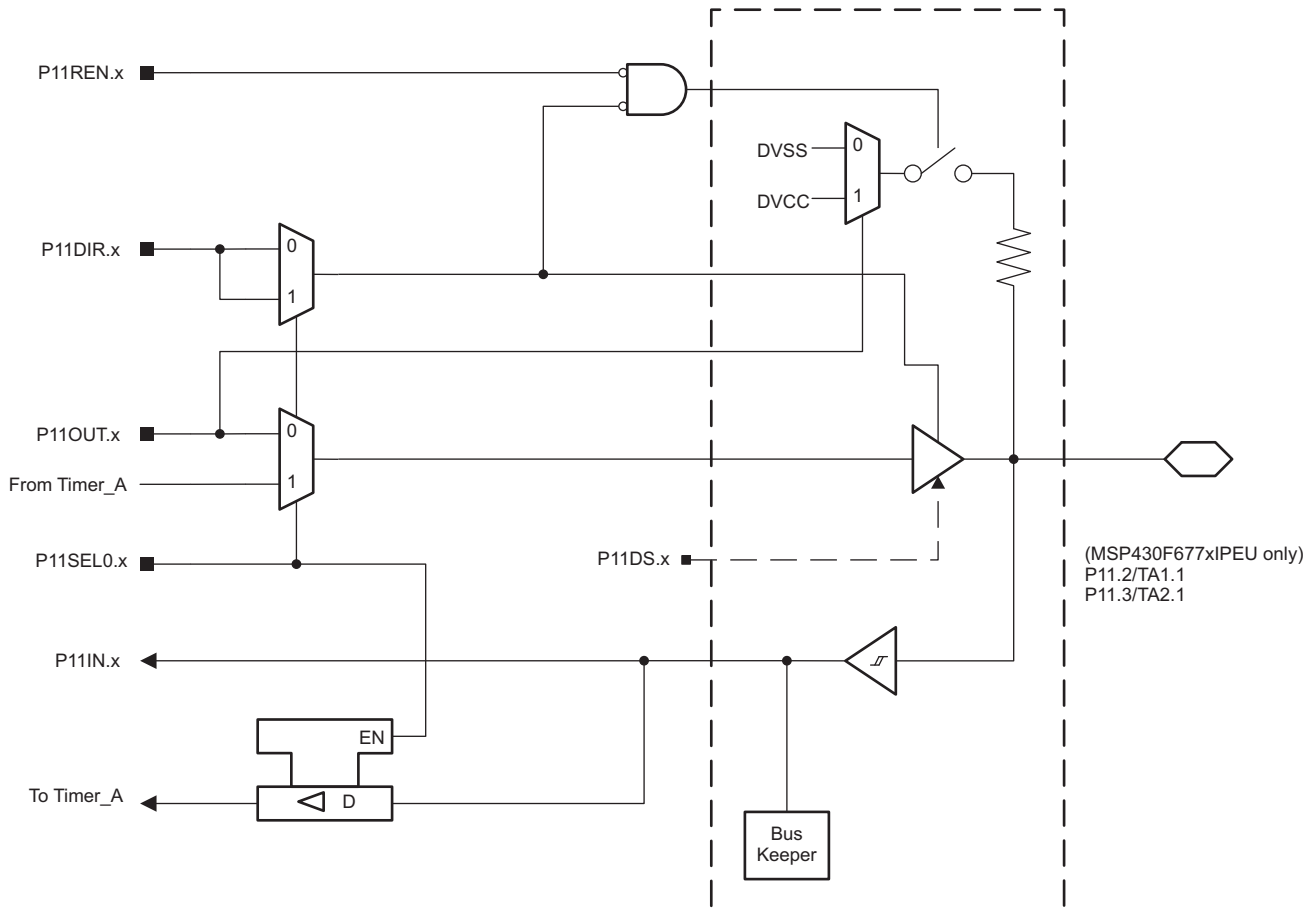


Figure 6-36. Port P11 (P11.2 and P11.3) Diagram (PEU Package Only)

Table 6-95. Port P11 (P11.2 and P11.3) Pin Functions (PEU Package Only)

| PIN NAME (P11.x) | x | FUNCTION | CONTROL BITS OR SIGNALS | |
|------------------|---|-------------|-------------------------|-----------|
| | | | P11DIR.x | P11SEL0.x |
| P11.2/TA1.1 | 2 | P11.2 (I/O) | I:0; O:1 | 0 |
| | | TA1.CCI1A | 0 | 1 |
| | | TA1.1 | 1 | 1 |
| P11.3/TA2.1 | 3 | P11.3 (I/O) | I:0; O:1 | 0 |
| | | TA2.CCI1A | 0 | 1 |
| | | TA2.1 | 1 | 1 |

6.12.32 Port P11 (P11.4 and P11.5) Input/Output With Schmitt Trigger (PEU Package Only)

Figure 6-37 shows the port diagram. Table 6-96 summarizes the selection of the pin functions.

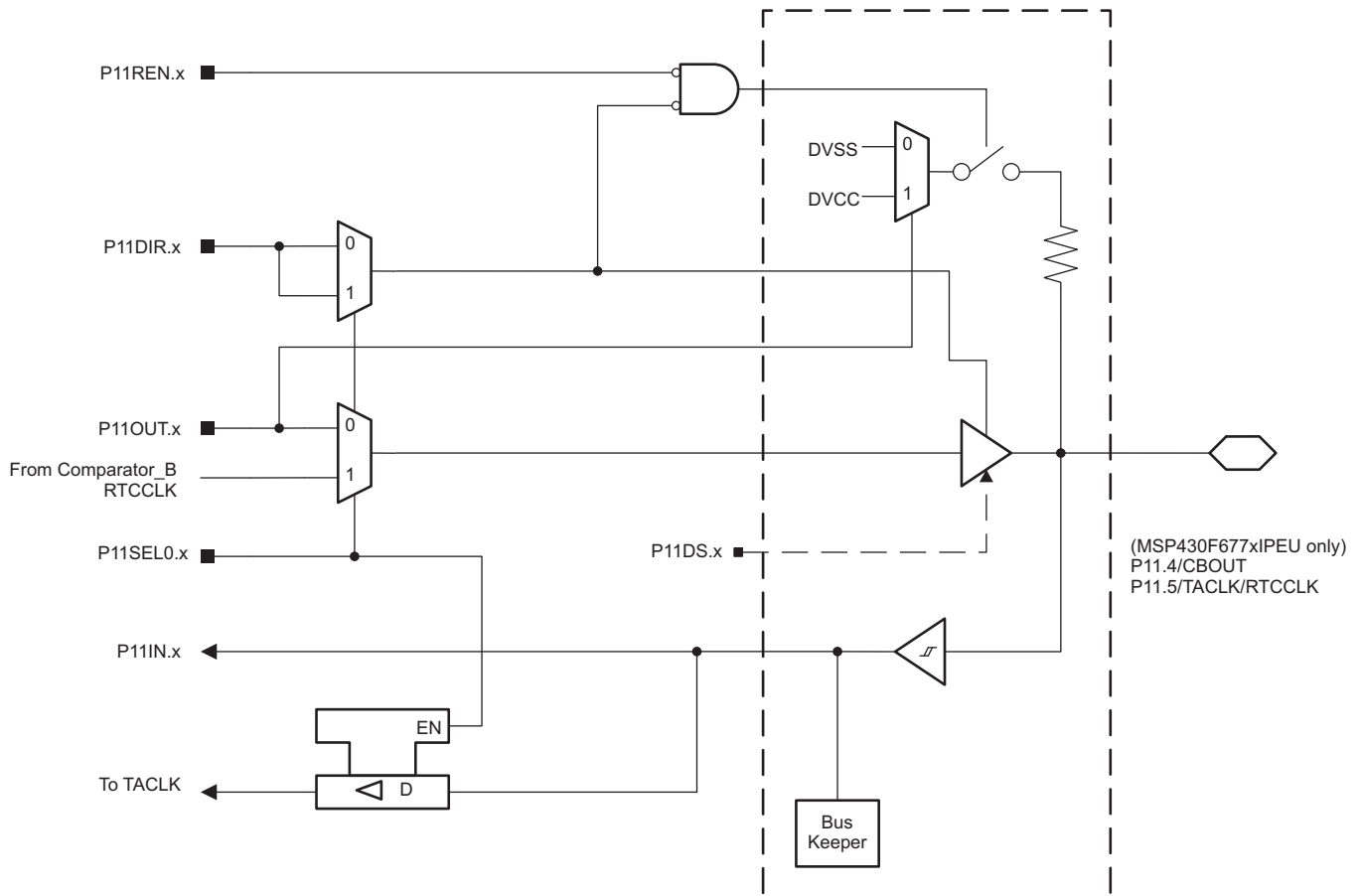


Figure 6-37. Port P11 (P11.4 and P11.5) Diagram (PEU Package Only)

Table 6-96. Port P11 (P11.4 and P11.5) Pin Functions (PEU Package Only)

| PIN NAME (P11.x) | x | FUNCTION | CONTROL BITS OR SIGNALS | |
|---------------------|---|-------------|-------------------------|-----------|
| | | | P11DIR.x | P11SEL0.x |
| P11.4/CBOUT | 4 | P11.4 (I/O) | I:0; O:1 | 0 |
| | | N/A | 0 | 1 |
| | | CBOUT | 1 | 1 |
| P11.5/TACLK/RTCCCLK | 5 | P11.5 (I/O) | I:0; O:1 | 0 |
| | | TACLK | 0 | 1 |
| | | RTCCCLK | 1 | 1 |

6.12.33 Port PJ (PJ.0) JTAG Pin TDO, Input/Output With Schmitt Trigger or Output

Figure 6-38 shows the port diagram. Table 6-97 summarizes the selection of the pin functions.

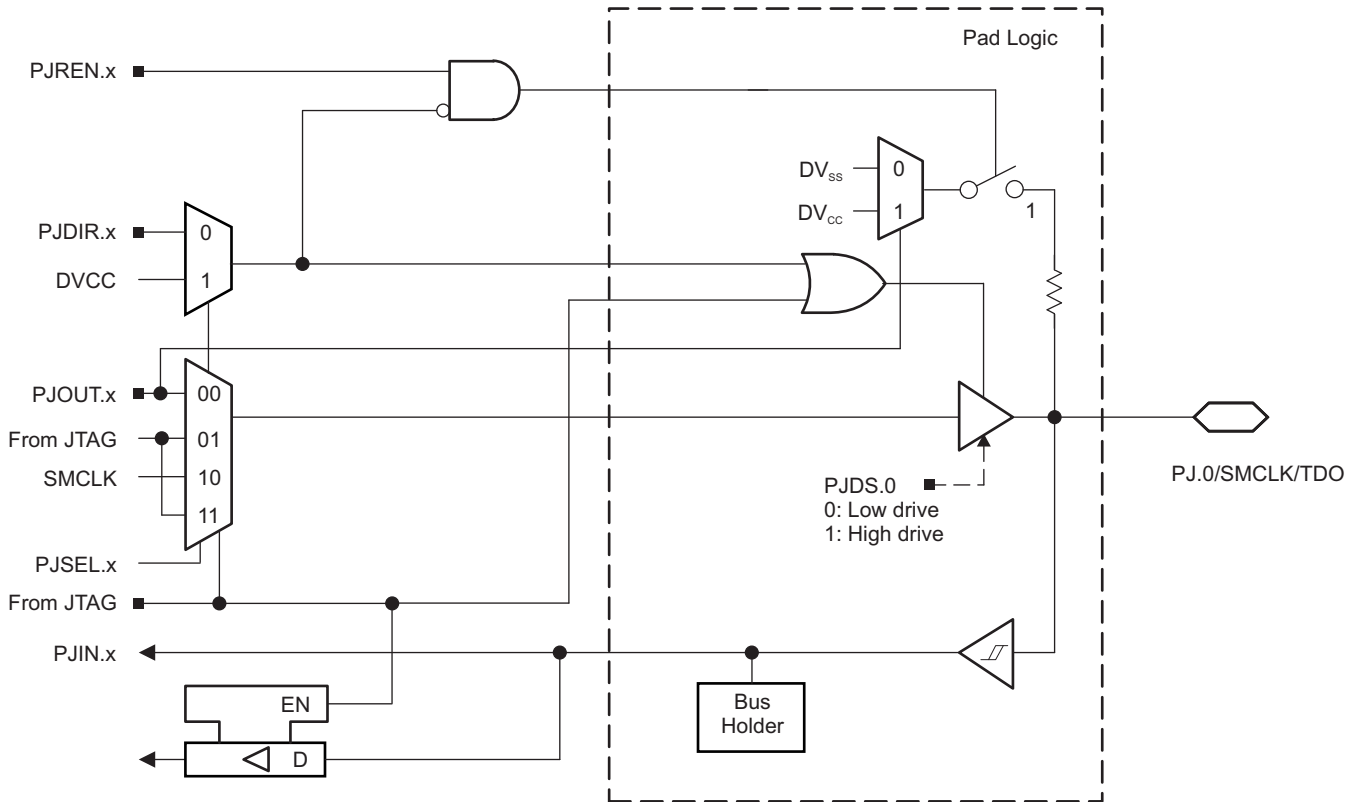


Figure 6-38. Port PJ (PJ.0) Diagram

6.12.34 Port PJ (PJ.0 to PJ.3) JTAG Pins TMS, TCK, TDI/TCLK, Input/Output With Schmitt Trigger or Output

Figure 6-39 shows the port diagram. Table 6-97 summarizes the selection of the pin functions.

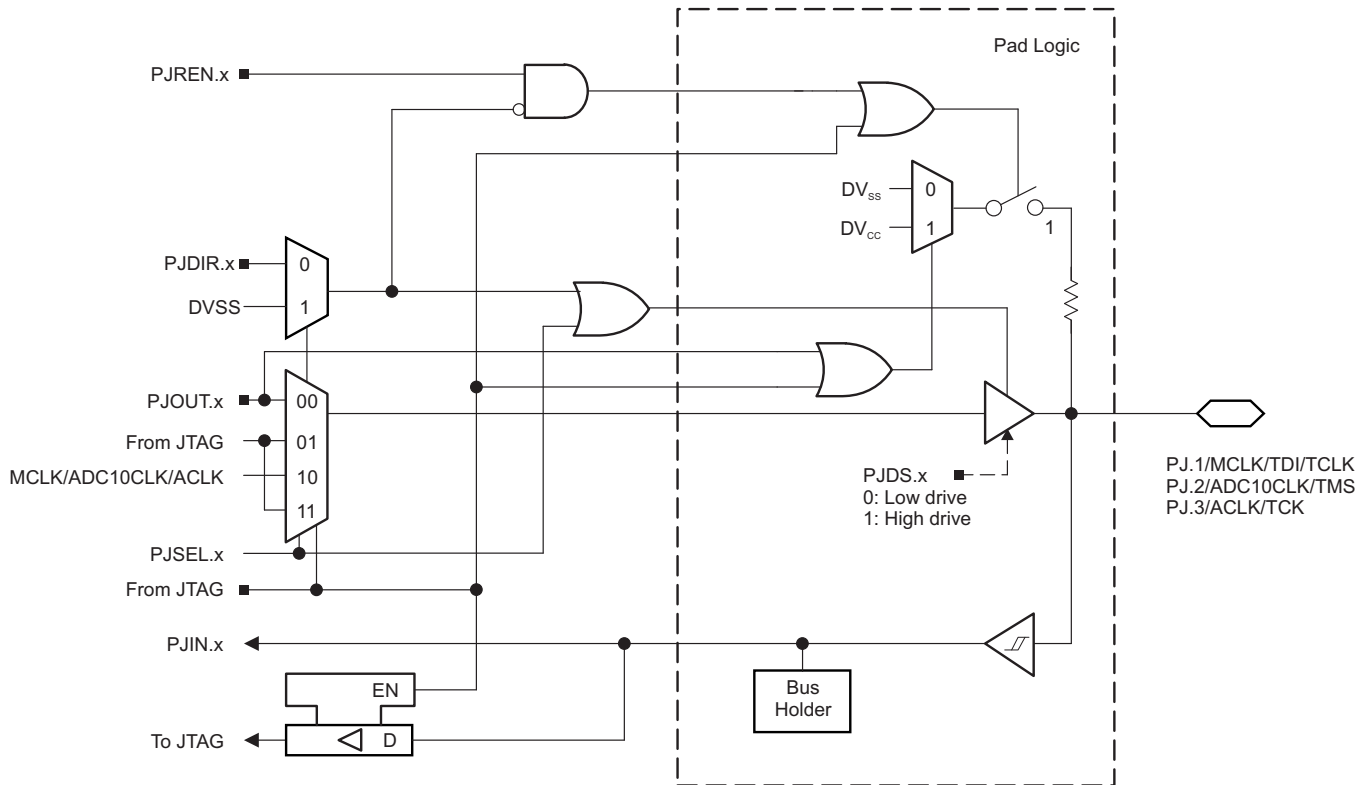


Figure 6-39. Port PJ (PJ.1 to PJ.3) Diagram

Table 6-97. Port PJ (PJ.0 to PJ.3) Pin Functions

| PIN NAME (PJ.x) | x | FUNCTION | CONTROL BITS OR SIGNALS ⁽¹⁾ | | |
|--------------------|---|-----------------------------|--|---------|-----------|
| | | | PJDIR.x | PJSEL.x | JTAG MODE |
| PJ.0/SMCLK/TDO | 0 | PJ.0 (I/O) ⁽²⁾ | I: 0; O: 1 | 0 | 0 |
| | | SMCLK | 1 | 1 | 0 |
| | | TDO ⁽³⁾ | x | x | 1 |
| PJ.1/MCLK/TDI/TCLK | 1 | PJ.1 (I/O) ⁽²⁾ | I: 0; O: 1 | 0 | 0 |
| | | MCLK | 1 | 1 | 0 |
| | | TDI/TCLK ^{(3) (4)} | x | x | 1 |
| PJ.2/ADC10CLK/TMS | 2 | PJ.2 (I/O) ⁽²⁾ | I: 0; O: 1 | 0 | 0 |
| | | ADC10CLK | 1 | 1 | 0 |
| | | TMS ^{(3) (4)} | x | x | 1 |
| PJ.3/ACLK/TCK | 3 | PJ.3 (I/O) ⁽²⁾ | I: 0; O: 1 | 0 | 0 |
| | | ACLK | 1 | 1 | 0 |
| | | TCK ^{(3) (4)} | x | x | 1 |

(1) X = don't care

(2) Default condition

(3) The pin direction is controlled by the JTAG module.

(4) In JTAG mode, pullups are activated automatically on TMS, TCK, and TDI/TCLK. PJREN.x are don't care.

6.13 Device Descriptors (TLV)

Table 6-98 through Table 6-100 list the contents of the device descriptor tag-length-value (TLV) structure for each device type.

Table 6-98. F677xA Device Descriptor

| DESCRIPTION | ADDRESS | SIZE (bytes) | VALUE | | | | | |
|-------------------|------------------------|--------------|----------|----------|----------|----------|----------|----------|
| | | | F6779A | F6778A | F6777A | F6776A | F6775A | |
| Info Block | Info length | 1A00h | 1 | 06h | 06h | 06h | 06h | 06h |
| | CRC length | 1A01h | 1 | 06h | 06h | 06h | 06h | 06h |
| | CRC value | 1A02h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Device ID | 1A04h | 2 | 8224h | 8223h | 8222h | 8221h | 8220h |
| | Hardware revision | 1A06h | 1 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Firmware revision | 1A07h | 1 | Per unit | Per unit | Per unit | Per unit | Per unit |
| Die Record | Die record tag | 1A08h | 1 | 08h | 08h | 08h | 08h | 08h |
| | Die record length | 1A09h | 1 | 0Ah | 0Ah | 0Ah | 0Ah | 0Ah |
| | Lot ID | 1A0Ah | 4 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | X position | 1A0Eh | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Y position | 1A10h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Test record CP | 1A12h | 1 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Test record FT | 1A13h | 1 | Per unit | Per unit | Per unit | Per unit | Per unit |
| ADC10 Calibration | ADC calibration tag | 1A14h | 1 | 13h | 13h | 13h | 13h | 13h |
| | ADC calibration length | 1A15h | 1 | 10h | 10h | 10h | 10h | 10h |
| | ADC gain factor | 1A16h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC offset | 1A18h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 15T30 | 1A1Ah | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 15T85 | 1A1Ch | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 20T30 | 1A1Eh | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 20T85 | 1A20h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 25T30 | 1A22h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| ADC 25T85 | 1A24h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit | |

Table 6-99. F676xA Device Descriptor

| DESCRIPTION | | ADDRESS | SIZE (bytes) | VALUE | | | | |
|-------------------|------------------------|---------|--------------|----------|----------|----------|----------|----------|
| | | | | F6769A | F6768A | F6767A | F6766A | F6765A |
| Info Block | Info length | 1A00h | 1 | 06h | 06h | 06h | 06h | 06h |
| | CRC length | 1A01h | 1 | 06h | 06h | 06h | 06h | 06h |
| | CRC value | 1A02h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Device ID | 1A04h | 2 | 821Fh | 821Eh | 821Dh | 821Ch | 821Bh |
| | Hardware revision | 1A06h | 1 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Firmware revision | 1A07h | 1 | Per unit | Per unit | Per unit | Per unit | Per unit |
| Die Record | Die record tag | 1A08h | 1 | 08h | 08h | 08h | 08h | 08h |
| | Die record length | 1A09h | 1 | 0Ah | 0Ah | 0Ah | 0Ah | 0Ah |
| | Lot ID | 1A0Ah | 4 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | X position | 1A0Eh | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Y position | 1A10h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Test record CP | 1A12h | 1 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Test record FT | 1A13h | 1 | Per unit | Per unit | Per unit | Per unit | Per unit |
| ADC10 Calibration | ADC calibration tag | 1A14h | 1 | 13h | 13h | 13h | 13h | 13h |
| | ADC calibration length | 1A15h | 1 | 10h | 10h | 10h | 10h | 10h |
| | ADC gain factor | 1A16h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC offset | 1A18h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 15T30 | 1A1Ah | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 15T85 | 1A1Ch | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 20T30 | 1A1Eh | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 20T85 | 1A20h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 25T30 | 1A22h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| ADC 25T85 | 1A24h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit | |

Table 6-100. F674xA Device Descriptor

| DESCRIPTION | | ADDRESS | SIZE (bytes) | VALUE | | | | |
|-------------------|------------------------|---------|--------------|----------|----------|----------|----------|----------|
| | | | | F6749A | F6748A | F6747A | F6746A | F6745A |
| Info Block | Info length | 1A00h | 1 | 06h | 06h | 06h | 06h | 06h |
| | CRC length | 1A01h | 1 | 06h | 06h | 06h | 06h | 06h |
| | CRC value | 1A02h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Device ID | 1A04h | 2 | 821Ah | 8219h | 8218h | 8217h | 8216h |
| | Hardware revision | 1A06h | 1 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Firmware revision | 1A07h | 1 | Per unit | Per unit | Per unit | Per unit | Per unit |
| Die Record | Die record tag | 1A08h | 1 | 08h | 08h | 08h | 08h | 08h |
| | Die record length | 1A09h | 1 | 0Ah | 0Ah | 0Ah | 0Ah | 0Ah |
| | Lot ID | 1A0Ah | 4 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | X position | 1A0Eh | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Y position | 1A10h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Test record CP | 1A12h | 1 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | Test record FT | 1A13h | 1 | Per unit | Per unit | Per unit | Per unit | Per unit |
| ADC10 Calibration | ADC calibration tag | 1A14h | 1 | 13h | 13h | 13h | 13h | 13h |
| | ADC calibration length | 1A15h | 1 | 10h | 10h | 10h | 10h | 10h |
| | ADC gain factor | 1A16h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC offset | 1A18h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 15T30 | 1A1Ah | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 15T85 | 1A1Ch | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 20T30 | 1A1Eh | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 20T85 | 1A20h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| | ADC 25T30 | 1A22h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit |
| ADC 25T85 | 1A24h | 2 | Per unit | Per unit | Per unit | Per unit | Per unit | |

6.14 Identification

6.14.1 Revision Identification

The device revision information is shown as part of the top-side marking on the device package. The device-specific errata sheet describes these markings. For links to all of the errata sheets for the devices in this data sheet, see [Section 8.4](#).

The hardware revision is also stored in the Device Descriptor structure in the Info Block section. For details on this value, see the "Hardware Revision" entries in [Section 6.13](#).

6.14.2 Device Identification

The device type can be identified from the top-side marking on the device package. The device-specific errata sheet describes these markings. For links to all of the errata sheets for the devices in this data sheet, see [Section 8.4](#).

A device identification value is also stored in the Device Descriptor structure in the Info Block section. For details on this value, see the "Device ID" entries in [Section 6.13](#).

6.14.3 JTAG Identification

Programming through the JTAG interface, including reading and identifying the JTAG ID, is described in detail in the [MSP430 Programming With the JTAG Interface](#).

7 Applications, Implementation, and Layout

NOTE

Information in the following Applications section is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

The following resources provide application guidelines and best practices when designing with the MSP430F677xA, MSP430F676xA, and MSP430F674xA devices.

Implementation of a 3-Phase Electronic Watt-Hour Meter Using the MSP430F677x(A)

This application report describes the implementation of a 3-phase electronic electricity meter using the TI MSP430F677x(A) metering processors. This application report includes the necessary information with regard to metrology software and hardware procedures for this single-chip implementation.

High-Accuracy 3-Phase Electricity Meter With Tamper Detection

The design implements a highly accurate 3-phase electric meter system using the MSP430F6779 smart meter SoC. It exceeds all of the requirements for ANSI C12.20 and IEC-62053 Class 0.2 meters. The F6779 SoC is the most integrated polyphase e-meter SoC with 512KB of flash. This allows developers to create a true single-chip smart e-meter with the highest performance and accuracy. In addition, this EVM has tamper detection capabilities which help the engineer develop methods to prevent theft of electricity from utilities.

Features

- Comprehensive design includes schematics, BOMs, design files, and test reports.
- Three-phase electricity meter which exceeds Class 0.2 accuracy requirements from ANSI and IEC
- TI Energy Library firmware calculates all energy measurement parameters including active and reactive power and energy, RMS current and voltage, power factor, and line frequency.
- Add-on communications modules for wireless communications standards such as ZigBee®, Wi-Fi®, Wireless M-Bus, and IEEE Std 802.15.4g, both 2.4 GHz and sub-1 GHz
- Built-in 160-segment display powered from 3-phase line voltage

8 Device and Documentation Support

8.1 Getting Started and Next Steps

For more information on the MSP430™ family of devices and the tools and libraries that are available to help with your development, visit the [Getting Started](#) page.

8.2 Device Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all MSP MCU devices. Each MSP MCU commercial family member has one of two prefixes: MSP or XMS. These prefixes represent evolutionary stages of product development from engineering prototypes (XMS) through fully qualified production devices (MSP).

XMS – Experimental device that is not necessarily representative of the final device's electrical specifications

MSP – Fully qualified production device

XMS devices are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

MSP devices have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (XMS) have a greater failure rate than the standard production devices. TI recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the temperature range, package type, and distribution format. [Figure 8-1](#) provides a legend for reading the complete device name.

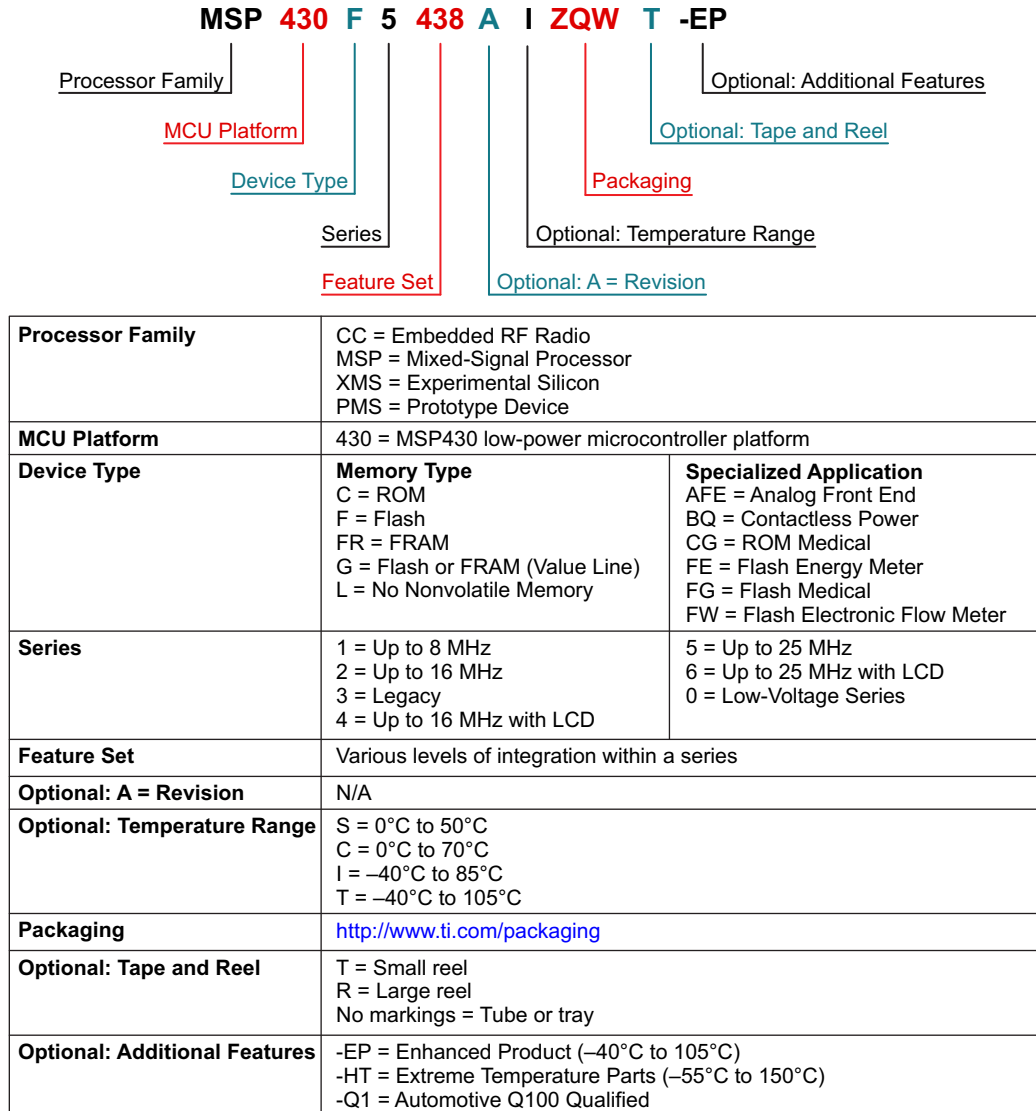


Figure 8-1. Device Nomenclature

8.3 Tools and Software

All MSP microcontrollers are supported by a wide variety of software and hardware development tools. Tools are available from TI and various third parties. See them all at [MSP430 Ultra-Low-Power MCUs – Tools & software](#).

Table 8-1 lists the debug features of the MSP430F677xA, MSP430F676xA, and MSP430F674xA MCUs. See the [Code Composer Studio for MSP430 User's Guide](#) for details on the available features.

Table 8-1. Hardware Debug Features

| MSP430 ARCHITECTURE | 4-WIRE JTAG | 2-WIRE JTAG | BREAK-POINTS (N) | RANGE BREAK-POINTS | CLOCK CONTROL | STATE SEQUENCER | TRACE BUFFER | LPMx.5 DEBUGGING SUPPORT |
|---------------------|-------------|-------------|------------------|--------------------|---------------|-----------------|--------------|--------------------------|
| MSP430Xv2 | Yes | Yes | 3 | Yes | Yes | No | No | Yes |

Design Kits and Evaluation Modules

3-Phase Electronic Watt-Hour EVM for Metering (EVM430-F6779) This EVM430-F6779 is a three-phase electricity meter evaluation module based on the MSP430F6779A device. The E-meter has inputs for three voltages and three currents, as well as an additional connection to demonstrate antitampering. The EVM lets you test the new F677x, F674x, F676x, F677x1, F674x1, F676x1 series and see the accuracy results, wide dynamic range achieved, and ease of calibration. The easy-to-use Energy Library provides metrology software for fast startup with this EVM. The software is also programmable for any user's needs.

Three-Phase Metrology With Enhanced ESD Protection and Tamper Detection Reference Design

This design implements an ANSI/IEC Class 0.2 three-phase energy meter with enhanced ESD protection. The design also features tamper detection to limit the feasibility of energy theft and communications through ZigBee connectivity. The e-meter SoC is used to perform all metrology functions and sends active power results to the CC2530EM add-on board. Developers can use the companion In Home Display TI Design (TIDM-LOWEND-IHD) to display results remotely.

128-Pin Target Development Board and MSP-FET Programmer Bundle for MSP430F6x MCUs The MSP-FET430U128 is a powerful flash emulation tool to quickly begin application development on the MSP430 MCU. It includes a USB debugging interface used to program and debug the MSP430 in system through the JTAG interface or the pin-saving Spy-Bi-Wire (2-wire JTAG) protocol.

Software

MSP430Ware™ Software MSP430Ware software is a collection of code examples, data sheets, and other design resources for all MSP430 devices delivered in a convenient package. In addition to providing a complete collection of existing MSP430 design resources, MSP430Ware software also includes a high-level API called MSP Driver Library. This library makes it easy to program MSP430 hardware. MSP430Ware software is available as a component of CCS or as a stand-alone package.

Energy Measurement Design Center for MSP430 MCUs The Energy Measurement Design Center is a rapid development tool that enables energy measurement using TI MSP430i20xx and MSP430F67xx flash-based microcontrollers (MCUs). It includes a graphical user interface (GUI), documentation, software library, and examples that can simplify development and accelerate designs in a wide range of power monitoring and energy measurement applications, including smart grid and building automation. Using the Design Center, you can configure, calibrate, and view results without writing a single line of code.

MSP Driver Library The abstracted API of MSP Driver Library provides easy-to-use function calls that free you from directly manipulating the bits and bytes of the MSP430 hardware. Thorough documentation is delivered through a helpful API Guide, which includes details on each function call and the recognized parameters. Developers can use Driver Library functions to write complete projects with minimal overhead.

MSP430F677x(1)A, MSP430F676x(1)A, MSP430F674x(1)A Code Examples C code examples that configure each of the integrated peripherals for various application needs are available for every MSP device.

MSP EnergyTrace™ Technology EnergyTrace technology for MSP430 microcontrollers is an energy-based code analysis tool that measures and displays the energy profile of the application and helps to optimize it for ultra-low-power consumption.

ULP (Ultra-Low Power) Advisor ULP Advisor™ software is a tool for guiding developers to write more efficient code to fully use the unique ultra-low-power features of MSP and MSP432 microcontrollers. Aimed at both experienced and new microcontroller developers, ULP Advisor checks your code against a thorough ULP checklist to help minimize the energy consumption of your application. At build time, ULP Advisor provides notifications and remarks to highlight areas of your code that can be further optimized for lower power.

Fixed Point Math Library for MSP The MSP IQmath and Qmath Libraries are a collection of highly optimized and high-precision mathematical functions for C programmers to seamlessly port a floating-point algorithm into fixed-point code on MSP430 and MSP432 devices. These routines are typically used in computationally intensive real-time applications where optimal execution speed, high accuracy, and ultra-low energy are critical. By using the IQmath and Qmath libraries, it is possible to achieve execution speeds considerably faster and energy consumption considerably lower than equivalent code written using floating-point math.

Floating Point Math Library for MSP430 Continuing to innovate in the low-power and low-cost microcontroller space, TI provides MSPMATHLIB. Leveraging the intelligent peripherals of our devices, this floating-point math library of scalar functions that are up to 26 times faster than the standard MSP430 math functions. Mathlib is easy to integrate into your designs. This library is free and is integrated in both Code Composer Studio IDE and IAR Embedded Workbench IDE.

Development Tools

Code Composer Studio™ Integrated Development Environment for MSP Microcontrollers Code Composer Studio (CCS) integrated development environment (IDE) supports all MSP microcontroller devices. CCS comprises a suite of embedded software utilities used to develop and debug embedded applications. It includes an optimizing C/C++ compiler, source code editor, project build environment, debugger, profiler, and many other features.

Command-Line Programmer MSP Flasher is an open-source shell-based interface for programming MSP microcontrollers through a FET programmer or eZ430 using JTAG or Spy-Bi-Wire (SBW) communication. MSP Flasher can download binary files (.txt or .hex) directly to the MSP microcontroller without an IDE.

MSP MCU Programmer and Debugger The MSP-FET is a powerful emulation development tool – often called a debug probe – which lets users quickly begin application development on MSP low-power MCUs. Creating MCU software usually requires downloading the resulting binary program to the MSP device for validation and debugging.

MSP-GANG Production Programmer The MSP Gang Programmer is an MSP430 or MSP432 device programmer that can program up to eight identical MSP430 or MSP432 flash or FRAM devices at the same time. The MSP Gang Programmer connects to a host PC using a standard RS-232 or USB connection and provides flexible programming options that let the user fully customize the process.

8.4 Documentation Support

The following documents describe the MSP430F677xA, MSP430F676xA, and MSP430F674xA MCUs. Copies of these documents are available on the Internet at www.ti.com.

Receiving Notification of Document Updates

To receive notification of documentation updates—including silicon errata—go to the product folder for your device on ti.com (for links to the product folders, see [Section 8.5](#)). In the upper right corner, click the "Alert me" button. This registers you to receive a weekly digest of product information that has changed (if any). For change details, check the revision history of any revised document.

Errata

- [MSP430F6779A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6778A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6777A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6776A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6775A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6769A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6768A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6767A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6766A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6765A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6749A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6748A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6747A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6746A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.
- [MSP430F6745A Device Erratasheet](#)** Describes the known exceptions to the functional specifications.

User's Guides

- [MSP430x5xx and MSP430x6xx Family User's Guide](#)** Detailed information on the modules and peripherals available in this device family.
- [MSP430™ Flash Device Bootloader \(BSL\) User's Guide](#)** The MSP430 bootloader (BSL) lets users communicate with embedded memory in the MSP430 microcontroller during the prototyping phase, final production, and in service. Both the programmable memory (flash memory) and the data memory (RAM) can be modified as required. Do not confuse the bootloader with the bootstrap loader programs found in some digital signal processors (DSPs) that automatically load program code (and data) from external memory to the internal memory of the DSP.
- [MSP430 Programming With the JTAG Interface](#)** This document describes the functions that are required to erase, program, and verify the memory module of the MSP430 flash-based and FRAM-based microcontroller families using the JTAG communication port. In addition, it describes how to program the JTAG access security fuse that is available on all MSP430 devices. This document describes device access using both the standard 4-wire JTAG interface and the 2-wire JTAG interface, which is also referred to as Spy-Bi-Wire (SBW).
- [MSP430 Hardware Tools User's Guide](#)** This manual describes the hardware of the TI MSP-FET430 Flash Emulation Tool (FET). The FET is the program development tool for the MSP430 ultra-low-power microcontroller. Both available interface types, the parallel port interface and the USB interface, are described.

Application Reports

Implementation of a Three-Phase Electronic Watt-Hour Meter Using MSP430F677x(A) This application report describes the implementation of a three-phase electronic electricity meter using the MSP430F677x(A) metering processor. This application report includes the necessary information with regard to metrology software, hardware procedures for this single-chip implementation.

Using TI's DLMS COSEM Library This application report describes in detail the usage of DLMS COSEM library developed by Texas Instruments for customers who use TI's microcontrollers in metering applications. The library is provided as object code with a configuration file for ease of use. The library can be obtained by contacting the regional sales and marketing offices.

Differences Between MSP430F67xx and MSP430F67xxA Devices This application report describes the enhancements of the MSP430F67xxA devices from the non-A MSP430F67xx devices. This application report describes the MSP430F67xx errata that are fixed in the MSP430F67xxA and the additional features added to the MSP430F67xxA devices. In addition, metrology results are compared to further show that the changes implemented in the MSP430F67xxA devices do not affect the metrology performance.

MSP430 32-kHz Crystal Oscillators Selection of the correct crystal, correct load circuit, and proper board layout are important for a stable crystal oscillator. This application report summarizes crystal oscillator function and explains the parameters to select the correct crystal for MSP430 ultra-low-power operation. In addition, hints and examples for correct board layout are given. The document also contains detailed information on the possible oscillator tests to ensure stable oscillator operation in mass production.

MSP430 System-Level ESD Considerations System-Level ESD has become increasingly demanding with silicon technology scaling towards lower voltages and the need for designing cost-effective and ultra-low-power components. This application report addresses three different ESD topics to help board designers and OEMs understand and design robust system-level designs.

Designing With MSP430 and Segment LCDs Segment liquid crystal displays (LCDs) are needed to provide information to users in a wide variety of applications from smart meters to electronic shelf labels (ESLs) to medical equipment. Several MSP430™ microcontroller families include built-in low-power LCD driver circuitry that allows the MSP430 MCU to directly control the segmented LCD glass. This application note helps explain how segmented LCDs work, the different features of the various LCD modules across the MSP430 MCU family, LCD hardware layout tips, guidance on writing efficient and easy-to-use LCD driver software, and an overview of the portfolio of MSP430 devices that include different LCD features to aid in device selection.

8.5 Related Links

Table 8-2 lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 8-2. Related Links

| PARTS | PRODUCT FOLDER | ORDER NOW | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|--------------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|
| MSP430F6779A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6778A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6777A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6776A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6775A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6769A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6768A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6767A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6766A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6765A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6749A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6748A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6747A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6746A | Click here | Click here | Click here | Click here | Click here |
| MSP430F6745A | Click here | Click here | Click here | Click here | Click here |

8.6 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

[TI E2E™ Community](#)

TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas, and help solve problems with fellow engineers.

[TI Embedded Processors Wiki](#)

Texas Instruments Embedded Processors Wiki. Established to help developers get started with embedded processors from Texas Instruments and to foster innovation and growth of general knowledge about the hardware and software surrounding these devices.

8.7 Trademarks

MSP430, MSP430Ware, EnergyTrace, ULP Advisor, Code Composer Studio, E2E are trademarks of Texas Instruments.

Wi-Fi is a registered trademark of Wi-Fi Alliance.

ZigBee is a registered trademark of ZigBee Alliance.

8.8 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.



ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.9 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

9 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|--------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| MSP430F6745AIP EU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6745A | Samples |
| MSP430F6745AIP EUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6745A | Samples |
| MSP430F6745AIP Z | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6745A | Samples |
| MSP430F6745AIP ZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6745A | Samples |
| MSP430F6746AIP EU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6746A | Samples |
| MSP430F6746AIP EUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6746A | Samples |
| MSP430F6746AIP Z | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6746A | Samples |
| MSP430F6746AIP ZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6746A | Samples |
| MSP430F6747AIP EU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6747A | Samples |
| MSP430F6747AIP EUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6747A | Samples |
| MSP430F6747AIP Z | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6747A | Samples |
| MSP430F6747AIP ZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6747A | Samples |
| MSP430F6748AIP EU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6748A | Samples |
| MSP430F6748AIP EUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6748A | Samples |
| MSP430F6748AIP Z | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6748A | Samples |
| MSP430F6748AIP ZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6748A | Samples |
| MSP430F6749AIP EU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6749A | Samples |
| MSP430F6749AIP EUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6749A | Samples |
| MSP430F6749AIP Z | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6749A | Samples |
| MSP430F6749AIP ZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6749A | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|--------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| MSP430F6765AIP EU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6765A | Samples |
| MSP430F6765AIP EUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6765A | Samples |
| MSP430F6765AIP Z | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6765A | Samples |
| MSP430F6765AIP ZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6765A | Samples |
| MSP430F6766AIP EU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6766A | Samples |
| MSP430F6766AIP EUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6766A | Samples |
| MSP430F6766AIP Z | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6766A | Samples |
| MSP430F6766AIP ZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6766A | Samples |
| MSP430F6767AIP EU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6767A | Samples |
| MSP430F6767AIP EUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6767A | Samples |
| MSP430F6767AIP Z | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6767A | Samples |
| MSP430F6767AIP ZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6767A | Samples |
| MSP430F6768AIP EU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6768A | Samples |
| MSP430F6768AIP EUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6768A | Samples |
| MSP430F6768AIP Z | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6768A | Samples |
| MSP430F6768AIP ZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6768A | Samples |
| MSP430F6769AIP EU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6769A | Samples |
| MSP430F6769AIP EUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6769A | Samples |
| MSP430F6769AIP Z | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6769A | Samples |
| MSP430F6769AIP ZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6769A | Samples |
| MSP430F6775AIP EU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6775A | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|-------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| MSP430F6775A1PEUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6775A | Samples |
| MSP430F6775A1PZ | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6775A | Samples |
| MSP430F6775A1PZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6775A | Samples |
| MSP430F6776A1PEU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6776A | Samples |
| MSP430F6776A1PEUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6776A | Samples |
| MSP430F6776A1PZ | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6776A | Samples |
| MSP430F6776A1PZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6776A | Samples |
| MSP430F6777A1PEU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6777A | Samples |
| MSP430F6777A1PEUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6777A | Samples |
| MSP430F6777A1PZ | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6777A | Samples |
| MSP430F6777A1PZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6777A | Samples |
| MSP430F6778A1PEU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6778A | Samples |
| MSP430F6778A1PEUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6778A | Samples |
| MSP430F6778A1PZ | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6778A | Samples |
| MSP430F6778A1PZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6778A | Samples |
| MSP430F6779A1PEU | ACTIVE | LQFP | PEU | 128 | 72 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6779A | Samples |
| MSP430F6779A1PEUR | ACTIVE | LQFP | PEU | 128 | 750 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6779A | Samples |
| MSP430F6779A1PZ | ACTIVE | LQFP | PZ | 100 | 90 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6779A | Samples |
| MSP430F6779A1PZR | ACTIVE | LQFP | PZ | 100 | 1000 | RoHS & Green | NIPDAU | Level-3-260C-168 HR | -40 to 85 | F6779A | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of ≤ 1000 ppm threshold. Antimony trioxide based flame retardants must also meet the ≤ 1000 ppm threshold requirement.

⁽³⁾ **MSL, Peak Temp.** - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ **Lead finish/Ball material** - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TRAY


Chamfer on Tray corner indicates Pin 1 orientation of packed units.

*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | Unit array matrix | Max temperature (°C) | L (mm) | W (mm) | K0 (µm) | P1 (mm) | CL (mm) | CW (mm) |
|-----------------|--------------|--------------|------|-----|-------------------|----------------------|--------|--------|---------|---------|---------|---------|
| MSP430F6745AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6745AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6746AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6746AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6747AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6747AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6748AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6748AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6749AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6749AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6765AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6765AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6766AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6766AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6767AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6767AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6768AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |

| Device | Package Name | Package Type | Pins | SPQ | Unit array matrix | Max temperature (°C) | L (mm) | W (mm) | K0 (µm) | P1 (mm) | CL (mm) | CW (mm) |
|-----------------|--------------|--------------|------|-----|-------------------|----------------------|--------|--------|---------|---------|---------|---------|
| MSP430F6768AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6769AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6769AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6775AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6775AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6776AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6776AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6777AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6777AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6778AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6778AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |
| MSP430F6779AIEU | PEU | LQFP | 128 | 72 | 6X12 | 150 | 315 | 135.9 | 7620 | 25.4 | 17.8 | 15.45 |
| MSP430F6779AIPZ | PZ | LQFP | 100 | 90 | 6 x 15 | 150 | 315 | 135.9 | 7620 | 20.3 | 15.4 | 15.45 |

PZ (S-PQFP-G100)

PLASTIC QUAD FLATPACK

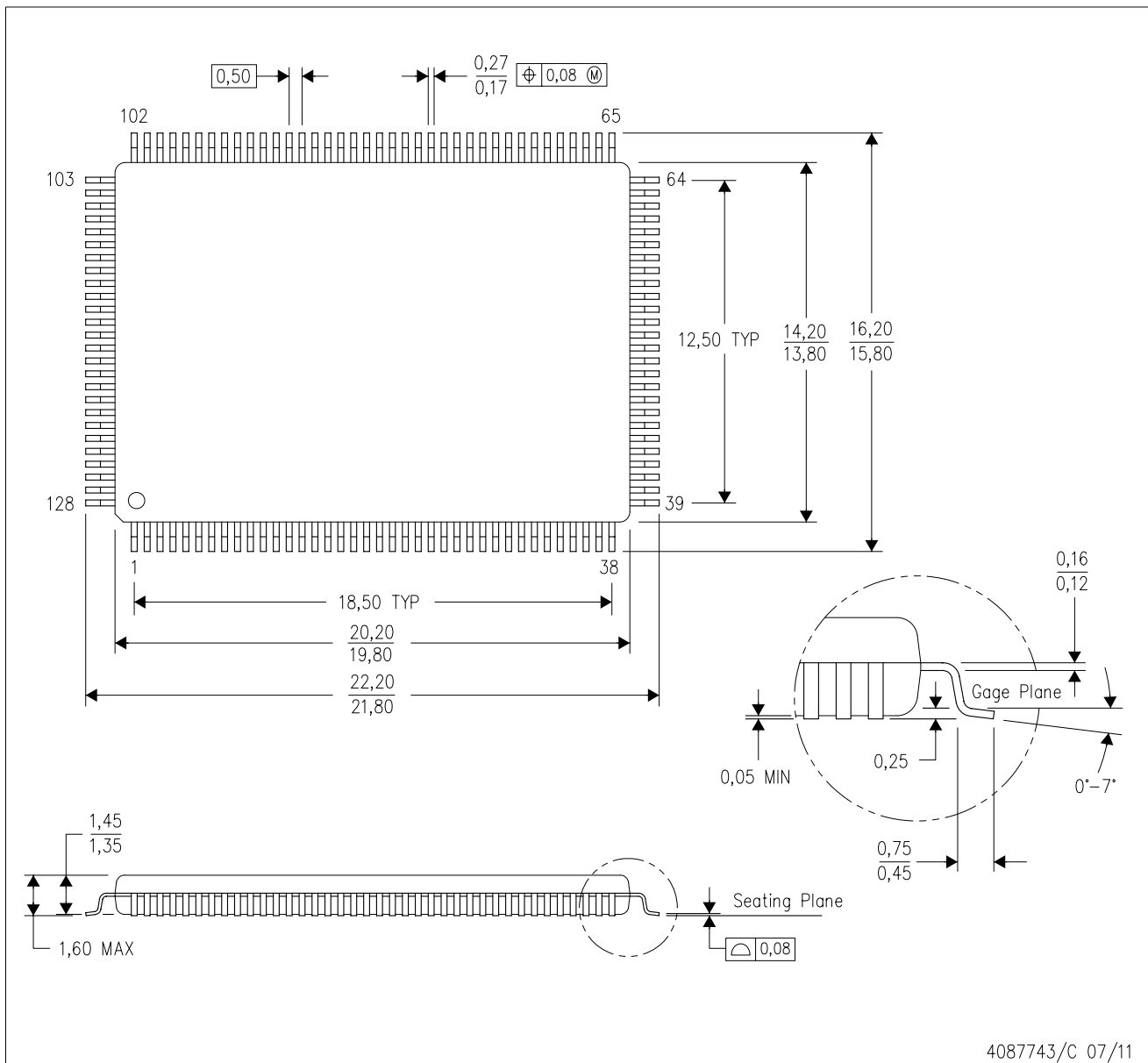


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-026

MECHANICAL DATA

PEU (R-PQFP-G128)

PLASTIC QUAD FLATPACK



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-026

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